

MSM64162A

4-Bit Microcontroller

User's Manual

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OKI ELECTRIC INDUSTRY CO., LTD.

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Introduction

The MSM64162A is a high-performance single chip microcontroller that uses a 4-bit CPU core (nX-4/20). This Oki-original CPU core architecture is combined with additional on-chip peripheral functions.

This manual explains hardware of the MSM64162A.

For details of the nX-4/20 core instruction set, refer to the "nX-4/20, nX-4/30 Core Instruction Manual."

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Overview

This chapter describes the features, block diagrams, pin configurations, pin descriptions and basic operation timings.

Chapter 1 Overview

1.1 Overview

The MSM64162A is a CMOS 4-bit microcontroller that has built-in 128-nibble RAM, 16 I/O ports, buzzer output, an RC oscillation type A/D converter and 24 LCD segment drivers.

The MSM64162A uses a high-performance 4-bit CPU core (nX-4/20) with byte processing instructions and is best suited for applications such as thermometers, hygrometers and body thermometers because of its compact chip layout and rich peripheral functions.

1.2 Features

- (1) Rich instruction set including byte operation instructions
 - 148 instructions
 - Byte addition/subtraction, byte transfer and byte comparison instructions
 - Bit manipulation instructions
 - Data exchange instructions
- (2) Rich addressing modes
 - Two kinds of indirect addressing modes using HL register and XY register
 - Bit manipulation on entire data memory area
 - Byte operation on entire data memory area
- (3) Operating frequencies
 - Low speed clock 32.768 kHz crystal oscillation (minimum instruction execution time: 91 μ s)
 - High speed clock 400 kHz RC oscillation
- (4) Built-in program memory : 2016 bytes
- (5) Built-in data memory : 128 nibbles
- (6) I/O ports : 16
 - 4-bit input/output port (NMOS open drain output/CMOS output selectable, input with pull-down/pull-up resistance or high-impedance input selectable) \times 2
 - 4-bit input port (Input with pull-down/pull-up resistance selectable) \times 1
 - 4-bit output port (NMOS open drain output/CMOS output selectable) \times 1
- (7) Buzzer output : 1
 - 4 output modes selectable
- (8) Battery check : 1

- (9) LCD driver : 24
 - At 1/4 duty and 1/3 bias : 80 segments (20 × 4)
 - At 1/3 duty and 1/3 bias : 63 segments (21 × 3)
 - At 1/2 duty and 1/2 bias : 44 segments (22 × 2)
 - Output port selectable by mask option for 8 drivers
- (10) RC oscillation method A/D converter : 2 channels
 - Time dividing 2-channel method
 - A counter: $1/(10^4 \times 8) \times 1$
 - B counter : $1/2^{14} \times 1$
- (11) Capture circuit : 2 channels
 - 256 Hz, 128 Hz, 64 Hz, and 32 Hz
- (12) Watchdog timer
- (13) Interrupt causes: 9 causes
 - 2 external causes, 5 time base causes, 1 A/D converter cause and 1 watchdog timer cause
- (14) Power supply voltage
 - 1.5 V/3 V selectable by mask option
- (15) Low power consumption (Typ.)

	CPU in halt state	CPU in operation state
1.5 V, 400kOSC halt	2 μ A	5 μ A
3.0 V, 400kOSC halt	1.5 μ A	5 μ A

- (16) Exterior
 - Chip : MSM64162A-xxx
 - 80-pin flat package : MSM64162A-xxxGS-BK (QFP80-P-1420-0.80-BK)

1.3 Block Diagram

Figure 1-1 shows the block diagram of the MSM64162A.

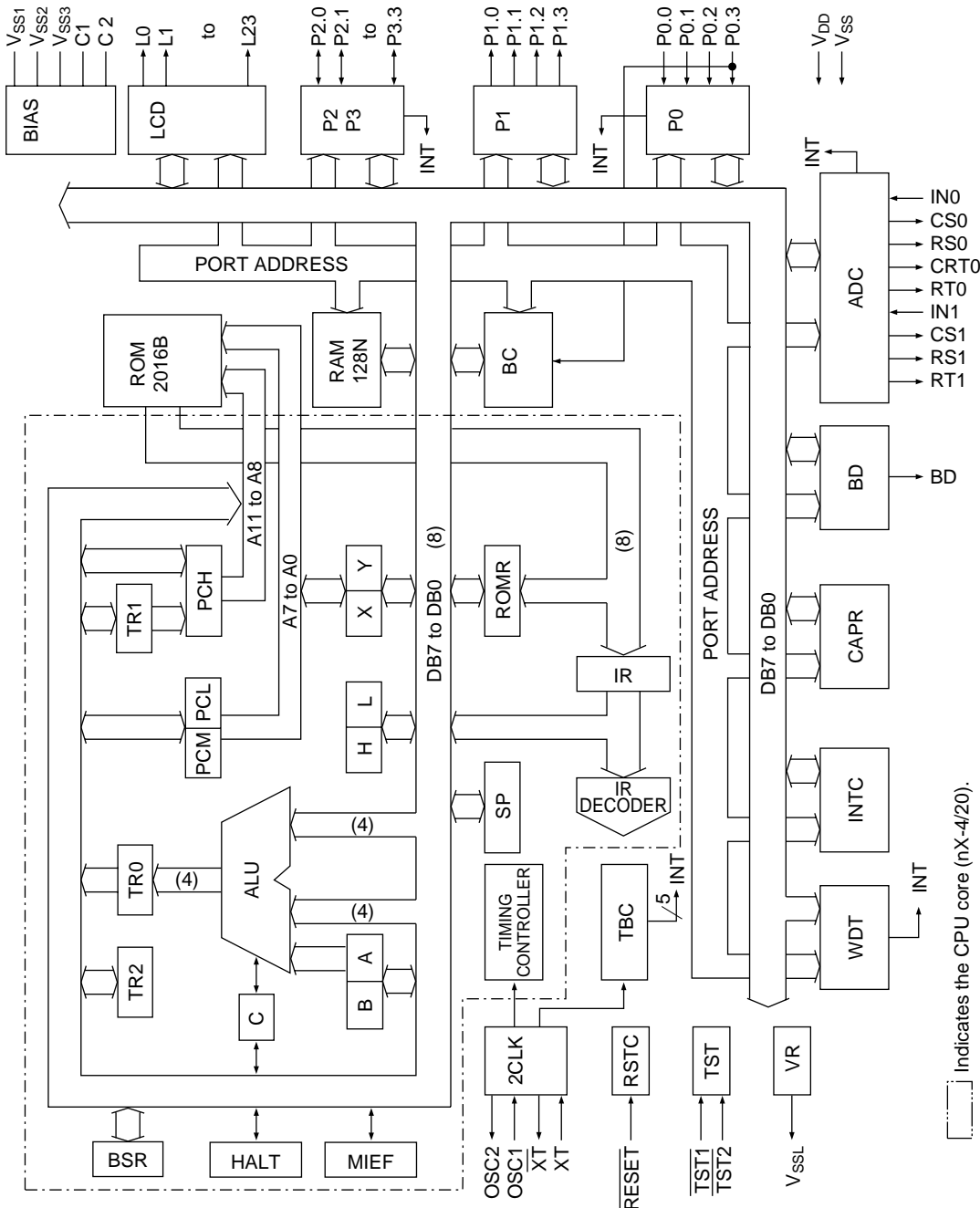
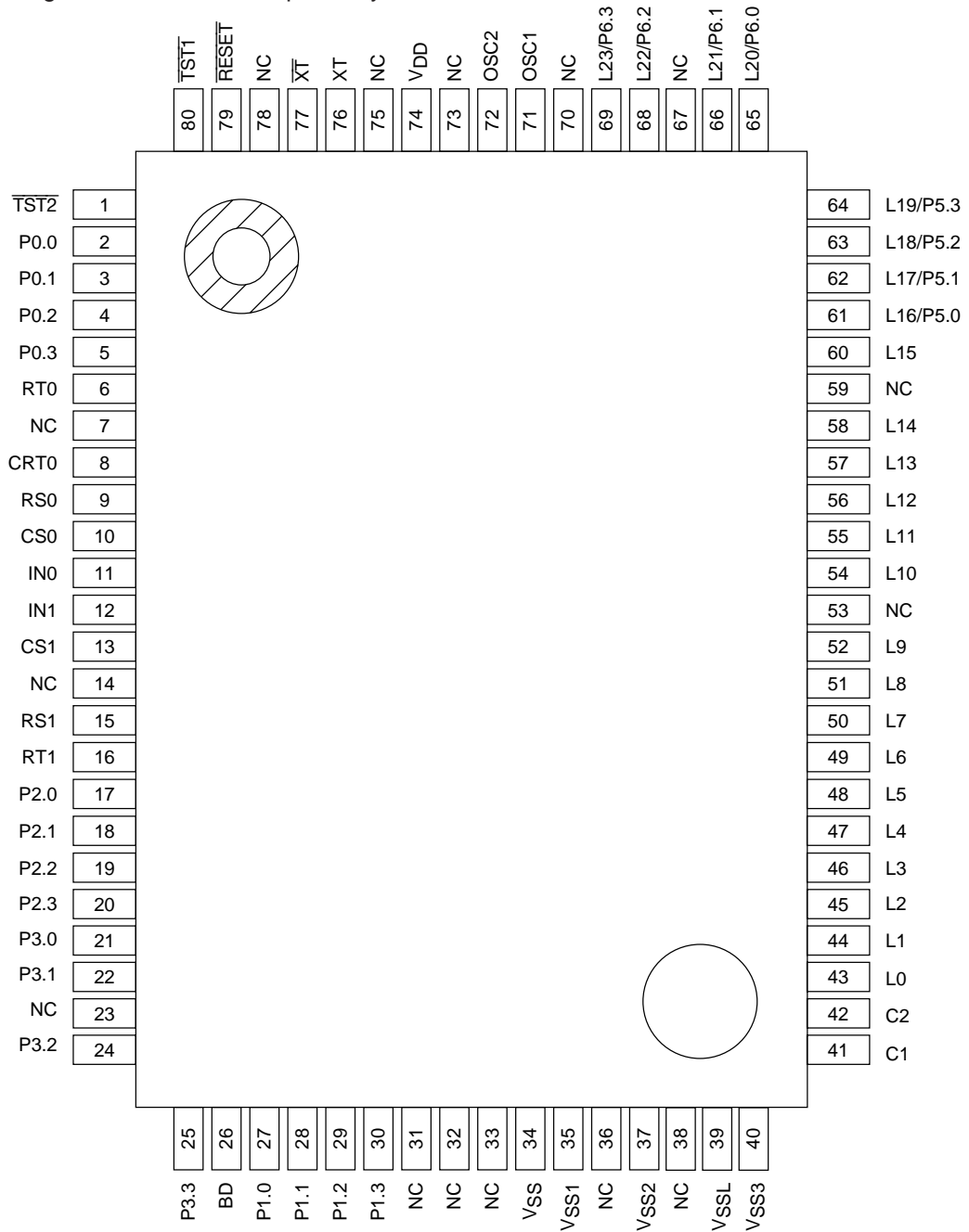


Figure 1-1 MSM64162A Block Diagram

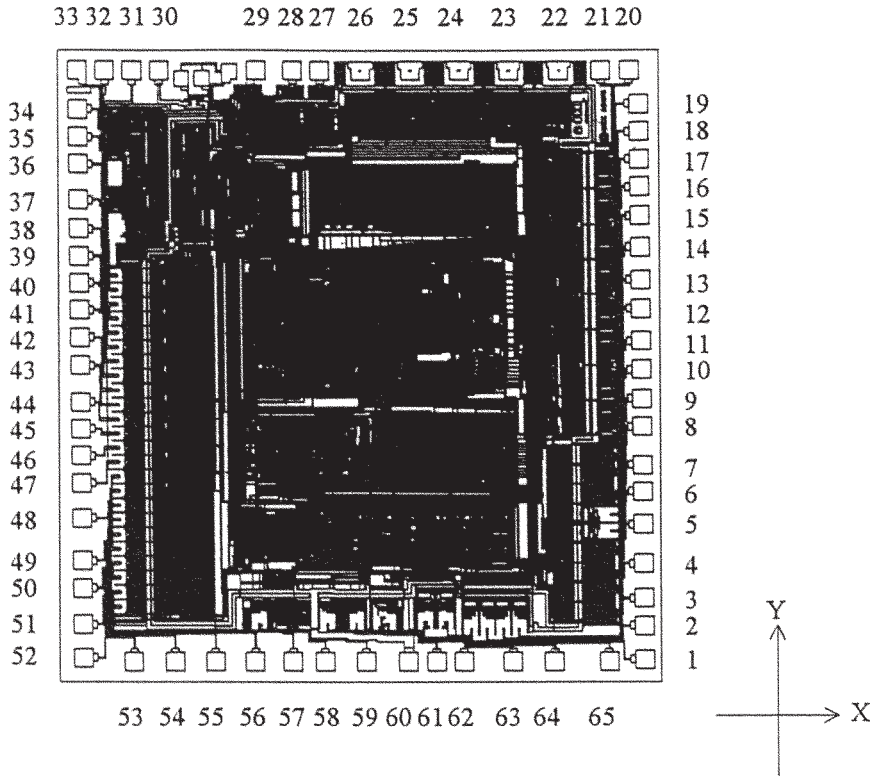
1.4 Pin Configuration

The pin configuration of the package of MSM64162A and the chip exterior figure are shown in Figures 1-2 and 1-3, respectively.



Note: A pin "NC" is an unused pin which is the open state.

Figure 1-2 MSM64162A (80QFP) Pin Configuration



- Chip Size : 3.96 mm × 4.32 mm
- Chip Thickness : 350 μm (Typ.)
- Coordinate Origin : Chip center
- Pad Hole Size : 110 μm × 110 μm
- Pad Size : 120 μm × 120 μm
- Minimum Pad Pitch : 180 μm

Note: The voltage level of the chip back is V_{DD} level.

Figure 1-3 MSM64162A Chip Exterior Figure

1.5 Pin Description

1.5.1 Description of Each Pin

The basic functions of each pin of the MSM64162A are shown in Table 1-1 and their secondary functions are shown in Table 1-2.

Table 1-1 (A) Description of Pin (Basic Function)

Classification	Pin name	Pin No.	Pad No.	Input/Output	Function
Power supply	V _{DD}	74	60	—	0 V power supply
	V _{SS}	34	27	—	Negative side power supply
	V _{SS1}	35	28	—	Negative side power supply (at 1.5 V spec.) Bias output for driving LCD (–1.5 V) (at 3.0 V spec.) At non-regulated LCD driver. Bias output for driving LCD (–1.2 V) (When constant voltage circuit for LCD is used)
	V _{SS2}	37	29	—	Negative side power supply (at 3.0 V spec.) Bias output for driving LCD (–3.0 V) (at 1.5 V spec.) At non-regulated LCD driver.
	V _{SS3}	40	31	—	Bias output for driving LCD (–4.5 V)
	C1	41	32	—	Capacitor connection pin for LCD
	C2	42	33	—	driving bias generation
	V _{SSL}	39	30	—	Negative side power supply pin for internal logic (internally generated constant voltage)
Oscillation	XT	76	61	Input	Low speed side clock oscillation input pin: Connects to the crystal oscillator (32.768 kHz).
	\overline{XT}	77	62	Output	Low speed side clock oscillation output pin: Connects to the crystal oscillator (32.768 kHz).
	OSC1	71	58	Input	High speed side clock pin: Connects to the external resistance of oscillation (R _{OS}).
	OSC2	72	59	Output	
Test	$\overline{TST1}$	80	64	Input	Input pin for test: Pulled-up to V _{DD} internally.
	$\overline{TST2}$	1	65	Input	
Reset	\overline{RESET}	79	63	Input	System reset input: When this pin becomes "H" level from "L" level, the internal state is initialized and execution of an instruction starts from address 000H. Pulled-up to V _{DD} internally.

Table 1-1 (B) Pin Description (Basic Functions)

Classification	Pin name	Pin No.	Pad No.	Input/Output	Function
Port	P0.0	2	1	Input	4-bit input port (P0): Can select (1) input with pull-up resistance, (2) input with pull-down resistance or (3) input with high impedance by the port 01 control register (P01CON). As a secondary function, P0.0 to P0.3 are assigned external interrupt functions, P0.0 and P0.1 are assigned a capture trigger function and P0.3 is assigned an analog comparator input for battery check.
	P0.1	3	2	Input	
	P0.2	4	3	Input	
	P0.3	5	4	Input	
	P1.0	27	23	Output	4-bit output port (P1): Can select NMOS open drain output or CMOS output by the port 01 control register (P01CON). P1.0 is a large current drive output port.
	P1.1	28	24	Output	
	P1.2	29	25	Output	
	P1.3	30	26	Output	
	P2.0	17	14	Input/Output	4-bit input/output port (P2): Can select (1) pull-up or pull-down resistance input, (2) high impedance input, (3) NMOS open drain output or (4) CMOS output by the port 2 control registers 0 to 3 (P20CON to P23CON). As secondary functions, P2.0 to P2.3 are assigned external interrupt functions.
	P2.1	18	15	Input/Output	
	P2.2	19	16	Input/Output	
	P2.3	20	17	Input/Output	
	P3.0	21	18	Input/Output	4-bit input/output port (P3): Can select (1) pull-up or pull-down resistance input, (2) high impedance input, (3) NMOS open drain output or (4) CMOS output by the port 3 control registers 0 to 3 (P30CON to P33CON). As secondary functions, P3.0 to P3.3 are assigned external interrupt functions, and P3.3 is assigned a monitor function of RC oscillation clock for A/D converter.
	P3.1	22	19	Input/Output	
	P3.2	24	20	Input/Output	
	P3.3	25	21	Input/Output	

Table 1-1 (C) Pin Description (Basic Functions)

Classification	Pin name	Pin No.	Pad No.	Input/Output	Function
Buzzer	BD	26	22	Output	Output pin for the buzzer drive
A/D converter	RT0	6	5	Output	Resistance sensor connection pin for measurement of Channel 0
	CRT0	8	6	Output	Resistance/capacitance sensor connection pin for measurement of Channel 0.
	RS0	9	7	Output	Reference resistance connection pin of Channel 0
	CS0	10	8	Output	Reference capacitance connection pin of Channel 0
	IN0	11	9	Input	Input pin of RC oscillation circuit Channel 0
	RT1	16	13	Output	Resistance sensor connection pin for measurement of Channel 1
	RS1	15	12	Output	Reference resistance connection pin of Channel 1
	CS1	13	11	Output	Reference capacitance connection pin of Channel 1
	IN1	12	10	Input	Input pin of RC oscillation circuit of Channel 1

Table 1-1 (D) Pin Description (Basic Functions)

Classification	Pin name	Pin No.	Pad No.	Input/Output	Function
LCD driver	L0	43	34	Output	LCD segment/common signal output pins.
	L1	44	35	Output	
	L2	45	36	Output	
	L3	46	37	Output	
	L4	47	38	Output	
	L5	48	39	Output	
	L6	49	40	Output	
	L7	50	41	Output	
	L8	51	42	Output	
	L9	52	43	Output	
	L10	54	44	Output	
	L11	55	45	Output	
	L12	56	46	Output	
	L13	57	47	Output	
	L14	58	48	Output	
L15	60	49	Output		
LCD driver	L16/P5.0	61	50	Output	LCD segment/common signal output pins. Can function as output ports by the mask option.
	L17/P5.1	62	51	Output	
	L18/P5.2	63	52	Output	
	L19/P5.3	64	53	Output	
	L20/P6.0	65	54	Output	
	L21/P6.1	66	55	Output	
	L22/P6.2	68	56	Output	
	L23/P6.3	69	57	Output	

Table 1-2 Pin Description (Secondary Functions)

Classification	Pin name	Pin No.	Pad No.	Input/Output	Function
External interrupt	P0.0	2	1	Input	Secondary function: An external interrupt input pin. Can receive interrupt by level change.
	P0.1	3	2		
	P0.2	4	3		
	P0.3	5	4		
	P2.0	17	14	Input	Secondary function: An external interrupt input pin. Can receive interrupt by level change.
	P2.1	18	15		
	P2.2	19	16		
	P2.3	20	17		
	P3.0	21	18		
	P3.1	22	19		
	P3.2	24	20		
	P3.3	25	21		
	Capture trigger	P0.0	2		
P0.1		3	2		
RC oscillation monitor	P3.3	25	21	Output	Secondary function: Monitor output pin of the RC oscillation clock for the system clock and the RC oscillation clock for the A/D converter.
Battery check	P0.3	5	4	Input	Secondary function: Analog comparator input port for battery check.

1.5.2 Unused Pin Description

Table 1-3 shows processing of unused pins.

Table 1-3 Processing of Unused Pins

Pin	Recommended pin connection
OSC1	Open
OSC2	Open
$\overline{TST1}$, $\overline{TST2}$	Open
P0.0 to P0.3	"L" level, "H" level or open (depends on input mode selection)
P1.0 to P1.3	Open
P2.0 to P2.3	At input: "L" level, "H" level or open (depends on input mode selection) At output: Open
P3.0 to P3.3	At input: "L" level, "H" level or open (depends on input mode selection) At output: Open
BD	Open
RT0	Open
CRT0	Open
RS0	Open
CS0	Open
IN0	Open
RT1	Open
RS1	Open
CS1	Open
IN1	Open
L0 to L23	Open

1.6 Basic Timing

The MSM64162A generates a system clock (CLK) by one of two methods, a 32.768 kHz crystal oscillator or a 400 kHz RC oscillator.

A phase of CLK correspondes to a phase of \overline{XT} or OSC1.

Each instruction is processed and executed between one machine cycle (minimum) and five machine cycles (maximum).

One machine cycle consists of three states S1 to S3. One state is a period from the falling edge of CLK to the next falling edge.

The S1 state of the first machine cycle (M1) of an instruction is M1•S1.

Figure 1-4 shows the relationship among system clock (CLK), the three states (S1, S2 and S3) and machine cycles.

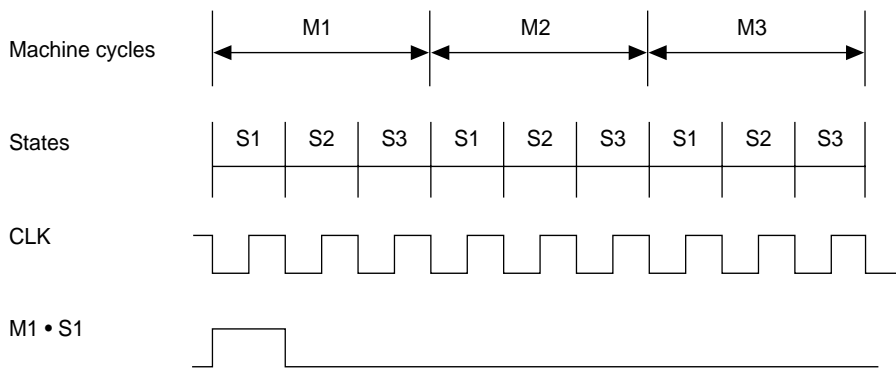


Figure 1-4 Machine Cycle Definition

CPU

Chapter 2 CPU

2.1 Overview

The instruction set of the MSM64162A is composed of 148 different instructions that contain byte operations. The address space of the MSM64162A is divided into 8-bit width program memory area and a 4-bit width data memory area.

Program data and 32-byte test data are assigned to the program memory area inside the chip. The data memory area has 128-nibble RAM in Bank 7 and the special function registers (SFRs) in Bank 0.

Stacks for subroutines and interrupts are placed in the 128 nibbles from address 780H to address 7FFH in Bank 7 by the stack pointer. Figure 2-1 shows each register and memory space.

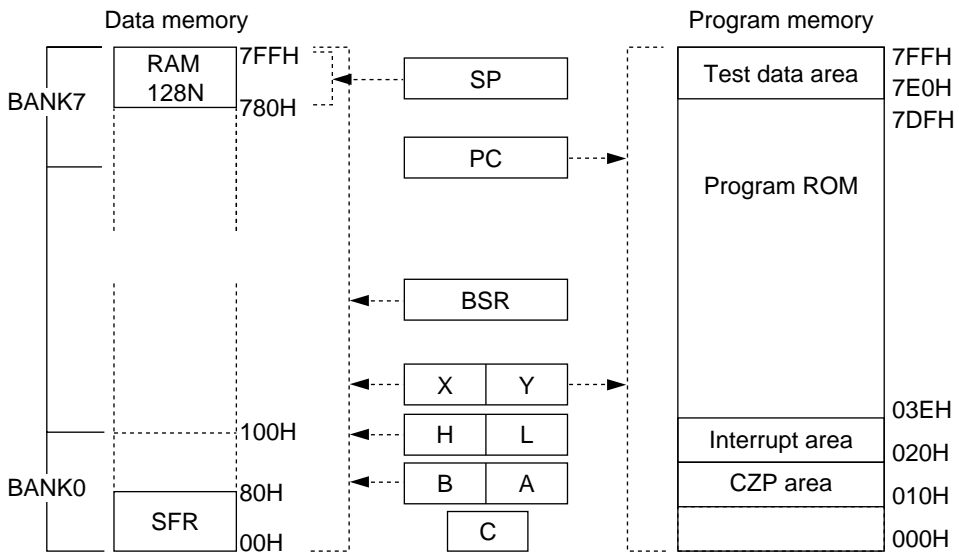


Figure 2-1 Registers and Memory Space

Notes:

- (1) Banks in data memory can be specified by the contents of the bank select registers (BSR0 and BSR1) and the state of the bank control flags (BCF and BEF).
- (2) The 32 bytes of address 07E0H to 07FFH in the program memory are for a factory test data area and cannot be used for a program data area.

2.2 Layout of Registers

Figure 2-2 shows the layout of registers of the MSM64162A.

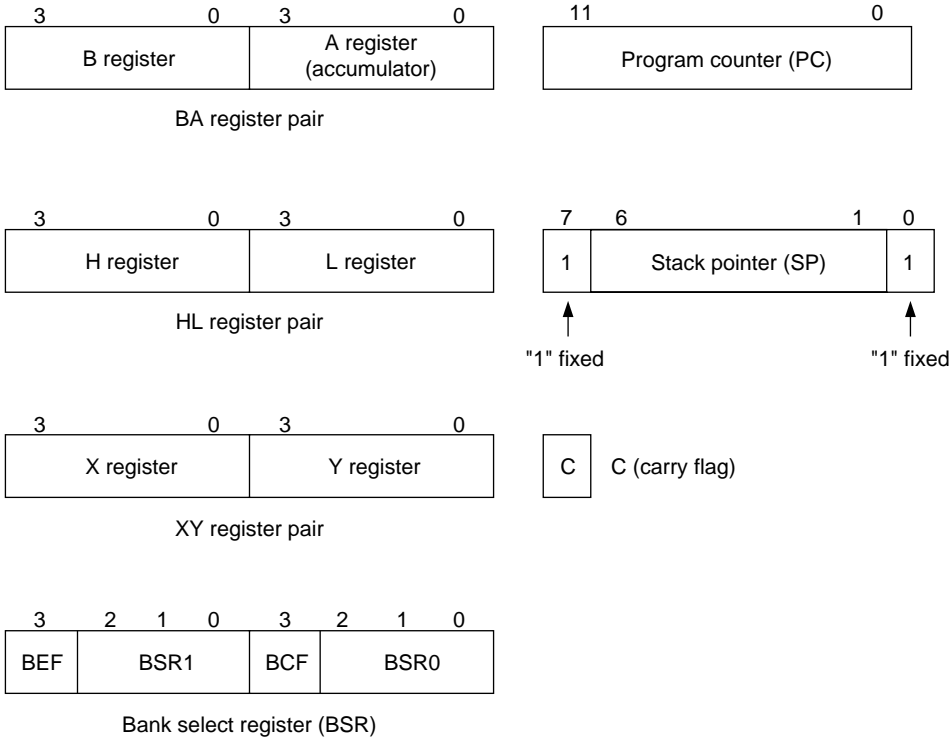
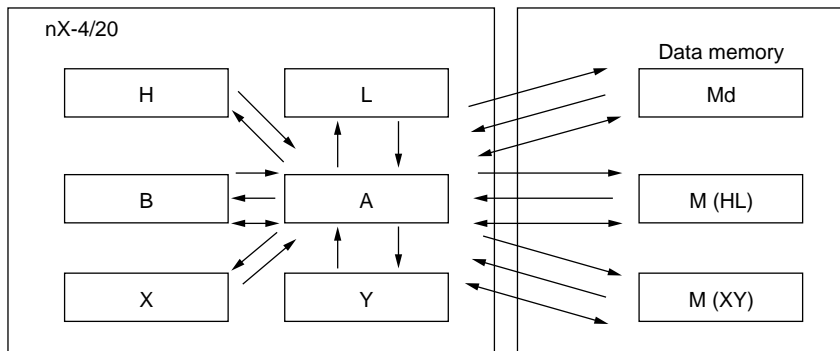


Figure 2-2 Register Layout of MSM64162A

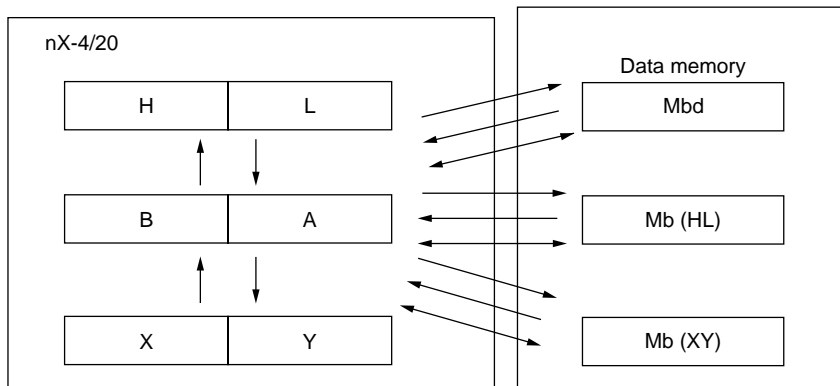
2.2.1 Registers A, B, H, L, X and Y

The A register (accumulator) is a central register of each operation processing. There are five working registers of B, H, L, X and Y. The B register combined with the A register plays a central role for processing byte data. H and L registers and X and Y registers are used for indirect addressing of data memory and for working registers of byte processing when they are used in pair. Figure 2-3 shows the possible combination of data transfer among each register and data memory.

(a) 4-bit transfer



(b) 8-bit transfer



Note: → , ← : data transfer instruction
↔ : data exchange instruction

Figure 2-3 Combination of Data Transfer among Registers

Here, "M" refers to data memory, index "d" refers to direct addressing mode, "(HL)" and "(XY)" refer to indirect addressing mode and "b" refers to byte data. The arrow indicates the data transfer direction.

When an interrupt is generated, the register pairs of BA and HL are automatically saved to the stack.

2.2.2 Program Counter (PC)

This is a counter of 11 bits and can select a program area of internal 2K bytes.

2.2.3 Stack Pointer (SP)

The stack pointer (SP) is a register to indicate the top address of the stack assigned from 7EH to 7FH on data memory bank 0.

SP is a 6-bit byte-processing-only up/down counter in which the lowest and the highest bits are fixed as "1". SP is counted down when data was saved to the stack and is counted up when data was returned from the stack.

At system reset, SP becomes "0FFH" and the stack addresses become 0FFH and 0FEH in Bank 7.

Please use a byte processing instruction for modification and read-out of the contents of SP. 4-bit processing instructions cannot read/write the contents of SP.

Bits 0 and 7 of SP are ignored at data write instructions and "1" is always read out by data read instructions.

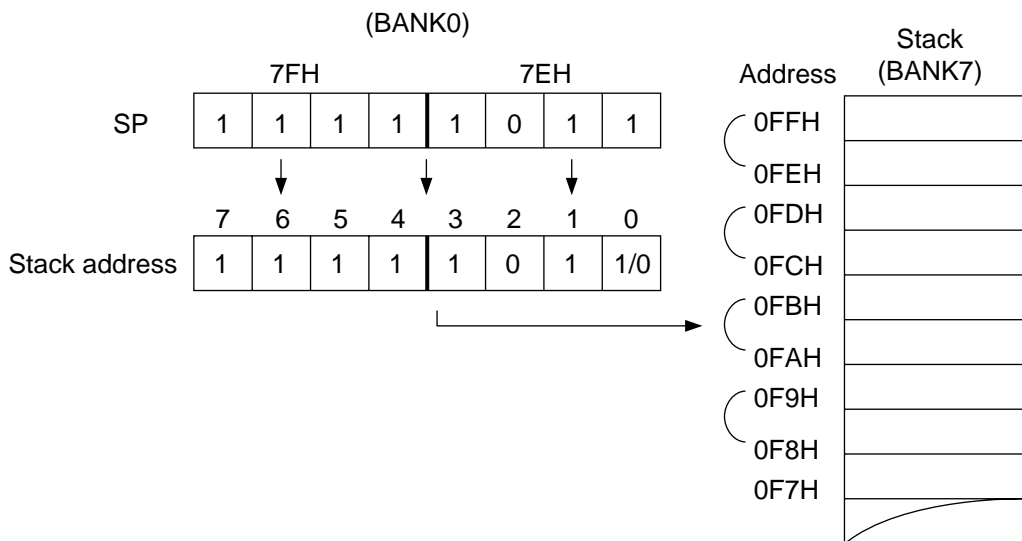


Figure 2-4 Relation between Stack Pointer, SP, and Stack Address

2.2.4 Carry Flag (C)

This is a one-bit flag and is loaded with a carry at the add instruction and is loaded with a borrow at the subtraction instruction. When an interrupt is generated, it is automatically saved to a stack.

2.3 Memory Space

2.3.1 Program Memory Space

The program memory space is a memory area for program data, the interrupt vector table, the CZP area, the start address area and the test data area.

The data length is 8 bits and is assigned from address 0 to address 2047.

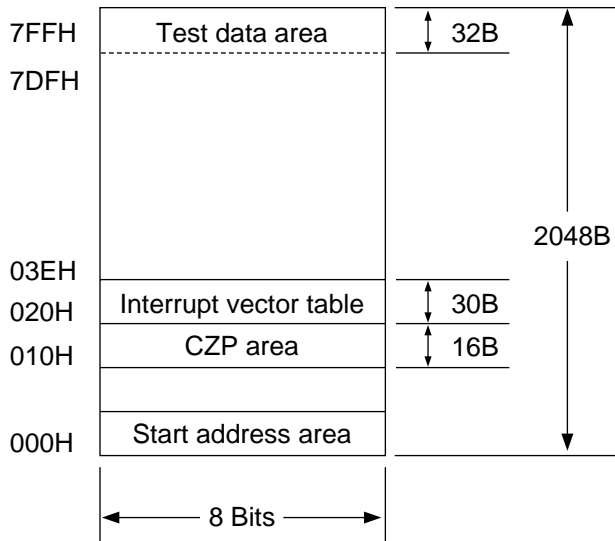


Figure 2-5 Program Memory Address Space

The address space of program memory is shown in Figure 2-5.

Address 0H is the start address of the instruction execution at system reset. The "CZP area" from address 10H to 1FH is the start address range of a CZP subroutine of one byte call instruction and maximum of 8 instructions can be placed. The interrupt vector table is assigned from address 020H to 03DH. 32 bytes from address 07E0H to 07FFH are a test data area and cannot be used as a program memory area.

For details of interrupts, refer to Chapter 4 "Interrupt" and related chapters for peripheral functions.

2.3.2 Data Memory Space

2.3.2.1 Data Memory Space

The data memory space is assigned data memory and special function registers (SFRs) and is located in a different address space from the program memory space. The data length is 4 bits. The data memory space uses two bank areas; one for the SFR area of Bank 0; the other for the data/stack area from address 780H to address 7FF in Bank 7.

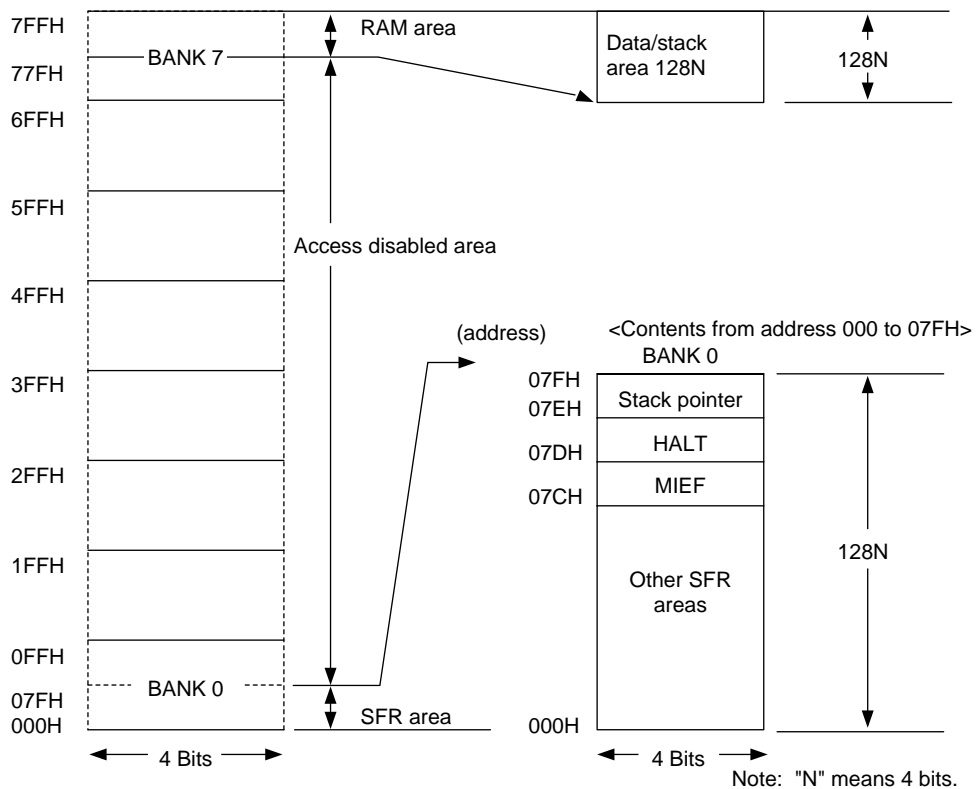


Figure 2-6 Data Memory Address Space

Figure 2-6 shows the address space of data memory. The "stack area" is a data-escape area used by subroutines and interrupts and is valid up to maximum 128 N in the direction toward lower addresses starting from the highest address of 7FFH of data memory.

Special function registers (SFRs) are assigned from address 07FH in Bank 0 in the direction toward lower addresses. For addressing mode of the data memory space, the upper 3 bits of the 11 bits of the data memory address can be determined by specifying the bank while the lower 8 bits are determined by either the HL indirect addressing mode, the XY indirect addressing mode or the direct addressing mode.

However, addresses 0H to 7FH of Bank 0 are an exception and if this area is selected by setting the bank common flag (BCF) to 1 in direct addressing mode, Bank 0 is always selected unconditionally. Bank selection is ignored for this case.

2.3.2.2 Bank Selection of Data Memory

Bank selection in data memory can be performed by the bank select registers (BSR0 and BSR1), the bank common flag (BCF) and the bank enable flag (BEF). These registers and flags can be saved and resorted to the stack altogether by the "PUSH BSR" and "POP BSR" instructions.

The HL indirect addressing mode, the XY indirect addressing mode, the direct addressing mode and the stack indirect addressing mode are available for intra-bank addressing in data memory. How each bank can be selected depends on the above mode.

Table 2-1 shows the functions of BCF and BEF. As shown in this table, the bank can be selected by BCF, BEF and addressing mode. "BSR0" and "BSR1" in the table indicate that a bank can be selected by BSR0 and BSR1, respectively. In direct addressing mode, Bank 0 can be selected unconditionally only when BCF = 1 and the addresses are specified as 0 to 7FH.

Table 2-2 shows the correspondence between the contents of BSR0 and BSR1 and the bank number.

Table 2-1 Relation between BCF, BEF and Bank Specification by Addressing Mode

BCF	BEF	HL indirect addressing	XY indirect addressing	Direct addressing	SP indirect addressing
0	0	BSR0	BSR0	BSR0	<BANK7>
0	1	BSR0	BSR1	BSR1	
1	0	BSR0	BSR0	<ul style="list-style-type: none"> • When addresses in bank are 0 to 7FH:<BANK0> • When addresses in bank are 80 to FFH:BSR0 	
1	1	BSR0	BSR1	<ul style="list-style-type: none"> • When addresses in bank are 0 to 7FH:<BANK0> • When addresses in bank are 80 to FFH:BSR1 	

Table 2-2 Correspondence between Contents of BSR0, BSR1 and Bank Number

BSR0, BSR1	Bank number	BSR0, BSR1	Bank number
0	BANK0	4	BANK0
1	BANK7	5	BANK7
2	BANK0	6	BANK0
3	BANK7	7	BANK7

2.3.2.3 Addressing Modes of Data Memory

(1) HL indirect addressing mode

Addresses within a bank can be specified by the HL register pair.

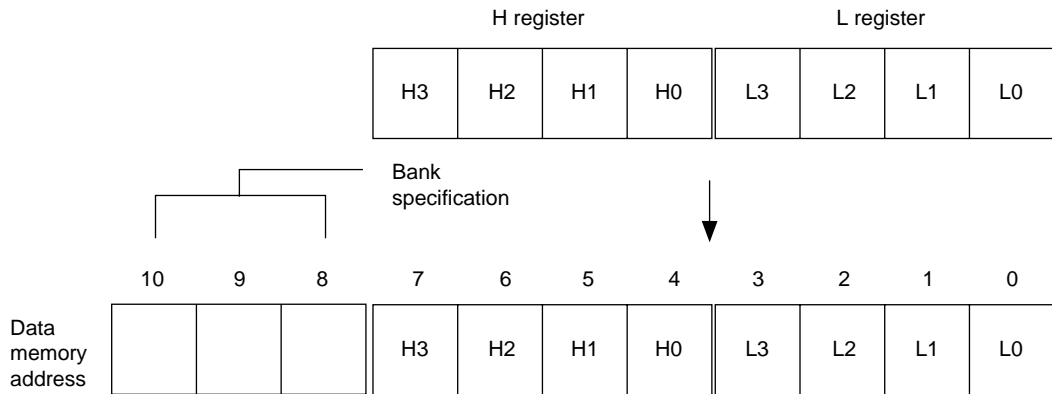


Figure 2-7 Data Memory Address of HL Indirect Addressing

(2) XY indirect addressing mode

Addresses within a bank can be specified by the XY register pair.

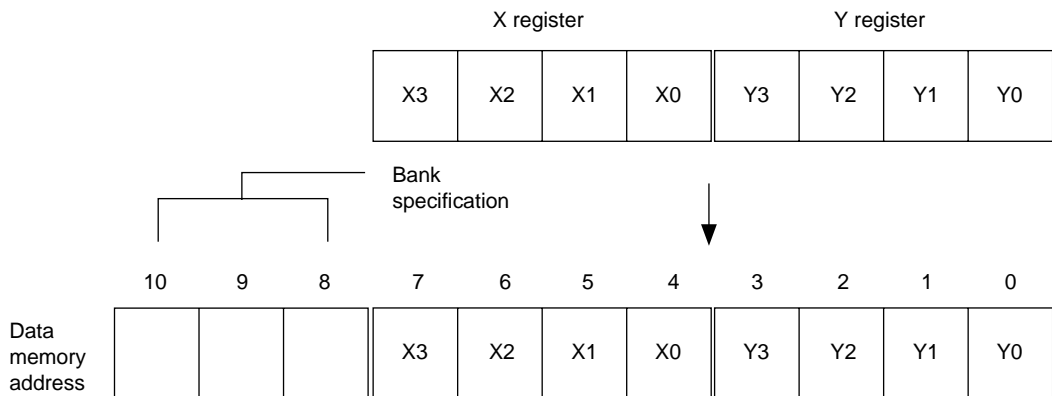


Figure 2-8 Data Memory Address of XY Indirect Addressing

(3) Direct addressing mode

Addresses in a bank can be specified by 8-bit immediate data contained in the instruction code.

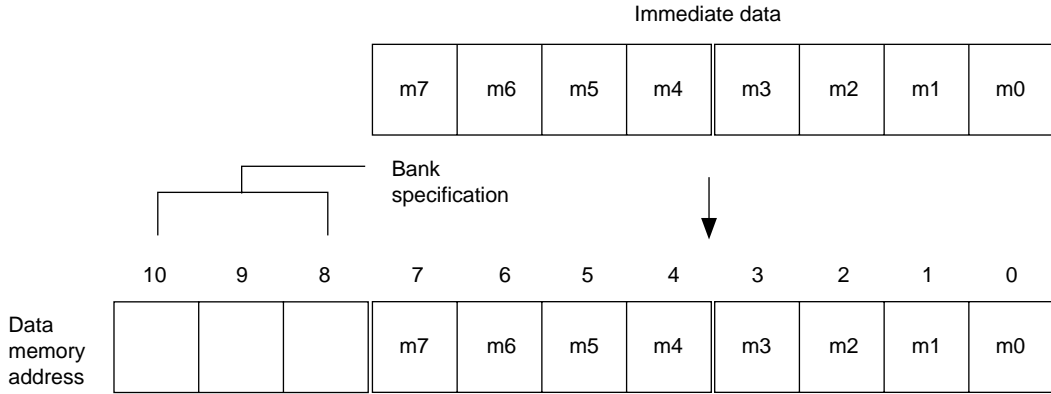


Figure 2-9 Data Memory Address of Direct Addressing

(4) Stack pointer indirect addressing mode

Addresses within Bank 7 can be specified by the stack pointer (SP). This mode is used when manipulating stacks such as the "PUSH" and "POP" instructions and subroutine call, return instructions and interrupts.

In this mode, Bit 0 of the address is not valid as data are always handled in 8 bits (two nibbles). Although SP is an 8 bit register, the highest and the lowest bits always are fixed as "1" and the remaining 6 bits function as an up/down counter.

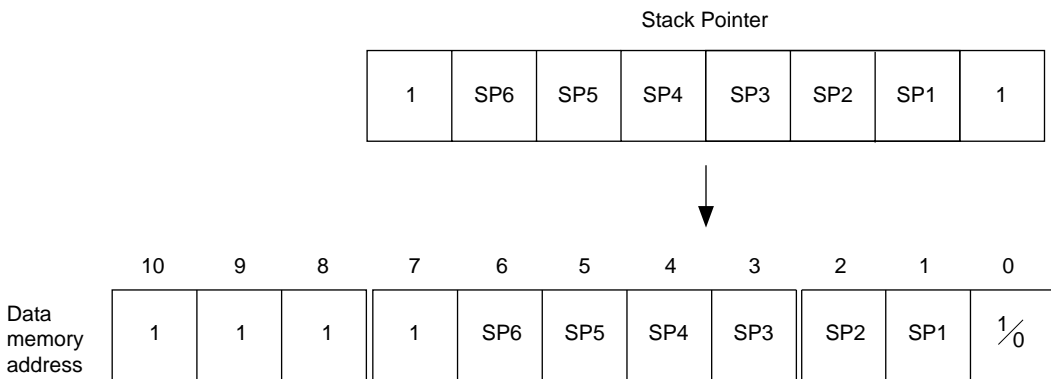


Figure 2-10 Data Memory Address by Stack Pointer Indirect Addressing

CPU Control Functions

Chapter 3 CPU Control Functions

3.1 Overview

The MSM64162A has halt mode besides operation mode. Operation status can be classified as follows including system reset mode:

- Normal operation mode
- System reset mode
- Halt mode

Figure 3-1 shows transition among each state.

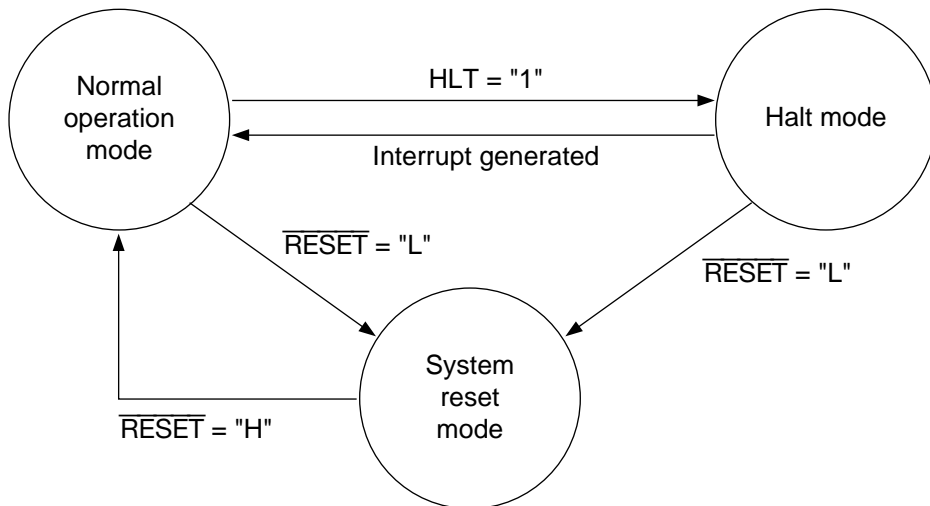


Figure 3-1 Operation Transition Diagram

Normal operation mode is a state that the CPU executes instructions successively. System reset mode is a state starting when the CPU begins system reset processing until each register and each pin are initialized to start execution of the instruction.

Halt mode is a state that the CPU repeats fetching the next instruction only and suspends the execution of instruction. Count-up to the PC is not performed in halt mode. Although the execution of the instruction is suspended in halt mode, internal peripheral functions continue to operate. Transition to this state begins by setting the HLT flag to "1". Halt mode does not influence the functions of ports and peripheral functions.

3.2 System Reset Function

3.2.1 System Reset Operation by $\overline{\text{RESET}}$ Input Pin

System reset mode is started when either power is turned on, oscillation of the system clock stops or the $\overline{\text{RESET}}$ pin becomes "L" level. In system reset mode, the following take place:

- (1) The CPU is initialized.
- (2) The power supply V_{SSL} for the crystal oscillation circuit and the logic circuit is set to the V_{SS} voltage level.

At 0.5 second after crystal oscillation starts, V_{SSL} is switched to a constant voltage level which is output of the power supply generation circuit for logic (VR).

- (3) The power supply generation circuit for logic (VR) is activated.
- (4) The output from the LCD driver is turned off at the V_{DD} level. At about 63 ms after the crystal oscillation starts, waveforms are output to the LCD driver.
- (5) All the special function registers (SFRs) are initialized. After the system reset processing, the execution of an instruction is started from address 000H.

Figures 3-2 and 3-3 show the system reset generation circuit and each signal at system reset.

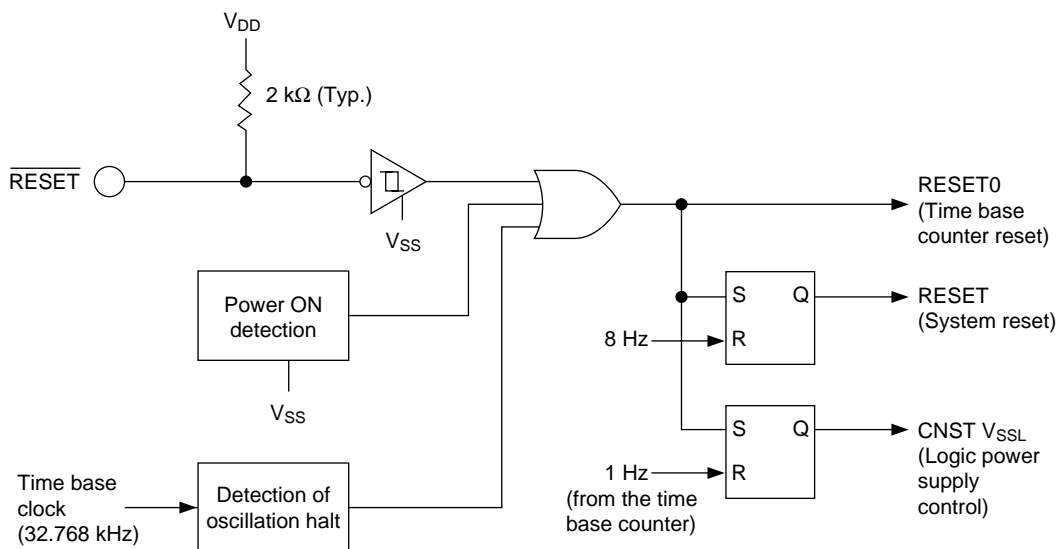


Figure 3-2 System Reset Generation Circuit

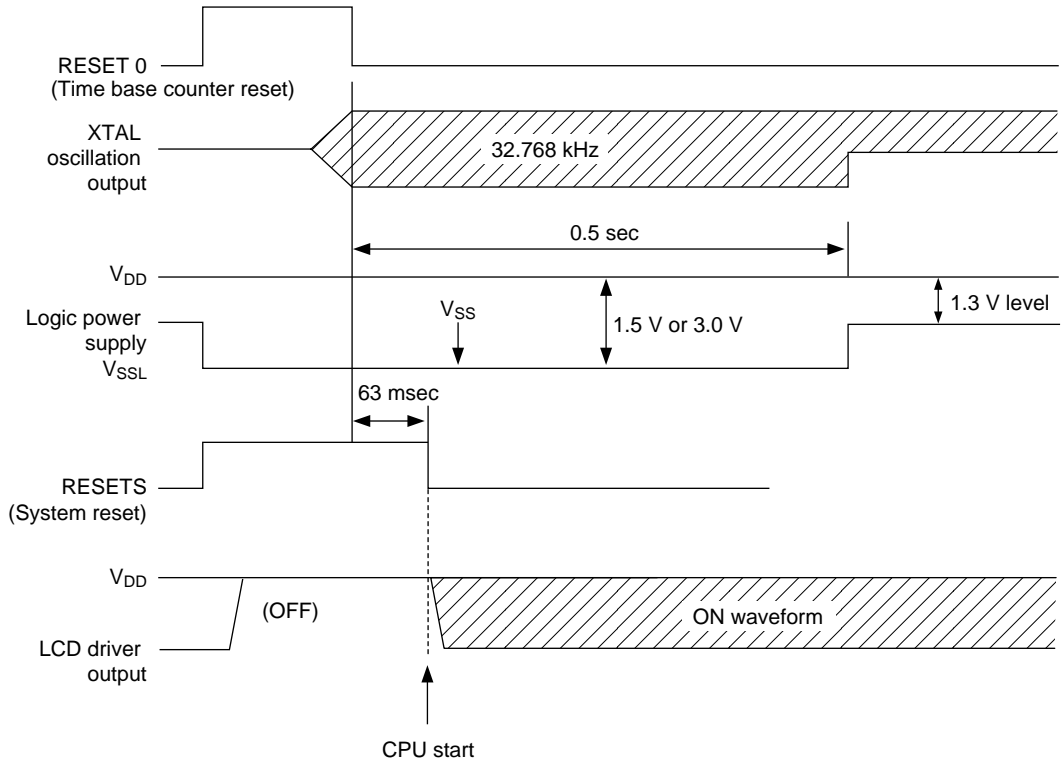


Figure 3-3 Each Signal at System Reset Generation

3.2.2 State at System Reset

Table 3-2 shows the state of the registers after system reset.

Table 3-2 (a) Initial Values at System Reset

Register/Flag	Value at system reset	Note
Program counter (PC)	000H	
A register (A)	0H	
B register (B)	0H	
Carry flag (C)	0	
HL register pair (HL)	00H	
XY register pair (XY)	00H	
Stack pointer (SP)	0FFH	
Bank select register 0 (BSR0)	0H	
Bank select register 1 (BSR1)	0H	
Bank common flag (BCF)	0	
Bank enable flag (BEF)	0	
Port 2 register (P2)	0H	
Port 3 register (P3)	0H	
Port 1 register (P1)	0H	
Port 20 control register (P20CON)	0H	Input mode, Input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 21 control register (P21CON)	0H	Input mode, Input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 22 control register (P22CON)	0H	Input mode, Input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 23 control register (P23CON)	0H	Input mode, Input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled

Table 3-2 (b) Initial Values at System Reset

Register/Flag	Value at system reset	Note
Port 30 control register (P30CON)	0H	Input mode, input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 31 control register (P31CON)	0H	Input mode, input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 32 control register (P32CON)	0H	Input mode, input with pull-up/pull-down resistance, 64 Hz sampling, interrupt disabled
Port 33 control register (P33CON)	0H	Input mode, input with pull-up/pull-down resistance, interrupt disabled
Port 01 control register (P01CON)	8H	P1 CMOS output mode, P0, P2, P3 input with pull-up resistance
Frequency control register (FCON)	0EH	Crystal oscillation clock
Buzzer driver control register (BDCON)	0H	Positive logic output, buzzer disabled, discontinuous sound 1 output
Buzzer frequency control register (BFCON)	0EH	Buzzer frequency 4 kHz
Capture control register (CAPCON)	0H	Capture 0,1 halt
Capture register 0 (CAPR0)	0H	
Capture register 1 (CAPR1)	0H	
Display control register (DSPCON)	0CH	1/4 duty
Display registers 0 to 20 (DSPR0 to 20)	0H	

Table 3-2 (C) Initial Values at System Reset

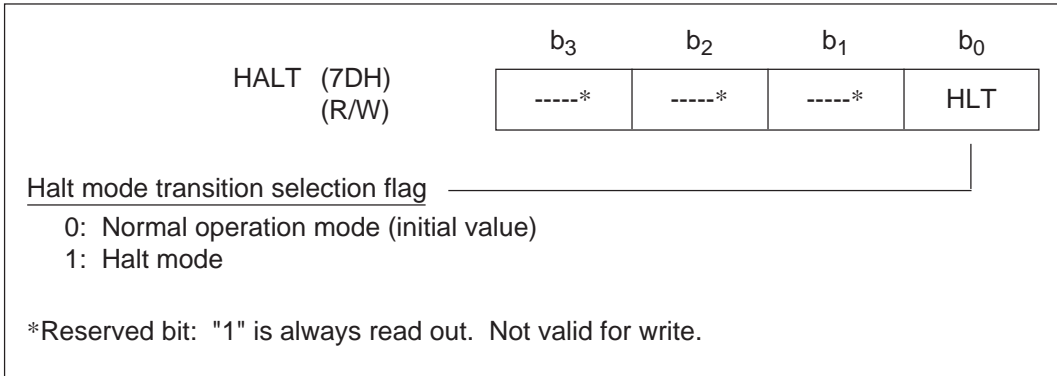
Register/Flag	Value at system reset	Note
A/D converter control register 0 (ADCON0)	0CH	Counter A select, RC oscillation halt
A/D converter control register 1 (ADCON1)	0H	IN0 clock input mode
A/D converter counter A register 0 (CNTA0)	0H	
A/D converter counter A register 1 (CNTA1)	0H	
A/D converter counter A register 2 (CNTA2)	0H	
A/D converter counter A register 3 (CNTA3)	0H	
A/D converter counter A register 4 (CNTA4)	8H	
A/D converter counter B register 0 (CNTB0)	0H	
A/D converter counter B register 1 (CNTB1)	0H	
A/D converter counter B register 2 (CNTB2)	0H	
A/D converter counter B register 3 (CNTB3)	0CH	
Watchdog timer control register (WDTCON)	—	Reset the watchdog timer counter
Backup control register (BUPCON)	8H	$V_{DD} - 1.3$ V level, battery check disabled
Interrupt request register 0 (IRQ0)	2H	
Interrupt request register 1 (IRQ1)	0H	
Interrupt request register 2 (IRQ2)	0CH	
Interrupt enable register 0 (IE0)	2H	Interrupt disabled
Interrupt enable register 1 (IE1)	0H	Interrupt disabled
Interrupt enable register 2 (IE2)	0EH	Interrupt disabled
Halt mode register (HALT)	0EH	Normal operation mode
Master interrupt enable register (MIEF)	0EH	Interrupt disabled

Note: System reset has the highest priority over all other processing and all the processes are suspended at system reset. Consequently, there is no guarantee for the contents of RAM that is initialized at system reset.

3.3 Halt Mode

3.3.1 Halt Mode Register (HALT)

This is a special function register (SFR) that controls transition to halt mode.



Bit 0: HLT

This is a flag to enter halt mode. By setting the HLT flag to "1", the CPU enters halt mode at the first machine cycle of the next instruction.

3.3.2 Operation of Halt Mode

When an instruction to set the HLT flag to "1" is executed, the CPU enters halt mode at the first machine cycle of the next instruction. However, since the condition for the release of halt mode is an interrupt request, CPU does not enter halt mode in an interrupt request state.

In halt mode, operation of oscillation and the time base counter is still continued and the CPU halts at fetching state S1 for the next instruction.

System reset or an interrupt can release halt mode (reset of the HLT flag). To release halt mode by an interrupt, it is necessary to set the interrupt enable flag to "1" before entering halt mode. Figure 3-4 shows timing to enter halt mode and release timing of halt mode by an interrupt.

Execution of instructions after the release of halt mode depends on the status of the master interrupt enable flag (MI). When the MI flag is "1", execution of instructions is resumed after one dummy cycle by an interrupt process routine as shown in Figure 3-4. When the MI flag is "0", execution of instructions is resumed with a dummy cycle after the following address that the halt instruction is placed as shown in Figure 3-5.

Note: To release halt mode, it is necessary to set an individual interrupt enable flag to "1" regardless of the state of the MI flag. When halt mode is released while the MI flag is "0", the individual interrupt request flag is set to "1".

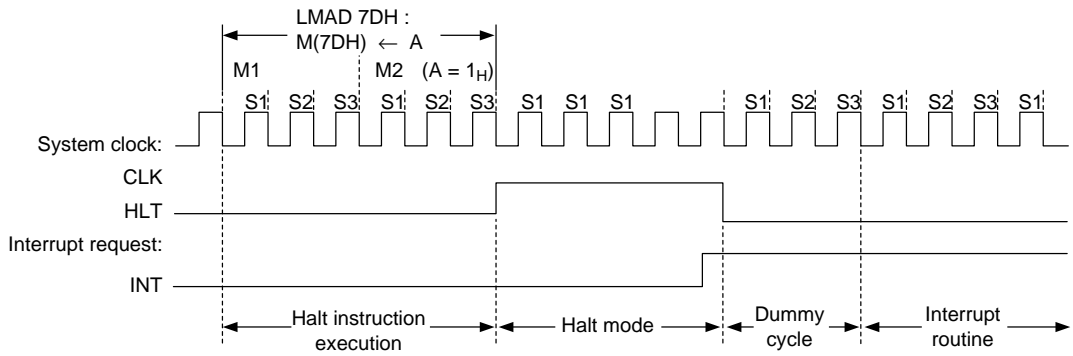


Figure 3-4 Timing of Halt Mode Set and Halt Mode Reset by Interrupt (when the MI flag = 1)

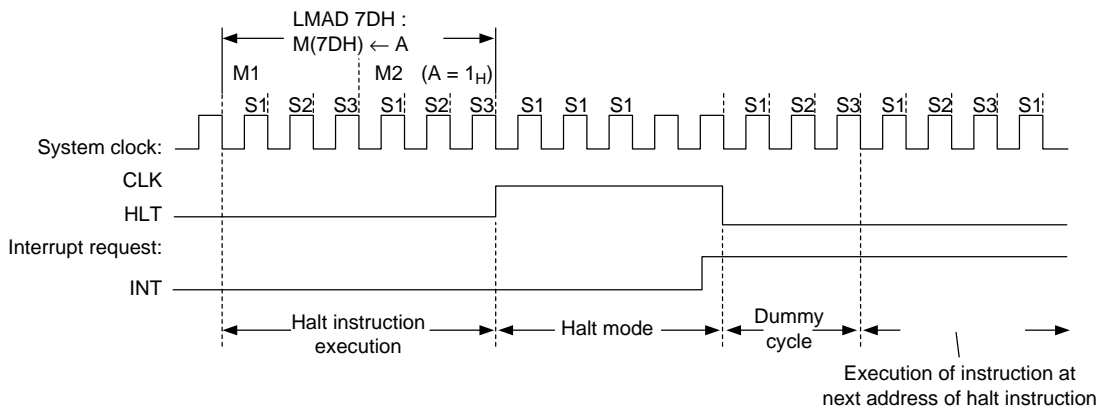


Figure 3-5 Timing of Halt Mode Set and Halt Mode Reset by Interrupt (when the MI flag = 0)

Interrupt (INTC)

Chapter 4 Interrupt (INTC)

4.1 Overview

The MSM64162A has nine interrupt causes (9 vector addresses), two of which are external interrupts from ports and 7 are internal interrupts.

Of the nine interrupt causes, only the watchdog interrupt cannot be disabled (non-maskable interrupt) and other 8 interrupts are controlled by the master interrupt enable flag (MI) and each interrupt enable register (IE0, IE1 and IE2) for enabling/disabling interrupts. When an interrupt condition is met, CPU branches to a vector address corresponded to the interrupt cause.

Table 4-1 shows the list of interrupt causes and vector address and Figure 4-1 shows the interrupt control equivalent circuit.

Table 4-1 List of Interrupt Causes

No.	Interrupt cause	Mnemonic	Vector address
1	Watchdog timer interrupt	WDTINT	03BH
2	External 0 interrupt (P2, P3)	XI0INT	038H
3	External 1 interrupt (P0)	XI1INT	032H
4	A/D converter interrupt	ADINT	02FH
5	256 Hz interrupt	256HzINT	02CH
6	32 Hz interrupt	32HzINT	029H
7	16 Hz interrupt	16HzINT	026H
8	1 Hz interrupt	1HzINT	023H
9	4 Hz interrupt	4HzINT	020H

When two interrupt causes are generated simultaneously, an interrupt with a higher vector address (WDTINT has the highest priority) is given the priority and is executed accordingly.

For details of each interrupt operation, refer to Chapter 6 "Time Base Counter," Chapter 7 "Ports," and Chapter 12 "A/D Converter".

(Notes)

The interrupt requests which are generated in the following cases are temporarily held.

- 1) As a result which executed an instruction with skip, when the skip condition is established.

(The skip action expends the same time as the executive machine cycle of the instruction to be skipped. For this reason, interrupt requests are held during the same time as the executive machine cycle of the instruction to be skipped.)

- 2) When LAI and LLI instructions (vertical stack instruction) are executed.
- 3) When ADCS and SUBCS instructions are executed.

The interrupt requests which are temporarily held in the abovementioned cases are received after the execution of the instructions is finished if the next coming instructions are not fitted to the aforementioned conditions.

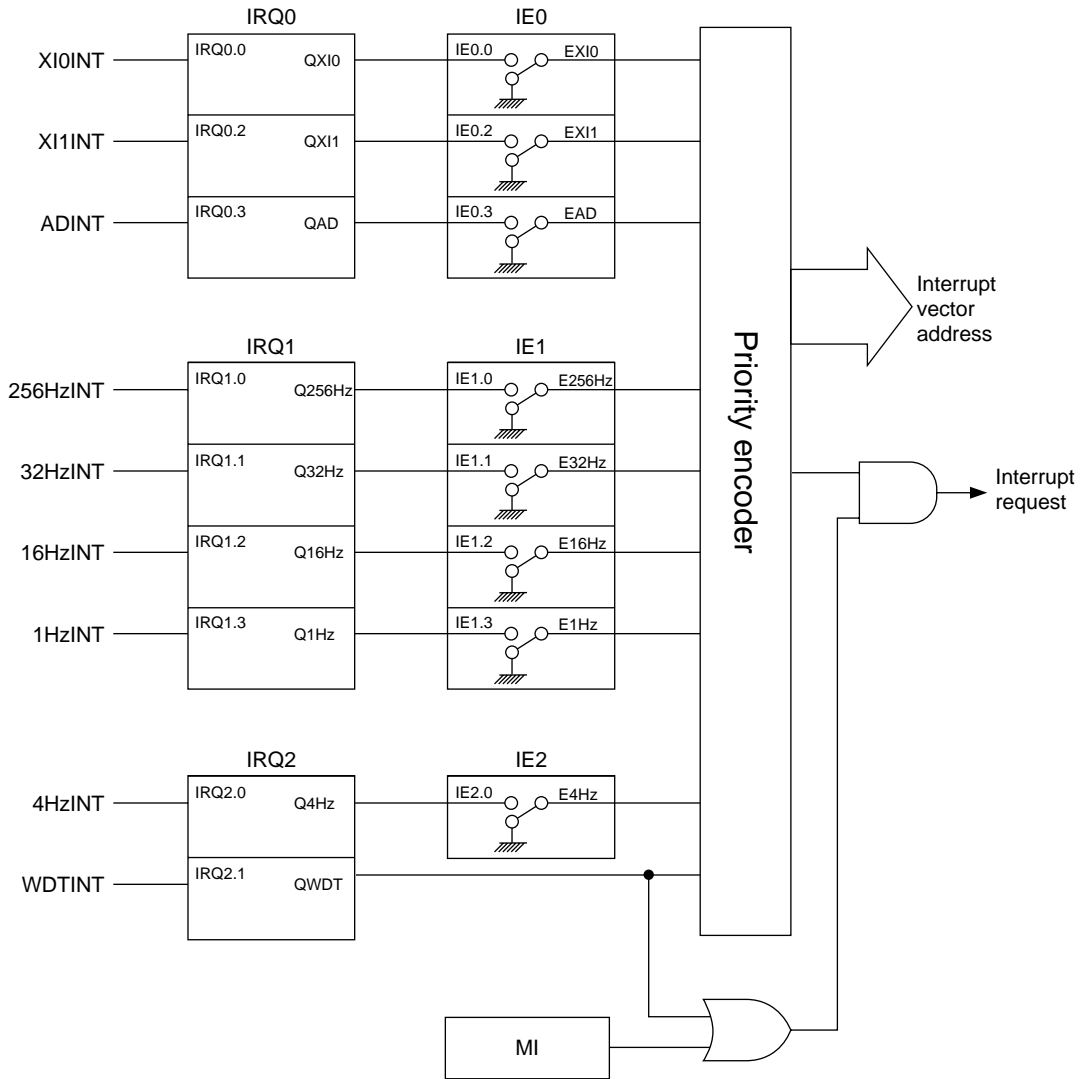


Figure 4-1 Interrupt Control Equivalent Circuit

4.2 Interrupt Sequence

Transition to interrupt processing is performed by generating an individual interrupt cause while the MI flag is set to "1".

An interrupt transition cycle is equivalent to 5 machine cycles and the following are executed:

- (1) The MI flag is reset to "0".
- (2) The contents of PC, A, B, H and L registers and the carry flag (C) are saved to stack.
- (3) The stack pointer (SP) is decremented by 8 ($SP \leftarrow SP-8$).
- (4) The program counter (PC) is loaded with the head address of the vector address. At the same time, the interrupt request flag for that interrupt is reset.

Figure 4-1 shows the contents of the stack after the generation of an interrupt.

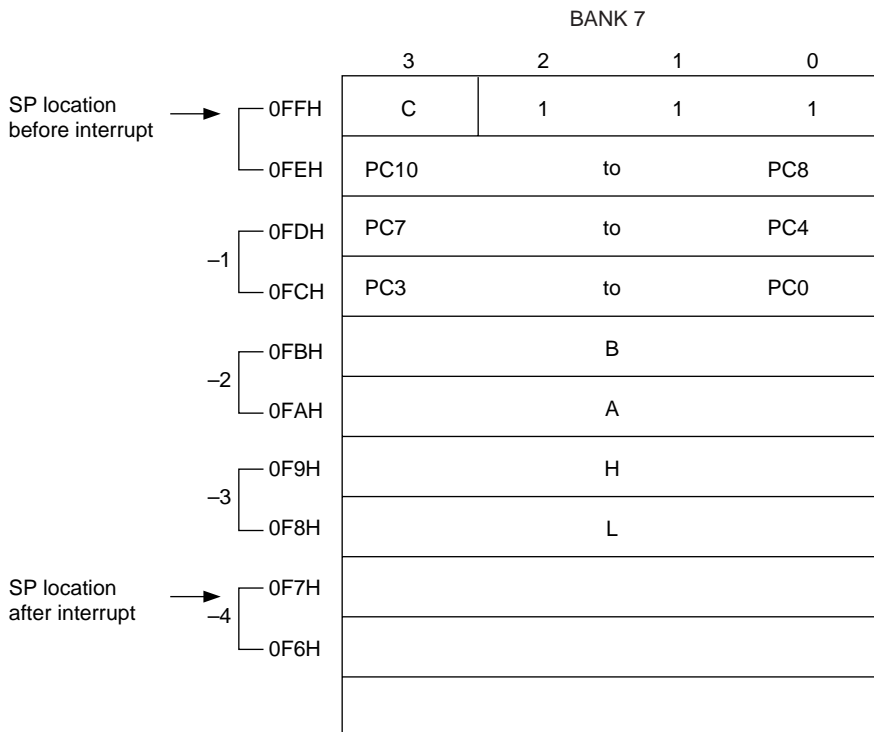


Figure 4-2 Contents of Stack after Interrupt Generation

Return from the interrupt routine is performed by the "RTI" instruction.

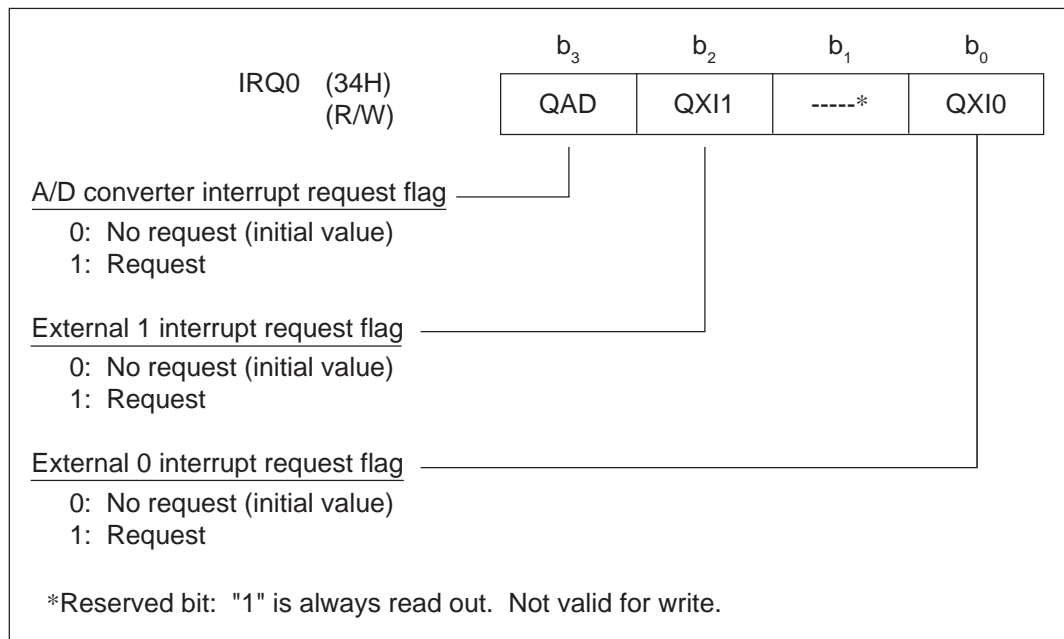
The return cycle is equivalent to 5 machine cycles and the following are carried out:

- (1) The contents of PC, A, B, H and L registers and the carry flag (C) are restored from the stack.
- (2) The stack pointer (SP) is incremented by 8 ($SP \leftarrow SP+8$).
- (3) The MI flag is set to "1".

4.3 Interrupt Control Register

4.3.1 Interrupt Request Registers (IRQ0, IRQ1 and IRQ2)

Each interrupt request register (IRQ0, IRQ1 and IRQ2) is composed of a 4-bit register. When an interrupt request is generated, a corresponding bit is set to "1" in the S1 state of the first machine cycle. When an interrupt is enabled by the interrupt enable register (IE0 to 2), the interrupt is requested to the CPU. The watch dog timer interrupt does not have an interrupt mask function caused by the interrupt enable register. By writing "1" to the interrupt request register, it is possible to generate a soft interrupt. When an interrupt is received, the corresponding bits of IRQ0, IRQ1 and IRQ2 are reset to "0" by hardware. IRQ0, IRQ1 and IRQ2 are initialized to 0H at system reset.



Bit 3: QAD

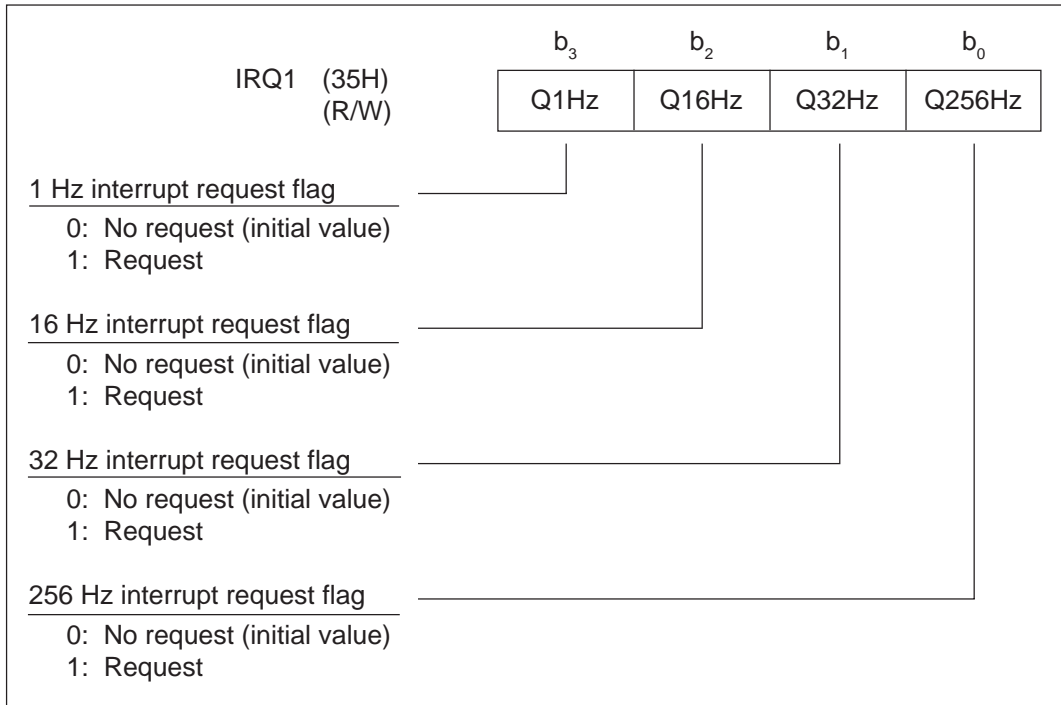
This bit is set to "1" by the counter overflow signal of the A/D converter.

Bit 2: QXI1

This bit is set to "1" by the change of input level of P0.0 to P0.3.

Bit 0: QXI0

This bit is set to "1" by the change of input level of P2.0 to P.2.3 and P3.0 to P3.3.



Bit 3: Q1Hz

This bit is set to "1" by falling of the 1 Hz output of the time base counter.

Bit 2: Q16Hz

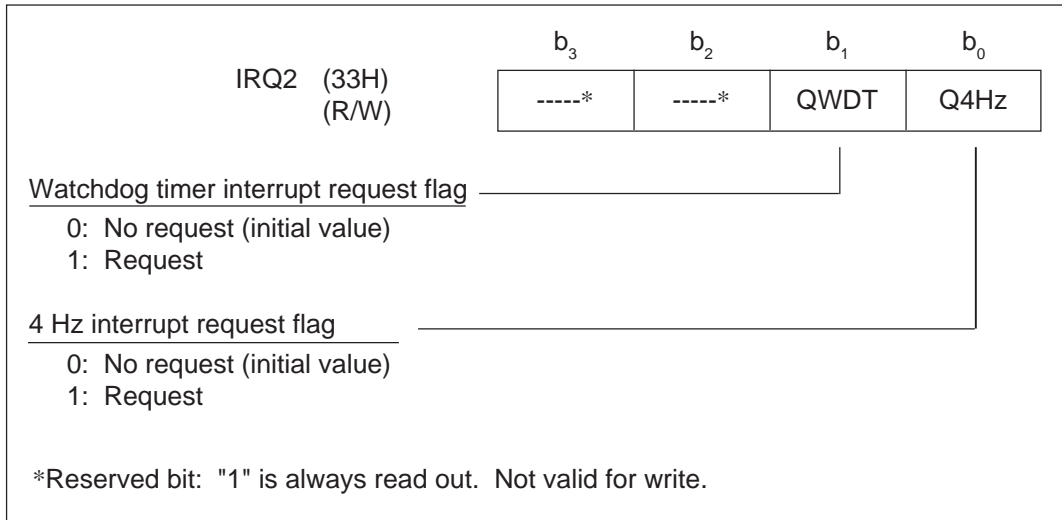
This bit is set to "1" by falling of the 16 Hz output of the time base counter.

Bit 1: Q32Hz

This bit is set to "1" by falling of the 32 Hz output of the time base counter.

Bit 0: Q256Hz

This bit is set to "1" by falling of the 256 Hz output of the time base counter.



Bit 1: QWDT

This bit is set to "1" by overflow of the watchdog timer. Interrupt disable cannot be allowed by the interrupt enable register.

Bit 0: Q4Hz

This bit is set to "1" by falling of the 4 Hz output of the time base counter.

4.3.2 Interrupt Enable Registers (IE0, IE1 and IE2)

Each of interrupt enable registers (IE0, IE1 and IE2) is composed of a 4-bit register and determines whether a request is sent to the CPU or not by AND with a corresponding bit of the interrupt request registers (IRQ0, IRQ1 and IRQ2).

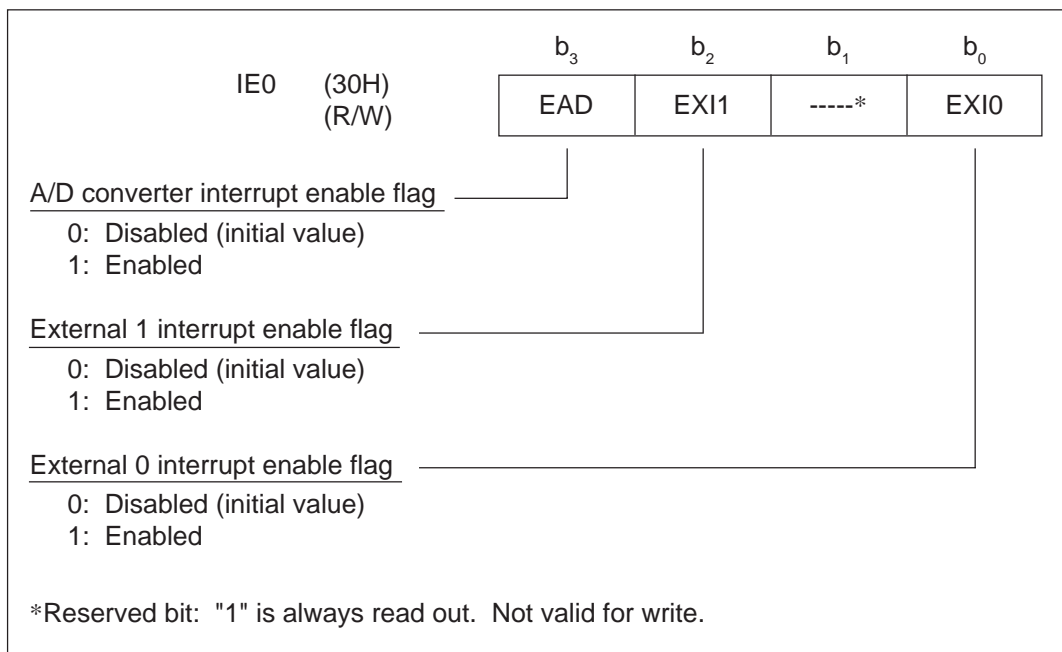
When multiple interrupts are requested to the CPU, those interrupts with higher priority (higher vector address) as shown in Table 4-1 are processed first and the interrupts with lower priority are held up during that time.

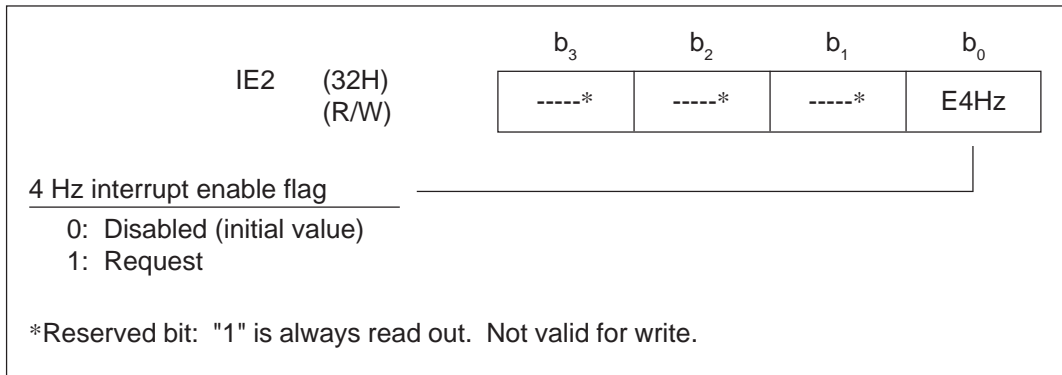
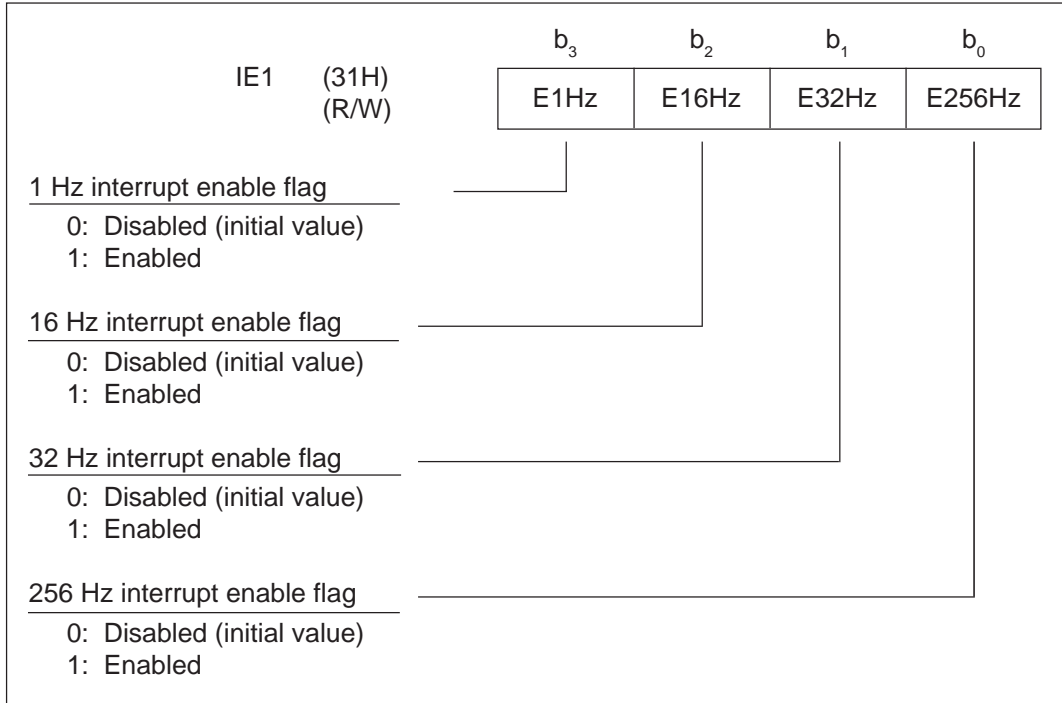
Although the master interrupt enable flag (MI) is cleared to "0" during an interrupt transition cycle, each bit of IE0 to IE2 is not cleared.

An interrupt request that is being held up will remain unchanged until the MI flag is set to "1" while the accepted interrupt request is being processed.

An interrupt request that is being held up will be accepted when the processing of the accepted interrupt request is ended by the RTI instruction and the MI flag is set to "1".

The interrupt enable registers (IE0 to 2) can be rewritten only when the master interrupt enable flag (MI) is reset to "0".





4.3.3 Master Interrupt Enable Register (MIEF)

The MI flag of the master interrupt enable register (MIEF) is to control disabling/enabling of all the interrupts excepting watchdog timer interrupt. When set to "1", interrupt is enabled and when set to "0", interrupt is disabled.

When an interrupt is received, the MI flag is reset to "0" during the interrupt transition cycle and is set to "1" by executing the RTI instruction which is a return instruction from the interrupt process routine.

It is also possible to do multiple interrupt processing by setting this flag to "1" during an interrupt process routine.

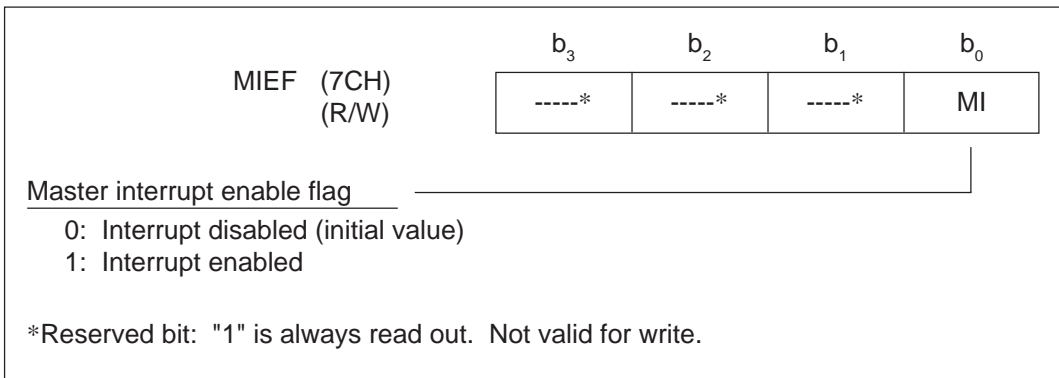


Table 4-2 shows the list of interrupt related registers.

Table 4-2 List of Interrupt Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
Interrupt enable register 0	IE0	30H	R/W	Yes	2H
Interrupt enable register 1	IE1	31H	R/W		0H
Interrupt enable register 2	IE2	32H	R/W	Yes	0EH
Interrupt request register 2	IRQ2	33H	R/W		0CH
Interrupt request register 0	IRQ0	34H	R/W	Yes	2H
Interrupt request register 1	IRQ1	35H	R/W		0H
Master interrupt enable register	MIEF	7CH	R/W	No	0EH

Clock Generation Circuit (2CLK)

Chapter 5 Clock Generation Circuit (2CLK)

5.1 Overview

The clock generation circuit (2CLK) of the MSM64162A is composed of a 32.768 kHz crystal oscillation circuit, a 400 kHz RC oscillation circuit and a clock control part. It generates the system clock (CLK) and the time base clock (32.768 kHz).

The system clock is the basic operation clock of the CPU while the time base clock is the basic operation clock of the time base counter and the buzzer driver.

By the contents of the frequency control register (FCON) the system clock can be switched at between 32.768 kHz which is output of the crystal oscillation circuit and 400 kHz which is output of the RC oscillation circuit.

Note: The oscillation frequency of the RC oscillation circuit varies depending on the value of external resistance (R_{OS}), operating power supply voltage (V_{DD}) and ambient temperatures (T_a). In this manual, the output of the RC oscillation circuit is taken as 400 kHz for convenience.

5.2 Layout of Clock Generation Circuit

Figure 5-1 shows layout of the clock generation circuit.

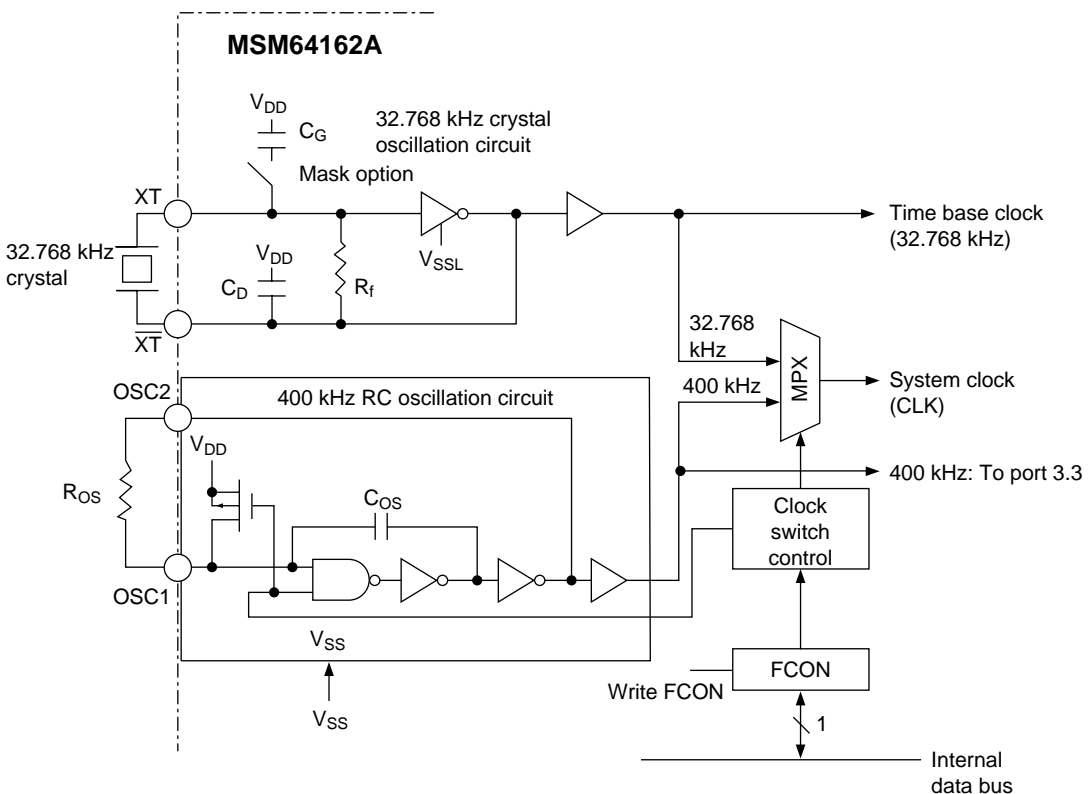


Figure 5-1 Layout of Clock Generation Circuit

5.3 Operation of Clock Generation Circuit

The 32.768 kHz crystal oscillation circuit oscillates by installing a 32.768 kHz crystal externally. When micro-tuning the 32.768 kHz frequency by an external capacitor, the built-in capacitance (C_G) can be cut off by selecting a mask option.

The 400 kHz oscillation circuit oscillates by installing a resistance (R_{OS}) externally. The RC oscillation circuit operates only when the system clock is set to the 400 kHz RC oscillation clock or when it is set to CPU clock output mode for high speed system clock by test functions. Otherwise it halts oscillation. For details of the test functions, refer to Chapter 15 "Test Circuit".

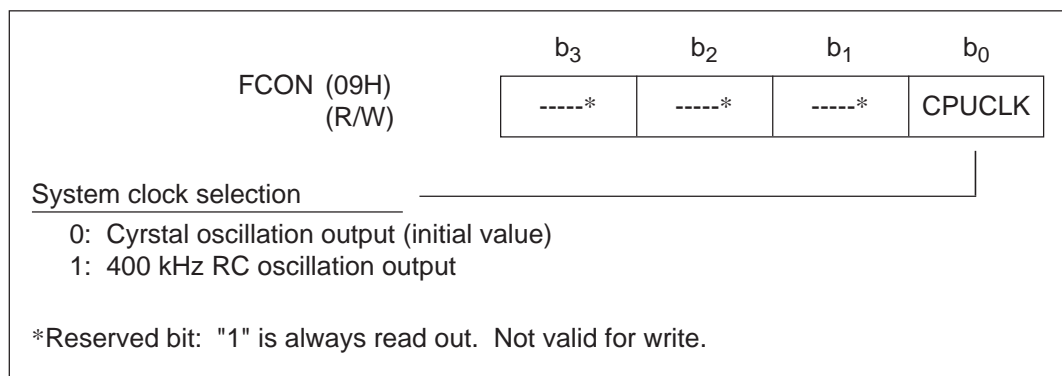
Selection of the system clock is performed by the frequency control register (FCON). When Bit 0 of FCON (CPUCLK) is reset to "0", output of the crystal oscillation circuit (32.768 kHz) becomes the system clock and when CPUCLK is set to "1", output of the RC oscillation circuit (400 kHz) becomes the system clock. Even though the 400 kHz oscillation circuit is selected, the crystal oscillation circuit is not halted.

When the crystal oscillation circuit is chosen as the system clock, oscillation of the RC oscillation circuit is halted and power consumption of the RC oscillation circuit becomes "0". Consequently, it is possible to lower power consumption by writing software in such a way that output of the RC oscillation circuit is selected (CPUCLK = 1) only when high speed operation is needed and that output of the crystal oscillation circuit (CPUCLK = 0) is selected otherwise.

Since the OSC1 pin is pulled up to V_{DD} when the 400 kHz RC oscillation circuit is not selected, leave OSC1/OSC2 open when not using output from the RC oscillation circuit (400 kHz).

5.4 Frequency Control Register (FCON)

The frequency control register (FCON) is a 4-bit special function register (SFR) to select a system clock.



Bit 0: CPUCLK

This bit is to select a system clock. At system reset, it is reset to "0" and the crystal oscillation output is selected.

5.5 System Clock Switch Timing

When the CPUCLK bit of the frequency control register (FCON) is set to "1", the system clock is switched from crystal oscillation output (32.768 kHz) to RC oscillation output (400 kHz). In other words, it is switched from low-speed clock to high-speed clock. At the same time, the internal logic power supply is switched from the V_{SSL} level to the power supply voltage level (V_{SS} level) in order to get a larger high-speed margin by increasing the internal voltage.

It takes 1 ms or more until the internal logic power supply reaches the power supply level (V_{SS}). For high-speed clock operation, do programming according to the following procedure using the backup control register described in Chapter 14 (refer to Figure 5-2).

5

- (1) Set the bit 0 (BUPF) of the backup control register (BUPCON) to "1" before switching to high-speed clock, and switch the internal logic voltage to the power supply voltage level (V_{SS}).
- (2) 1 ms or more later, set the CPUCLK bit of the frequency control register (FCON) to "1", and switch the system clock from crystal oscillation output (32.768 kHz) to RC oscillation output (400 kHz).

*Program example

SMBD 37H, 0 ; Set BUPF to "1".

[WAIT 1 ms] ; Wait 1 ms.

SMBD 09H, 0 ; Set CPUCLK to "1".

- (3) After switching the system clock to the high-speed clock mode, BUPF may be reset to "0" at any timing. Take care of the status of BUPF when the system clock switches to the low-speed clock mode. It is impossible to get a low current consumption without resetting BUPF to "0".

Figure 5-2 shows the system clock switch timing and the internal logic power supply.

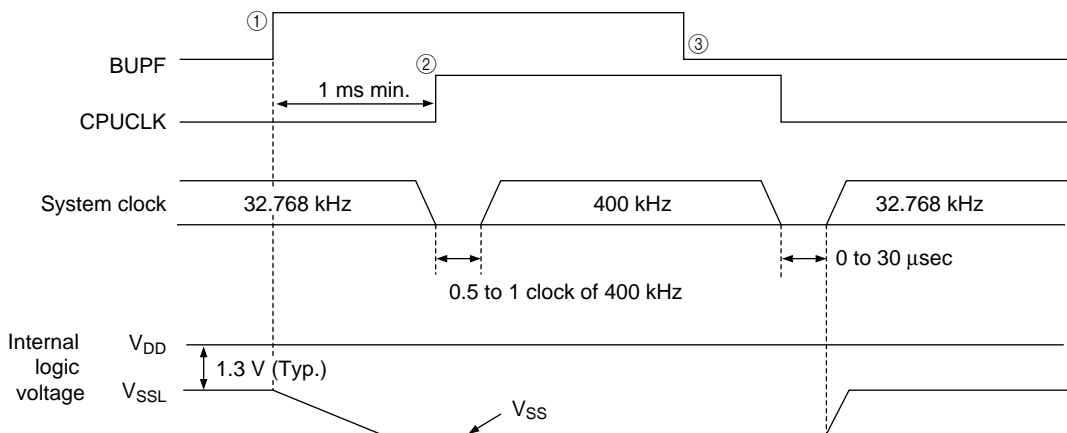


Figure 5-2 System Clock Switch Timing

Table 5-1 shows the clock generation circuit related pins. Table 5-2 shows typical values of oscillation frequencies of the RC oscillation circuit.

Table 5-1 Clock Generation Circuit Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Note
XT	76	61	Input	Low speed side clock oscillation input pin: This pin is connected to the crystal oscillator (32.768 kHz).
$\overline{\text{XT}}$	77	62	Output	Low speed side clock oscillation output pin: This pin is connected to the crystal oscillator (32.768 kHz).
OSC1	71	58	Input	High speed side clock oscillation pin: This pin is connected to the external resistance (R_{OS}) for oscillation.
OSC2	72	59	Output	

Table 5-2 Typical Values of Oscillating Frequencies of RC Oscillation Circuit
($T_a = 25^\circ\text{C}$)

V_{DD} (V)	R_{OS} (k Ω)	f_{osc} (kHz)
3.0	100	400
1.5	300	220

Chapter 6

Time Base Counter (TBC)

Chapter 6 Time Base Counter (TBC)

6.1 Overview

The MSM64162A has a built-in time base counter (TBC) that generates clocks to be supplied to internal peripheral circuits. The time base counter is composed of 15 binary counters. The count clock of the time base is supplied with the oscillation clock (32.768 kHz) of the crystal oscillation circuit. Output of the time base counter is used for the buzzer driver, the system reset circuit, the watchdog timer, the time base interrupt, sampling clocks of each port and the capture circuit.

6.2 Layout of Time Base Counter

Figure 6-1 shows the layout of the time base counter (TBC).

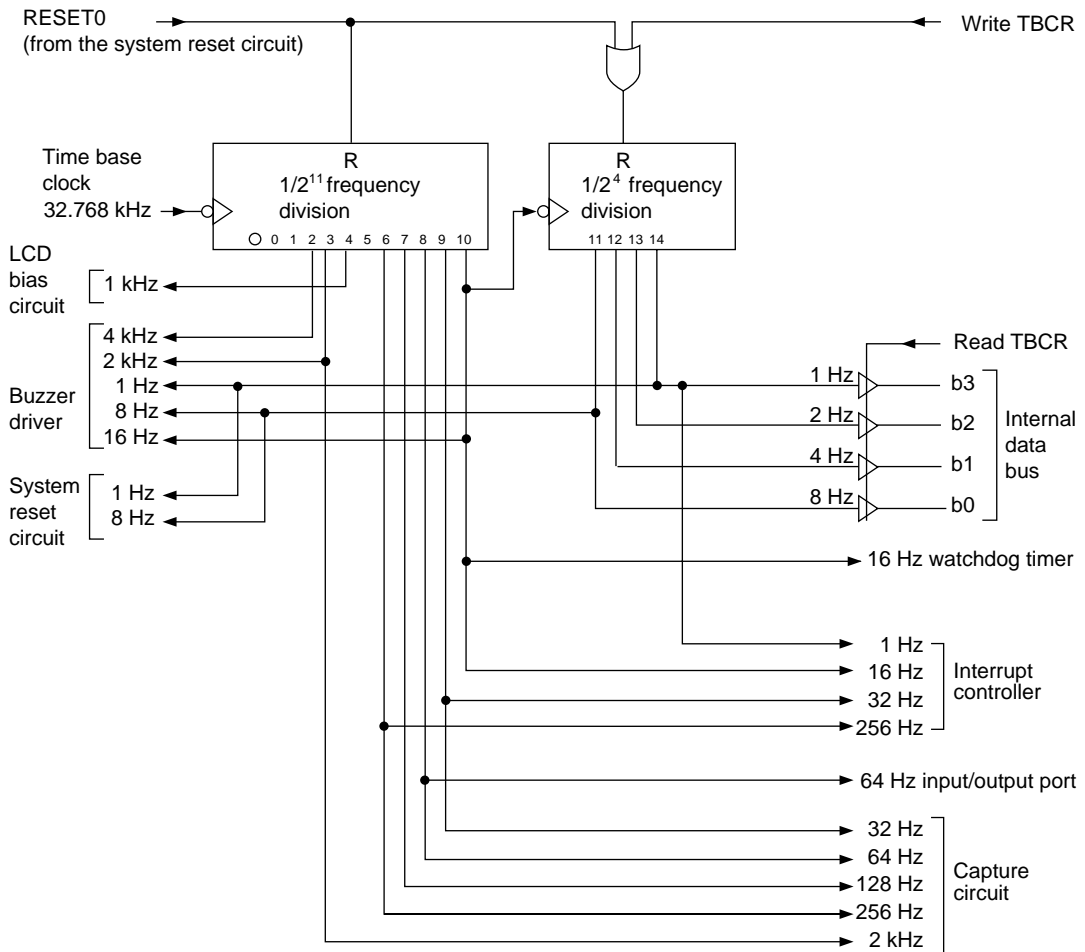


Figure 6-1 Layout of Timer Base Counter

6.3 Operation of Time Base Counter

The time base counter (TBC) starts count-up from 0000H after system reset. Count-up is started by falling of the time base clock (32.768 kHz).

256 Hz/32 Hz/16 Hz/4 Hz/1 Hz output of the time base counter is used as the timer base interrupt and a timer base interrupt request is generated at falling of each output.

The 16 Hz output of the time base counter is output to the watchdog timer. The output of 1 Hz/8 Hz/16 Hz and 4 kHz, 2 kHz is used by the buzzer driver and various buzzer sounds are output. The 64 Hz output is used as a sampling clock of input ports. The 1 Hz/8 Hz output is input to the system reset circuit and is used to generate reset timing at system reset and to switch a logic power supply. The output of 256 Hz/128 Hz/64 Hz/32 Hz becomes input data for the capture circuit.

The output of 1 Hz/2 Hz/4 Hz/8 Hz of the time base counter can be read by the time base counter register (TBCR). When a write operation is performed on TBCR, the counters of 1 Hz/2 Hz/4 Hz/8 Hz are reset to "0".

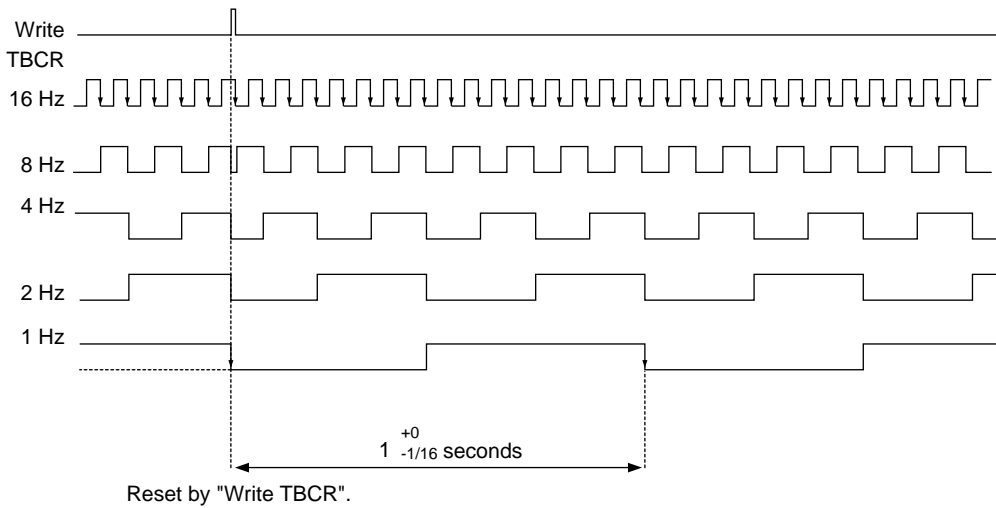
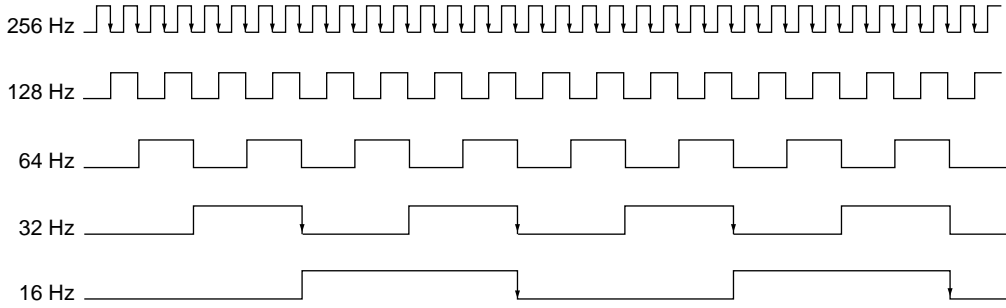
Figure 6-2 shows interrupt timing of the time base counter and reset timing by writing to TBCR.

Note: Outputs of 8 Hz to 1 Hz of the time base counter can be read by the time base counter register (TBCR) and they are reset to "0" by writing to TBCR. In this write operation, data to write have no significance. For example, writing by the "LMAD TBCR" instruction does not depend on the contents of the A register at all. When writing to TBCR and resetting 8 Hz to 1 Hz of the time base counter, a time base interrupt is generated when each output is "1". For example, when the 1 Hz output is "1", a 1 Hz interrupt request is generated. When an interrupt is invalidated, please write to TBCR and reset the interrupt request flag (Q1Hz) to "0" after resetting the master interrupt enable flag (MI) or the interrupt enable flag (E1Hz) to "0".

6.4 Time Base Counter Register (TBCR)

This register is a 4-bit special function register (SFR) to read 8 Hz to 1 Hz output of the time base counter. When writing, it resets the 8 Hz to 1 Hz output.

TBCR (0FH) (R/W)	b ₃	b ₂	b ₁	b ₀
	1Hz	2Hz	4Hz	8Hz
<u>Values of 8 Hz to 1 Hz of the time base counter</u>				



Note:  indicates interrupt timing.

Figure 6-2 Time Base Counter Interrupt Timing and Reset Timing by TBCR Writing

Chapter 7

Ports (P0, P1, P2 and P3)

Chapter 7 Ports (P0, P1, P2 and P3)

7.1 Overview

The MSM64162A has one 4-bit input port, two 4-bit input/output ports and one 4-bit output port built-in.

Table 7-1 shows the list of functions of each port. For secondary functions of the capture timer and the A/D converter, refer to Chapter 10 "Capture Circuit" and Chapter 12 "A/D Converter", respectively.

Table 7-1 List of Functions of Each Port

Pin name	Pin No.	Pad No.	Input/Output	Function
P0.0	2	1	Input	4-bit input port (P0): Can select (1) pull-up resistance input, (2) pull-down resistance input or (3) high-impedance input by the port 01 control register (P01CON). As a secondary function, P0.0 to P0.3 are assigned external interrupt functions and P0.0 and P0.1 are assigned a capture trigger function. In addition, P0.3 is assigned an analog comparator input for battery check.
P0.1	3	2	Input	
P0.2	4	3	Input	
P0.3	5	4	Input	
P1.0	27	23	Output	4-bit output port (P1): Can select NMOS open drain output or CMOS output by the port 01 control register (P01CON). P1.0 is a large current drive output port.
P1.1	28	24	Output	
P1.2	29	25	Output	
P1.3	30	26	Output	
P2.0	17	14	Input/Output	4-bit input/output port (P2): Selection of (1) pull-up/pull-down resistance input, (2) high-impedance input, (3) NMOS open drain output and (4) CMOS output by the port 2 control registers 0 to 3 (P20CON to P23CON) is possible. As a secondary function, an external interrupt function is assigned.
P2.1	18	15	Input/Output	
P2.2	19	16	Input/Output	
P2.3	20	17	Input/Output	
P3.0	21	18	Input/Output	4-bit input/output port (P3): Selection of (1) pull-up/pull-down resistance input, (2) high-impedance input, (3) NMOS open drain output and (4) CMOS output by the port 3 control registers 0 to 3 (P30CON to P33CON) is possible. As a secondary function, P3.0 to P3.3 are assigned an external interrupt function and P3.3 is assigned a monitor function of oscillator clock for A/D conversion.
P3.1	22	19	Input/Output	
P3.2	24	20	Input/Output	
P3.3/MON	25	21	Input/Output	

7.2 Port 0 and Port 1 (P0.0 to P0.3 and P1.0 to P1.3)

7.2.1 Layout of Port 0 and Port 1

Port 0 is a 4-bit input only port. Port 0 can be switched to either pull-up resistance input, pull-down resistance input or high-impedance input by the port 01 control register (P01CON). As a secondary function, an external interrupt function is assigned by level change. P0.0 and P0.1 are also assigned as trigger input pins of the capture circuit. For details of the capture circuit, refer to Chapter 10 "Capture Circuit".

Port 1 is a 4-bit output only port. Port 1 can be switched to either CMOS output or Nch open drain output by the port 01 control register (P01CON).

Figure 7-1 shows the layout of Port 0 and Port 1.

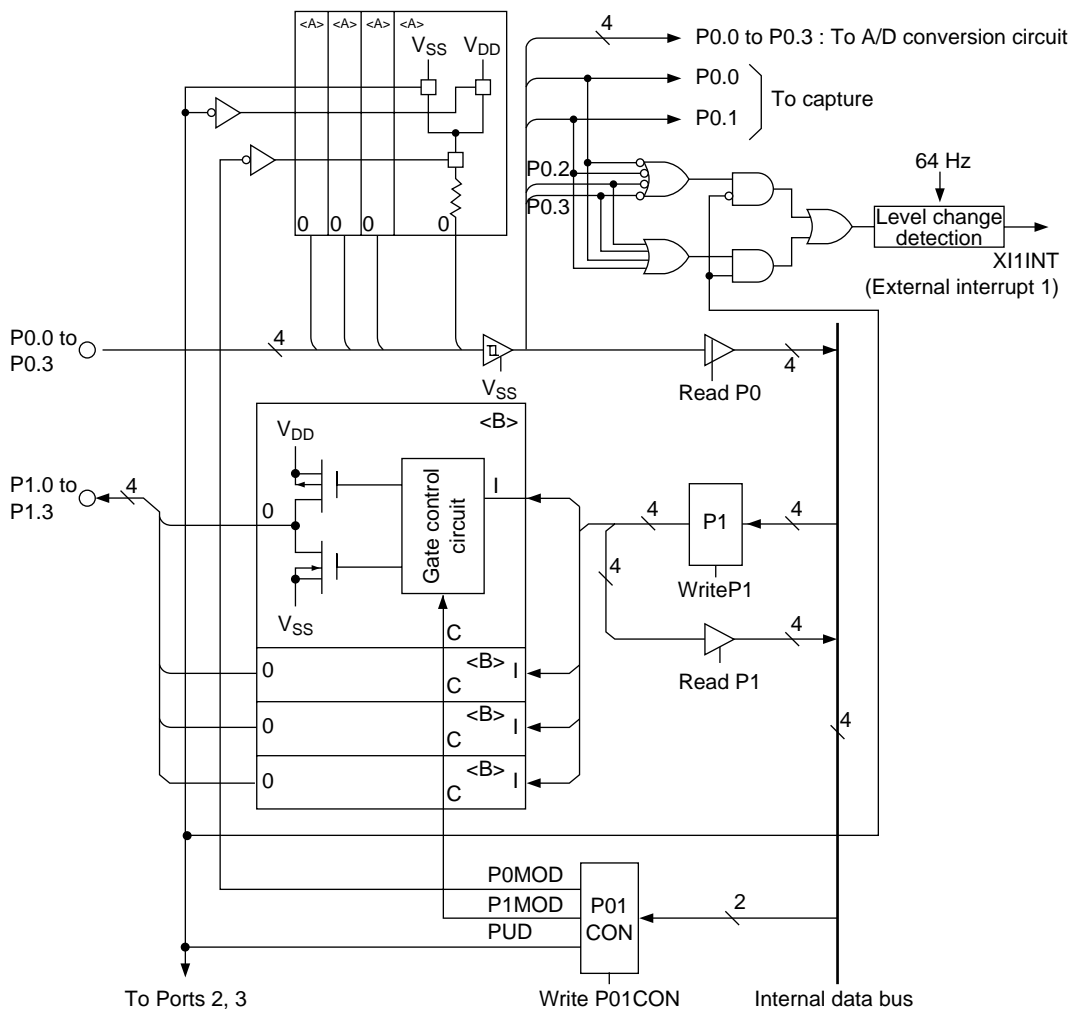
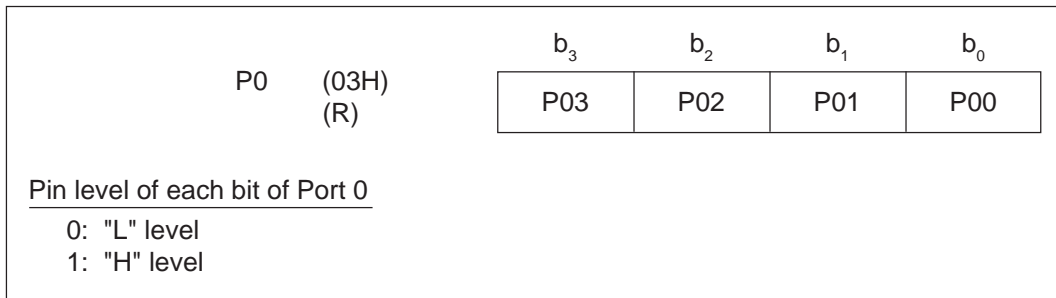


Figure 7-1 Layout of Port 0 and Port 1

7.2.2 Registers Related to Port 0 and Port 1

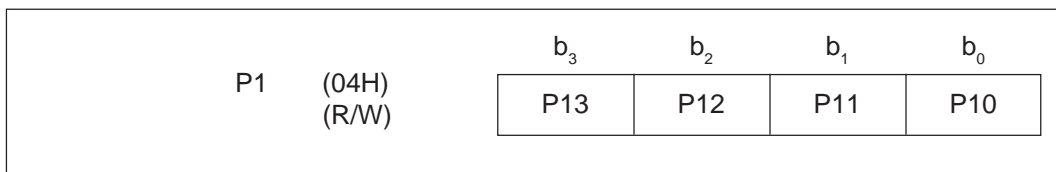
(1) Port 0 register (P0)

The port 0 register is a 4-bit read only special function register (SFR) to read out the level of each port or Port 0.



(2) Port 1 register (P1)

The port 1 register is a 4-bit special function register (SFR) to set the output value of Port 1.



At system reset, P1 is reset to "0".

When writing data to the port 1 register, actual timing of the change of the pin is the second half of State 3 of the last machine cycle of the write instruction. Figure 7-2 shows an example of varying timing of the port.

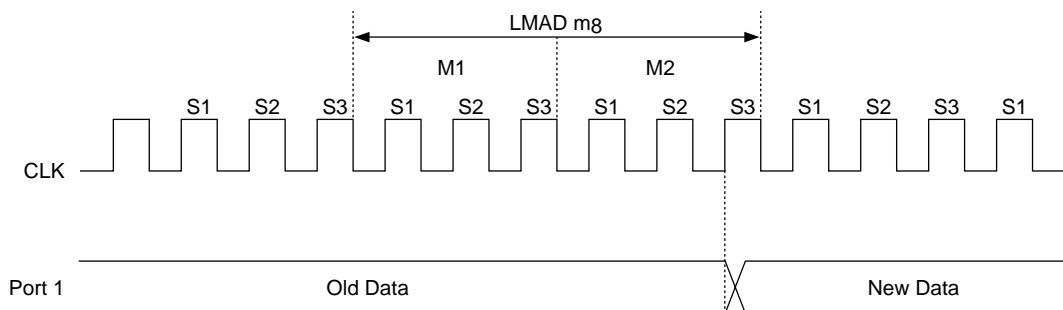


Figure 7-2 Example of Writing to Port Data Register by "LMAD mg" Instruction

When the data is read in from the port, the data is taken in the accumulator (A register) or the BA register pair at the latter half of the state 2 (S2) in the last machine cycle of the read instruction.

Figure 7-3 shows the timing example.

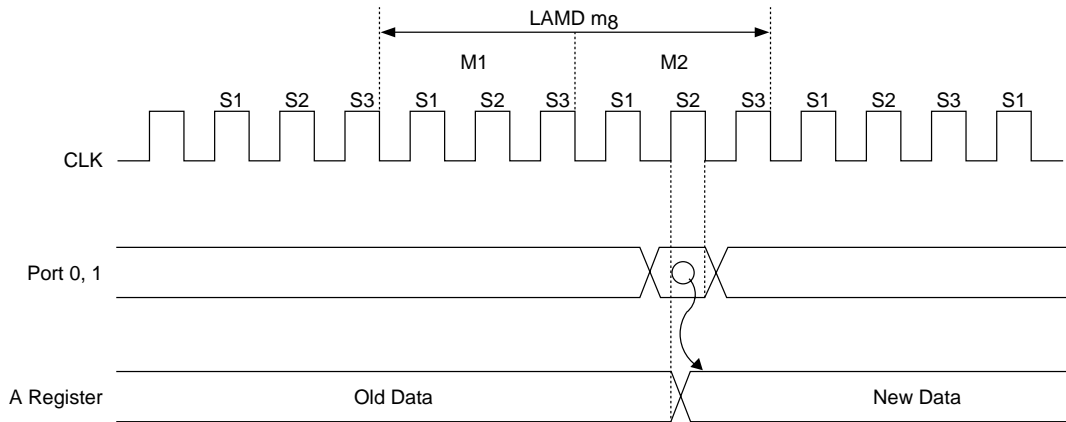
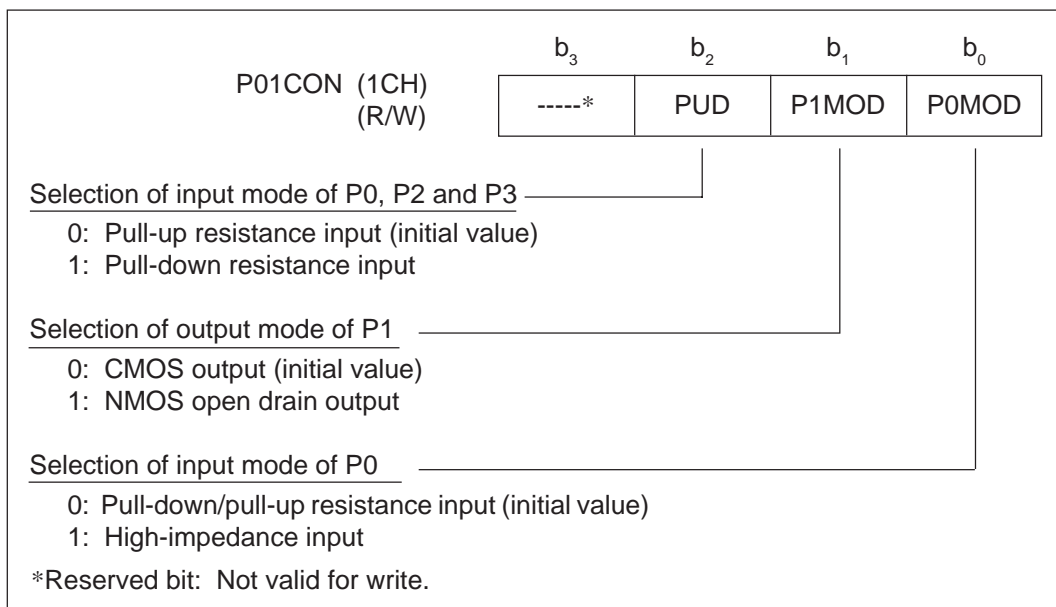


Figure7-3 Example of Reading the Data from the Port by the "LAMD mg" Instruction

(3) Port 01 control register (P01CON)

The Port 01 control register (P01CON) is a 4-bit special function register (SFR) to control input mode of Port 0, output mode of Port 1 and pull-down/pull-up resistance input when Ports 2 to 3 are selected as input. Since P01CON is a write-only register, bit manipulation and increment/decrement instructions cannot be used.



Bit 2: PUD

This bit is to select a pull-down/pull-up resistance when P0MOD is reset to "0" and Port 0 is selected as pull-down/pull-up resistance input. When PUD is reset to "0", Port 0 becomes pull-up resistance input and when PUD is set to "1", Port 0 becomes pull-down resistance input. When Ports 2 to 3 are set as input and pull-down/pull-up resistance input, PUD can select either pull-up resistance input or pull-down resistance input. At system reset, PUD is reset to "0".

Note: Input setting of Ports 2 to 3 and selection of pull-down/pull-up resistance input can be done by resetting the DIR bits and the MOD bits of the control registers of Ports 2 to 3 (P20CON to P23CON and P30CON to P33CON).

It is not possible to specify pull-up resistance input and pull-down resistance input of Port 0 and Ports 2 to 3 separately.

Bit 1: P1MOD

This bit is to select output mode of Port 1. By resetting P1MOD to "0", Port 1 becomes CMOS output and by setting P1MOD to "1", Port 1 becomes NMOS open drain output. At system reset, P1MOD is reset to "0". (It is not possible to control P1.0 to P1.3 separately.)

Bit 0: P0MOD

This bit is to select input mode of Port 0. By resetting P0MOD to "0", Port 0 becomes pull-down/pull-up resistance input and by setting P0MOD to "1", Port 0 becomes high-impedance input. When selecting pull-down/pull-up resistance input, either pull-down resistance input or pull-up resistance input is selected by the PUD bit. At system reset, P0MOD is reset to "0". (It is not possible to controlling P0.0 to P0.3 separately).

7.2.3 Port 0 External Interrupt Generation Timing

External interrupt generation of Port 0 is triggered by the falling of the 64 Hz output of the time base counter which is the sampling clock.

Delay time until the External 1 interrupt request flag (QX11) is set after the level of P0.n is changed to output XI1INT signal is a maximum period of 64 Hz (15.625 ms). Since the External 1 interrupt request flag (QX11) is set by level change of OR signal of Port 0 ports, which port the interrupt request comes from is judged by reading out Port 0.

The External 1 interrupt is generated by OR of P0.0 to P0.3. When the PUD bit is set to "1", the External 1 interrupt is generated when (1) input to all the ports is set to the "L" level when all the ports is in "H" and (2) input to any one of the ports is set to the "H" level when all the ports is in "L".

When the PUD bit is reset to "0", the External 1 interrupt is generated when (1) input to any one of the ports is set to the "L" level when all the input to P0.0 to P0.3 is in "H" and (2) input to all the ports is set to the "H" level when all the input to P0.0 to P0.3 is in "L".

The interrupt vector address of the External 1 interrupt is address 032H.

Figure 7-4 shows the generation circuit of External 1 interrupt. Figure 7-5 and Figure 7-6 show generation timing of the External 1 interrupt by the PUD bit.

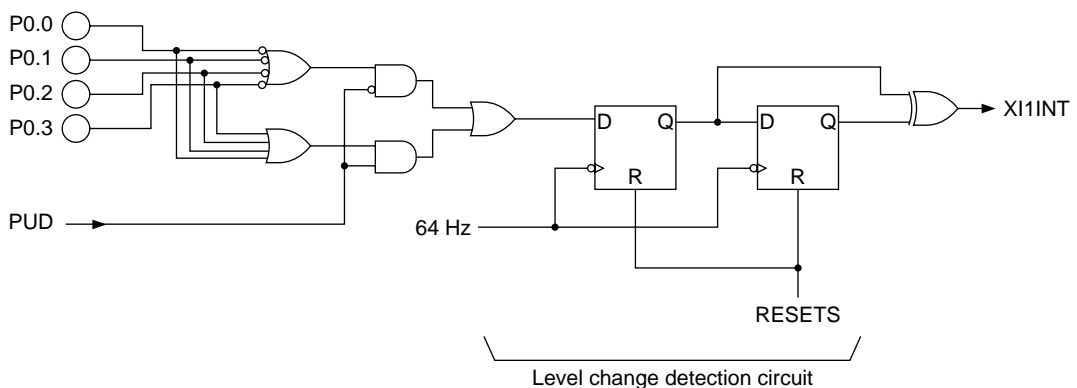


Figure 7-4 External 1 Interrupt Generation Circuit

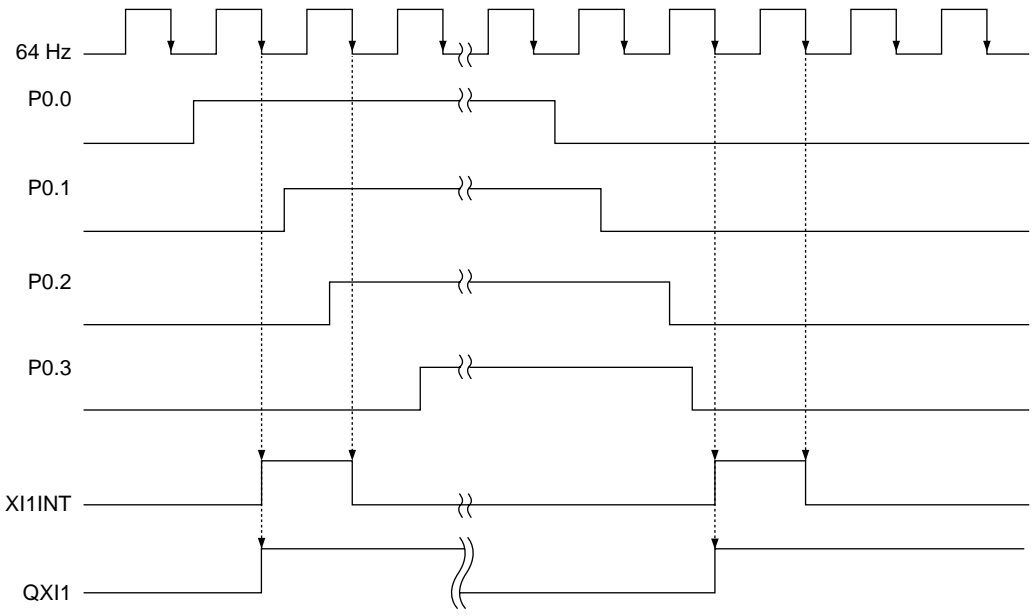


Figure 7-5 External 1 Interrupt Generation Timing (When PUD = 1)

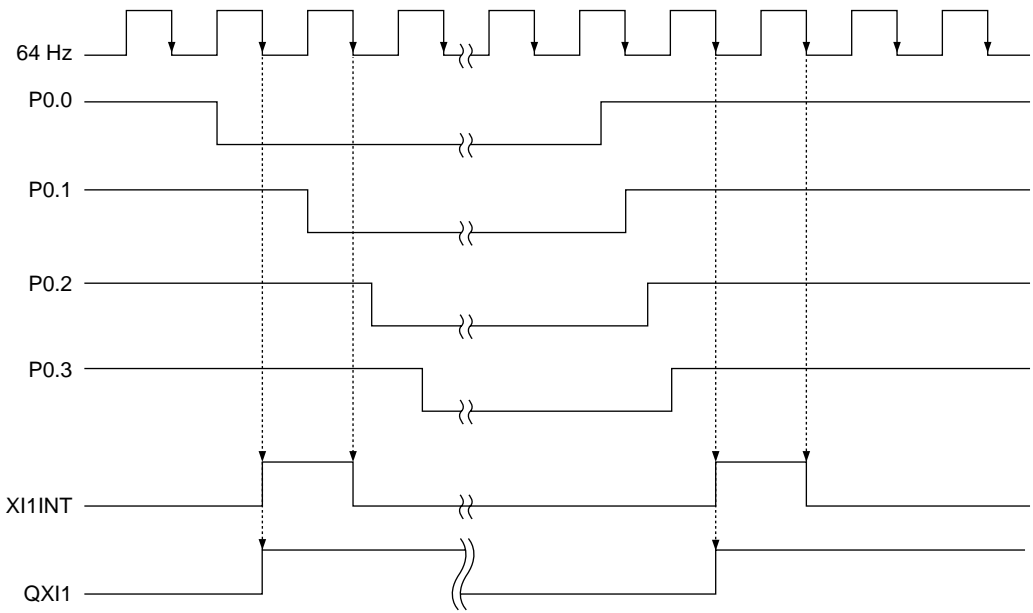


Figure 7-6 External 1 Interrupt Generation Timing (When PUD = 0)

7.3 Port 2 and Port 3 (P2.0 to P2.3 and P3.0 to P3.3)

7.3.1 Layout of Port 2 and Port 3

Ports 2 and 3 are 4-bit input/output ports. Each bit can be switched to either pull-up/pull-down resistance input, high-impedance input, CMOS output or NMOS open drain output by the Control registers of Ports 2 and 3 (P20CON to P23CON and P30CON to P33CON). Pull-up resistance input or pull-down resistance input can be selected by the PUD bit of the Port 01 control register (P01CON).

These ports are assigned an external interrupt function by level change as a secondary function. A RC oscillation clock monitor function is assigned for P3.3. For details of the monitor functions of the RC oscillation clock, refer to Chapter 12 "A/D Converter" and Chapter 15 "Test Circuit".

Figure 7-7 shows the layout of Port 2 and Port 3.

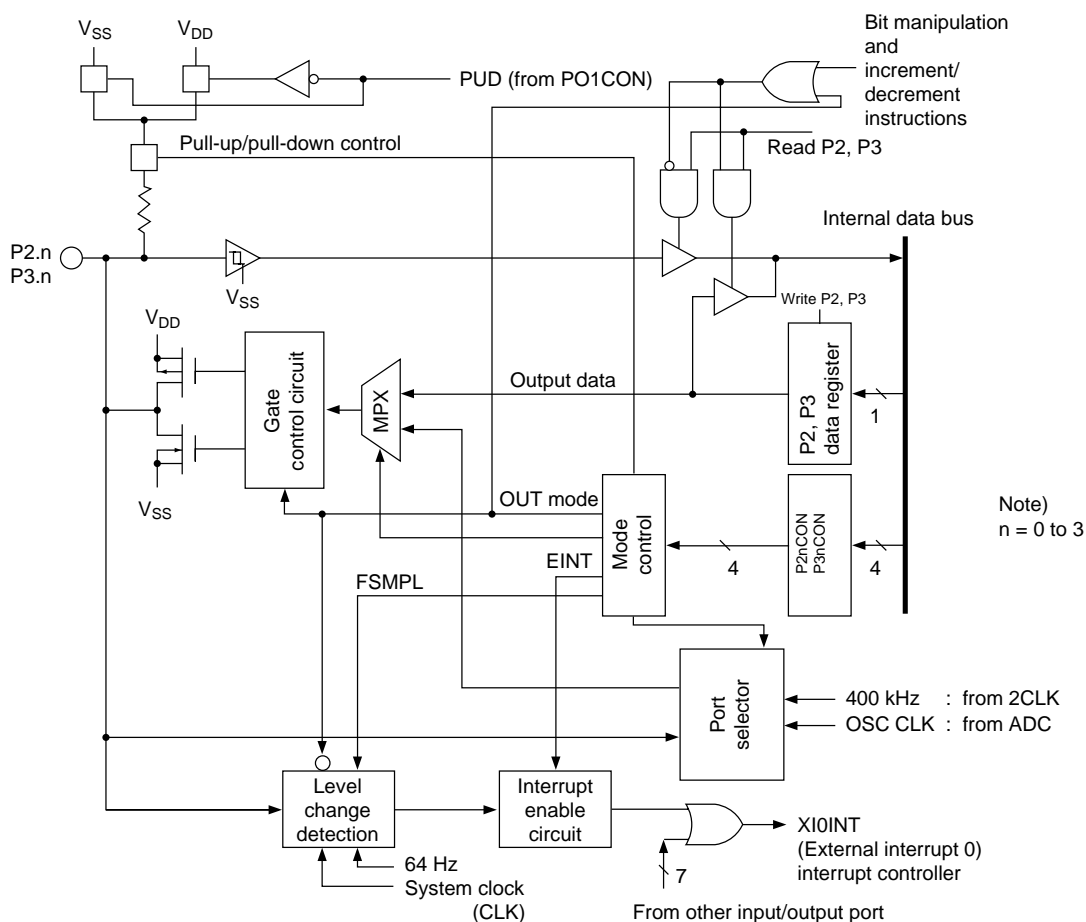


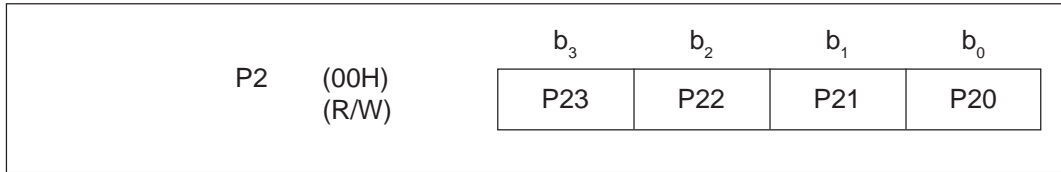
Figure 7-7 Layout of Port 2 and Port 3

7.3.2 Registers Related to Port 2 and Port 3

(1) Port 2 register (P2)

The Port 2 register is a 4-bit special function register to set the output value of the port. When bit 1 (P20DIR to P23DIR) of the Port 2 control register (P20CON to P23CON) is set to "1" to select output mode, the contents of the Port 2 register are output to the port.

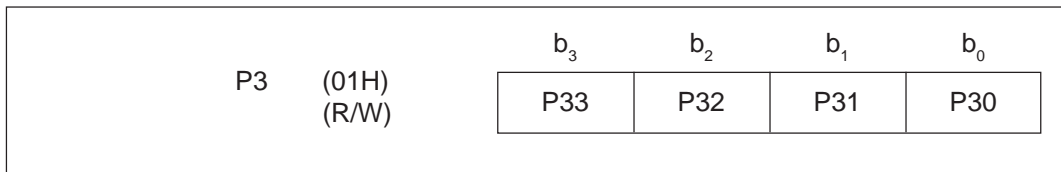
When reading out P2 while output mode is selected (P20DIR to P23DIR = 1), the contents of the Port 2 register are read. However, when P2 is read while input mode is selected (P20DIR to P23DIR = 0), the pin level of port is read out.



(2) Port 3 register (P3)

The Port 3 register is a 4-bit special function register to set the output value of the port. When bit 1 (P30DIR to P33DIR) of the Port 3 control register (P30CON to P33CON) is set to "1" to select output mode, the contents of the Port 3 register are output to the port.

When reading out P3 while output mode is selected (P30DIR to P33DIR = 1), the contents of the Port 3 register are read. However, when P3 is read while input mode is selected (P30DIR to P33DIR = 0), the pin level of port is read out.



It is possible to specify input/output bitwise by each Port control register for Ports 2 and 3. Consequently, depending on how each DIR bit is specified, contents of each register are read for some bits while the level of each pin are read for other bits.

At system reset, the Port 2 and 3 registers (P2, P3) are reset to "0".

When writing data to each register, actual timing of each pin is the second half of State 3 of the last machine cycle of the write instruction. Figures 7-8 shows an example of varying timing of the ports.

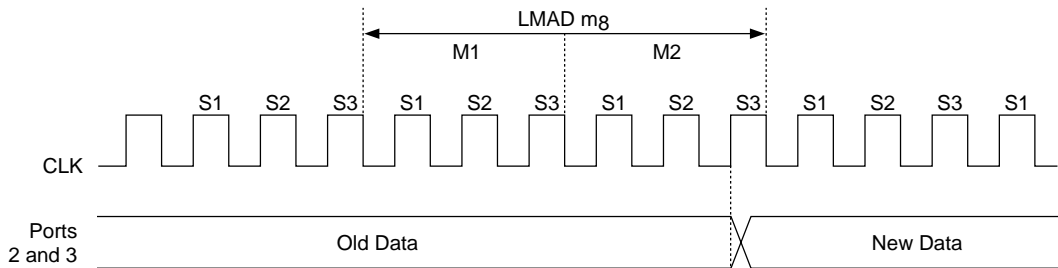


Figure 7-8 Example of Writing of Port Data Register by the "LMAD mg" Instruction

When the data is read in from the Port, the data is taken in the accumulator (A register) or the BA register pair at the latter half of the state 2 (S2) in the last machine cycle of the read instruction.

Figure 7-9 shows the timing example.

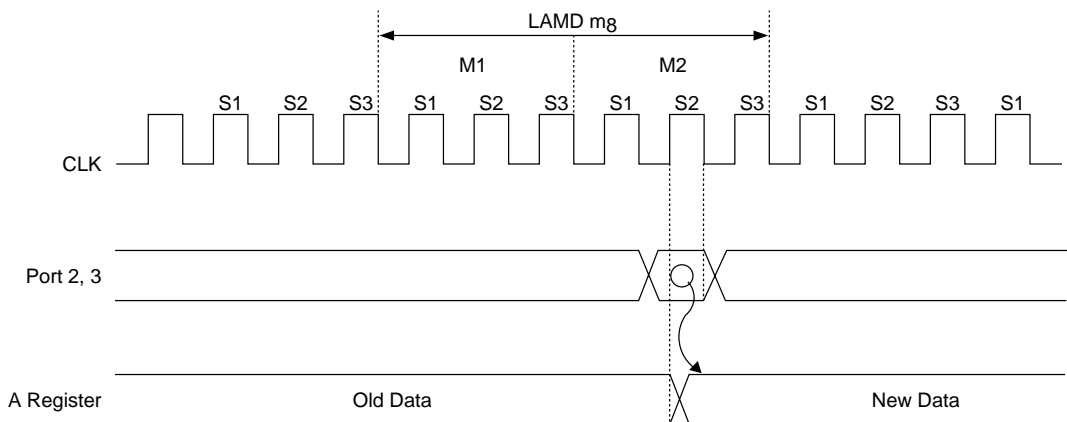
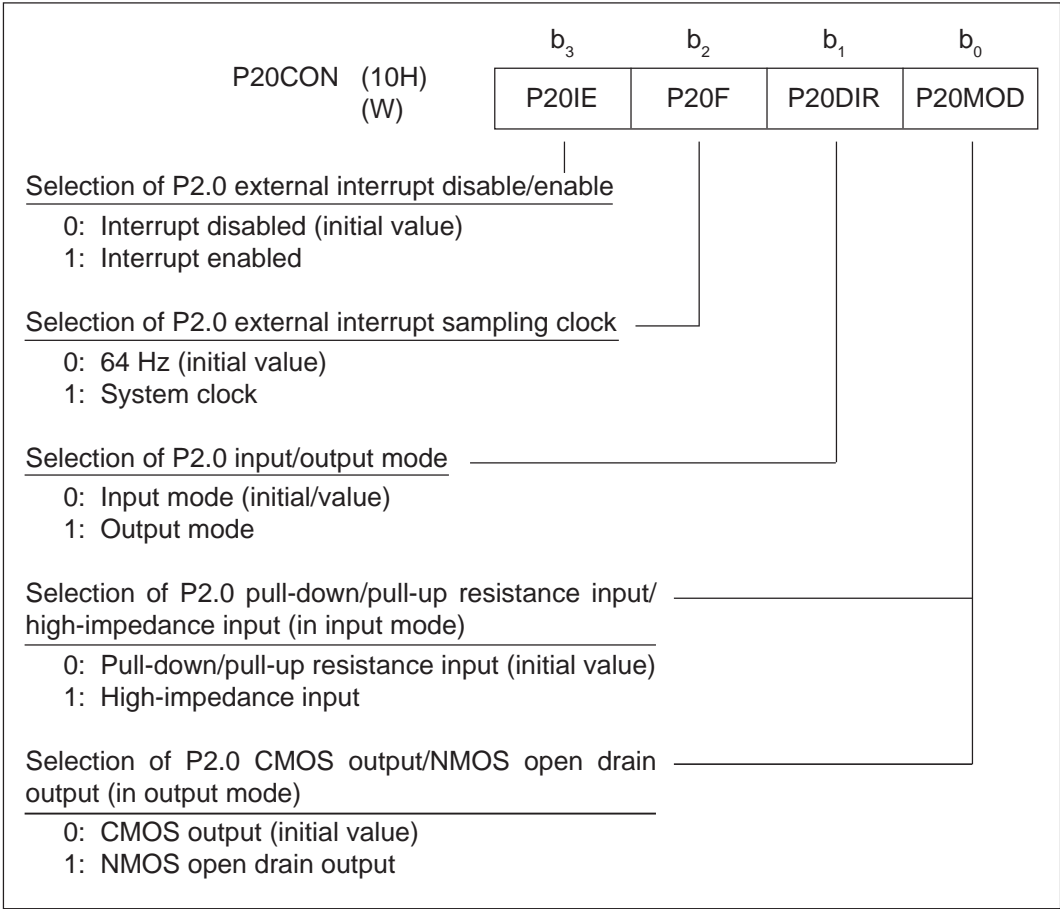
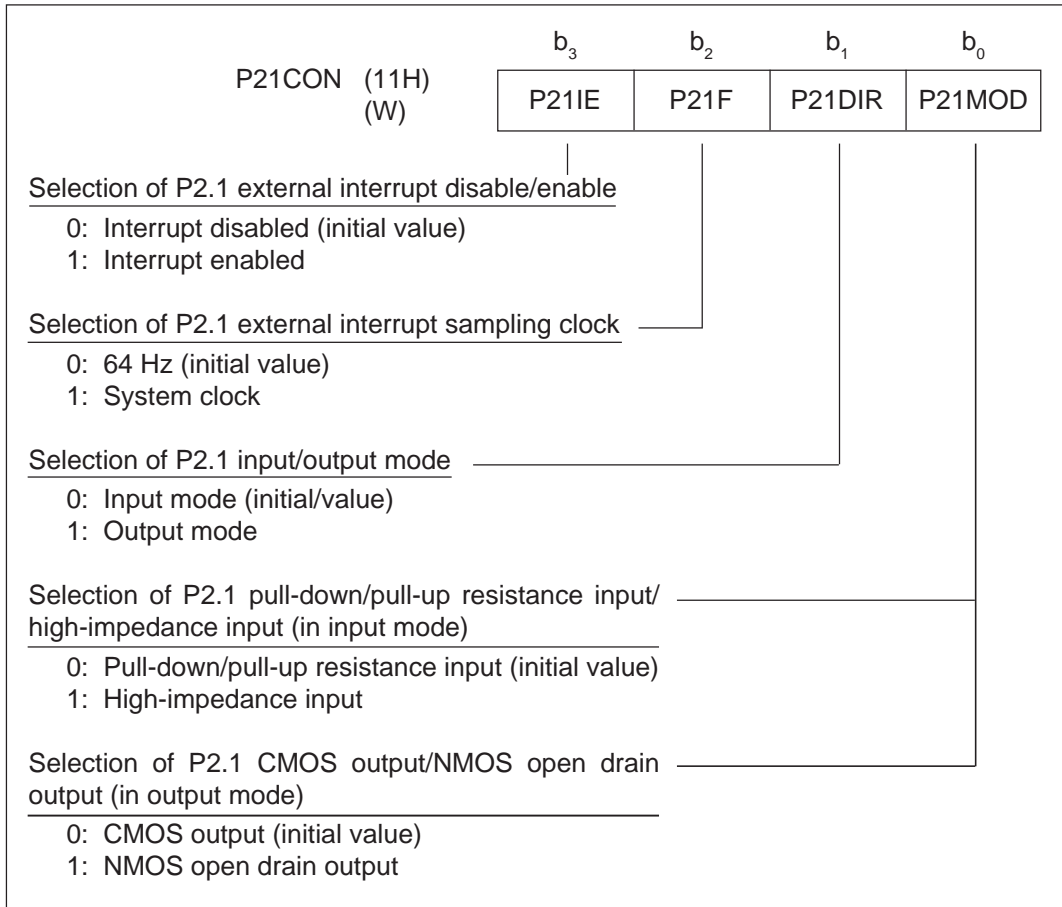


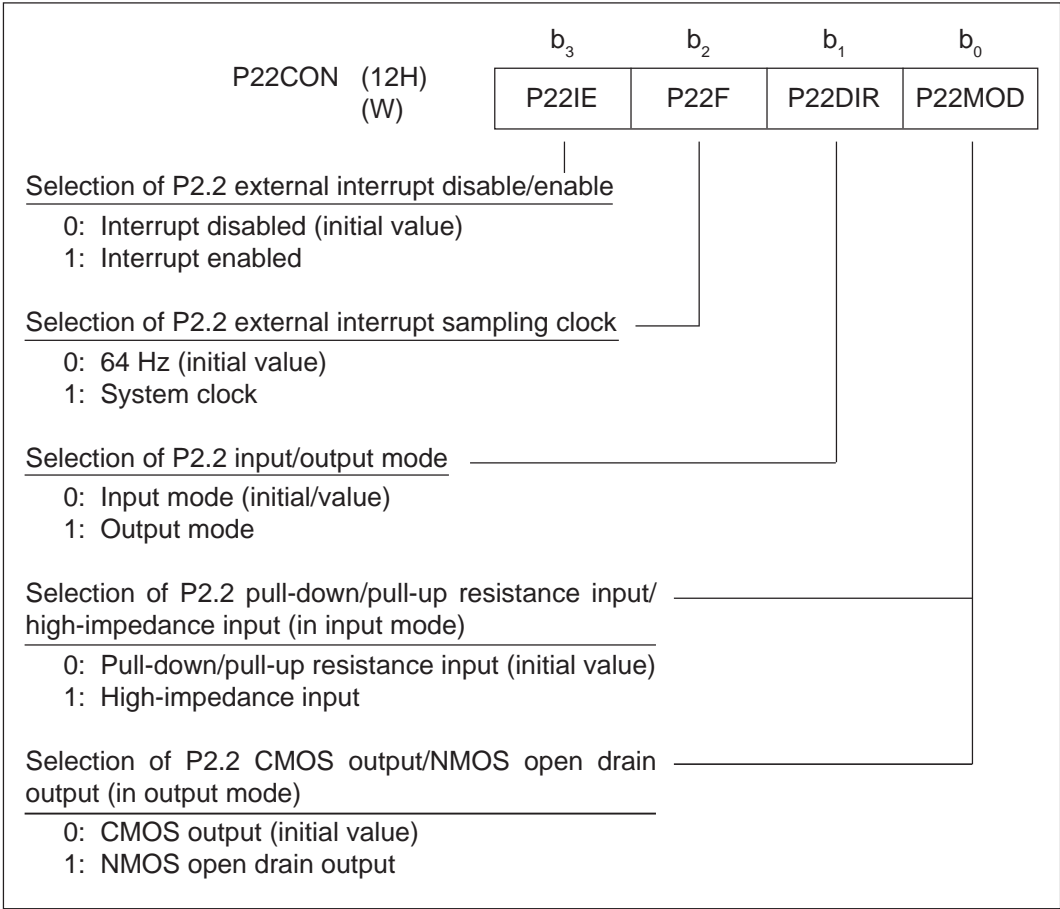
Figure 7-9 Example of Reading the Data from the Port by the "LAMD mg" Instruction

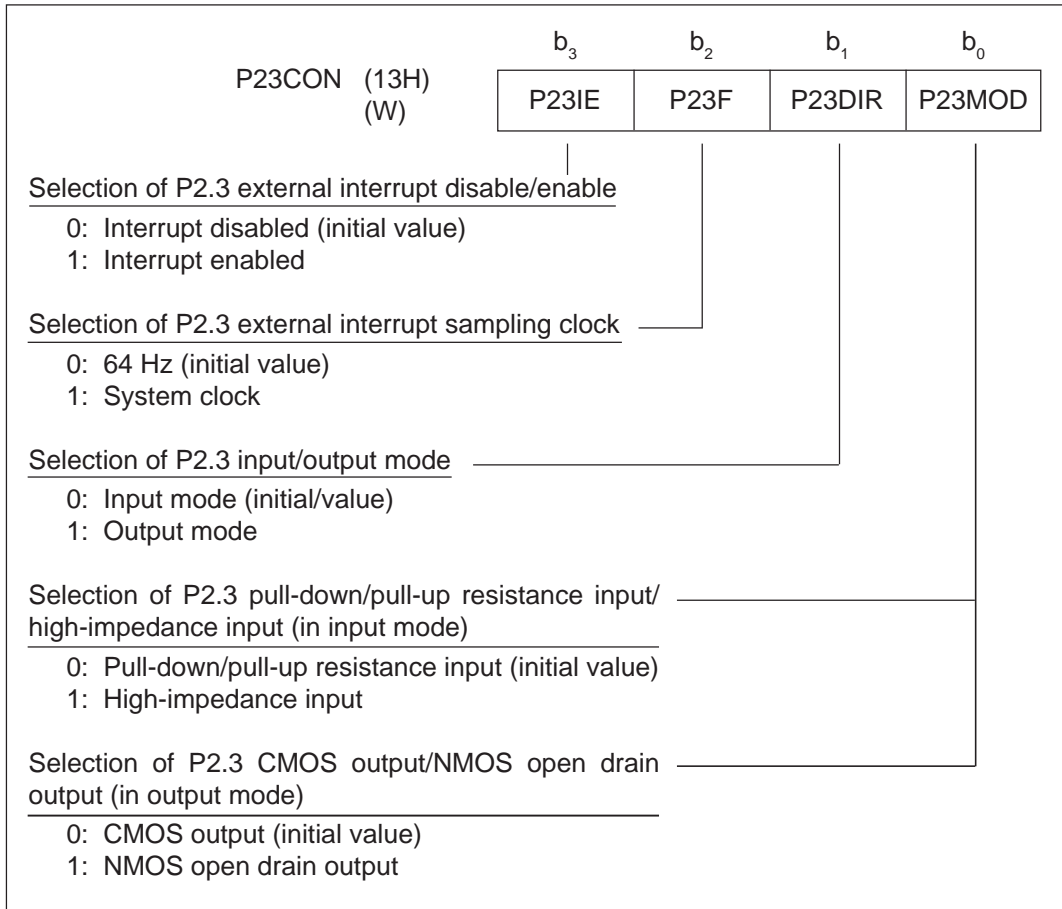
(3) Port 2 control registers (P20CON to P23CON)

The Port 2 control registers (P20CON to P23CON) are 4-bit special function registers (SFRs) to perform selection of input/output mode, selection of pull-down/pull-up resistance input or high impedance input in input mode, selection of CMOS output or NMOS open drain output in output mode, selection of external interrupt disable or enable and selection of sampling clocks of external interrupts. Since P20CON to P23CON are write-only registers, it is not possible to use bit manipulation instructions and increment/decrement instructions.



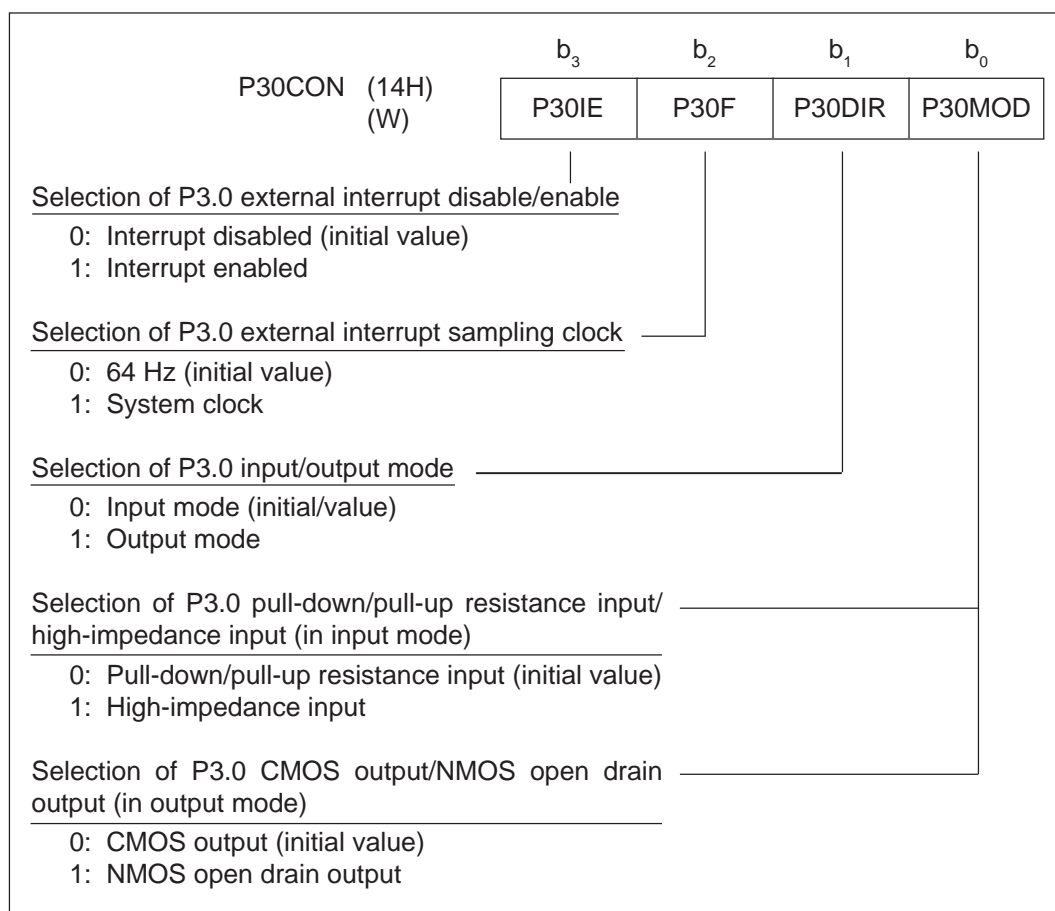


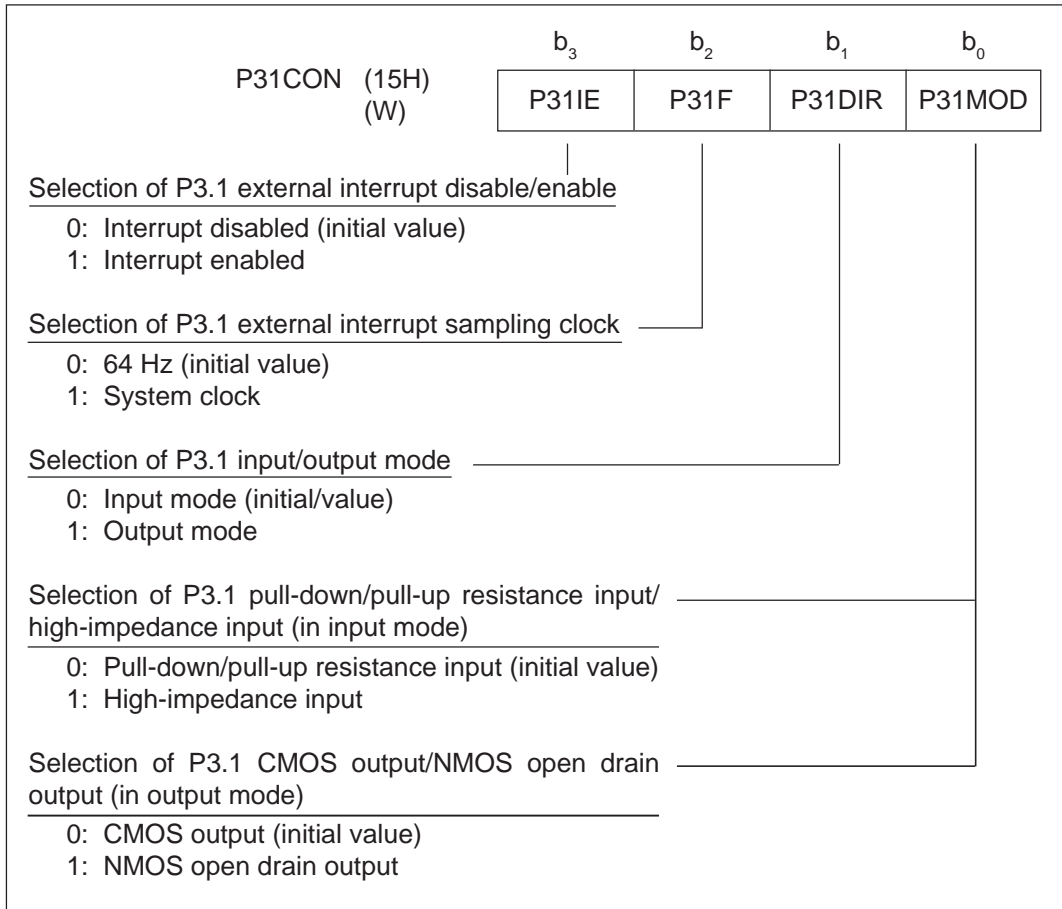


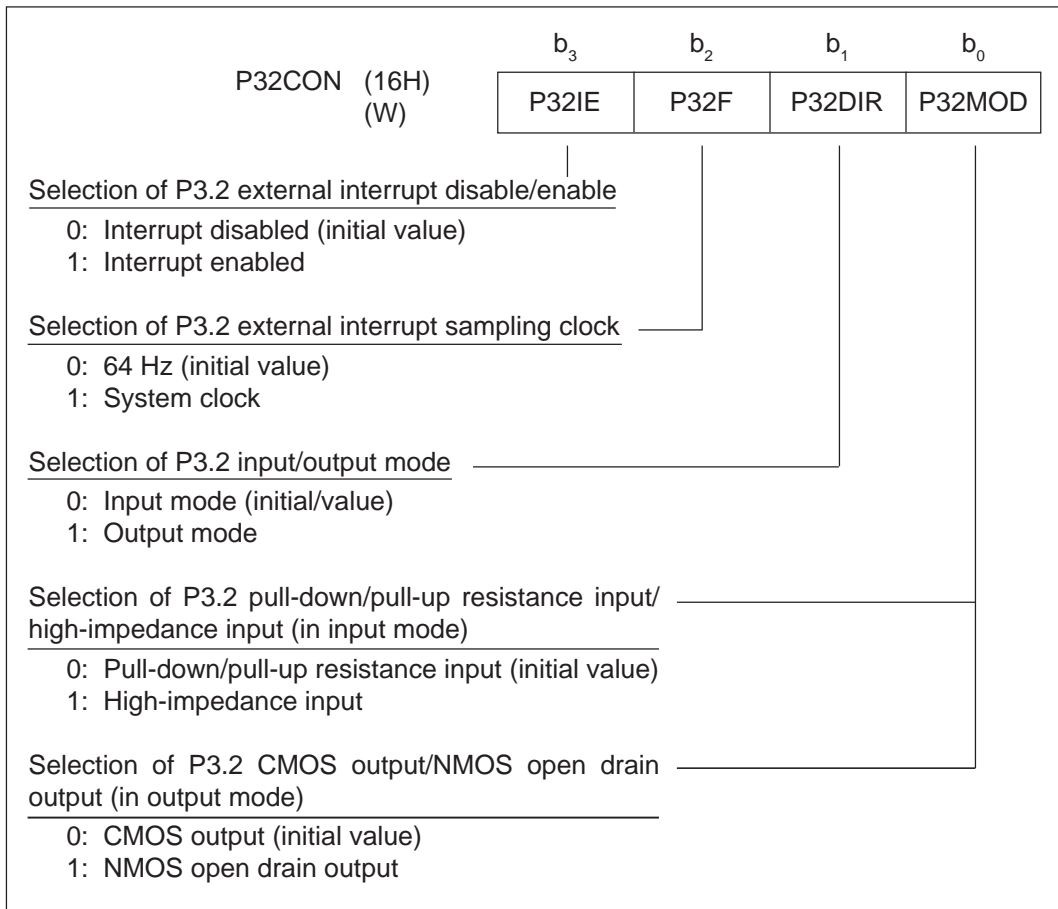


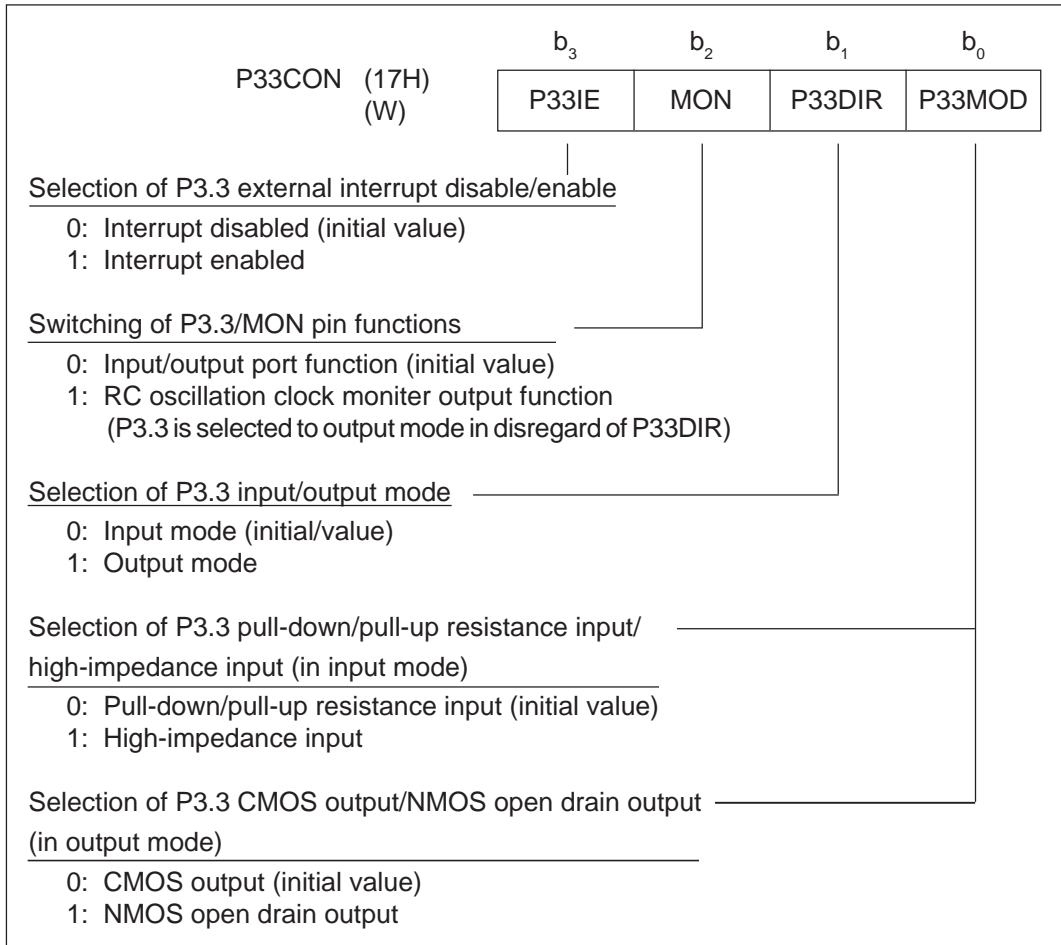
(4) Port 3 control registers (P30CON to P33CON)

The Port 3 control registers (P30CON to P33CON) are 4-bit special function registers (SFRs) to perform selection of input/output mode, selection of pull-down/pull-up resistance input or high impedance input in input mode, selection of CMOS output or NMOS open drain output in output mode, selection of external interrupt disable or enable and selection of sampling clocks of external interrupts. There is no selection bit of sampling clock of an external interrupt for Port 3.3 and selection of the RC oscillation output Monitor (MON) function is assigned which is a secondary function of the A/D converter. Since P30CON to P33CON are write-only registers, it is not possible to use bit manipulation instructions and increment/decrement instructions.









Bit 3: P20IE to P23IE and P30IE to P33IE

This bit is to select disabling/enabling external interrupts. When each IE bit is reset to "0", external interrupts are disabled and when each IE bit is set to "1", the external 0 interrupt request is generated by detecting the change of input level of the pin if the corresponding port is an input port. At system reset, each IE bit is reset to "0".

Bit 2: P20F to P23F and P30F to P32F

This bit is to select a sampling clock of an external interrupt. When each F bit is reset to "0", the 64 Hz output of the time base counter is chosen as the sampling clock and when each F bit is set to "1", the system clock (32.768 kHz or 400 kHz) is selected as the sampling clock. At system reset, each F bit is reset to "0". There is no selection function of the sampling clock of external interrupts for P3.3 and it is fixed at 64 Hz.

Bit 2: MON (P33CON)

This bit is to set output of RC oscillation clock (MON) which is a secondary function of Port 3.3. When MON is reset to "0", P3.3 becomes a normal port function and when MON is set to "1", output function of A/D converter RC oscillation clock is assigned. When MON is set to "1", P3.3 is automatically set to output mode. At system reset, MON is reset to "0".

Bit 1: P20DIR to P23DIR and P30DIR to P33DIR

This bit is to select input/output of each port. When each DIR bit is reset to "0", each port becomes input mode and when each DIR bit is set to "1", each port becomes output mode. At system reset, each DIR bit is reset to "0".

Bit 0: P20MOD to P23MOD and P30MOD to P33MOD

When each DIR bit is reset to "0" to select input mode, pull-down/pull-up resistance input or high-impedance input is selected.

When each DIR bit is set to "1" to select output mode, CMOS output or NMOS open drain output is selected.

When each MOD bit is reset to "0", pull-down/pull-up resistance input is selected in input mode and CMOS output mode is selected in output mode. When each MOD bit is set to "1", high-impedance input is selected in input mode and NMOS open drain output mode is selected in output mode. Selection of pull-up input is done by bit 2 (PUD) of the Port 01 control register (P01CON). When PUD is reset to "0", it becomes pull-up resistance input and when PUD is set to "1", it becomes pull-down resistance input.

At system reset, each MOD bit is reset to "0".

Table 7-2 shows relationship among each DIR bit, each MOD bit and each PUD bit.

Table 7-2 Relation among Each DIR Bit, Each MOD Bit and Each PUD Bit

Each DIR	Each MOD	PUD	State of input/output
0	0	0	Pull-up resistance input selected
0	0	1	Pull-down resistance input selected
0	1	—	High-impedance input selected
1	0	—	CMOS output selected
1	1	—	NMOS open drain output selected

7.3.3 External Interrupt Generation Timing of Port 2 and Port 3

External interrupt of Ports 2 and 3 are generated when each IE bit (P20IE to P23IE and P30IE to P33IE) of P2.0 to P2.3 and P3.0 to P3.3 are set to "1" and by the change of an input level of those ports for which each DIR bit (P20DIR to P23DIR and P30DIR to P33DIR) is set to "0" (set for interrupt enable and input mode). An External 0 interrupt is generated by OR signal of each level change detection signal.

Change of input level can be sampled by 64 Hz output of the time base counter which is the sampling clock or by falling of the system clock (32.768 kHz or 400 kHz). Selection of the sampling clock is performed by Bit 2 (P20F to P23F, P30F to P32F) of each port control register and when the F bit is reset to "0", the sampling clock becomes 64 Hz and when the F bit is set to "1", the sampling clock changes to the system clock. There is no function to select the sampling clock for P3.3 and they are fixed at 64 Hz output of the time base counter.

Delay time until the External 0 interrupt request flag (QXIO) is set after the level of Port 2 and Port 3, is changed to output XI0INT signals is one period of the sampling clock. Since the External 0 interrupt request flag (QXIO) is set by input level change of one of Port 2 and Port 3, which port the interrupt request comes from should be judged by checking the signal level after reading out each port.

The interrupt vector address of External interrupt XI0INT is address 038H.

Figures 7-10 and 7-11 show the External 0 interrupt generation circuit and timing.

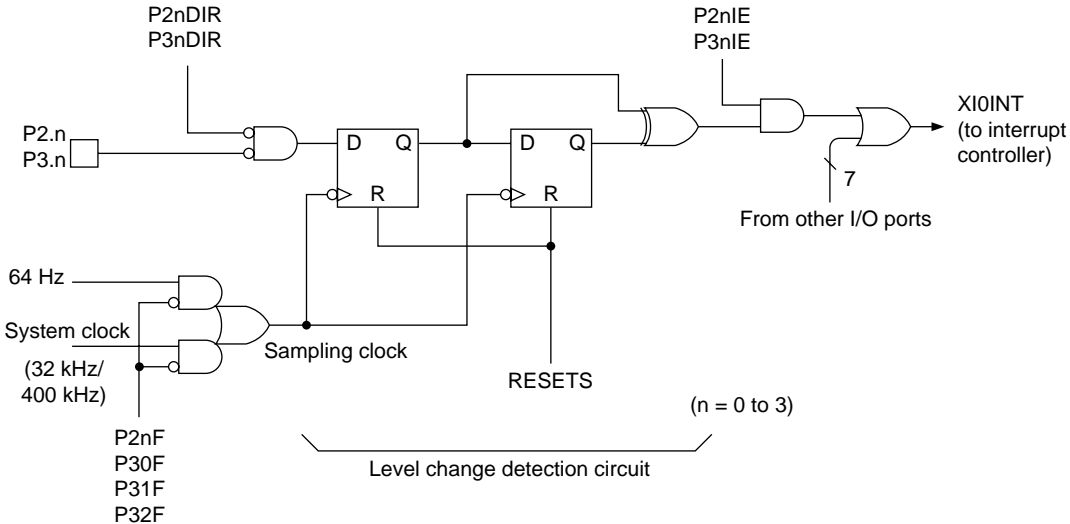


Figure 7-10 External 0 Interrupt Generation Circuit (one bit)

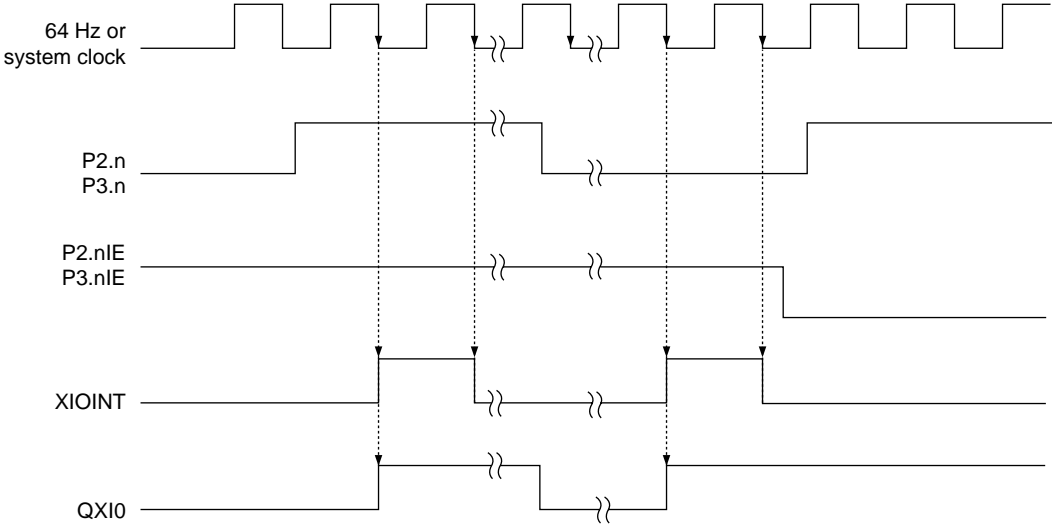


Figure 7-11 External 0 Interrupt Generation Timing

Table 7-3 shows the list of port-related registers.

Table 7-3 List of Port-Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
Port 2 register	P2	00H	R/W	Yes	0H
Port 3 register	P3	01H	R/W		0H
Port 0 register	P0	03H	R	No	Depends on input value
Port 1 register	P1	04H	R/W	No	0H
Port 20 control register	P20CON	10H	W	Yes	0H
Port 21 control register	P21CON	11H	W		0H
Port 22 control register	P22CON	12H	W	Yes	0H
Port 23 control register	P23CON	13H	W		0H
Port 30 control register	P30CON	14H	W	Yes	0H
Port 31 control register	P31CON	15H	W		0H
Port 32 control register	P32CON	16H	W	Yes	0H
Port 33 control register	P33CON	17H	W		0H
Port 01 control register	P01CON	1CH	W	No	8H
Interrupt enable register 0	IE0	30H	R/W	Yes	2H
Interrupt request register 0	IRQ0	34H	R/W	Yes	2H

Chapter 8

Battery Check (BC)

Chapter 8 Battery Check (BC)

8.1 Overview

The battery check circuit applies current to the external IC load equalizing resistor (R_{BLD}) and detects the level down of current voltage by comparing the voltage with the internal reference voltage (V_{rb}).

8.2 Layout of Battery Check Circuit

The battery check circuit is composed of a comparator and reference voltage generation circuit. The comparator input is assigned P0.3 port (also used as input port).

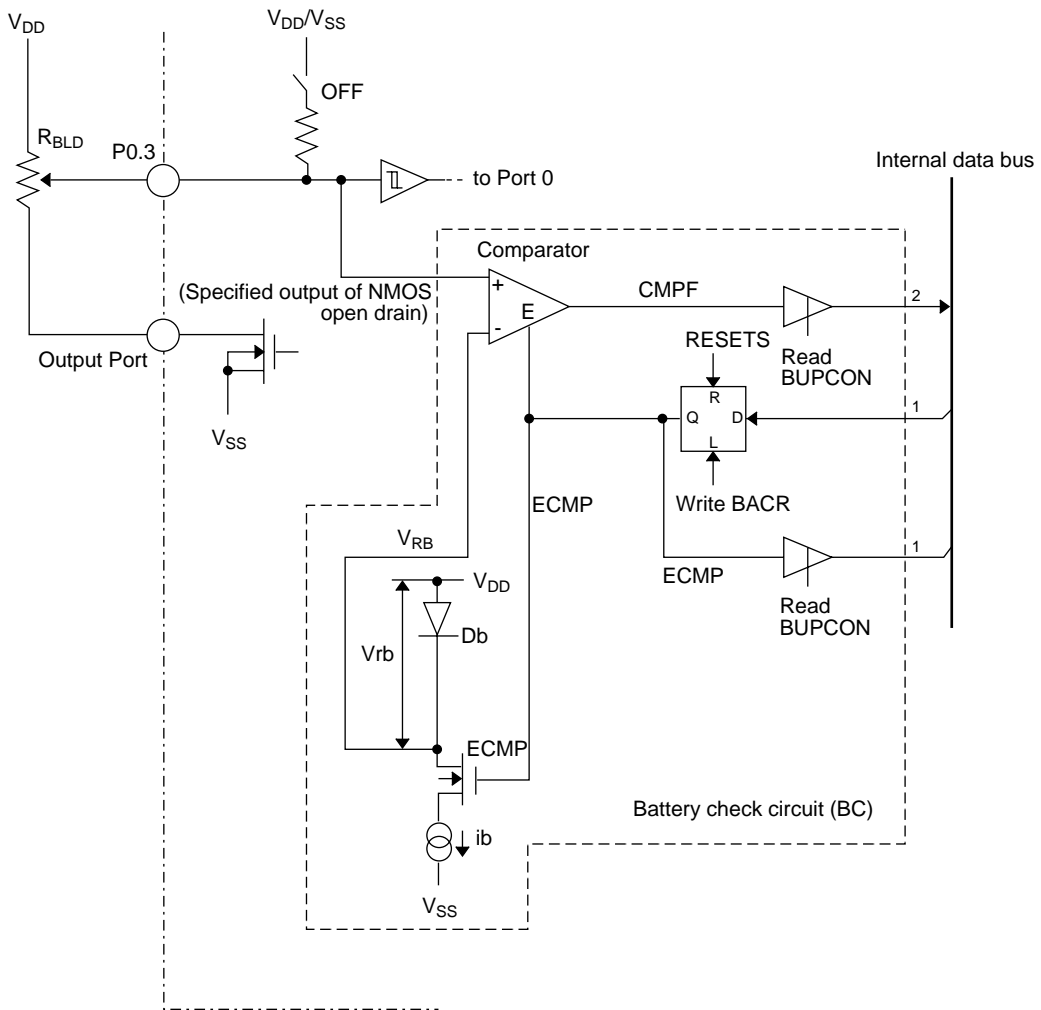


Fig. 8-1 Layout of Battery Check Circuit

Figure 8-1 shows the layout of the battery check circuit.

As shown in Figure 8-1, the P0.3 input port is also used as the comparator input.

Therefore, cut off the pull-up or pull-down resistor before battery check.

By controlling ON/OFF of the external resistor (RBLD) with the NMOS open drain output port, a simple battery check circuit is available.

The reference voltage V_{rb} is about V_{DD} 0.6 V. However, because this voltage level is not accurate, in order to correct the variation in the voltage level, it is required to match it to the necessary battery check voltage level with an external variable resistor RBLD.

8.3 Operation of Battery Check Circuit

The battery check circuit is controlled and checked by the ECMP and CMPF assigned to the Back-up control register BUPCON (refer to Chapter 14).

The ECMP is an enable bit of comparator. When ECMP is set to "1", the reference voltage is generated and comparator is started and when it is set to "0", the comparator is halted.

The CMPF is an output of comparator. When CMPF is "1", the input voltage level is higher than the reference voltage level, and when it is "0", the input voltage is lower than the reference voltage. The value of CMPF is not valid when the ECMP is "0".

Figure 8-2 shows operation timing of the battery check operation.

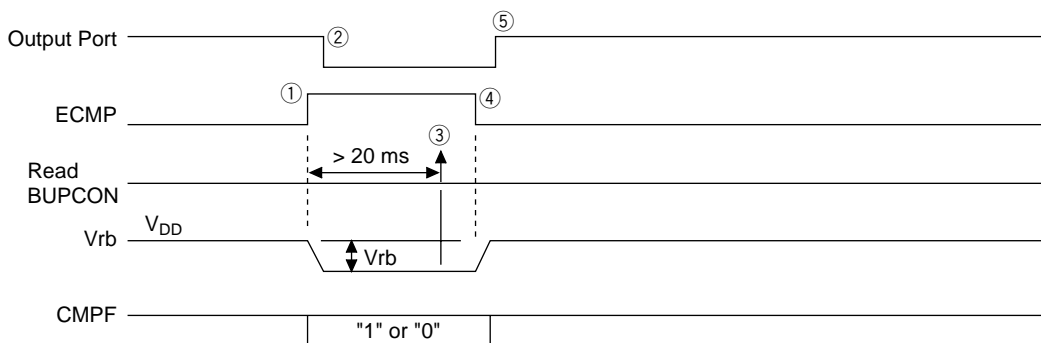


Figure 8-2 Battery Check Timing

The operations in Figure 8-2 are described below.

First, set ECMP to "1" to operate the battery check circuit (①), and switch the output port X from "1" to "0" to input the divided supply voltage to P0.3 (②).

Next, t_D after the operation (①), read CMPF that is the results of battery check (③).

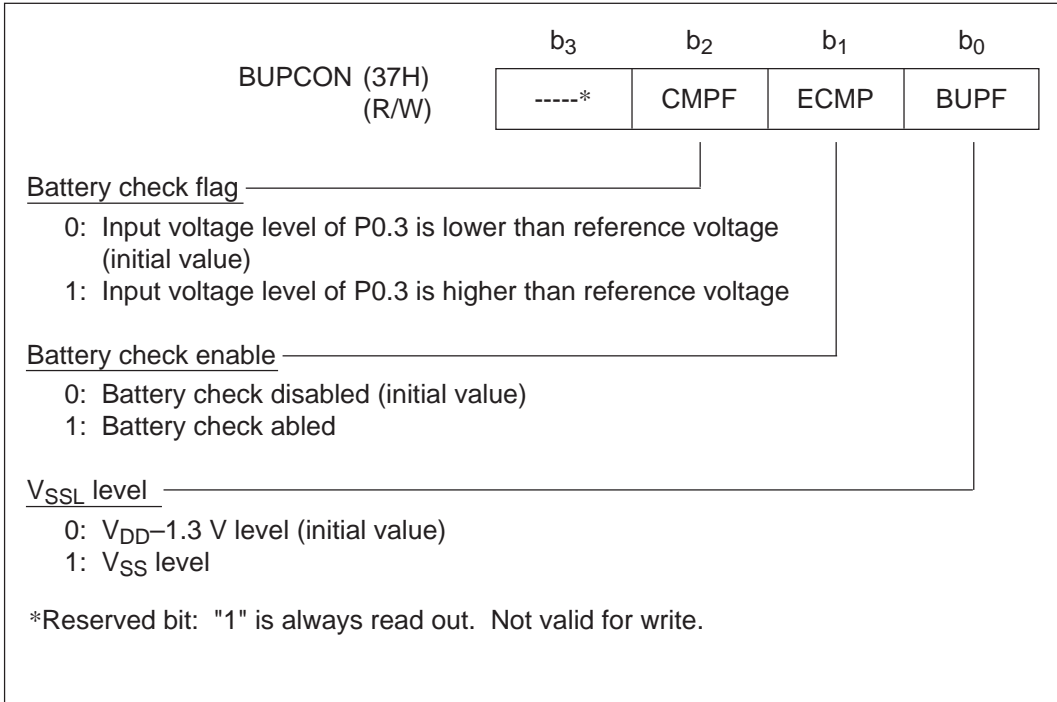
t_D should be 20 msec or more, which is required to stabilize the battery check circuit operation.

After reading CMPF, set ECMP to "0" and the output port X to "1" (④, ⑤).

Thus, all processings are complete.

8.4 Registers Related to Battery Check

The battery check circuit is controlled by the ECMP and CMPF assigned to the Back-up control register (BUPCON).



For details of BUPF at bit 0, refer to Chapter 14 "Constant Voltage Circuit for Logic Power Supply (VR)".

Chapter 9

Buzzer Driver (BD)

Chapter 9 Buzzer Driver (BD)

9.1 Overview

The MSM64162A has a built-in buzzer driver with 2 buzzer output frequencies and 4 buzzer output modes. Each buzzer output is selected by the Buzzer control register (BDCON) and the Buzzer frequency control register (BFCON).

9.2 Layout of Buzzer Driver

Figure 9-1 shows the layout of the buzzer driver.

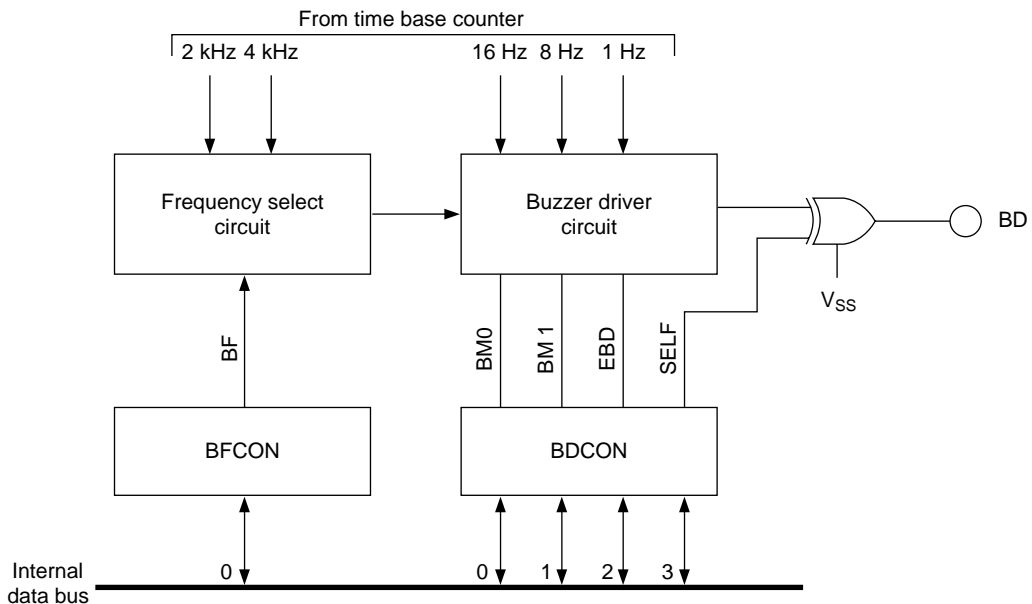


Figure 9-1 Layout of Buzzer Driver

9.3 Operation of Buzzer Driver

When Bit 2 (EBD) of the Buzzer control register (BDCON) is set to "1", buzzer drive signal is output at the buzzer driver pin. The buzzer frequency control register can select either 4 kHz or 2 kHz. In buzzer output mode, two kinds of discontinuous sounds, a single sound and a continuous sound can be selected by Bit 1/0 (BM1/BM0) of BDCON. Bit 3 (SELF) of BDCON can select output logic of the BD pin. When the SELF bit is reset to "0", positive logic output ("L" level output at halt) is selected and negative logic output ("H" level output at halt) is selected when it is set to "1". The duty of buzzer output frequencies is 50%.

In (a) discontinuous sound 1 mode, waveforms which are synchronized with 8 Hz output of the time base counter are output. In (b) discontinuous sound 2 mode, waveforms that are synchronized to the logical AND of 8 Hz signal output and a "L" level of 1 Hz signal are output. In (c) single sound mode, output begins synchronizing with the rising of EBD and stops at the falling of 16 Hz output of the time base counter. In (d) continuous sound mode, output is continued while EBD is "1".

Figure 9-2 shows output waveforms in each output mode. Shaded area in the figure indicates the buzzer output frequency signal.

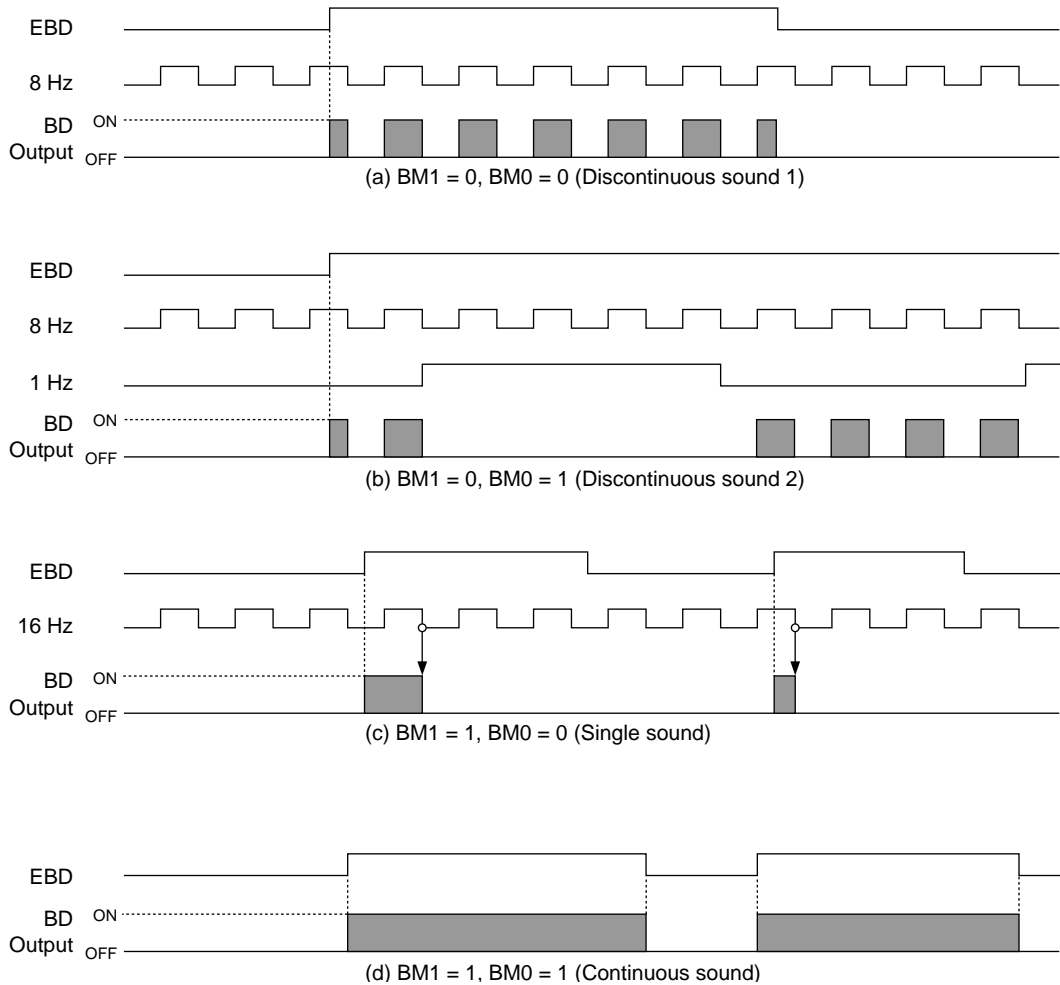
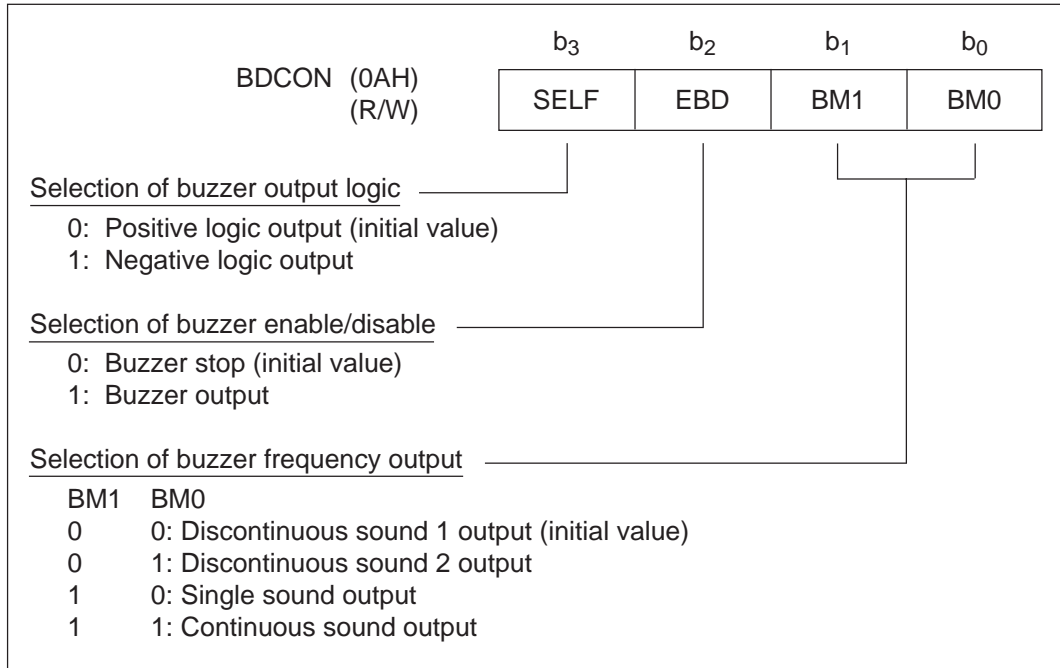


Figure 9-2 Buzzer Driver Output Waveforms in Each Output Mode

9.4 Registers Related to Buzzer Driver

(1) Buzzer control register (BDCON)

The Buzzer control register (BDCON) is a 4-bit special function register (SFR) that controls output logic of the BD pin, 4 types of buzzer output modes and ON/OFF of buzzer output.



Bit 3: SELF

This bit is to select output logic of the BD pin. When reset to "0", positive logic output is selected ("L" level output when output is halted) and negative logic output ("H" level output when output is halted) is selected when set to "1". At system reset, it is reset to "0" and positive logic output is selected.

Bit 2:EBD

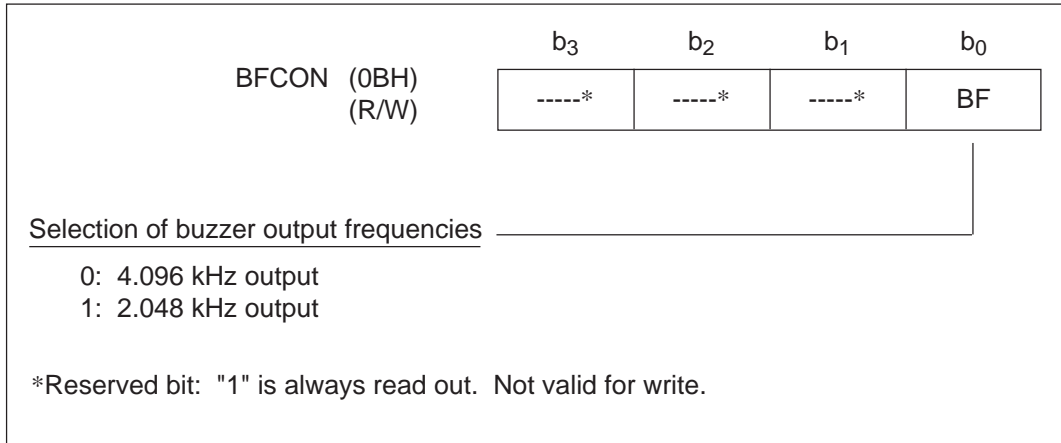
This bit selects ON/OFF of the buzzer driver output. At system reset, it is reset to "0" so that no buzzer is output.

Bits 1 and 0: BM1 and BM0

This bit is to select output mode of the buzzer driver. It can select two types of discontinuous sounds, a single sound and a continuous sound. At system reset, BM1 and BM0 are reset to "0" so that discontinuous sound 1 output is selected.

(2) Buzzer frequency control register (BFCON)

The buzzer frequency control register (BFCON) is a 4-bit special function register (SFR) to control output frequencies of the buzzer.



Bit 0: BF

This bit selects buzzer output frequency. At system reset, BF is reset to "0" so that 4 kHz output is selected.

Each output frequency is output with 50% duty.

Tables 9-1 and 9-2 show the lists of buzzer driver-related registers and related pins.

Table 9-1 Buzzer Driver-Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
Buzzer driver control register	BDCON	0AH	R/W	Yes	0H
Buzzer frequency control register	BFCON	0BH	R/W		0EH

Table 9-2 Buzzer Driver-Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Note
BD	26	22	Output	Buzzer driver pin

9.5 BD Output Waveform and External Circuit

Figure 9-3 shows the output waveform of the output pin of the buzzer driver. Output level of $V_{DD}-V_{SS}$ is output at the BD pin.

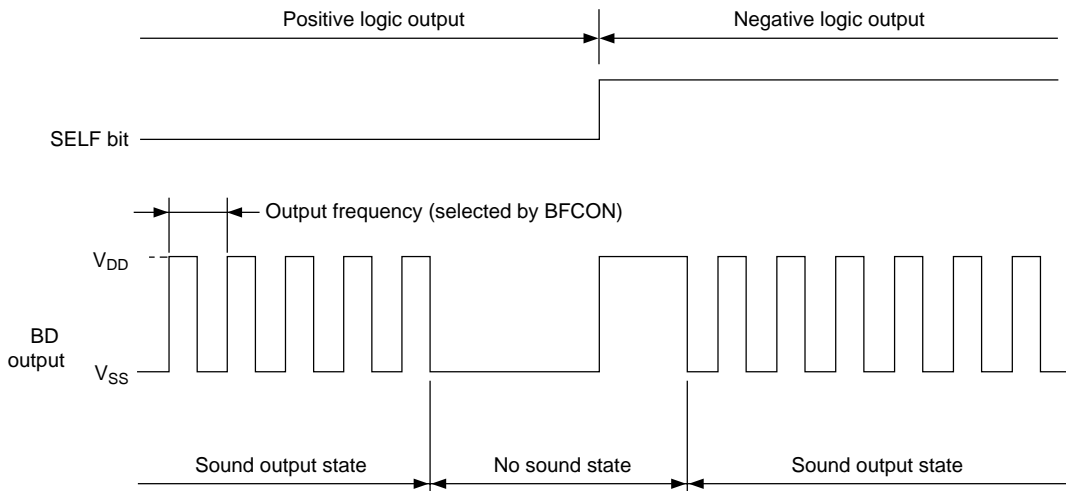
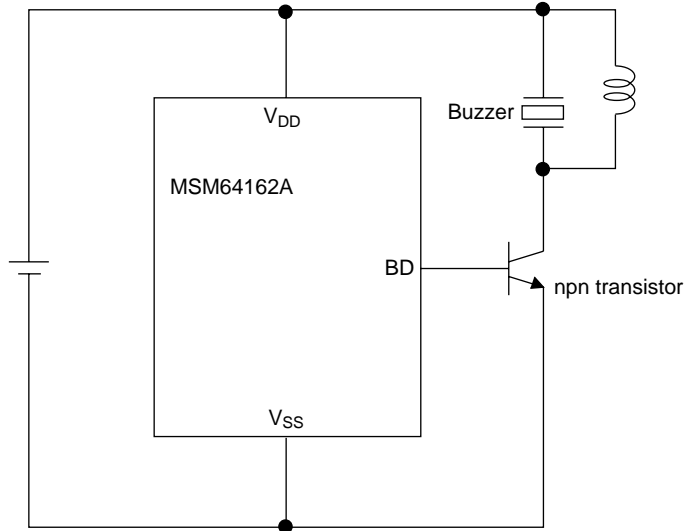


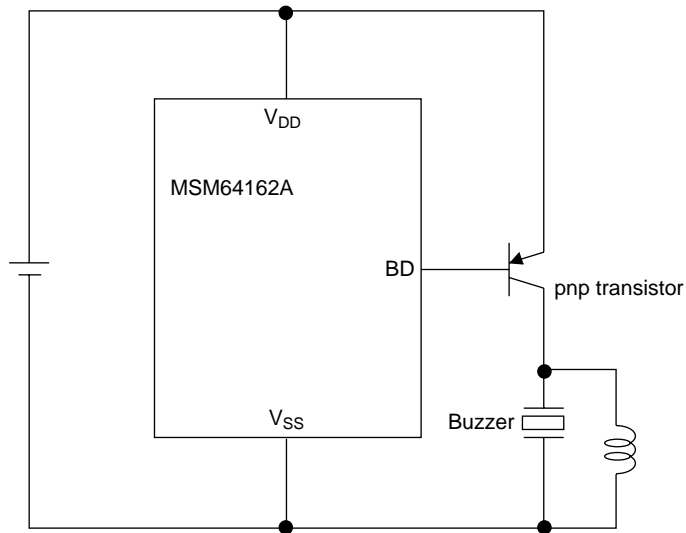
Figure 9-3 Waveform at BD Pin

Figure 9-4 shows an example of the exterior circuit for the buzzer driver.

As illustrated below, do the buzzer driving through an exterior transistor and avoid the buzzer driving directly at the BD terminal.



(a) In the case of SELF bit = "0"



(b) In the case of SELF bit = "1"

Figure 9-4 Circuit Example of a Buzzer Driver Mounted Outside

Chapter 10

Capture Circuit (CAPR)

Chapter 10 Capture Circuit (CAPR)

10.1 Overview

The MSM64162A has a capture circuit that fetches 32 Hz to 256 Hz output of the time base counter at the falling of Port 0.0 or 0.1 (P0.0 or P0.1) to "L" level when the pull-up resistance input is chosen or at the rising to "H" level when the pull-down resistance input is chosen. The capture circuit is composed of the Capture control register (CAPCON) and the Capture registers (CAPR0, CAPR1) that fetch output from the time base counter.

10.2 Layout of Capture Circuit

Figure 10-1 shows the layout of the capture circuit.

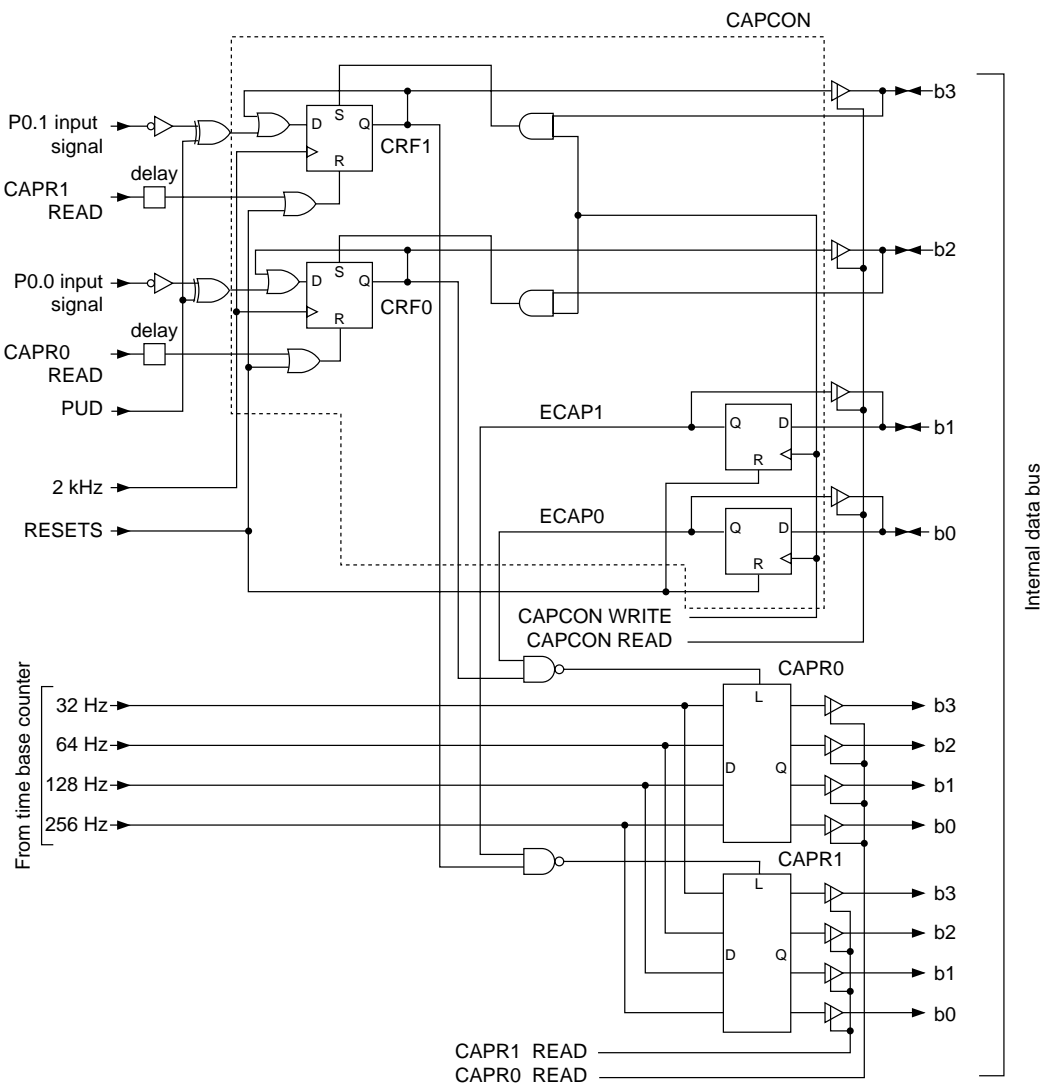


Figure 10-1 Layout of Capture Circuit

10.3 Operation of Capture Circuit

Figure 10-2 shows data latch timing of the Capture data register 0 (CAPR0).

In Figure 10-1, CRF0 is set to "1" at the rising edge of 2 kHz output of the time base counter either when P0.0 input signal becomes "L" level selecting pull-up resistance input or when it becomes "H" level selecting pull-down resistance input while ECAP0 is set to "1" (① in Figure 10-2). When CRF0 is set to "1", the latch signal of the Capture data register 0 (CAPR0) becomes "L" level and 32 Hz to 256 Hz of the time base counter is latched to CAPR0 (②). When CAPR0 is read out, CRF0 is reset to "0" (③).

A similar operation is performed when "1" is written to CRF0 even though P0.0 input signal is neither at "L" level nor at "H" level (④).

When ECAP0 is reset to "0" during the latching state, latch operation of CAPR0 is cancelled (⑤).

If the latch signal of CAPR0 is at "H" level (i.e. CRF0 or ECAP0 is reset to "0"), when CAPR0 is read out, 32 Hz to 256 Hz of the time base counter then is read out.

In Figure 10-1, CRF1 is set to "1" at the rising edge of 2 kHz output of the time base counter either when P1.1 of the input port becomes "L" level selecting pull-up resistance input or when it becomes "H" level selecting pull-down resistance input while ECAP1 is set to "1". When CRF1 is set to "1", the latch signal of the Capture data register 1 (CAPR1) becomes "L" level and 32 Hz to 256 Hz of the time base counter is latched to CAPR1. When CAPR1 is read out, CRF1 is reset to "0".

A similar operation is performed when "1" is written to CRF1 even though P0.1 input signal is neither in "L" level nor in "H" level.

If the latch signal of CAPR1 is at "H" level (i.e. CRF1 or ECAP1 is reset to "0"), when CAPR1 is read, 32 Hz to 256 Hz of the time base counter then is read out.

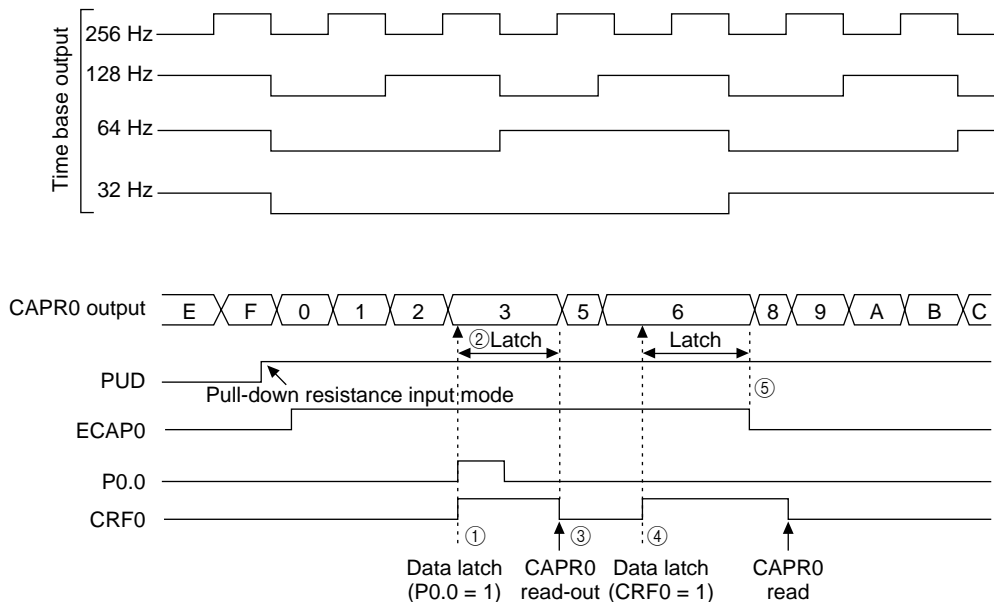
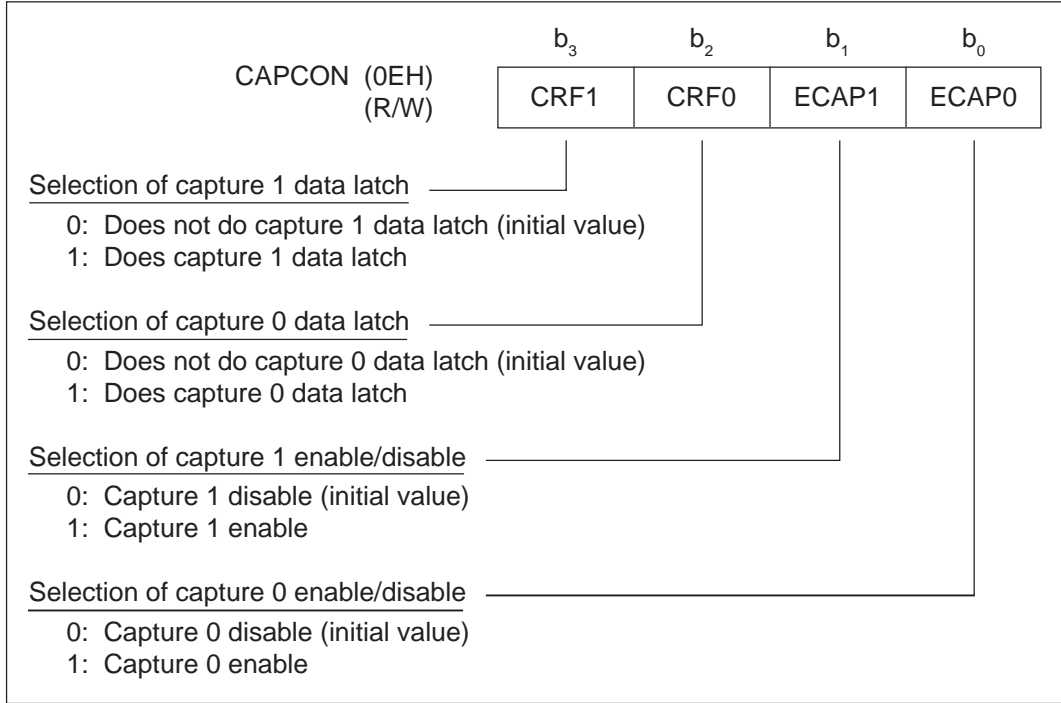


Figure 10-2 Data Latch Timing of Capture Data Register 0 (CAPR0)

10.4 Registers Related to Capture Circuit

(1) Capture control register (CAPCON)

The Capture control register (CAPCON) is a 4-bit special function register (SFR) to control the capture circuit.



Bit 3:CRF1

This bit is the capture flag for the Capture register 1 (CAPR1). CRF1 is set to "1" when P0.1 of the input port detects "L" level selecting pull-up resistance input or when it detects "H" level selecting pull-down resistance input. When CRF1 is set to "1" while ECAP1 is set to "1", 32 Hz to 256 Hz output of the time base counter is latched to CAPR1. When "1" is written to CRF1, a similar operation to the detection of "H" level or "L" level by P0.1 is performed.

CRF1 is reset to "0" when reading out CAPR1. At system reset, CRF1 is reset to "0".

Bit 2:CRF0

This bit is the capture flag for the Capture register 0 (CAPR0). CRF0 is set to "1" when P0.0 of the input port detects "L" level selecting pull-up resistance input or when it detects "H" level selecting pull-down resistance input. When CRF0 is set to "1" while ECAP0 is set to "1", 32 Hz to 256 Hz output of the time base counter is latched to CAPR0. When "1" is written to CRF0, a similar operation to the detection of "H" level or "L" level by P0.0 is performed.

CRF0 is reset to "0" when reading out CAPR0. At system reset, CRF0 is reset to "0".

Bit 1:ECAP1

This bit enables/disables latch of output of the time base counter by the Capture register 1 (CAPR1). When ECAP1 is reset to "0", output of the time base counter is not latched and when CAPR1 is read out, the time base counter value at that time is read out.

When CRF1 is set to "1" while ECAP1 is set to "1", 32 Hz to 256 Hz of the time base counter is latched by CAPR1 and when CAPR1 is read out, the value of latched time base counter is read out.

At system reset, ECAP1 is reset to "0".

Bit 0:ECAP0

This bit enables/disables latch of output of the time base counter by the Capture register 0 (CAPR0). When ECAP0 is reset to "0", output of the time base counter is not latched and when CAPR0 is read out, the time base counter value at that time is read out.

When CRF0 is set to "1" while ECAP0 is set to "1", 32 Hz to 256 Hz of the time base counter is latched by CAPR0 and when CAPR0 is read out, the value of latched time base counter is read out.

At system reset, ECAP0 is reset to "0".

(2) Capture registers (CAPR0, CAPR1)

The capture registers (CAPR0, CAPR1) are 4-bit special function registers (SFRs) to read out latch data of 32 Hz to 256 Hz of the time base counter.

		b_3	b_2	b_1	b_0
CAPR0 (0CH) (R)		32Hz	64Hz	128Hz	256Hz
<u>Value of 32 Hz to 256 Hz of time base counter</u>					

		b_3	b_2	b_1	b_0
CAPR1 (0DH) (R)		32Hz	64Hz	128Hz	256Hz
<u>Value of 32 Hz to 256 Hz of time base counter</u>					

Tables 10-1 and 10-2 show the list of capture circuit-related registers and pins.

Table 10-1 List of Capture Circuit-Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
Capture control register	CAPCON	0EH	R/W	No	0H
Capture register 0	CAPR0	0CH	R	Yes	0H
Capture register 1	CAPR1	0DH	R		0H

Table 10-2 Capture Circuit-Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Note
P0.0	2	1	Input	Trigger input of CAPR0
P0.1	3	2	Input	Trigger input of CAPR1

Chapter 11

Watchdog Timer (WDT)

Chapter 11 Watchdog Timer (WDT)

11.1 Overview

The MSM64162A has a built-in watchdog timer to prevent the CPU from crashing. The watchdog timer is composed of a 6-bit watchdog timer (WDT) and a watchdog timer control register (WDTCON) to reset WDT.

11.2 Layout of Watchdog Timer

Figure 11-1 shows the layout of the watchdog timer.

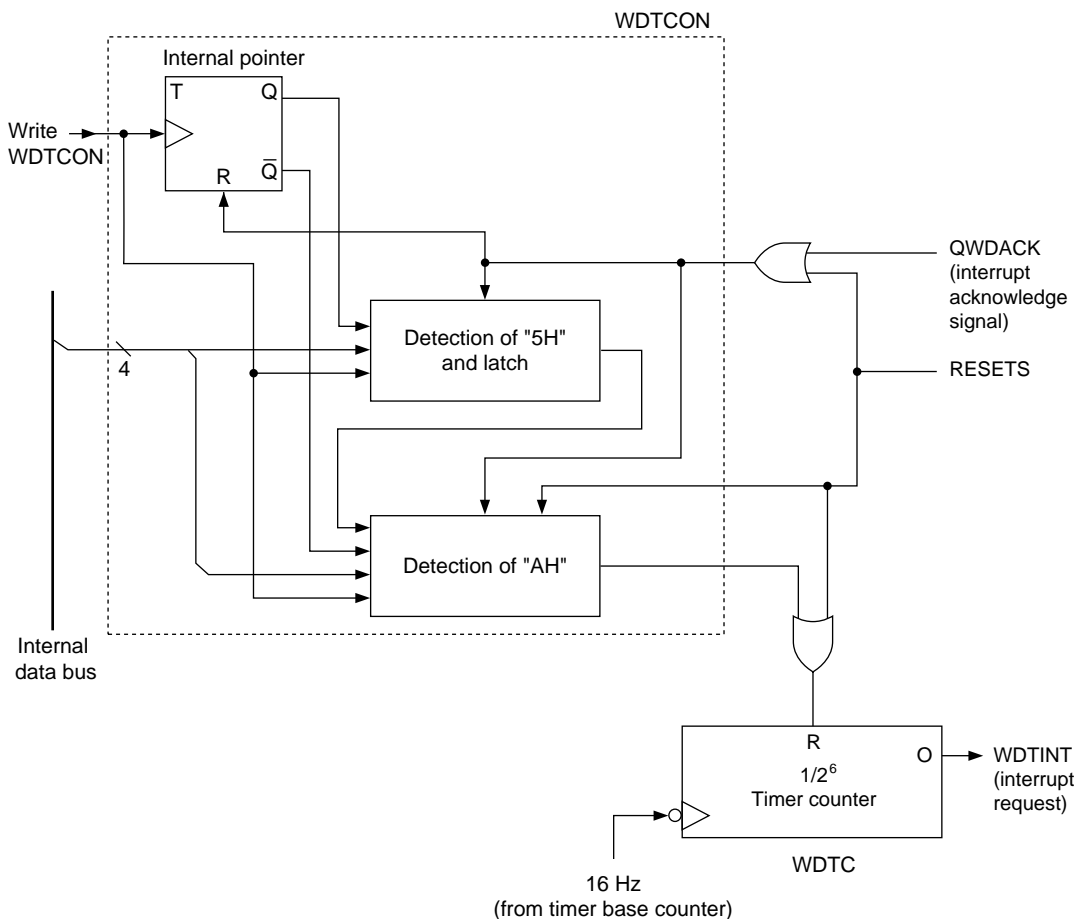


Figure 11-1 Layout of Watchdog Timer

11.3 Operation of Watchdog Timer

When the system reset is released, the Watchdog timer (WDT) is automatically started and the Watchdog timer counter (WDTC) begins count-up. WDTC reset can be performed by writing "5H" and "0AH" alternatively to the Watchdog timer control register (WDTCON).

If WDTC is not reset, WDTC overflows after 1.9 to 2.0 seconds and the Watchdog timer interrupt request (WDTINT) is generated. WDTINT is an interrupt that software cannot disable (non-maskable interrupt) and has the highest priority over other interrupts. Normally WDTC is to be programmed to be reset every one second by software. When reset of WDTC is not performed normally by a CPU crash, WDTC overflows and WDTINT is generated. In the watchdog timer interrupt routine, the return operation to a normal routine should be performed from an abnormal state.

Note: The watchdog timer cannot detect all abnormal operations. If WDTC is in reset state, error cannot be detected even if the CPU crashes.

Figure 11-2 shows the reset flowchart of the watchdog timer. As shown in the figure, WDT is reset by writing "5H" when the internal pointer is "0" and writing "0AH" when it is "1" to WDTCON. The internal pointer is reset to "0" at system reset and by WDTC overflow and is reversed each time WDTCON is written.

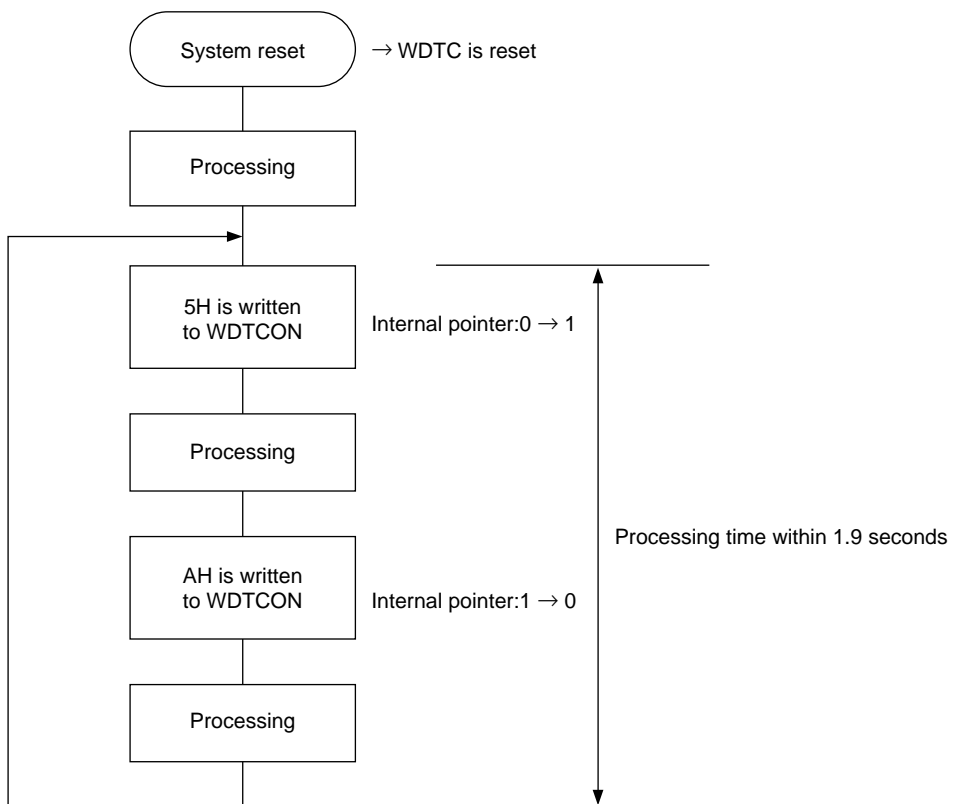


Figure 11-2 Flowchart of Watchdog Timer

Figure 11-3 shows the operation time chart of the watchdog timer.

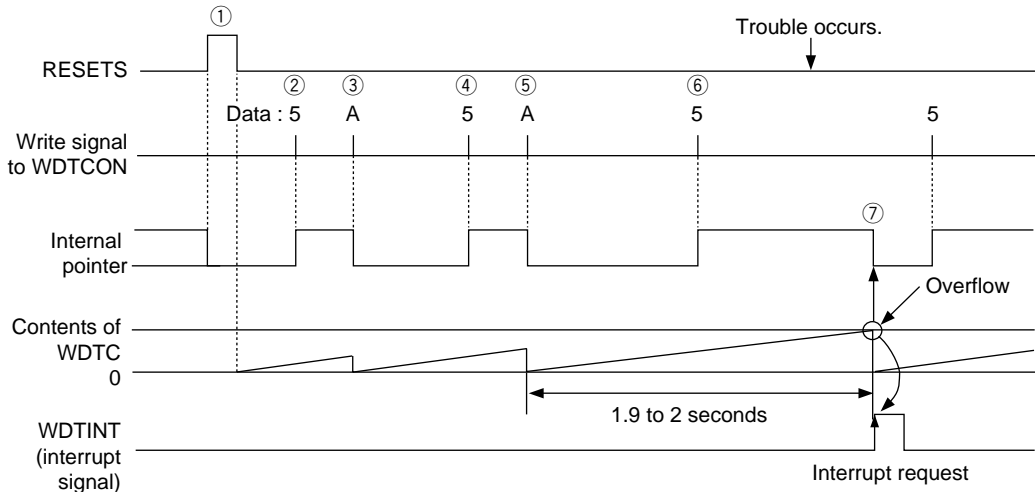


Figure 11-3 Operation Time Chart of Watchdog Timer

The operation of the watchdog timer is as follows:

- ① The contents of the internal pointer and the Watchdog timer counter (WDC) are reset by the system reset (RESETS).
- ② "5H" is written to WDTCON (internal pointer 0→1).
- ③ "0AH" is written to WDTCON and the watchdog timer is reset (internal pointer 1→0).
- ④ "5H" is written to WDTCON (internal pointer 0→1).
- ⑤ "0AH" is written to WDTCON and the watchdog timer is reset (internal pointer 1→0).
- ⑥ "5H" is written to WDTCON (internal pointer 0→1).
- ⑦ When "0AH" is not written to WDTCON while the internal pointer is "1" (i.e. the CPU crashes and the watchdog timer is not reset), the watchdog timer interrupt (WDTINT) is generated by WDC overflow. The internal pointer becomes "0" then.

11.4 Watchdog Timer Control Register (WDTCON)

The watchdog timer control register (WDTCON) is a 4-bit special function register (SFR) to reset the watchdog timer.

	b_3	b_2	b_1	b_0
WDTCON (36H) (W)	d3	d2	d1	d0

Chapter 12

A/D Converter (ADC)

Chapter 12 A/D Converter (ADC)

12.1 Overview

The MSM64162A has a built-in 2-channel RC oscillation method A/D converter. The A/D converter is composed of a 2-channel oscillation circuit, Counter A (CNTA0 to 4) which is a 4.8-digit decade counter, Counter B (CNTB0 to 3) which is a 14-bit binary counter and A/D converter control registers 0 and 1 (ADCON0, ADCON1).

By counting oscillation frequencies due to resistance or capacitance connected to the RC oscillation circuit, the A/D converter converts resistance values or capacitance values to corresponding digital values. By using a thermistor or a humidity sensor as a resistance, a thermometer or a hygrometer can be constructed. By applying sensors to the 2-channel RC oscillation circuit, it is also possible to extend measurement ranges or measurement at two places.

12.2 Layout of A/D Converter

Figure 12-1 shows the layout of the A/D converter.

12.3 Operation of A/D Converter

As shown in Figure 12-1, the RC oscillation circuit can be made by connecting resistances and capacitances to each pin.

Counter A (CNTA0 to 4) is a 4.8-digit decade counter ($1/10^4 \times 8$) to count the system clock (CLK) which is the time reference and can count up to a maximum of 79,999.

Counter B (CNTB0 to 3) is a 14-stage binary counter to count the oscillation clock (OSCCLK) of the RC oscillation circuit and can count up to a maximum of 16,383.

Both Counter A and Counter B have the overflow flags (OVFA and OVFB) and overflow output generates the A/D converter interrupt request (ADINT). ADINT due to overflow of either Counter A or Counter B is selected by Bit 1 (SADI) of the A/D converter control register 0 (ADCON0). By resetting SADI to "0", overflow of Counter A is selected and by setting SADI to "1", overflow of Counter B is selected. The vector address of ADINT is at address 02FH.

Bit 0 (EADC) of ADCON0 is a bit to select operation/halt of the A/D conversion. By resetting EADC to "0", the RC oscillation is halted and no counting is performed. By setting EADC to "1", the RC oscillation is begun and counting of the RC oscillation clock and the system clock is started.

Various oscillation mode of the RC oscillation part is performed by the A/D converter control register 1 (ADCON1). The RC oscillation clock can be monitored by outputting to P4.3 in test function. For details of the test functions, refer to Chapter 15 "Test Circuit".

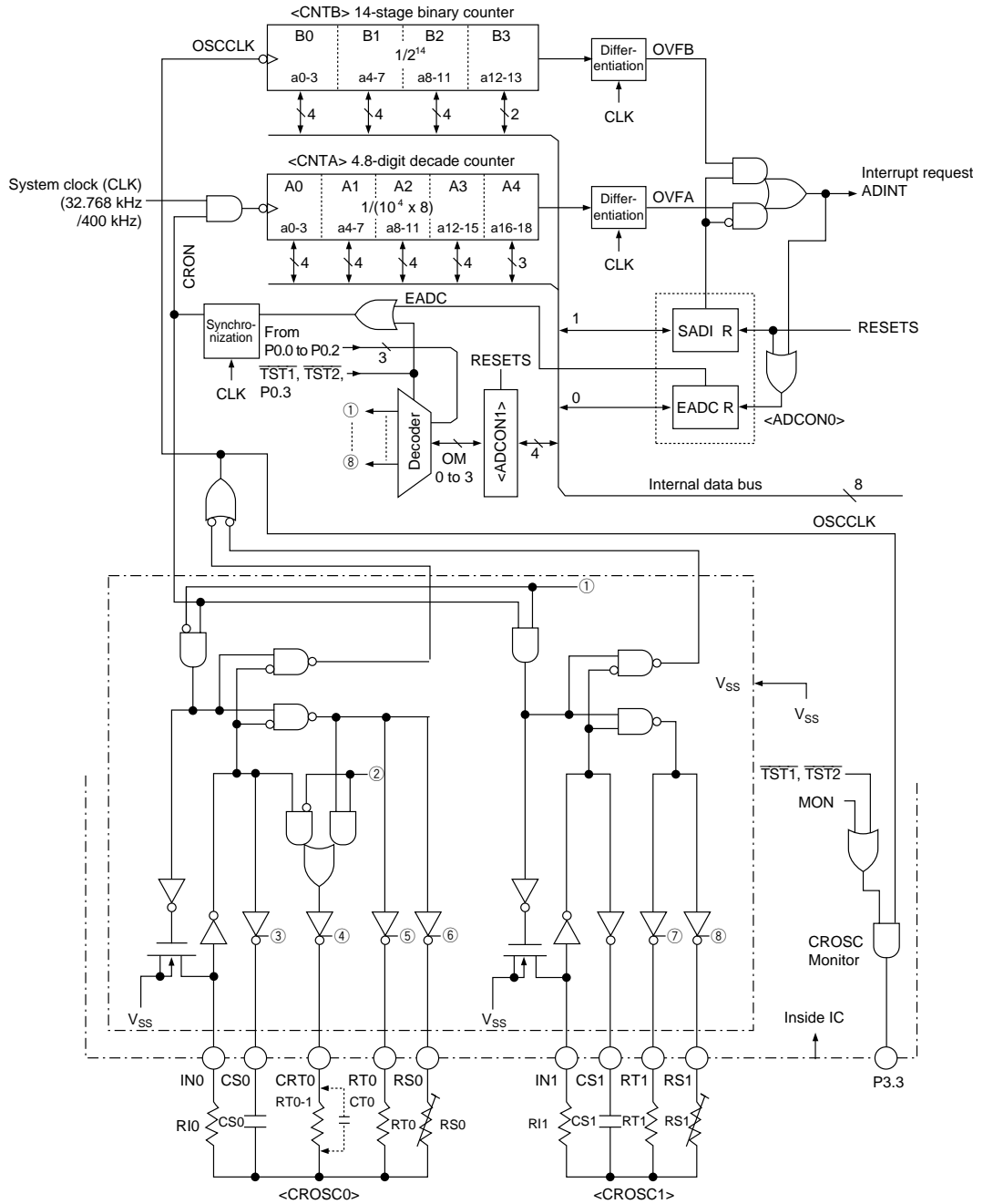


Figure 12-1 Layout of A/D Converter

12.3.1 RC Oscillation Circuit

The A/D converter of the RC oscillation method performs A/D conversion by digitizing the ratio of a reference resistance (or capacitance) to a resistance sensor, such as thermistor sensor (or capacitance sensor).

By taking the ratio of oscillation frequencies of the reference to the sensor, it is possible to A/D convert the characteristics of a sensor itself by canceling error factors intrinsic to the RC oscillation circuit. Consequently, it is necessary to oscillate the reference side and the sensor side with the same oscillation circuit and a pair of the reference side and the sensor side is usually used.

Table 12-1 shows the oscillation mode by Bits 3 to 0 (OM3 to OM0) of the A/D converter control register (ADCON1). Figures 12-2 to 12-5 show the layout and values of the OM3 to 0 bits.

Table 12-1 Oscillation Mode by OM3 to OM0 Bits

Mode No.	ADCON1				CROSC0 output pins				CROSC1 output pins		Mode
	OM3	OM2	OM1	OM0	RS0	RT0	CRT0	CS0	RS1	RT1	
0	0	0	0	0	Z	Z	Z	Z	Z	Z	IN0 external clock input mode
1	0	0	0	1	1/0	Z	Z	0/1	Z	Z	RS0-CS0 oscillation
2	0	0	1	0	Z	1/0	Z	0/1	Z	Z	RT0-CS0 oscillation
3	0	0	1	1	Z	Z	1/0	0/1	Z	Z	RT ₀₋₁ -CS0 oscillation
4	0	1	0	0	1/0	Z	0/1	Z	Z	Z	RS0-CT0 oscillation
5	0	1	0	1	Z	Z	Z	Z	1/0	Z	RS1-CS1 oscillation
6	0	1	1	0	Z	Z	Z	Z	Z	1/0	RT1-CS1 oscillation
7	0	1	1	1	Z	Z	Z	Z	Z	Z	IN1 external clock input mode
8	1	—	—	—	Z	Z	Z	Z	Z	Z	—

Note: Z: High-impedance output

1/0, 0/1: Active output

—: Arbitrary

Modes No.0 and No.7 in Table 12-1 are to measure the external clock which is input to the IN0 pin or the IN1 pin by halting the operation of the RC oscillation circuit.

As shown in Table 12-1, no two oscillation circuits can operate simultaneously. This prevent interference to the oscillation operation when two are operated simultaneously.

An equation between oscillation frequency (f_{OSCCLK}), capacitance value (C) and resistance value (R).

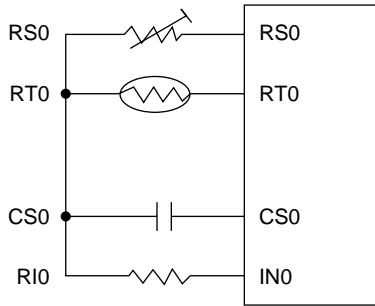
$$\frac{1}{f_{OSCCLK}} = t_{OSCCLK} = k_{OSCCLK} \cdot C \cdot R$$

where t_{OSCCLK} is the period of the oscillation frequency, k_{OSCCLK} is a proportionality constant and $C \cdot R$ is product of C_S or C_T and R_S or R_T . The value of k_{OSCCLK} varies slightly depending on V_{DD} (power supply voltage), R_I , C and R and its standard values are listed in Table 12-2.

Table 12-2 Standard Value of k_{OSCCLK} of RC Oscillation Circuit

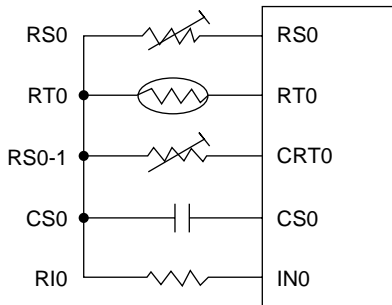
V_{DD} (V)	R_{In} (k Ω)	C_{Sn}, C_{Tn} (pF)	R_{Sn}, R_{Tn} (k Ω)	k_{OSCCLK} (Typ.)
3	10	820	100	1.9
		820	10	2.2
1.5	10	820	100	2.1
		820	10	2.3

Note: n = 0, 1, 0-1



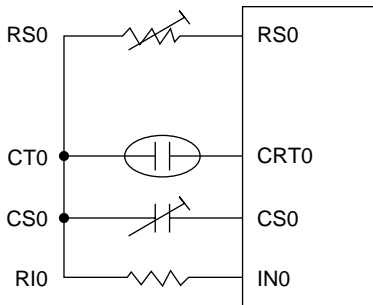
OM3	OM2	OM1	OM0	Oscillation mode
0	0	0	1	Oscillation with reference resistance RS0
0	0	1	0	Oscillation with sensor RT0

Figure 12-2 Measurement of CROSC0 by a Resistance Sensor



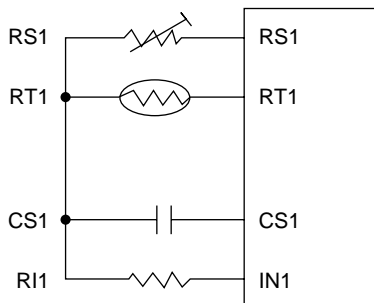
OM3	OM2	OM1	OM0	Oscillation mode
0	0	0	1	Oscillation with reference resistance RS0
0	0	1	0	Oscillation with sensor RT0
0	0	1	1	Oscillation with reference resistance RS ₀₋₁

Figure 12-3 Measurement of CROSC0 by a Resistance Sensor
(when two-point adjustment with two reference resistances)



OM3	OM2	OM1	OM0	Oscillation mode
0	0	0	1	Oscillation with reference capacitance CS0
0	1	0	0	Oscillation with sensor CT0

Figure 12-4 Measurement of CROSC0 by a Capacitance Sensor



OM3	OM2	OM1	OM0	Oscillation mode
0	1	0	1	Oscillation with reference resistance RS1
0	1	1	0	Oscillation with sensor RT1

Figure 12-5 Measurement of CROSC1 by a Resistance Sensor

Note: Unused pins should be left open.

12.3.2 Counter A/B Reference Mode

The conversion operation of the A/D converter is performed by the following two modes.

- Counter A Reference Mode (SADI bit of ADCON0 = 0)
This is the mode to set gate time by the system clock (CLK) and Counter A, to count the RC oscillation clock (OSCCLK) by Counter B with the gate time and to output contains of Counter B as a digital value.
The digital value is proportional to the RC oscillation frequency.
- Counter B Reference Mode (SADI bit of ADCON0 = 1)
This is the mode to set gate time by the RC oscillation clock (OSCCLK) and Counter B, to count the system clock (CLK) by Counter A with the gate time and to output contains of counter A as a digital value.
The digital value is inverse proportional to the RC oscillation frequency.

(1) Operation of Counter A Reference Mode

Counter A reference mode is performed by the following procedure:

- [1] Subtract "nA0" (the count value) from the maximum value + 1 (80,000) and set that value to Counter A (CNTA4 to 0). The count value, "nA0", indicates the gate time.

$$\text{Counter A} \leftarrow 80,000 - nA0$$

- [2] Clear Counter B (CNTB3 to 0) to 0000H.

$$\text{Counter B} \leftarrow 0000H$$

- [3] Set the OM 3 to 0 bits of ADCON1 to a necessary oscillation mode (refer to Table12-1).

- [4] Write "1H" to ADCON0 (SADI = 0, EADC = 1)

Note: The order of [1] to [3] is arbitrary.

By [4], A/D conversion starts.

Counter A starts counting the system clock (CLK) when EADC is set to "1" and the CRON signal that synchronizes with the falling of the system clock is set to "1". When Counter A overflows, [5] the EADC bit is automatically reset and the counting is finished. At the same time, [6] the A/D converter interrupt request signal (ADINT) becomes "1" to generate the A/D converter interrupt request.

When the CRON signal is set to "1", the RC oscillation is started and Counter B starts counting the RC oscillation clock (OSCCLK). When Counter A overflows and the EADC bit is automatically reset, the counting of counter B is finished.

The last count value of "nB0" at Counter B is the count value of OSCCLK during the gate time "nA0 • t_{SYSCLK}" and is expressed by

$$nB0 \doteq nA0 \cdot \frac{t_{SYSCLK}}{t_{OSCCLK}} \propto f_{OSCCLK}$$

where t_{SYSCLK} is the period of CLK and t_{OSCCLK} is the period of OSCCLK.

In other words, "nB0" is proportional to the RC oscillation frequency (f_{OSCCLK}).

Figure 12-6 shows the operating timing of Counter A reference mode.

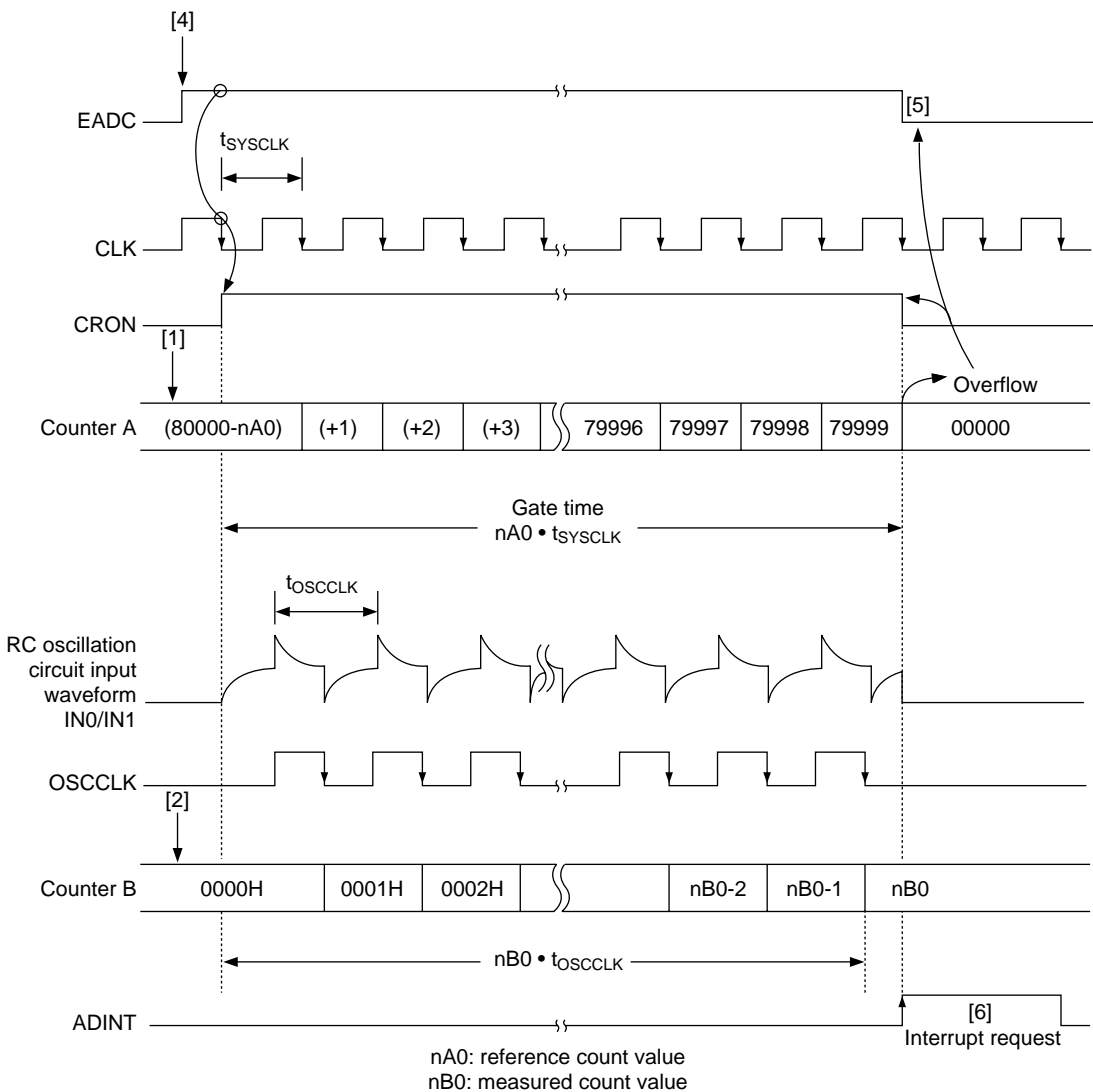


Figure 12-6 Operating Timing of Counter A Reference Mode

(2) Operation of Counter B Reference Mode

Figure 12-7 shows the operating timing of Counter B reference mode.

Counter B reference mode is performed by the following procedure:

- [1] Subtract "nB1" (the count value) from the maximum value + 1 (4000H) and set the result to Counter B (CNTB3 to 0). The count value, "nB1", denotes the gate time.

$$\text{Counter B} \leftarrow 4000 - nB1$$

- [2] Clear Counter A (CNTA4 to 0) to 0000H.

$$\text{Counter A} \leftarrow 0000H$$

- [3] Set the OM 3 to 0 bits of ADCON1 to a necessary oscillation mode (refer to Table 12-1).

- [4] Write "3H" to ADCON0 (SADI = 1, EADC = 1).

Note: The order of [1] to [3] is arbitrary.

By [4], A/D conversion starts.

Counter B starts counting the RC oscillation clock (OSCCLK) when the EADC bit is set to "1" and the CRON signal (signal that synchronizes with the falling of the system clock) is set to "1". When Counter B overflows, [5] the EADC bit is automatically reset and the conversion is finished. At the same time, [6] the A/D converter interrupt request signal (ADINT) becomes "1" to generate the A/D converter interrupt request.

When the CRON signal is set to "1", Counter A starts counting the system clock (CLK). When Counter B overflows and the EADC bit is automatically reset, the counting of counter A is finished.

The last count value of "nA1" at Counter A is the count value of SYSCLK during the gate time "nB1 • t_{OSCCLK}" and is expressed by

$$nA1 \doteq nB1 \cdot \frac{t_{OSCCLK}}{t_{SYSCLK}} \propto \frac{1}{f_{OSCCLK}}$$

where nA1 is counter proportional to the RC oscillation frequency (f_{OSC}).

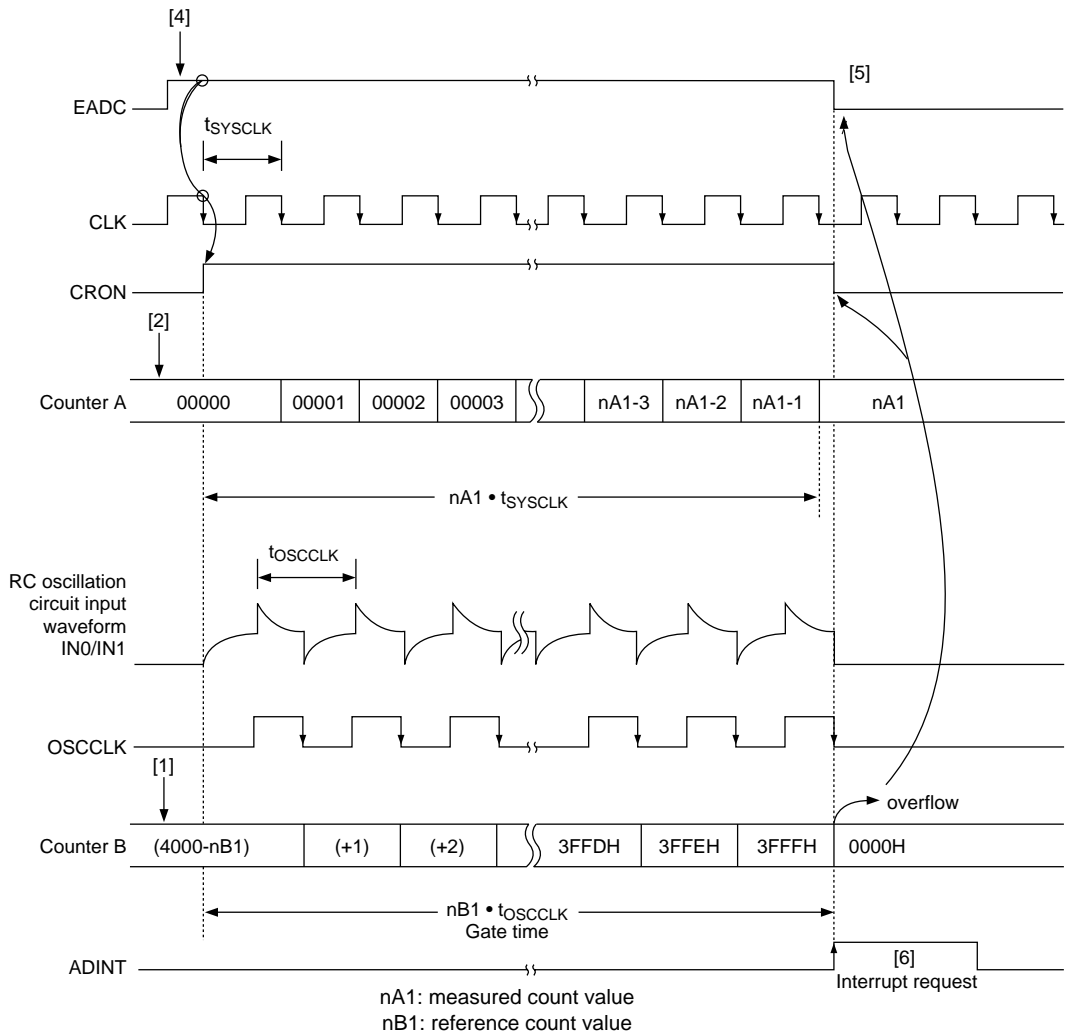


Figure 12-7 Operating Timing of Counter B Reference Mode

12.3.3 Example of Usage of A/D Converter

The method to perform A/D conversion of sensor values by using Counter A reference mode and Counter B reference mode is explained by taking temperature measurement with a thermistor as an example.

Figure 12-8 shows the layout of RC oscillation circuit.

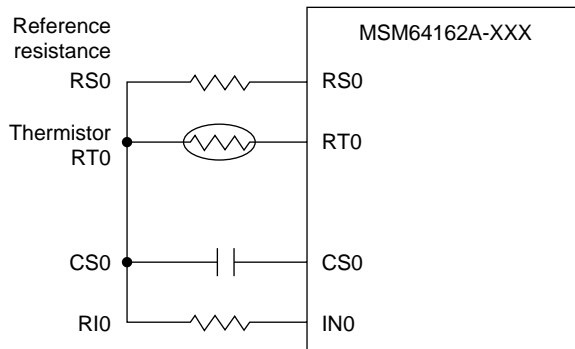


Figure 12-8 Layout of RC Oscillation Circuit of a Thermistor Using CROSC0

Figure 12-9 shows the temperature characteristics of the resistance value, $RT0$, of the thermistor.

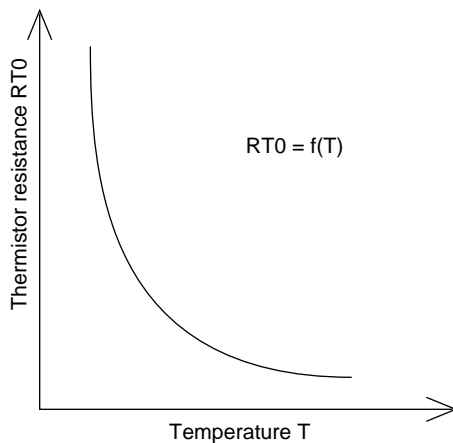


Figure 12-9 Temperature Characteristics of Thermistor

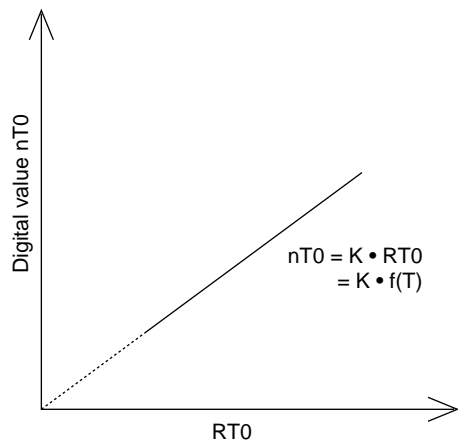


Figure 12-10 A/D Conversion Characteristics

$RT0$ is expressed as a function of temperature T as

$$RT0 = f(T)$$

Figure 12-10 shows the ideal characteristics of A/D conversion taking $RT0$ as an analog quantity and the A/D conversion value $nT0$ is completely proportional to $RT0$. The value of $nT0$ is expressed by temperature T and the proportionality factor K as

$$nT0 = K \cdot RT0 = K \cdot f(T) \quad \text{----- equation (a)}$$

Consequently, by performing conversion processing corresponding to the characteristics shown by Figure 12-9 to $nT0$, it is possible to express temperatures by digital values.

The conversion method from an analog value of $RT0$ to a digital value of $nT0$ is now explained.

To convert $RT0$ to a digital value, the ratio of oscillation frequencies of $RT0$ to $RS0$ (ideal if independent of temperature) is used. This is to cancel the error factors of the oscillation characteristics.

As shown in Figures 12-9 and 12-11, $RT0$ depends on temperature T and $RS0$ is always constant regardless of temperature T . The oscillation characteristics, $f_{OSC} - T$, using these resistances is ideal if the solid lines of Figures 12-12 and 12-13 can be realized. However, in reality, the dotted lines are obtained due to error factors of the temperature characteristics of the IC and others. Since the conditions of $f_{OSC}(RT0)$ and $f_{OSC}(RS0)$ are about the same except the resistance, their error should be similar each to other and consequently, if the ratio of one to the other is taken, the error should be canceled.

The ratio of $f_{OSC}(RT0)$ to $f_{OSC}(RS0)$ corresponds to the A/D conversion value of $nT0$ which, ideally, depends solely on $RT0$.

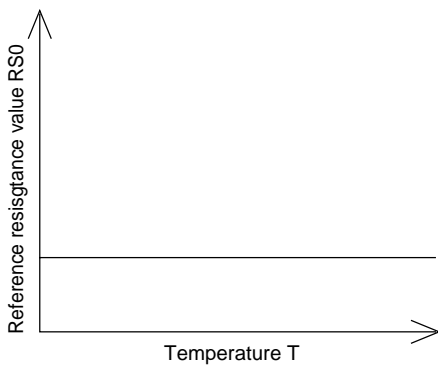


Figure 12-11 Temperature Characteristics of Reference Resistance

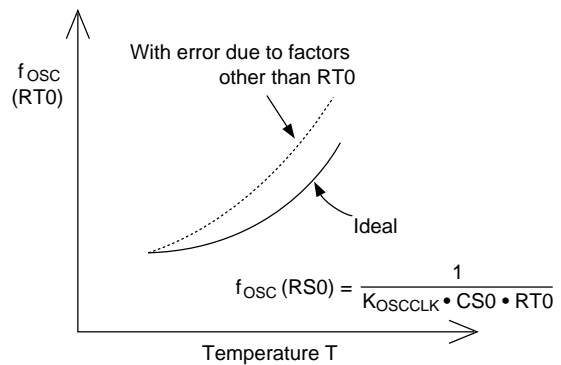


Figure 12-12 Oscillation Characteristics of Thermistor

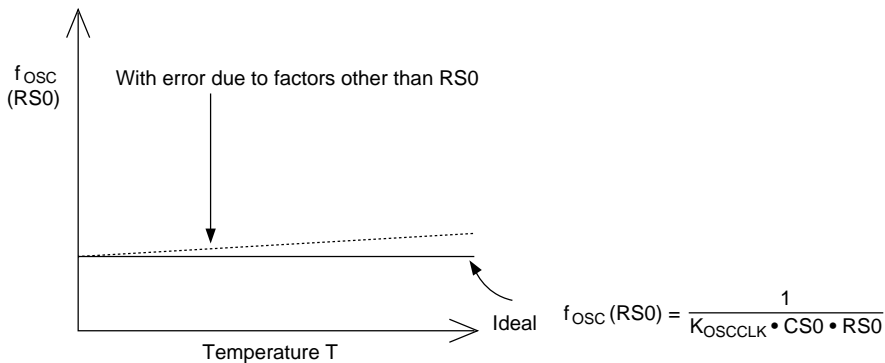


Figure 12-13 Oscillation Characteristics of Reference Resistance

Figure 12-14 shows the conversion to digital values from the RT0 values, i.e. one cycle time chart of temperature measurement.

One cycle of A/D conversion needs to be composed of two steps shown in Figure 12-14 because the reference resistance and the thermistor must be oscillated independently when taking the ratio of them.

In this example, those two steps are taken by the following combination:

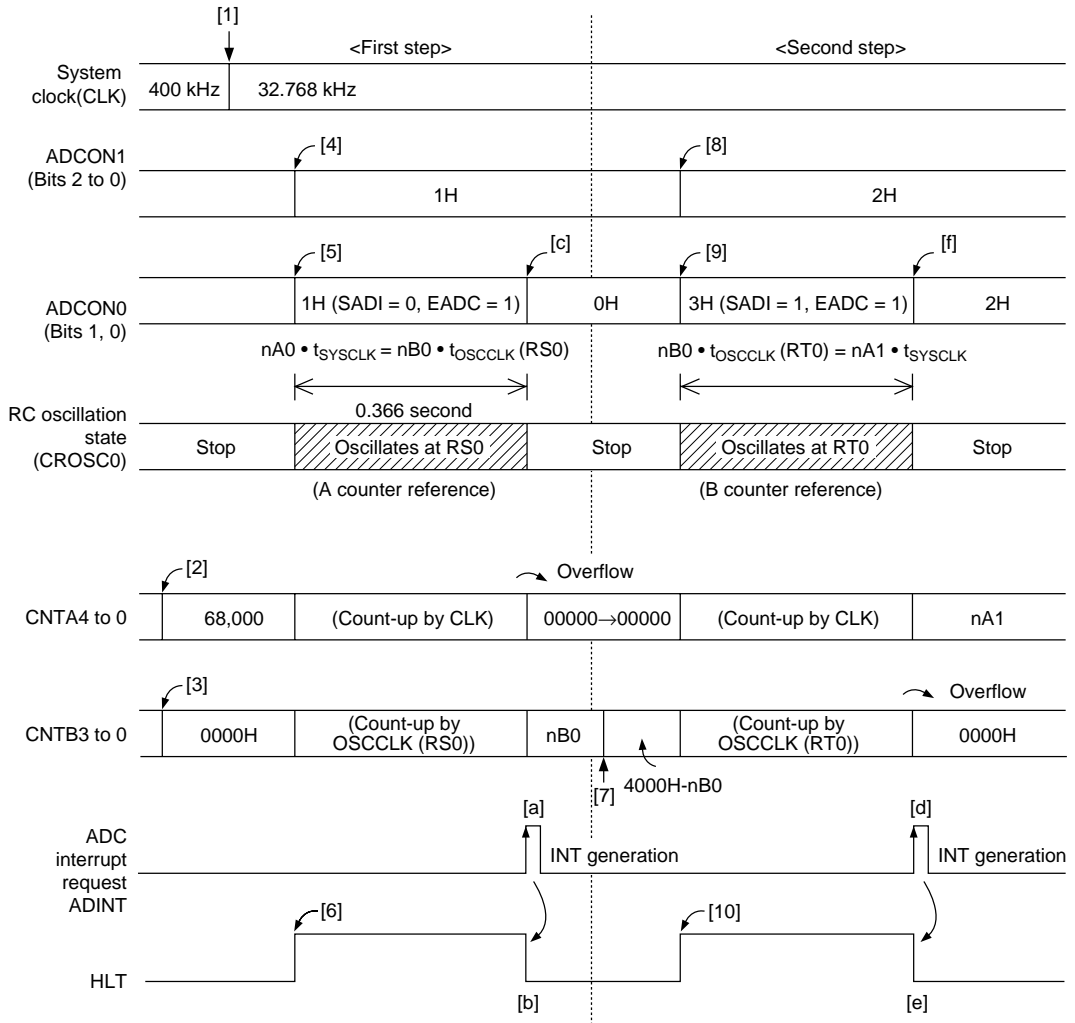
- ┌ First step = RC oscillation by RS0 with A counter reference
- └ Second step = RC oscillation by RT0 with B counter reference

Various other methods are possible besides the one above.

In the above method, the operating time by the second step varies by the value of thermistor RT0. However, if it is necessary to avoid such variation, the following combination is recommended:

- ┌ First step = RC oscillation by RS0 with B counter reference
- └ Second step = RC oscillation by RT0 with A counter reference

In the following, the procedure of A/D conversion will be explained taking Figure 12-14 as an example.



Notes: $nA0 = 12,000$, $t_{SYSCLK} = 1/32768$ Hz, [1] to [10]: software processing, [a] to [f] : hardware processing

Figure 12-14 Time Chart of One Cycle of Temperature Measurement

<First Step>

[1] Set the system clock to 32.768 kHz (Write 0H to FCON), if using 400 kHz clock as system clock.

[2] Set "80,000-nA0" to Counter A.

Note: nA0 is taken as 12,000 in order to set the gate time $nA0 \cdot t_{\text{SYSCLK}}$ of oscillation mode of the reference resistance RS0 as 0.366 second. The value of nA0 depends on the size of quantum error of A/D conversion and the larger nA0, the smaller the error.

[3] Clear Counter B to "0000H".

[4] Write "1H" to ADCON1 and set it to oscillation mode with reference resistance RS0.

Note: The order of [1] to [4] is arbitrary.

[5] Write "1H" to ADCON0 and start A/D conversion in Counter A reference mode.

[6] Set the HLT bit of HALT register to "1" for halt mode.

Note: By selecting halt mode, noise to the RC oscillation circuit may be reduced. In regular usage, halt mode is recommended during RC oscillation operation.

The RC oscillation circuit (CROSC0) continues oscillation with reference resistance RS0 for about 0.366 second at this time and when Counter A overflows, [a] the ADINT signal is set to "1" and the A/D converter interrupt request is generated. By the generation of the interrupt request, [b] halt mode is released and [c] the A/D conversion operation is stopped (the EADC bit = 0). At this moment, Counter A is in 00000 state.

The contents of Counter B are expressed as

$$nB0 = nA0 \cdot \frac{t_{\text{SYSCLK}}}{t_{\text{OSCCLK}}(\text{RS0})} \quad \text{----- equation (b)}$$

<Second Step>

[7] Calculate "4000H-nB0" by the contents "nB0" of Counter B and set that value to Counter B.

Note: Although clearing of Counter A is needed, additional processing is not necessary as it is already in "00000" state.

[8] Write "2H" to ADCON1 and start oscillation mode with thermistor RT0.

[9] Write "3H" to ADCON0 and start A/D conversion in Counter B reference mode.

[10] Set the HLT bit of HALT register to "1" to start halt mode.

The RC oscillation circuit (CROSC0) oscillates with thermistor RT0 from this time until overflow of Counter B. This period is equivalent to product of "nB0" from first step and $t_{OSCCLK(RT0)}$ due to RT0.

When Counter B overflows, [d] the ADINT signal is set to "1" and the A/D converter interrupt request is generated. By the generation of the interrupt request, [e] halt mode is released and [f] the A/D conversion operation is stopped (the EADC bit = "0"). The contents of Counter A becomes the A/D conversion value of nA1 and is expressed by the following:

$$nA1 = nB0 \cdot \frac{t_{OSCCLK(RT0)}}{t_{SYSCLK}} \quad \text{----- equation (c)}$$

By equations (b) and (c), nA1 is expressed as

$$nA1 = nA0 \cdot \frac{t_{OSCCLK(RT0)}}{t_{OSCCLK(RS0)}} \quad \text{----- equation (d)}$$

where $t_{OSCCLK(RS0)}$ is the period of the oscillation clock by reference resistance RS0 and $t_{OSCCLK(RT0)}$ is the period of the oscillation clock by thermistor RT0.

The oscillation period is expressed ideally as

$$\begin{aligned} t_{OSCCLK(RS0)} &= k_{OSCCLK} \cdot CS0 \cdot RS0 \\ t_{OSCCLK(RT0)} &= k_{OSCCLK} \cdot CS0 \cdot RT0 \end{aligned} \quad \text{----- equation (e)}$$

By substituting equation (e) to equation (d), nA1 is expressed as

$$nA1 = nA0 \cdot \frac{RT0}{RS0}$$

As "nA0" (12,000 in this example) and RS0 are fixed constants, "nA1" becomes a digital value proportional to RT0. This "nA1" is equivalent to "nT0" in equation (a).

The obtained "nA1" must be further converted to a temperature display value depending on the temperature-resistance characteristics of the thermistor in a program.

12.3.4 RC Oscillation Monitor

By setting Bit 2 (MON) of the Port 33 control register (P33CON) to "1", the RC oscillation clock (OSCCLK) can be output to P3.3.

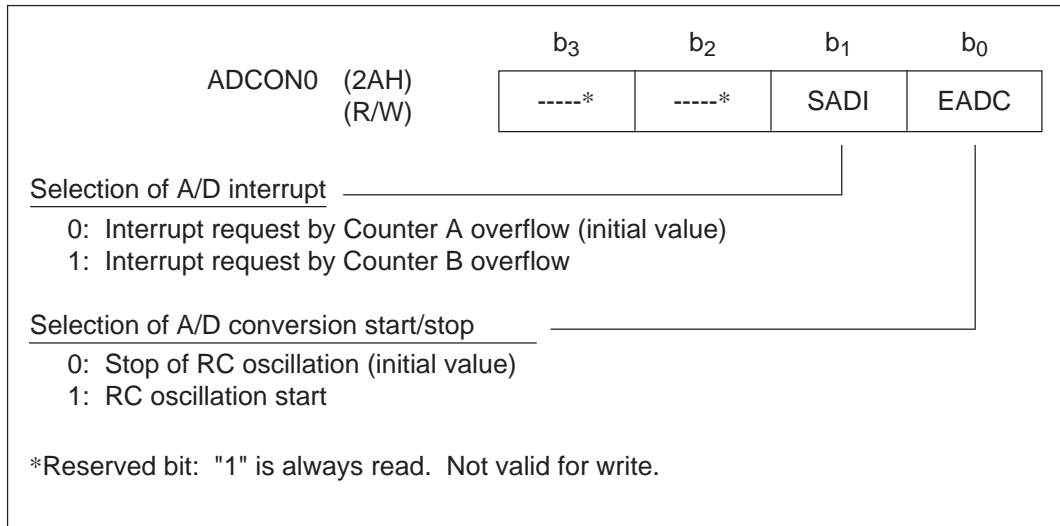
By using the test functions, the RC oscillation clock can be output at P3.3 without using software. For details of the test functions, refer to Chapter 15 "Test Circuit".

The RC oscillation monitor is useful when checking the characteristics of the RC oscillation circuit. For instance, it is possible to measure relationship between sensors such as a thermistor and an oscillation frequency. For example, by examining the relationship between ambient temperature of a thermistor built-in RC oscillation circuit and oscillation frequencies of the thermistor and the reference resistance, it is possible to obtain the conversion coefficient from the value of nA1 to the temperature display values.

12.4 Registers Related to A/D Converter

(1) A/D converter control register 0 (ADCON0)

The A/D converter control register 0 (ADCON0) is a 4-bit special function register (SFR) that selects start/stop of RC oscillation of the A/D converter and the A/D converter interrupt by Counter A or Counter B.



Bit 1: SADI

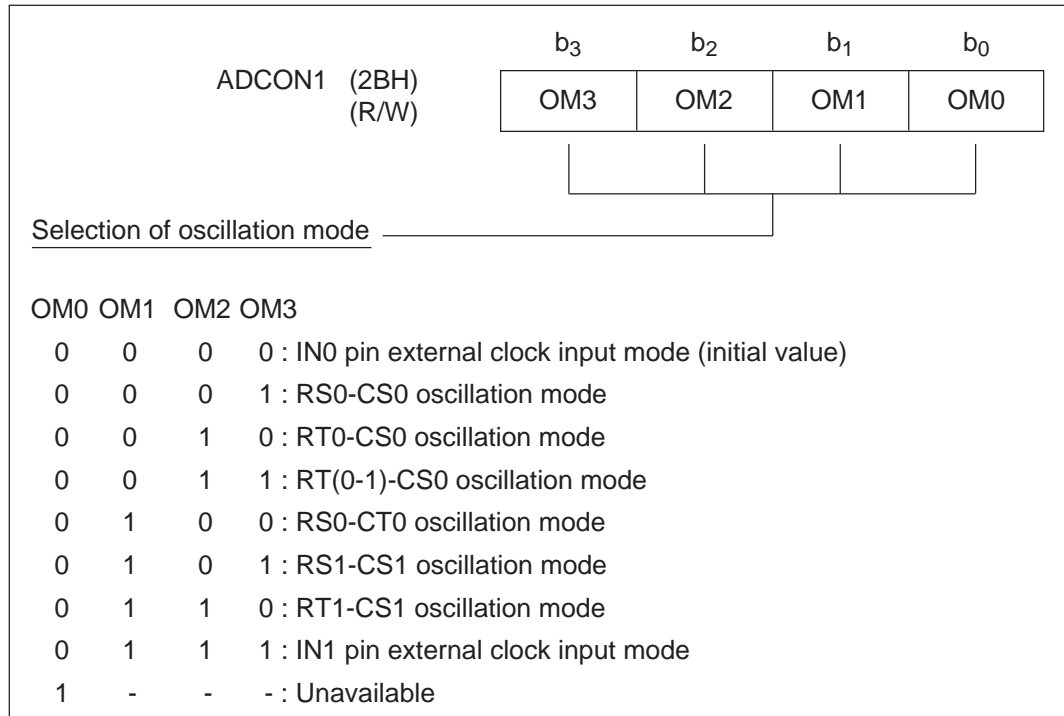
This bit is to select the A/D converter interrupt request (ADINT) by overflow of either Counter A or Counter B. By resetting SADI to "0", the interrupt request by overflow of Counter A is selected and by setting SADI to "1", the interrupt request by overflow of Counter B is selected. At system reset, SADI is reset to "0".

Bit 0: EADC

This bit is to select start/stop of conversion of the A/D converter. When set to "1", A/D conversion is started and when reset to "0", A/D conversion is stopped. When either Counter A or Counter B overflows while EADC is set to "1" to start counting, the EADC bit is set to "0" automatically. Consequently, EADC indicates that the measurement is in progress. At system reset, the EADC bit is reset to "0" and is in stop state.

(2) A/D converter control register 1 (ADCON1)

The A/D converter control register 1 (ADCON1) is a 4-bit special function register (SFR) to select oscillation mode of the RC oscillation circuit.



(3) A/D converter counter A registers (CNTA0 to 4)

The A/D converter counter A registers (CNTA0 to 4) are 4-bit special function registers (SFRs) to read or write the Counter A.

Note that CNTA0 to CNTA3 can handle only data located in 0H to 9H because these registers are decimal counters.

	b ₃	b ₂	b ₁	b ₀
CNTA0 (20H) (R/W)	a3	a2	a1	a0
<u>Bits 0 to 3 of Counter A</u>				

	b ₃	b ₂	b ₁	b ₀
CNTA1 (21H) (R/W)	a7	s6	a5	a4
<u>Bits 4 to 7 of Counter A</u>				

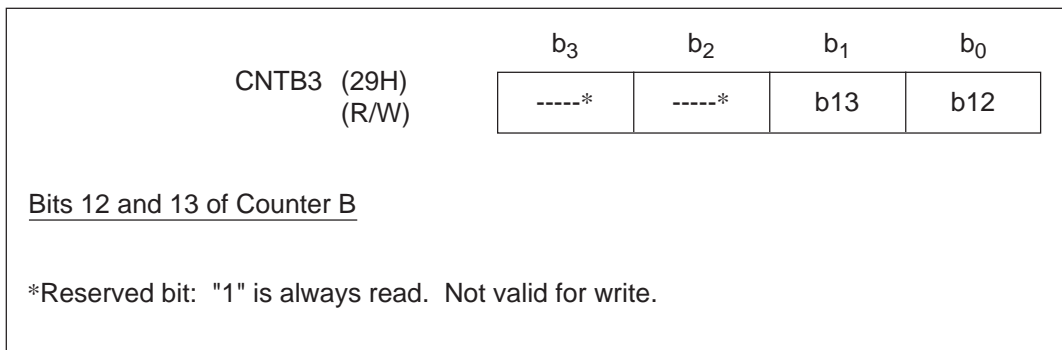
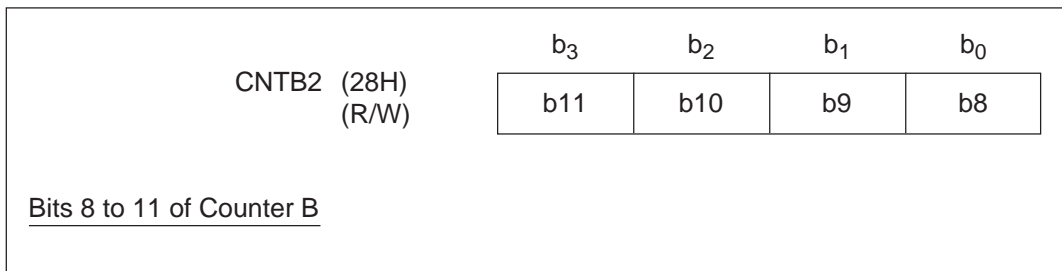
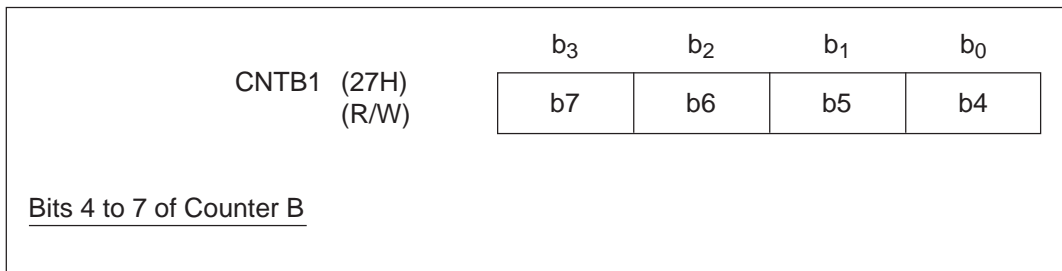
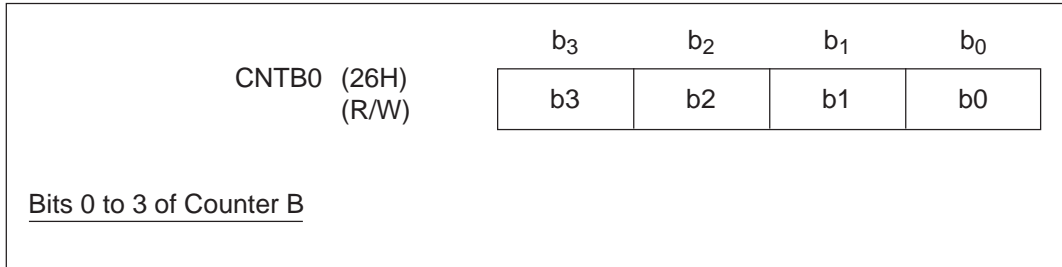
	b ₃	b ₂	b ₁	b ₀
CNTA2 (22H) (R/W)	a11	a10	a9	a8
<u>Bits 8 to 11 of Counter A</u>				

	b ₃	b ₂	b ₁	b ₀
CNTA3 (23H) (R/W)	a15	a14	a13	a12
<u>Bits 12 to 15 of Counter A</u>				

	b ₃	b ₂	b ₁	b ₀
CNTA4 (24H) (R/W)	----*	a18	a17	a16
<u>Bits 16 to 18 of Counter A</u>				
*Reserved bit: "1" is always read. Not valid for write.				

(4) A/D converter counter B registers (CNTB0 to 3)

The A/D converter counter B registers (CNTB0 to 3) are 4-bit special function registers (SFRs) to read/write the Counter B.



Tables 12-3 and 12-4 list A/D converter-related registers and pins.

Table 12-3 List of A/D Converter-Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
A/D converter control register 0	ADCON0	2AH	R/W	Yes	0CH
A/D converter control register 1	ADCON1	2BH	R/W		0H
A/D converter counter A register 0	CNTA0	20H	R/W	Yes	0H
A/D converter counter A register 1	CNTA1	21H	R/W		0H
A/D converter counter A register 2	CNTA2	22H	R/W	Yes	0H
A/D converter counter A register 3	CNTA3	23H	R/W		0H
A/D converter counter A register 4	CNTA4	24H	R/W	No	8H
A/D converter counter B register 0	CNTB0	26H	R/W	Yes	0H
A/D converter counter B register 1	CNTB1	27H	R/W		0H
A/D converter counter B register 2	CNTB2	28H	R/W	Yes	0H
A/D converter counter B register 3	CNTB3	29H	R/W		0CH

Table 12-4 List of A/D Converter-Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Note
RT0	6	5	Output	Resistance sensor connection pin to measure Channel 0
CRT0	8	6	Output	Resistance/capacitance sensor connection pin to measure Channel 0
RS0	9	7	Output	Reference resistance connection pin for Channel 0
CS0	10	8	Output	Reference capacitance connection pin for Channel 0
IN0	11	9	Input	Input pin of RC oscillation circuit of Channel 0
RT1	16	13	Output	Resistance sensor connection pin to measure Channel 1
RS1	15	12	Output	Reference resistance connection pin for Channel 1
CS1	13	11	Output	Reference capacitance connection pin for Channel 1
IN1	12	10	Input	Input pin of RC oscillation circuit of Channel 1

Chapter 13

LCD Driver (LCD)

Chapter 13 LCD Driver (LCD)

13.1 Overview

The MSM64162A has a built-in LCD driver.

The LCD driver section consists of (21×4 bits) display registers (DSPR0 to DSPR20), display control register (DSPCON), LCD drivers for 24 outputs, constant voltage circuit for LCD, and bias generator circuit.

In the bias generator circuit for LCD drivers, each bias voltage is generated either by multiplying or dividing the power supply voltage through an external capacitor, or by multiplying the constant voltage ($V_{SS1} = -1.2\text{ V}$) through the constant voltage circuit for LCD. One of the above two methods for bias generation can be selected by mask option.

There are three types of driving methods, i.e. 1/4 duty, 1/3 duty and 1/2 duty. Maximum of 80 segments can be driven for 1/4 duty, 63 segments for 1/3 duty and 44 segments for 1/2 duty, respectively.

The mask option can select either a common driver or a segment driver for each LCD driver pin. The mask option can also specify assignment of each bit of the display register to each segment.

On the one hand, all the display registers to be used must be selected by the mask option. If not, note that the display registers can not be used.

Refer to Appendix F on the mask options.

L16 to L23 of the LCD driver can become output ports by the mask option.

The following is the relation among the duty, the bias method and the maximum segment number.

1/4 duty 1/3 bias method ($V_{DD} = 0\text{ V}$, $V_{SS1} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$) - 80 segments
1/3 duty 1/3 bias method ($V_{DD} = 0\text{ V}$, $V_{SS1} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$) - 63 segments
1/2 duty 1/2 bias method ($V_{DD} = 0\text{ V}$, $V_{SS1} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$) - 44 segments

13.2 Layout of LCD Driver

The layout of the LCD driver is shown in Figure 13-1. Figures 13-2 and 13-3 show the LCD driver and its peripheral circuits.

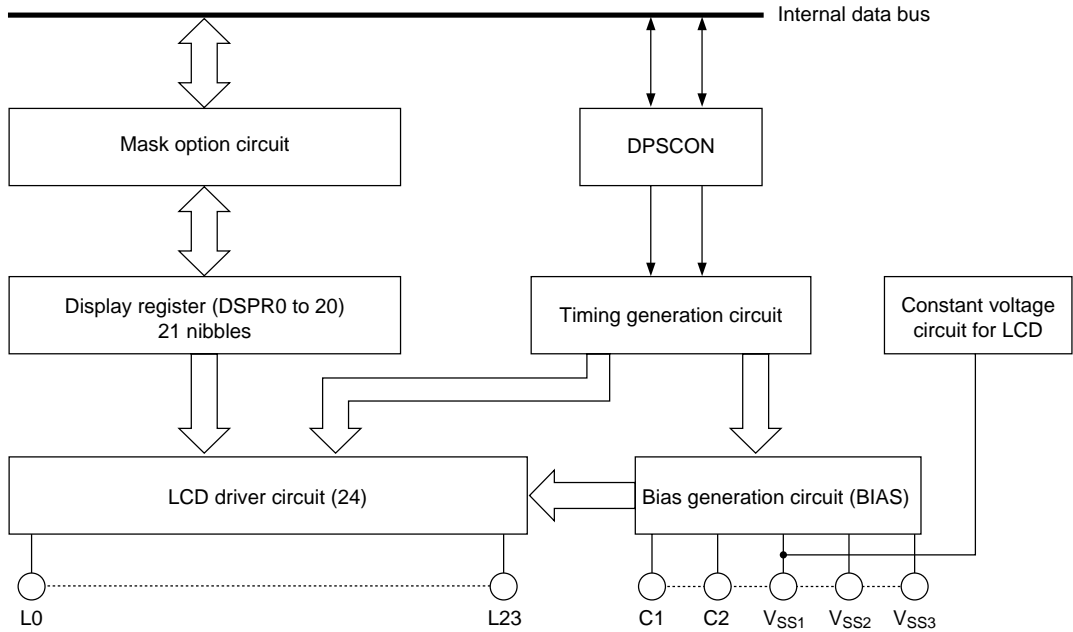


Figure 13-1 Layout of LCD Driver

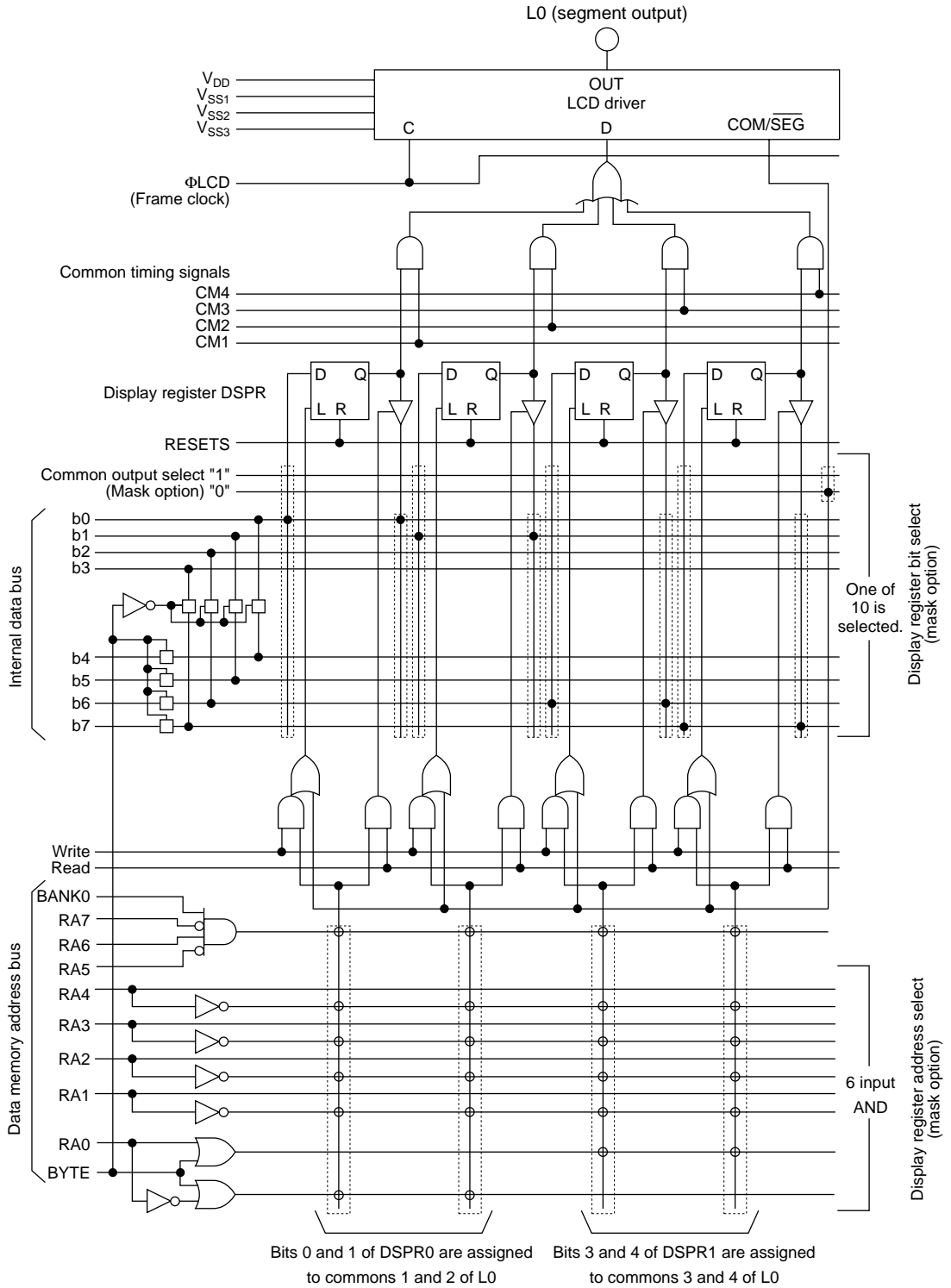


Figure 13-2 LCD Driver and Display Register (Circuit layout of L0 to L15: One output)

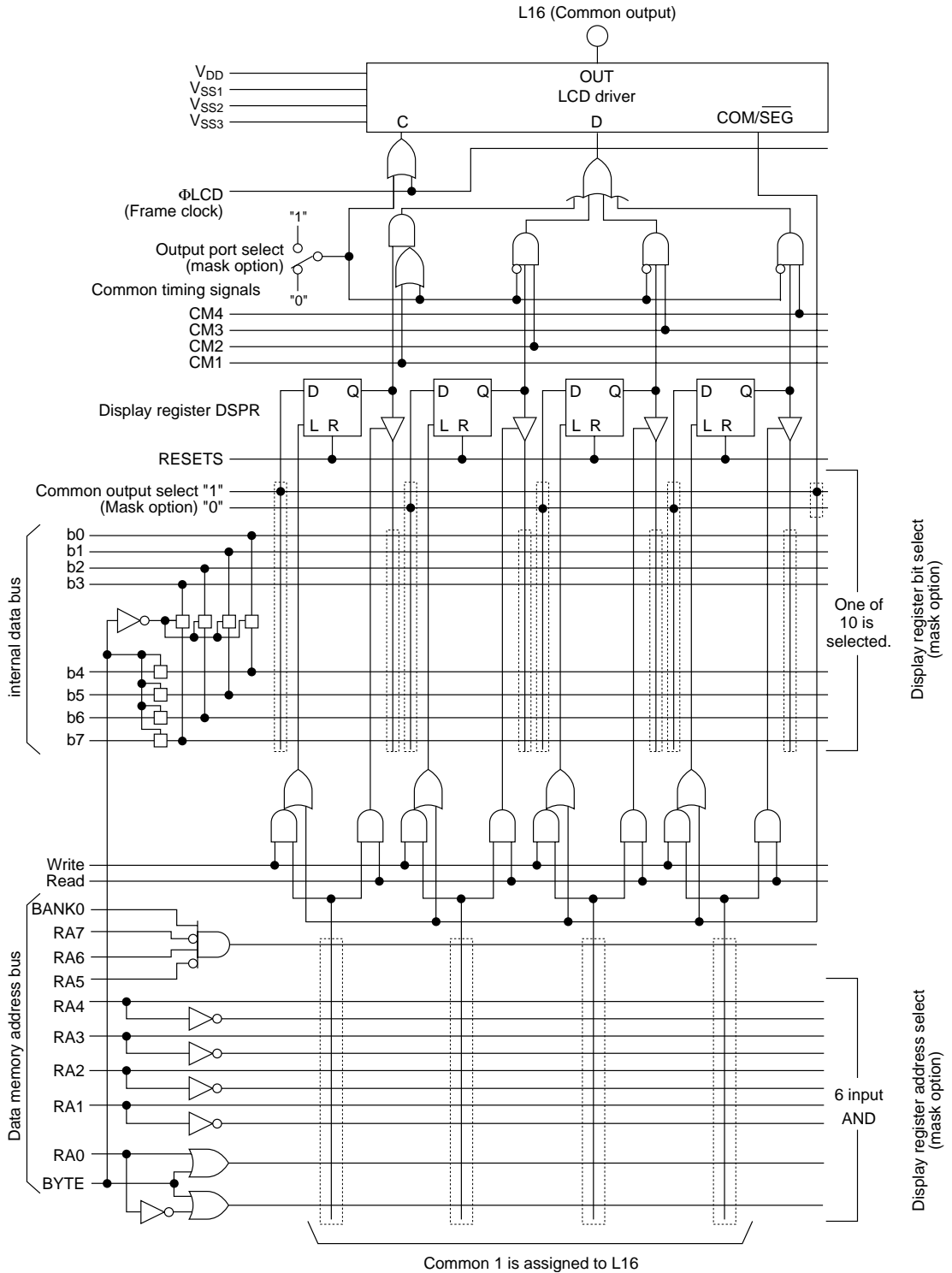


Figure 13-3 LCD Driver and Display Register (Circuit layout of L16 to L23: One output)

13.3 Operation of LCD Driver

The LCD driver outputs LCD square waveforms based on data written to the display registers.

The mask option can select the address of the display register, bit assignment and a segment driver/a common driver.

4 segment display registers per one segment driver are assigned. All the 4 segments are used for 1/4 duty, 3 segments for 1/3 duty and 2 segments for 1/2 duty, respectively.

In Figure 13-2, the L0 output is assigned to the segment driver output.

Bits 0 and 1 are assigned to a segment corresponding to commons 1 and 2, and bits 2 and 3 of DSPR1 are assigned to a segment corresponding to commons 3 and 4.

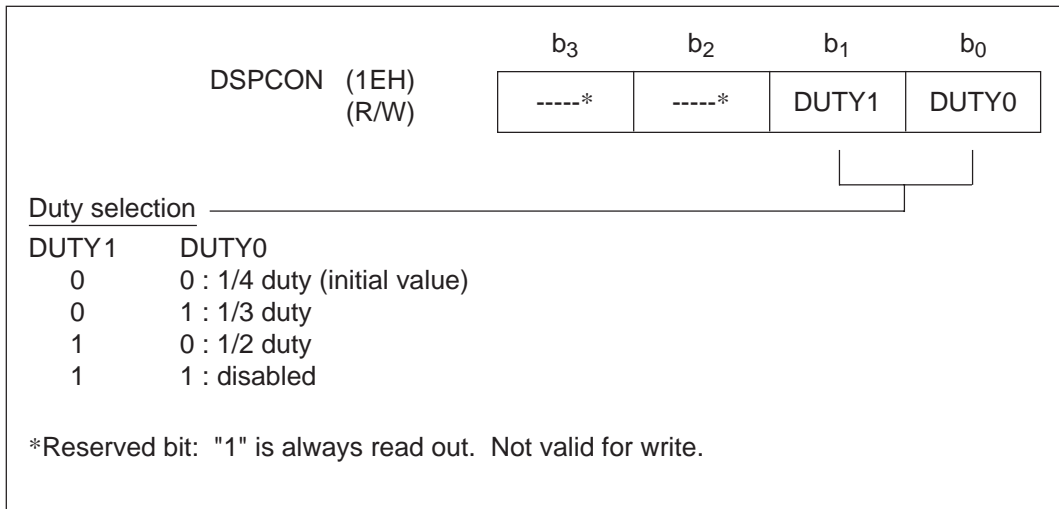
In Figure 13-3, the L16 output is assigned to the common driver 1 output.

Thus, it is possible to assign an arbitrary display register and bits to an arbitrary segment by mask option.

Duty of the LCD driver is selected by the display control register (DSPCON).

13.4 Display Control Register (DSPCON)

The display control register (DSPCON) is a 4-bit special function register (SFR) to control the duty ratio of the LCD driver.

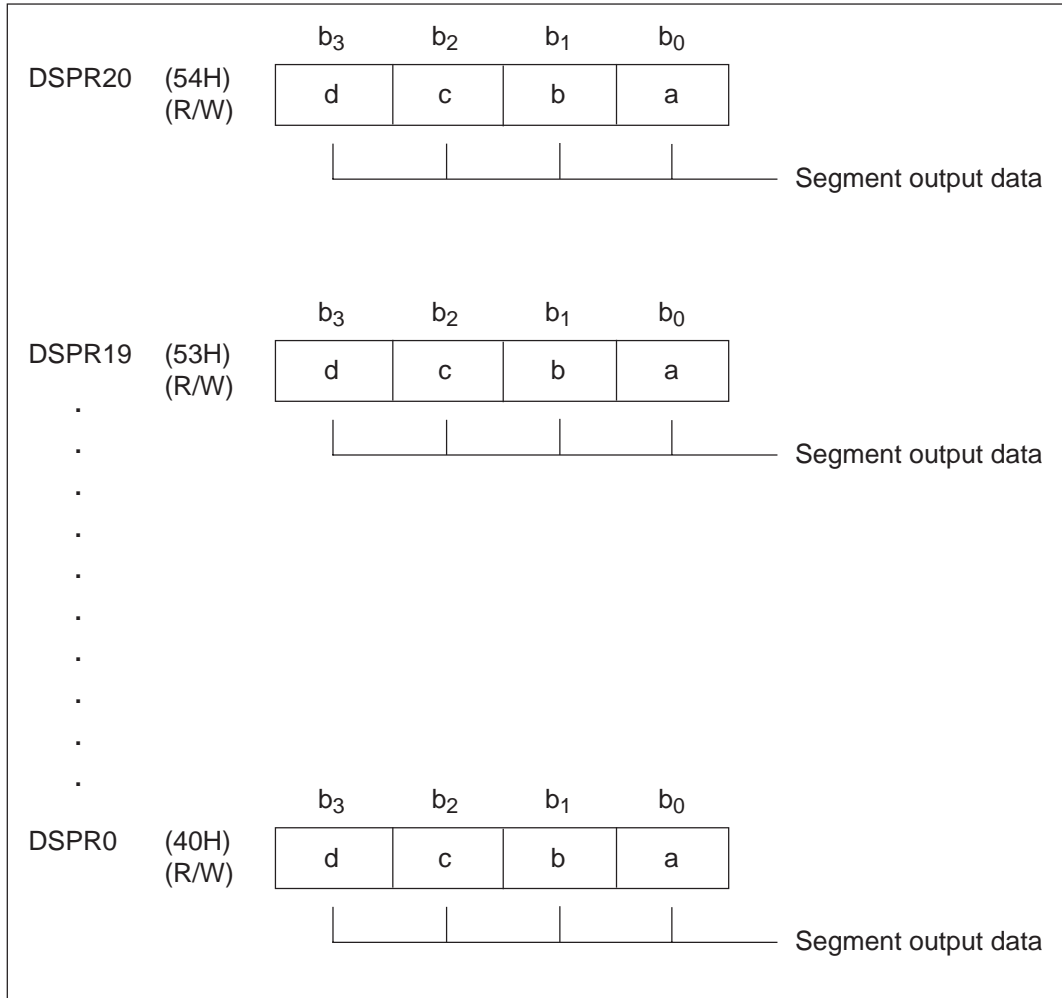


Bits 1 and 0: DUTY1, DUTY0

DUTY1 and DUTY0 are bits to select the duty ratio of the LCD driver. They are reset to "0" at system reset and 1/4 duty is selected. Setting both DUTY1 and DUTY0 to "1" is disabled.

13.5 Display Registers 0 to 20 (DSPR0 to 20)

The display registers 0 to 20 (DSPR0 to 20) are data registers for segment output of the LCD driver. They are assigned to addresses 40H to 54H of Bank 0.



It is possible to assign an arbitrary bit of the display register to an arbitrary segment driver by the mask option. At system reset, all the display registers are reset to "0" and LCD segments are all off. Those bits set to "1" in the display register are in on state on the LCD segments while those bits reset to "0" are in off state.

For details of assignment of each bit of the display register for the display segment, refer to "List of LCD Driver Mask Option" in "Appendix F: Mask Options".

13.6 Output Port Selection by Mask Option

Each of the 8 pins of L16 to L23 of the LCD driver can be selected as an output port by the mask option. When these pins are selected as output ports, one port pin is assigned to one bit of the display register. Figure 13-4 shows an example of assigning DSPR0 to L16 to L19 as an output port. The output voltage level at this time is at the V_{DD} level at "H" output and is at the V_{SS} level (IC power supply voltage level) when outputting "L".

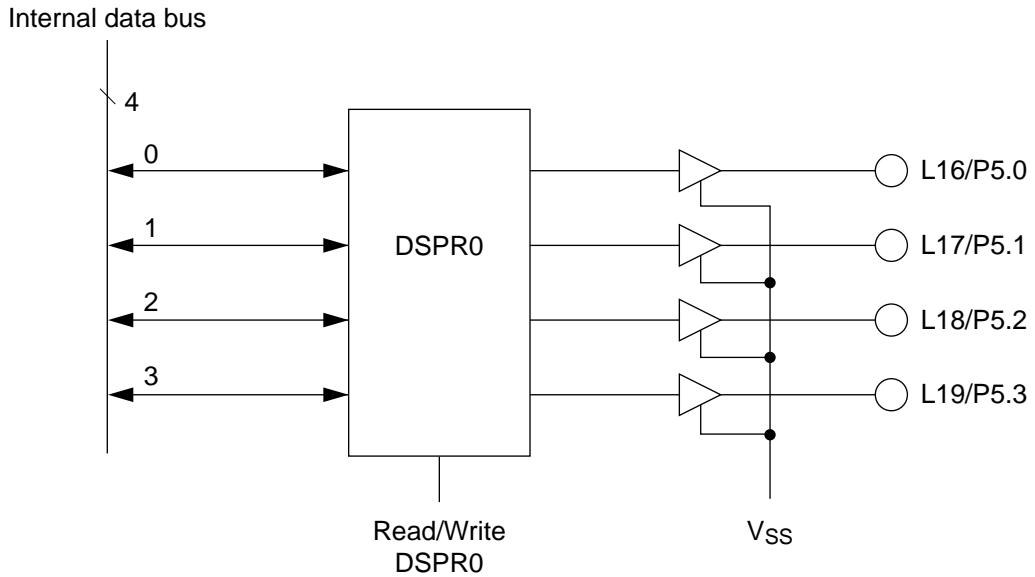


Figure 13-4 Equivalent Circuit when DSPR0 is Assigned to L16 to L19 as an Output Port

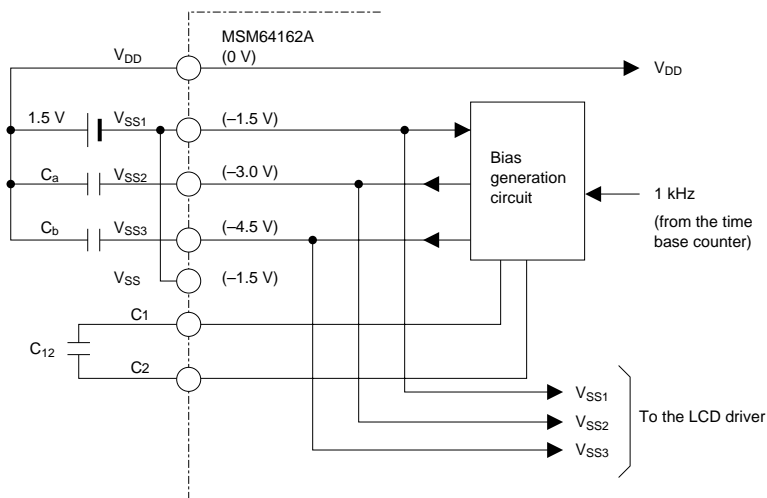
Only DSPR0 and DSPR1 can be used as output ports. Other registers cannot be used as output ports.

For bit assignment of the display register for output pins and selection of output ports, refer to "List of LCD Driver Mask Options" in "Appendix F: Mask Options".

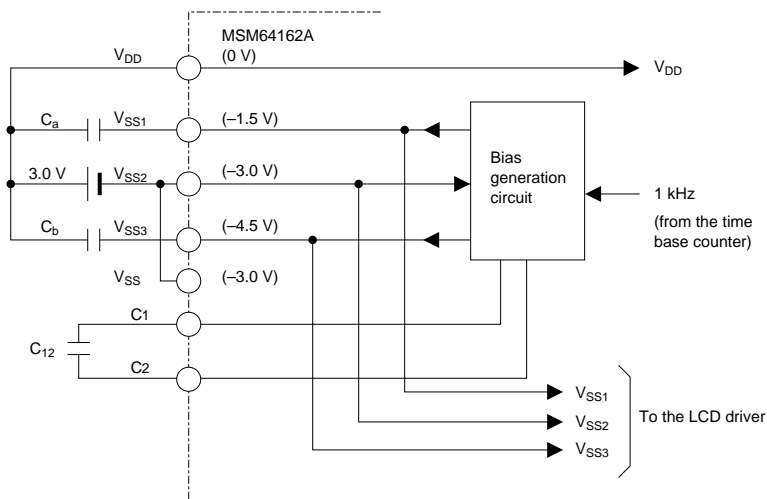
13.7 Bias Generation Circuit for LCD Driver (BIAS)

In the bias generator circuit for LCD drivers, each bias voltage is generated either by multiplying or dividing the power supply voltage through an external capacitor, or by multiplying the constant voltage ($V_{SS1} = -1.2\text{ V}$) through the constant voltage circuit for LCD. One of the above two methods for bias generation can be selected by mask option.

(1) Figure 13-5 shows the layout of the bias generation circuit when a constant voltage circuit for LCD is not used by mask option.



(a) 1.5 V spec.



(b) 3.0 V spec.

Figure 13-5 Layout of the Bias Generation Circuit

(When constant voltage circuit for LCD is not used) (C_a , C_b , $C_{12} = 0.1\ \mu\text{F}$)

Notes: In a case that LCD driver is not used, it is unnecessary to connect capacitor C_a , C_b and C_{12} and the corresponding pins should be left open.

In a case that LCD duty ratio is selected to 1/2 (1/2 duty), it is unnecessary to connect capacitor C_b to V_{SS3} pin.

(2) Figure 13-6 shows the layout of the bias generation circuit when a constant voltage circuit for LCD is used by mask option.

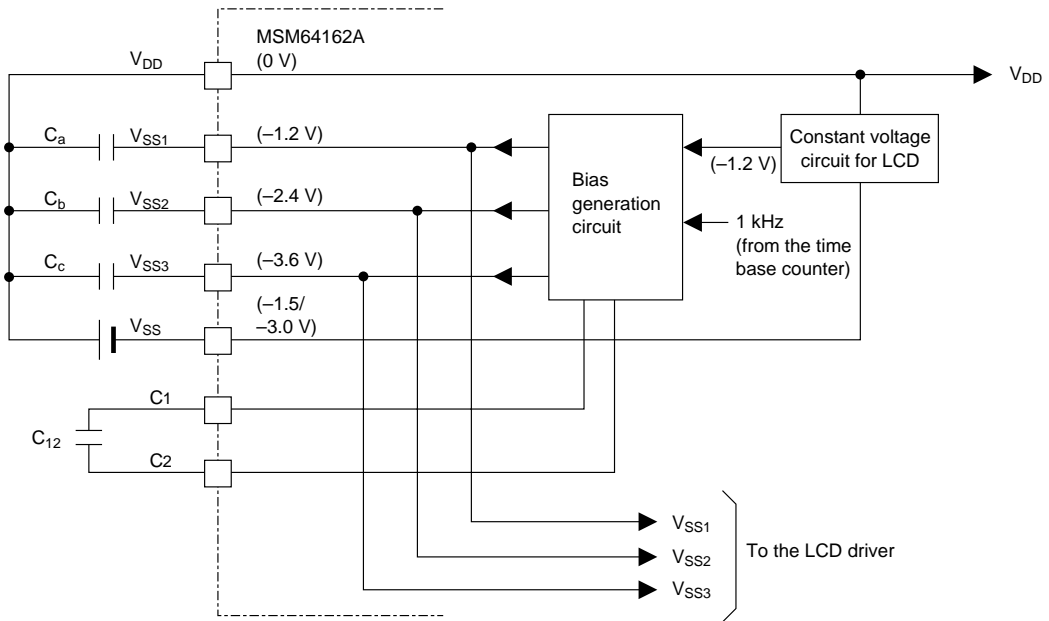


Figure 13-6 Layout of the Bias Generation Circuit
(When constant voltage circuit for LCD is used) (C_a , C_b , C_c , $C_{12} = 0.1 \mu\text{F}$)

13.8 LCD Driver Output Waveforms

Figures 13-6 (a) to (c) show 1/4 duty of output waveforms of the LCD driver and Figures 13-7 (a) and (b) show 1/3 duty and Figures 13-8 (a) and (b) show 1/2 duty.

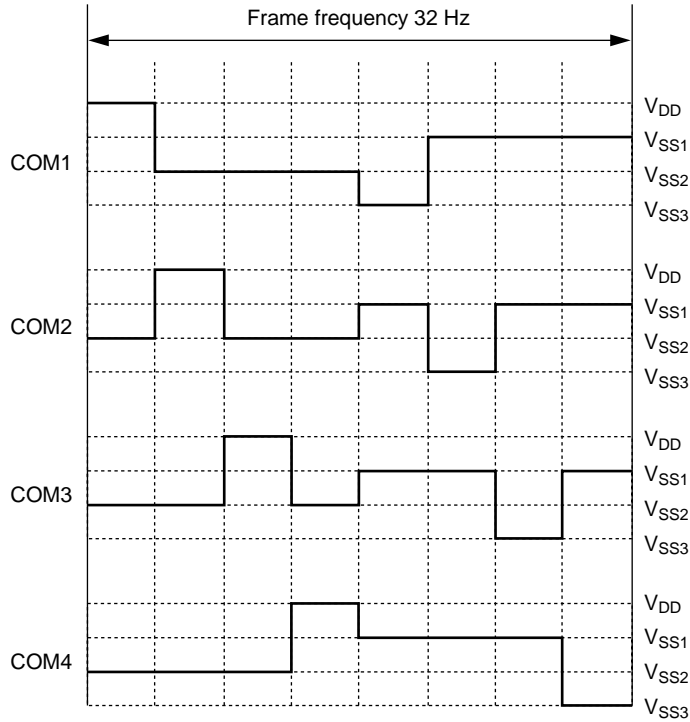


Figure 13-6 (a) 1/4 Duty Common Driving Waveforms (1/3 bias)

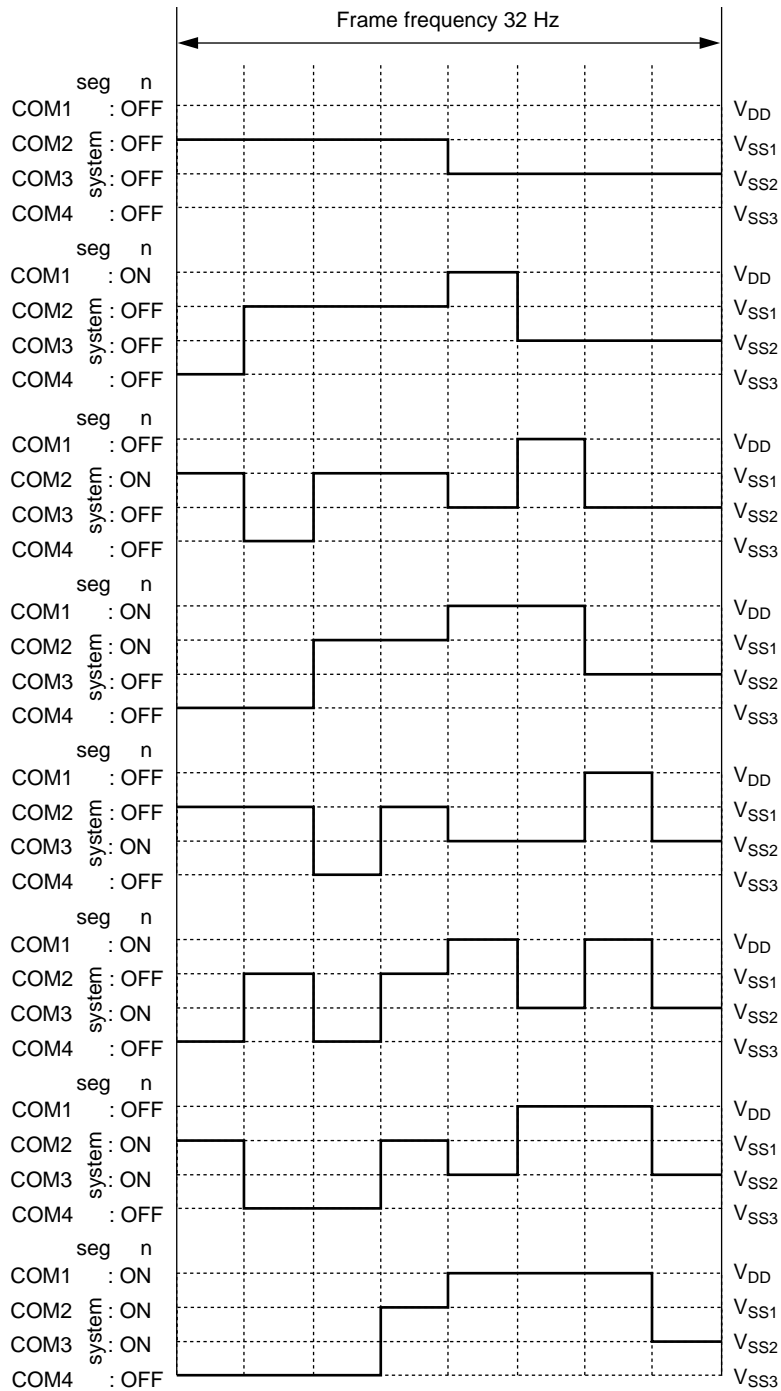


Figure 13-6 (b) 1/4 Duty Common Driving Waveforms (1/3 bias)

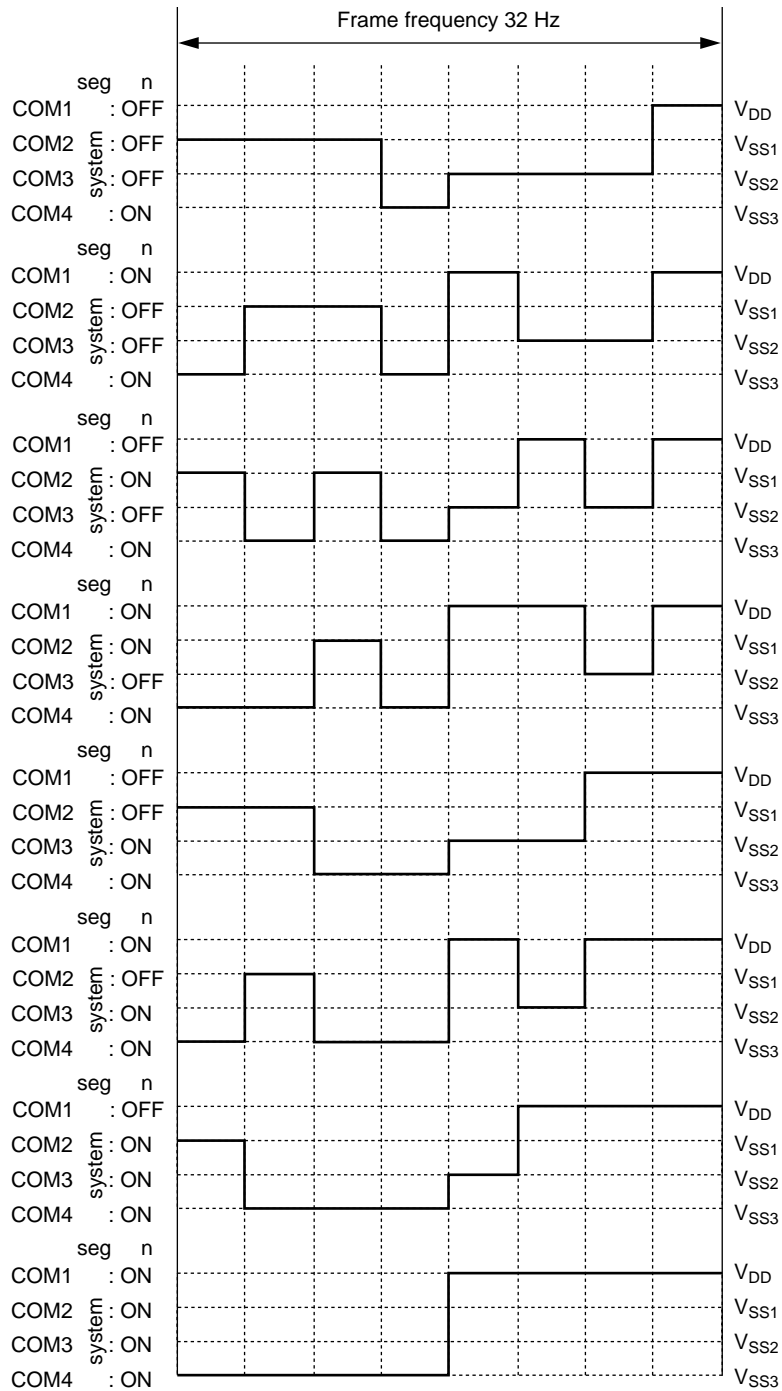


Figure 13-6 (c) 1/4 Duty Common Driving Waveforms (1/3 bias)

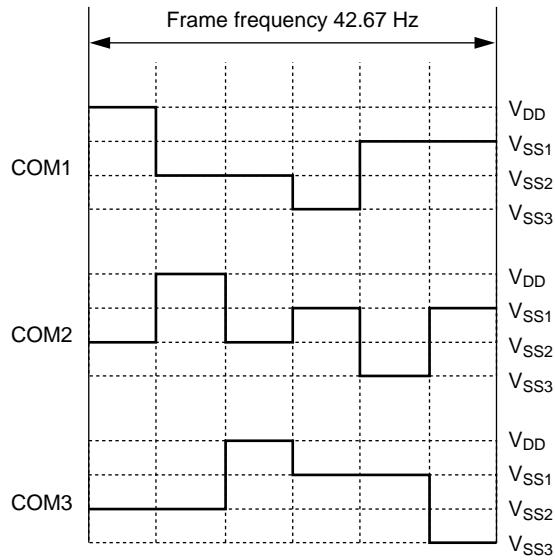


Figure 13-7 (a) 1/3 Duty Common Driving Waveforms (1/3 bias)

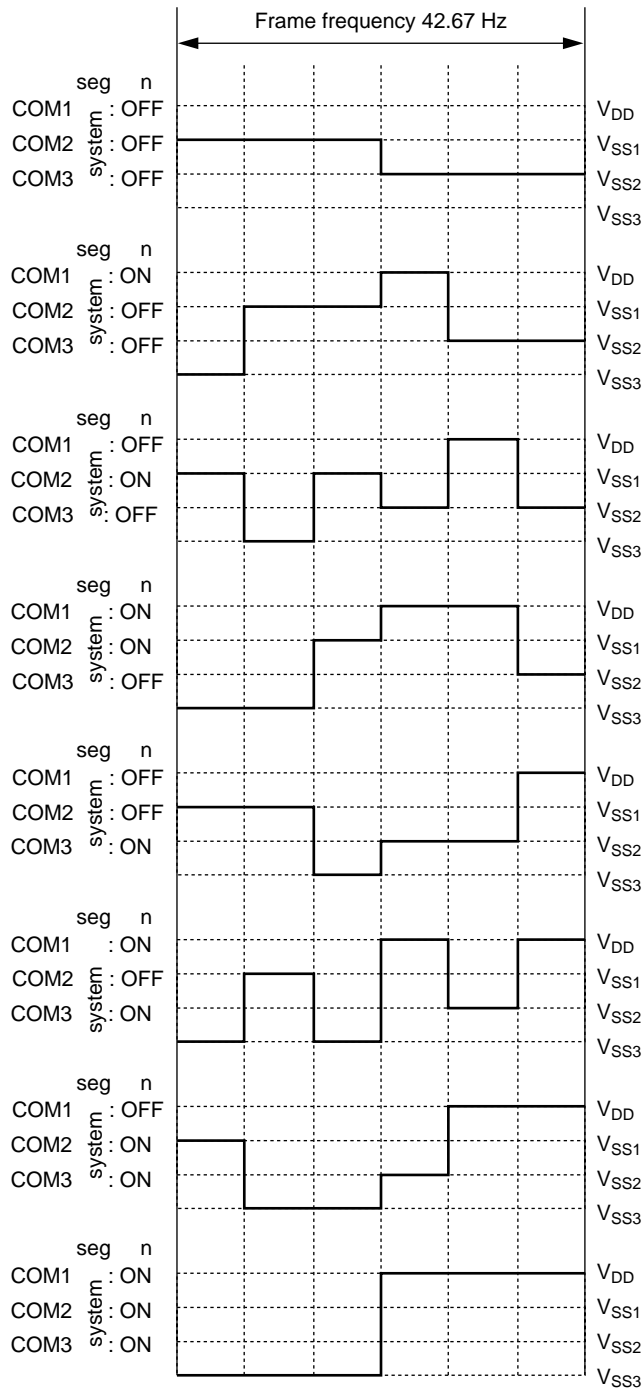


Figure 13-7 (b) 1/3 Duty Common Driving Waveforms (1/3 bias)

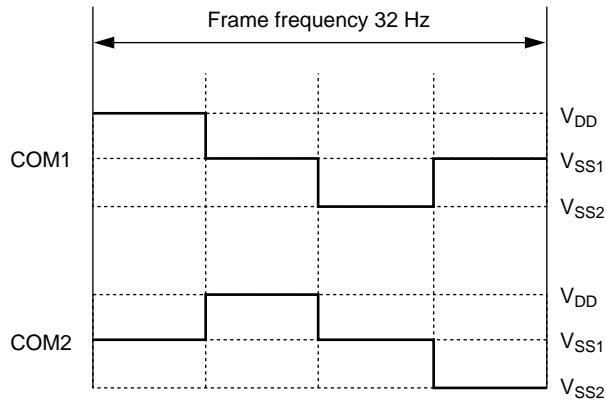


Figure 13-8 (a) 1/2 Duty Common Driving Waveforms (1/2 bias)

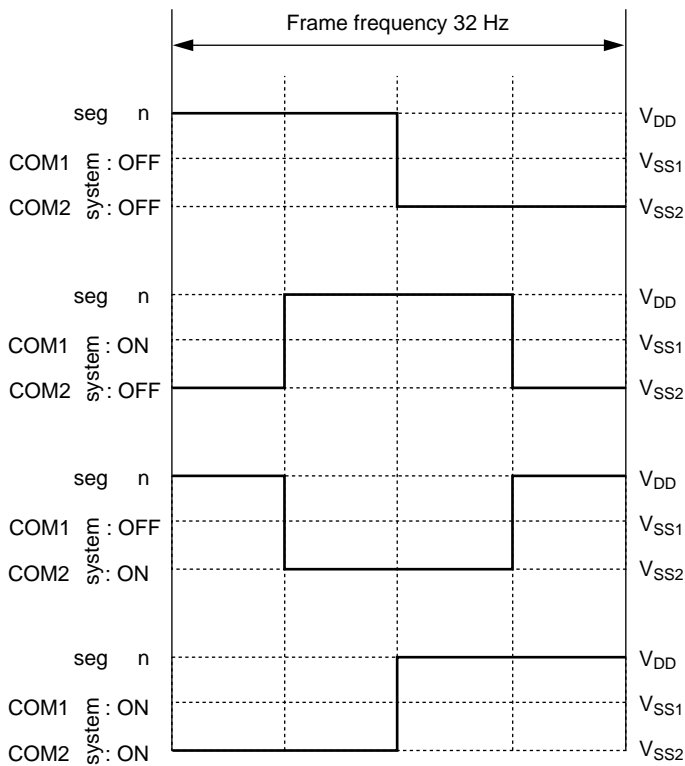


Figure 13-8 (b) 1/2 Duty Common Driving Waveforms (1/2 bias)

Tables 13-1 and 13-2 show the list of LCD driver-related registers and pins.

Table 13-1 List of LCD Driver-Related Registers

Register name	Symbol	Address	Read/Write	Byte access	Value at system reset
Display control register	DSPCON	1EH	R/W	No	0CH
Display register 0	DSPR0	40H	R/W	Yes	0H
Display register 1	DSPR1	41H	R/W		0H
Display register 2	DSPR2	42H	R/W	Yes	0H
Display register 3	DSPR3	43H	R/W		0H
Display register 4	DSPR4	44H	R/W	Yes	0H
Display register 5	DSPR5	45H	R/W		0H
Display register 6	DSPR6	46H	R/W	Yes	0H
Display register 7	DSPR7	47H	R/W		0H
Display register 8	DSPR8	48H	R/W	Yes	0H
Display register 9	DSPR9	49H	R/W		0H
Display register 10	DSPR10	4AH	R/W	Yes	0H
Display register 11	DSPR11	4BH	R/W		0H
Display register 12	DSPR12	4CH	R/W	Yes	0H
Display register 13	DSPR13	4DH	R/W		0H
Display register 14	DSPR14	4EH	R/W	Yes	0H
Display register 15	DSPR15	4FH	R/W		0H
Display register 16	DSPR16	50H	R/W	Yes	0H
Display register 17	DSPR17	51H	R/W		0H
Display register 18	DSPR18	52H	R/W	Yes	0H
Display register 19	DSPR19	53H	R/W		0H
Display register 20	DSPR20	54H	R/W	No	0H

Note : The display registers 0 through 20 are registers that can not be used without selection by mask option.

All the display registers to be used must be allocated on the LCD driver mask option table per bit. (Refer to Appendix F on the mask options.)

Table 13-2 List of LCD Driver-Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Function
V _{SS1}	35	28	—	Negative side power supply (at 1.5 V spec.) Bias output for driving LCD (–1.5 V) (at 3.0 V spec.) At non-regulated LCD driver. Bias output for driving LCD (–1.2 V) At regulated LCD driver.
V _{SS2}	37	29	—	Negative side power supply (at 3.0 V spec.) Bias output for driving LCD (–3.0 V) (at 1.5 V spec.) At non-regulated LCD driver.
V _{SS3}	40	31	—	Bias output for driving LCD (–4.5 V) At non-regulated LCD driver.
C1	41	32	—	Capacitor connection pin for LCD driving bias generation
C2	42	33	—	
L0	43	34	Output	LCD segment/common signal output pins
L1	44	35	Output	
L2	45	36	Output	
L3	46	37	Output	
L4	47	38	Output	
L5	48	39	Output	
L6	49	40	Output	
L7	50	41	Output	
L8	51	42	Output	
L9	52	43	Output	
L10	54	44	Output	
L11	55	45	Output	LCD driver output pins or output ports due to the mask option.
L12	56	46	Output	
L13	57	47	Output	
L14	58	48	Output	
L15	60	49	Output	
L16/P5.0	61	50	Output	
L17/P5.1	62	51	Output	
L18/P5.2	63	52	Output	
L19/P5.3	64	53	Output	
L20/P6.0	65	54	Output	
L21/P6.1	66	55	Output	
L22/P6.2	68	56	Output	
L23/P6.3	69	57	Output	

Chapter 14

Constant Voltage Circuit for Logic Power Supply (VR)

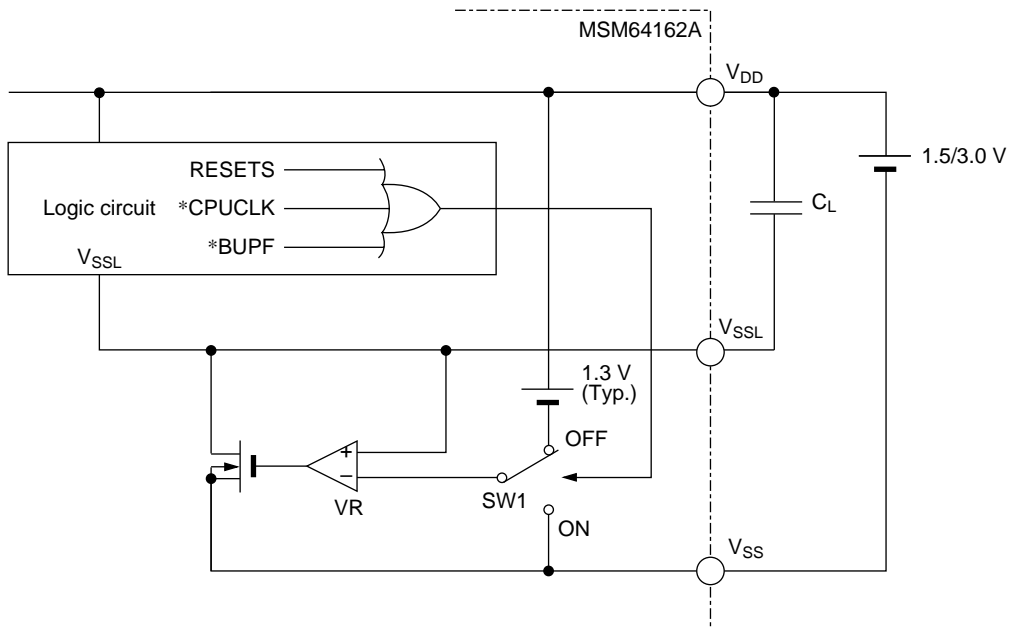
Chapter 14 Constant Voltage Circuit for Logic Power Supply (VR)

14.1 Overview

The MSM64162A has a built-in constant voltage circuit for the logic power supply (VR).

14.2 Layout of Constant Voltage Circuit for Logic Power Supply

Figure 14-1 shows the layout of the constant voltage circuit for the logic power supply.



* BUPF indicates output of the backup flag.
 CPUCLK indicates output of the system clock selection bit.

Figure 14-1 Constant Voltage for Logic Power Supply Circuit

In Figure 14-1, the " C_L " capacitor is a noise smoothing capacitor on the V_{SSL} line of the logic circuit and it is necessary to install the capacitor of $0.05\ \mu\text{F}$ to $0.2\ \mu\text{F}$ for C_L . SW1 in the Figure becomes ON state when (1) the system clock selection bit (CPUCLK) is set to "1", (2) in system reset mode or (3) the backup flag (BUPF) is set to "1".

When developing an application in which CPUCLK or BUPF is set to "1" in the 3.0 V specifications, install the capacitor of $0.47\ \mu\text{F} \pm 30\%$ for C_L . In other cases, install the capacitor of $0.05\ \mu\text{F}$ to $0.2\ \mu\text{F}$ for C_L .

14.3 Operation of Constant Voltage Circuit for Logic Power Supply

The constant voltage for the logic power supply (VR) outputs a constant voltage of $V_{DD}-1.3$ V (Typ.) to the V_{SSL} pin and supplies V_{SSL} level as the power supply of the logic circuit.

At system reset or when selecting 400 kHz RC oscillation output as the system clock, the V_{SSL} output is forced to be switched to V_{SS} .

In normal operation mode, the V_{SSL} output is switched to V_{SS} when Bit 0 (BUPF) of the backup control register (BUPCON) is set to "1" while the crystal oscillation output is the system clock. When resetting BUPF to "0", the V_{SSL} output becomes approximately $V_{DD}-1.3$ V.

In system reset mode, BUPF is reset to "0" but as shown in Figure 14-2, the V_{SSL} output becomes V_{SS} level for 0.5 second after crystal oscillation started.

Table 14-1 shows output state of V_{SSL} by the CPUCLK bit, BUPF flag and system reset mode and Figure 14-2 shows output status of V_{SSL} in system reset mode.

Table 14-1 Output State of V_{SSL}

System reset mode	CPUCLK flag	BUPF flag	V_{SSL} output level
0.5 sec duration	—	—	V_{SS}
—	0	0	about $V_{DD}-1.3$ V
—	0	1	V_{SS}
—	1	—	V_{SS}

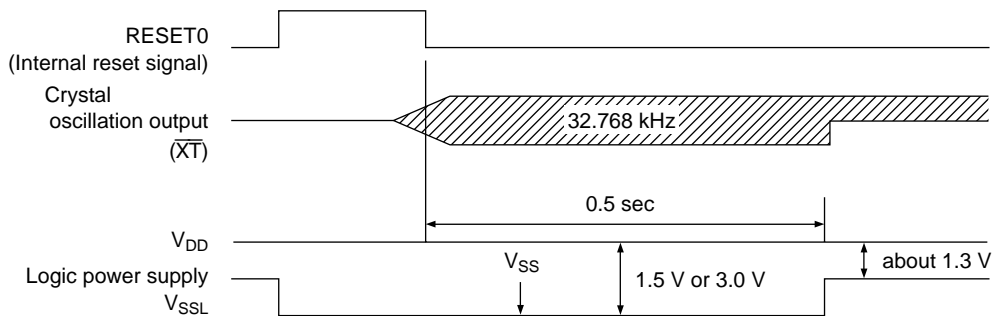
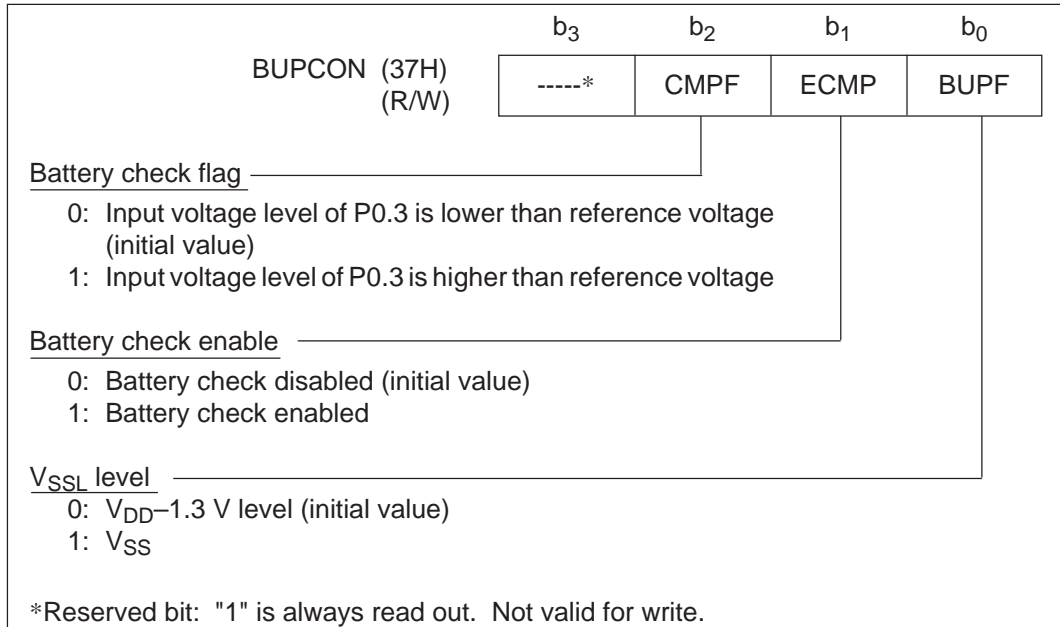


Figure 14-2 V_{SSL} Output State in System Reset Mode

14.4 Backup Control Register (BUPCON)

The Backup control register (BUPCON) is a 4-bit special function register (SFR) to control the output voltage level of V_{SSL} which is output of the constant voltage circuit for logic or the battery checking circuit. In addition, refer to Chapter 8 "Battery Checking Circuit" regarding the battery checking circuit.



Bit 2: CMPF

This bit is an output flag for the comparator of battery checking circuit. When CMPF = "1", the input voltage level is higher than the reference voltage level and when CMPF = "0", the input voltage level is lower than the reference voltage level. In addition, when battery check enable ECMP = "0", CMPF value has no meaning.

Bit 1: ECMP

This bit is an enable for the comparator of battery checking circuit. By setting ECMP to "1", the reference voltage is generated and the comparator is operated. By resetting ECMP to "0", the comparator stops operating.

Bit 0: BUPF

This bit is a flag to select output voltage level of V_{SSL} which is output of the constant voltage circuit for logic (VR). By resetting BUPF to "0", the V_{SSL} output becomes $V_{DD}-1.3$ V and by setting BUPF to "1", the V_{SSL} output becomes V_{SS} level. At system reset, it is reset to "0". For 0.5 second after the system reset, the V_{SSL} output is forced to be switched to V_{SS} level.

Table 14-2 shows those pins related to the constant voltage circuit for logic.

Table 14-2 Pins Related to Constant Voltage Circuit for Logic

Pin name	Pin No.	Pad No.	Input/Output	Note
V _{SS}	34	27	—	Digital negative side power supply
V _{SS1}	35	28	—	Digital negative side power supply (at 1.5 V spec.) Bias output to drive LCD (–1.5 V) (at 3.0 V spec.) At non-regulated LCD driver. Bias output for driving LCD (–1.2 V) At regulated LCD driver.
V _{SS2}	37	29	—	Digital negative side power supply (at 3.0 V spec.) Bias output to drive LCD (–3.0 V) (at 1.5 V spec.) At non-regulated LCD driver.
V _{SSL}	39	30	—	Negative side power supply pin for internal logic (internally generated voltage)

Chapter 15

Test Circuit (TST)

Chapter 15 Test Circuit (TST)

15.1 Overview

The MSM64162A can output RC oscillation clock of the A/D converter or 400 kHz RC oscillation clock of the system clock to Port 3.3 using $\overline{TST1}$ and $\overline{TST2}$, which are test pins.

By monitoring each RC oscillation clock, it is possible to measure the conversion characteristics of the A/D converter and the frequency of the RC oscillation side system clock.

15.2 Operation of Test Circuit

When releasing system reset mode by inputting "H" to the \overline{RESET} pin after selecting system reset mode by inputting "L" to the \overline{RESET} pin while $\overline{TST1}$ is in "H" level and $\overline{TST2}$ is in "L" level, the test mode is selected.

To return from test mode to normal mode, both $\overline{TST1}$ and $\overline{TST2}$ must be left open or in a state where "H" level is input. When both $\overline{TST1}$ and $\overline{TST2}$ are open, test mode is released. However, normal operation mode is not restored until the system reset is input.

Figure 15-1 shows the relationship among the $\overline{TST1}$, $\overline{TST2}$ pins and the \overline{RESET} pin.

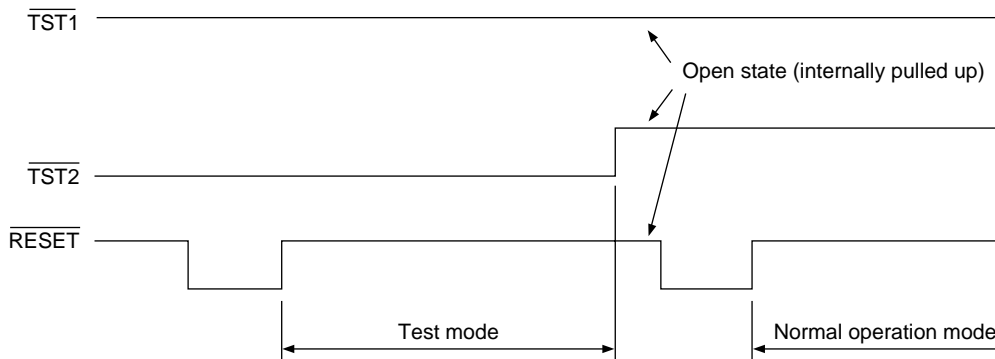


Figure 15-1 Relationship among the $\overline{TST1}$, $\overline{TST2}$ pins and the \overline{RESET} pin

Depending the state of Ports 0.0 to 0.3, various RC oscillation signals are output to Port 3.3 after switching to test mode.

Tables 15-1 and 15-2 show the list of test modes and test circuit -related pins. Figure 15-2 shows an example of connection in test mode.

Notes:

Please note that there is no guarantee of normal operation if both $\overline{TST1}$ and $\overline{TST2}$ are not simultaneously open or at "H" level or if $\overline{TST2}$ only is at "L" level.

Table 15-1 List of Test Modes

TST1	TST2	P0.3	P0.2	P0.1	P0.0	P3.3 output mode	
1	0	1	0	0	0	CROSC0 oscillation stop (P3.3 = IN0 input)	CROSC0 oscillation mode
1	0	1	0	0	1	RS0-CS0 oscillation clock	
1	0	1	0	1	0	RT0-CS0 oscillation clock	
1	0	1	0	1	1	RT0-1-CS0 oscillation clock	
1	0	1	1	0	0	CT0-1-RS0 oscillation clock	
1	0	1	1	0	1	RS1-CS1 oscillation clock	CROSC1 oscillation mode
1	0	1	1	1	0	RT1-CS1 oscillation clock	
1	0	1	1	1	1	CROSC1 oscillation stop (P3.3 = IN1 input)	
1	0	0	—	—	—	400 kHz RC oscillation clock output	

Notes: 0: "L" level input
1: "H" level input
—: Arbitrary

Table 15-2 Test Circuit-Related Pins

Pin name	Pin No.	Pad No.	Input/Output	Notes
TST1	80	64	Input	Test input
TST2	1	65	Input	Test input
RESET	79	63	Input	Reset input
P0.0	2	1	Input	Test mode selection
P0.1	3	2	Input	Test mode selection
P0.2	4	3	Input	Test mode selection
P0.3	5	4	Input	Test mode selection
P3.3	25	21	Output	RC oscillation clock monitor output

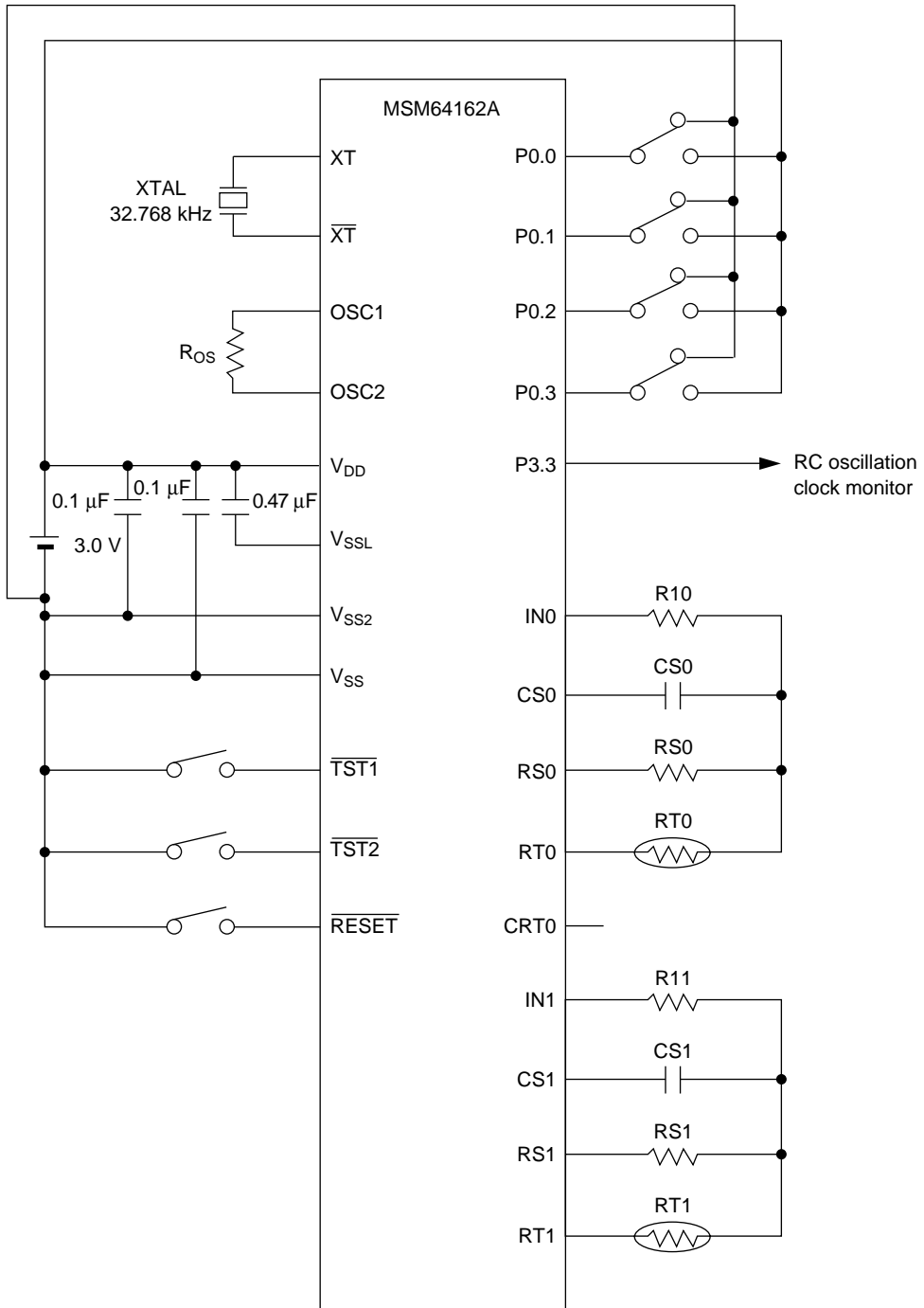


Figure 15-2 Connection Example of Test Mode (3.0 V operation mode)

Appendixes



Appendix A:

List of Special Function Registers

Register name	Symbol	Address	b3	b2	b1	b0	R/W	Byte access	Value at system reset
Port 2 register	P2	00H	P23	P22	P21	P20	R/W	Yes	0H
Port 3 register	P3	01H	P33	P32	P31	P30	R/W		0H
Port 0 register	P0	03H	P03	P02	P01	P00	R	No	Depends on input value
Port 1 register	P1	04H	P13	P12	P11	P10	R/W	No	0H
Frequency control register	FCON	09H	*—	*—	*—	CPUCLK	R/W	No	0EH
Buzzer driver control register	BDCON	0AH	SELF	EBD	BM1	BM0	R/W	Yes	0H
Buzzer frequency control register	BFCON	0BH	*—	*—	*—	BF	R/W		0EH
Capture register 0	CAPR0	0CH	32Hz	64Hz	128Hz	256Hz	R	Yes	0H
Capture register 1	CAPR1	0DH	32Hz	64Hz	128Hz	256Hz	R		0H
Capture control register	CAPCON	0EH	CRF1	CRF0	ECAP1	ECAP0	R/W	No	0H
Time base counter register	TBCR	0FH	1Hz	2Hz	4Hz	8Hz	R/W	No	0H
Port 20 control register	P20CON	10H	P20IE	P20F	P20DIR	P20MOD	W	Yes	0H
Port 21 control register	P21CON	11H	P21IE	P21F	P21DIR	P21MOD	W		0H
Port 22 control register	P22CON	12H	P22IE	P22F	P22DIR	P21MOD	W	Yes	0H
Port 23 control register	P23CON	13H	P23IE	P23F	P23DIR	P23MOD	W		0H

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Appendix A

Register name	Symbol	Address	b3	b2	b1	b0	R/W	Byte access	Value at system reset
Port 30 control register	P30CON	14H	P30IE	P30F	P30DIR	P30MOD	W	Yes	0H
Port 31 control register	P31CON	15H	P31IE	P31F	P31DIR	P31MOD	W		0H
Port 32 control register	P32CON	16H	P32IE	P32F	P32DIR	P32MOD	W	Yes	0H
Port 33 control register	P33CON	17H	P33IE	MON	P33DIR	P33MOD	W		0H
Port 01 control register	P01CON	1CH	*—	PUD	P1MOD	P0MOD	W	No	8H
Display control register	DSPCON	1EH	*—	*—	DUTY1	DUTY0	R/W	No	0CH
A/D converter counter A register 0	CNTA0	20H	a3	a2	a1	a0	R/W	Yes	0H
A/D converter counter A register 1	CNTA1	21H	a7	a6	a5	a4	R/W		0H
A/D converter counter A register 2	CNTA2	22H	a11	a10	a9	a8	R/W	Yes	0H
A/D converter counter A register 3	CNTA3	23H	a15	a14	a13	a12	R/W		0H
A/D converter counter A register 4	CNTA4	24H	*—	a18	a17	a16	R/W	No	8H
A/D converter counter B register 0	CNTB0	26H	b3	b2	b1	b0	R/W	Yes	0H
A/D converter counter B register 1	CNTB1	27H	b7	b6	b5	b4	R/W		0H
A/D converter counter B register 2	CNTB2	28H	b11	b10	b9	b8	R/W	Yes	0H

Register name	Symbol	Address	b3	b2	b1	b0	R/W	Byte access	Value at system reset
A/D converter counter B register 3	CNTB3	29H	*—	*—	b13	b12	R/W	Yes	0CH
A/D converter control register 0	ADCON0	2AH	*—	*—	SADI	EADC	R/W	Yes	0CH
A/D converter control register 1	ADCON1	2BH	OM3	OM2	OM1	OM0	R/W		0H
Interrupt enable register 0	IE0	30H	EAD	EXI1	*—	EXI0	R/W	Yes	2H
Interrupt enable register 1	IE1	31H	E1Hz	E16Hz	E32Hz	E256Hz	R/W		0H
Interrupt enable register 2	IE2	32H	*—	*—	*—	E4Hz	R/W	Yes	0EH
Interrupt request register 2	IRQ2	33H	*—	*—	QWDT	Q4Hz	R/W		0CH
Interrupt request register 0	IRQ0	34H	QAD	QXI1	*—	QXI0	R/W	Yes	2H
Interrupt request register 1	IRQ1	35H	Q1Hz	Q16Hz	Q32Hz	Q256Hz	R/W		0H
Watchdog timer control register	WDTCN	36H	d3	d2	d1	d0	W	No	0H
Backup control register	BUPCON	37H	*—	CMPP	ECMP	BUPF	R/W	No	08H
Display register 0	DSPR0	40H	d	c	b	a	R/W	Yes	0H
Display register 1	DSPR1	41H	d	c	b	a	R/W		0H
Display register 2	DSPR2	42H	d	c	b	a	R/W	Yes	0H
Display register 3	DSPR3	43H	d	c	b	a	R/W		0H
Display register 4	DSPR4	44H	d	c	b	a	R/W	Yes	0H
Display register 5	DSPR5	45H	d	c	b	a	R/W		0H
Display register 6	DSPR6	46H	d	c	b	a	R/W	Yes	0H
Display register 7	DSPR7	47H	d	c	b	a	R/W		0H
Display register 8	DSPR8	48H	d	c	b	a	R/W	Yes	0H
Display register 9	DSPR9	49H	d	c	b	a	R/W		0H
Display register 10	DSPR10	4AH	d	c	b	a	R/W	Yes	0H

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Appendix A

Register name	Symbol	Address	b3	b2	b1	b0	R/W	Byte access	Value at system reset
Display register 11	DSPR11	4BH	d	c	b	a	R/W	Yes	0H
Display register 12	DSPR12	4CH	d	c	b	a	R/W	Yes	0H
Display register 13	DSPR13	4DH	d	c	b	a	R/W		0H
Display register 14	DSPR14	4EH	d	c	b	a	R/W	Yes	0H
Display register 15	DSPR15	4FH	d	c	b	a	R/W		0H
Display register 16	DSPR16	50H	d	c	b	a	R/W	Yes	0H
Display register 17	DSPR17	51H	d	c	b	a	R/W		0H
Display register 18	DSPR18	52H	d	c	b	a	R/W	Yes	0H
Display register 19	DSPR19	53H	d	c	b	a	R/W		0H
Display register 20	DSPR 20	54H	d	c	b	a	R/W	No	0H
Master interrupt enable register	MIEF	7CH	*—	*—	*—	MI	R/W	No	0EH
Halt mode register	HALT	7DH	*—	*—	*—	HLT	R/W	No	0EH
Stack pointer	SP	7EH	SP3	SP2	SP1	*—	R/W	Yes	0FFH
		7FH	*—	SP6	SP5	SP4			

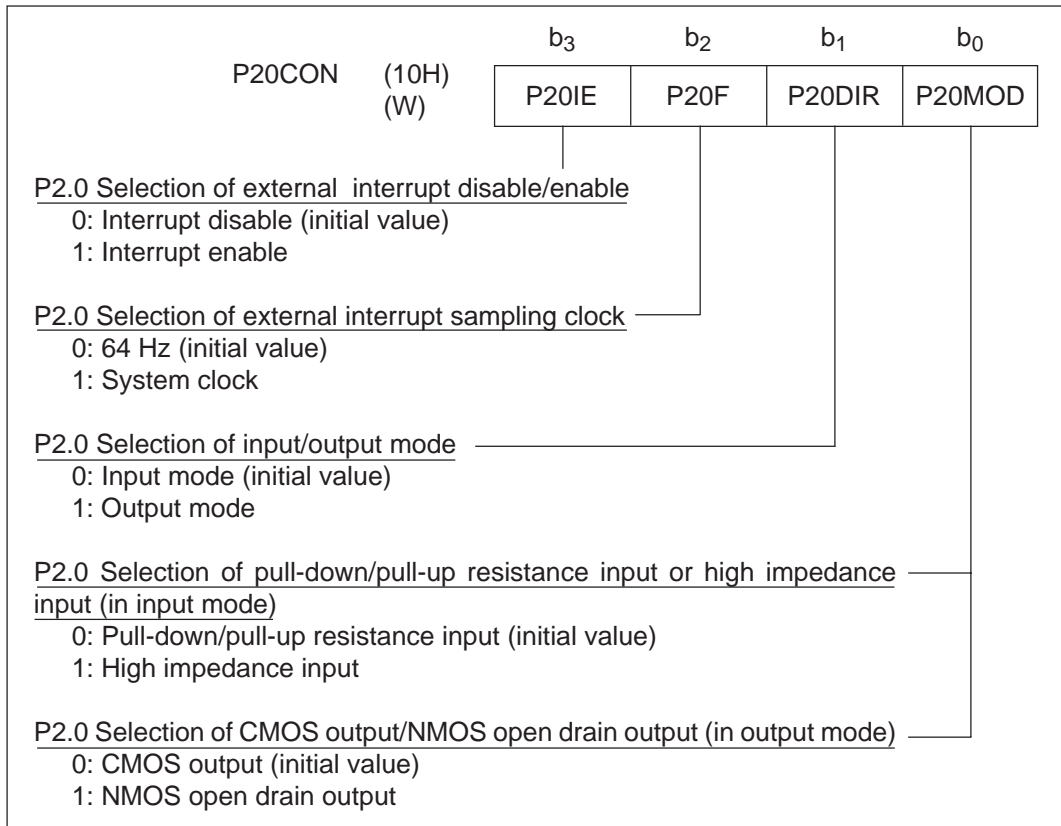
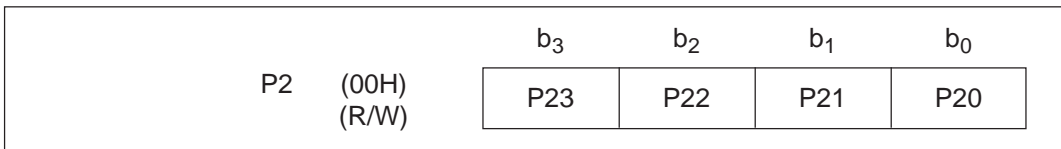
Notes:

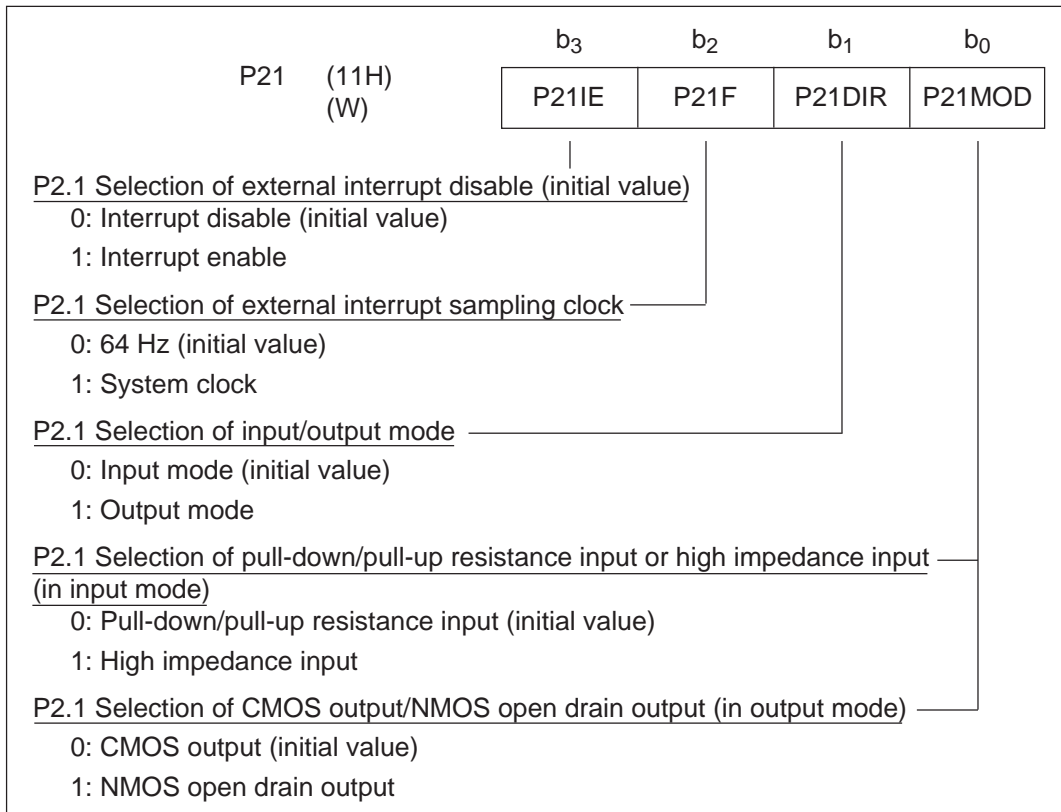
- (1) Only byte access is possible for the Stack pointer.
- (2) "*—" in the table is a reserved bit. "1" is always read out. Not valid for write.
- (3) The display registers 0 through 20 are registers that can not be used without selection by mask option.
 All the display registers to be used must be allocated on the LCD driver mask option table per bit. (Refer to Appendix F on the mask options.)

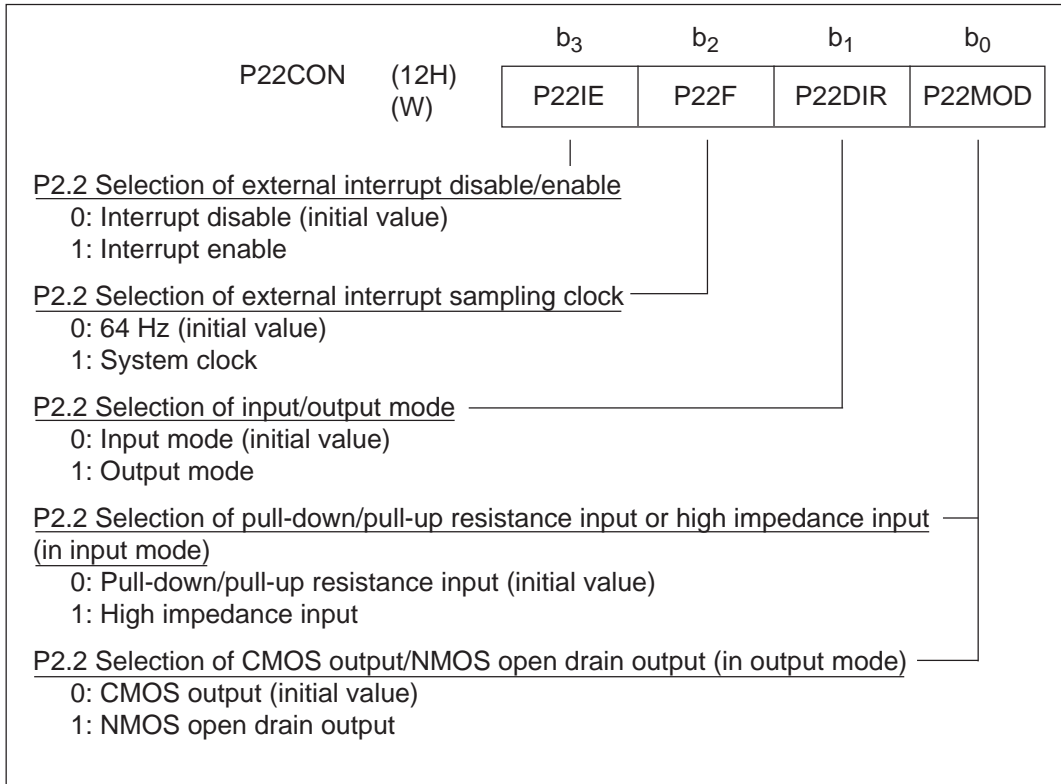
Appendix B:

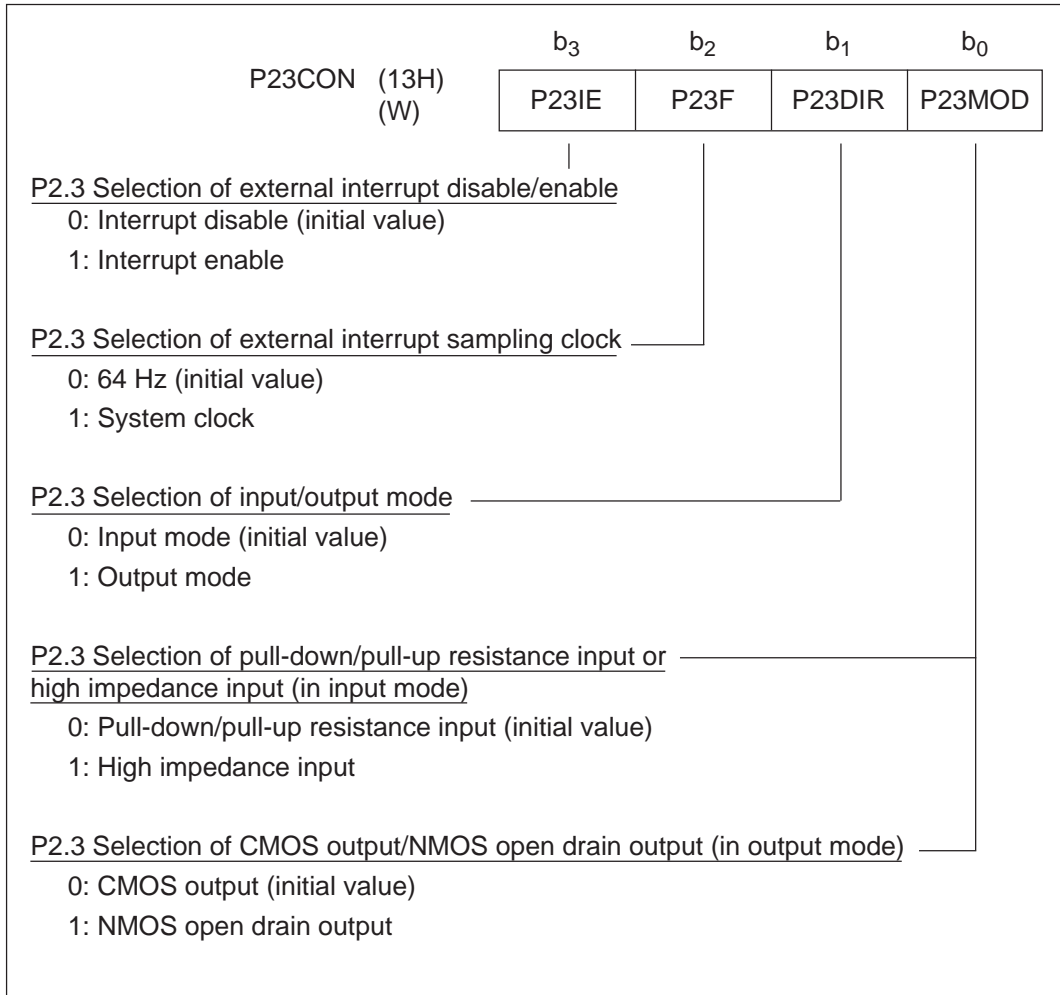
Description of Special Function Registers

Register name	Symbol	Address	Read/Write	Value at system reset
Port 2 register	P2	00H	R/W	0H
Port 20 control register	P20CON	10H	W	0H
Port 21 control register	P21CON	11H	W	0H
Port 22 control register	P22CON	12H	W	0H
Port 23 control register	P23CON	13H	W	0H



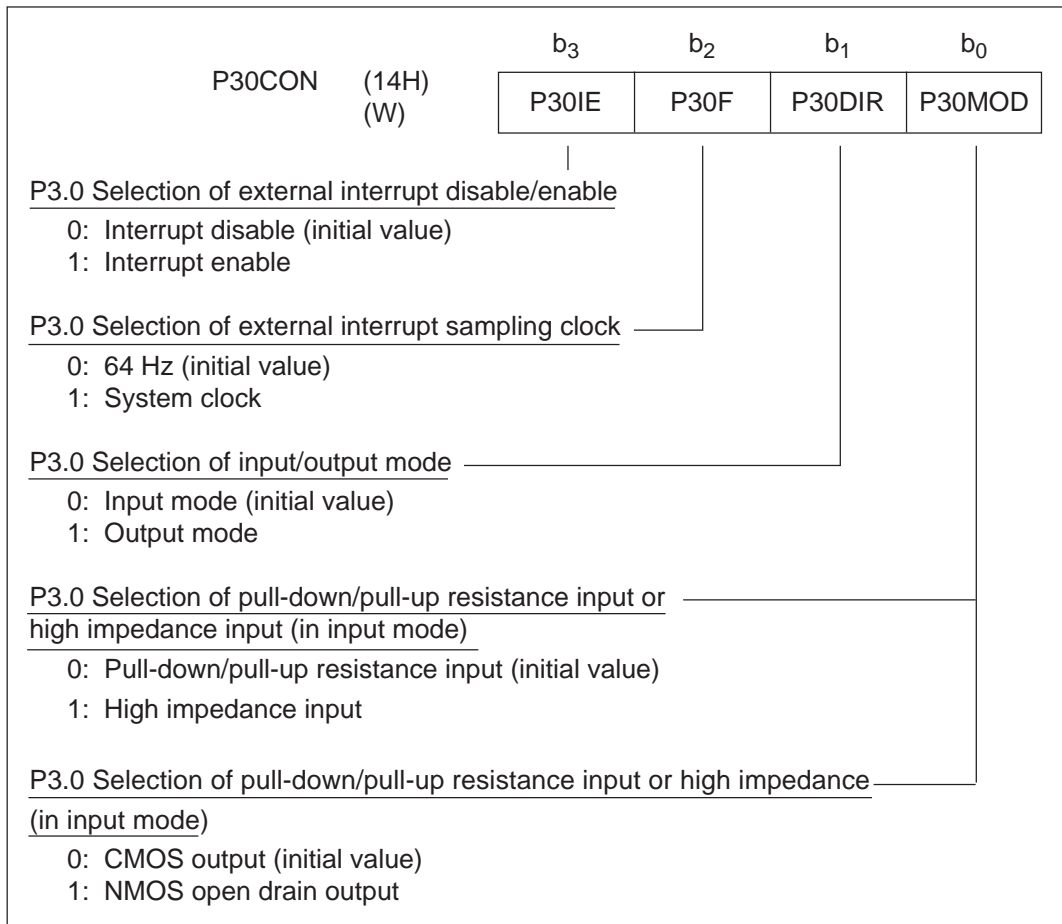
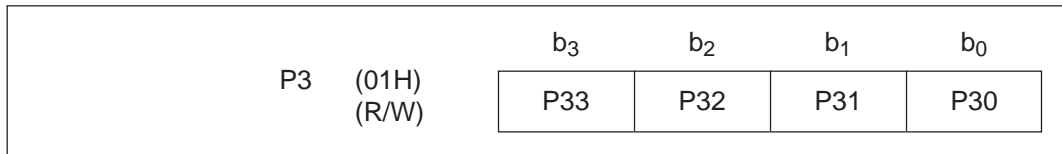


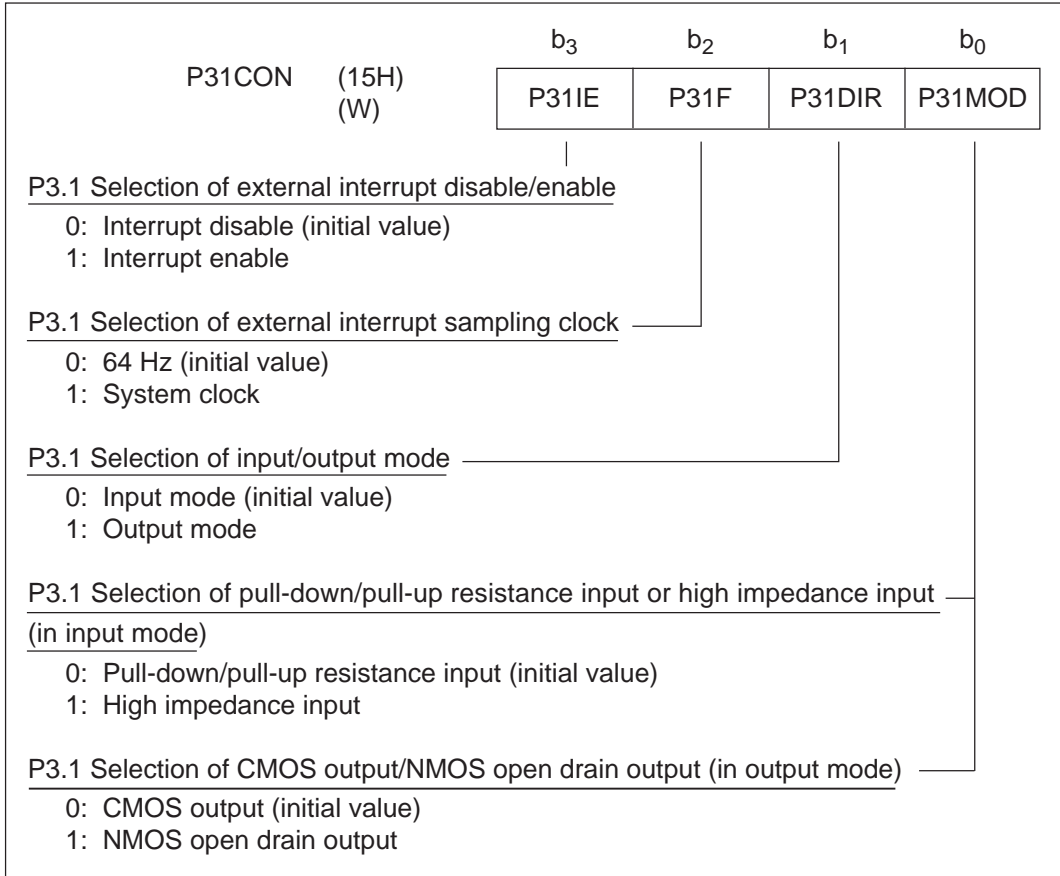


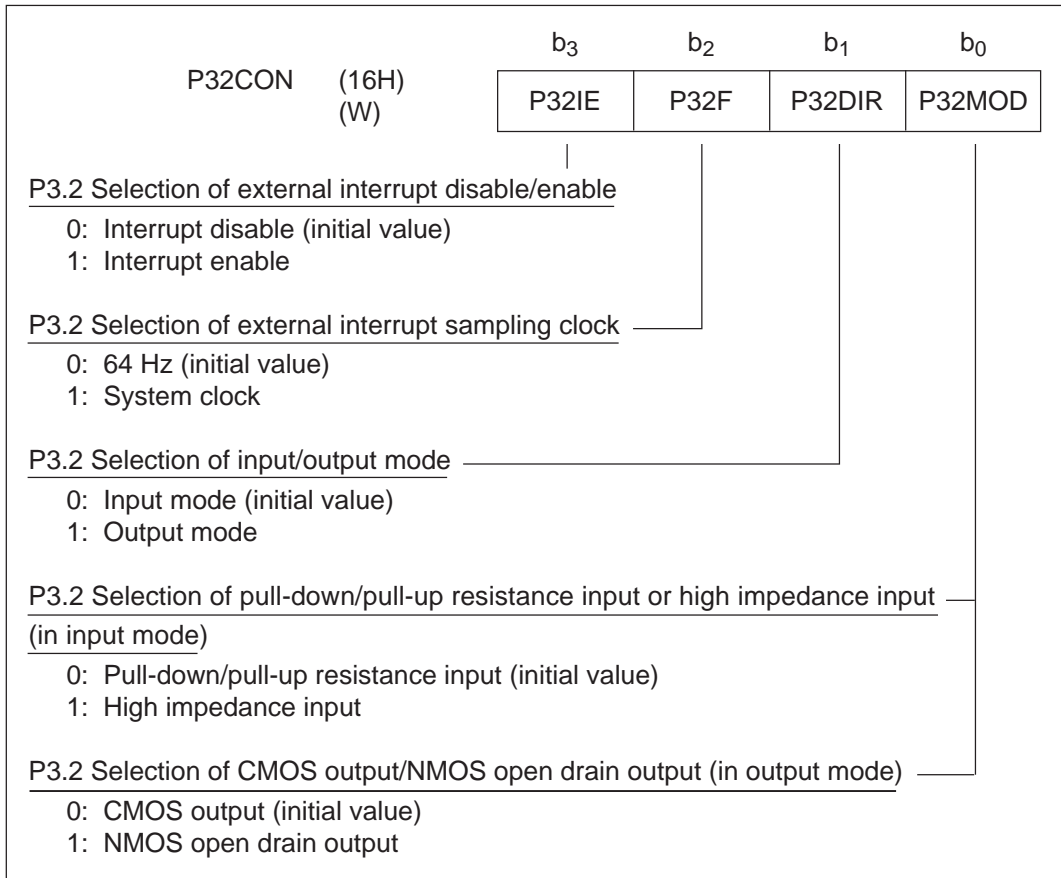


Description
<p>The Port 2 register (P2) is a data register to output data to Port 2. When P2 is read out while Bit 1 (each DIR bit) of P20CON to P23CON is reset to "0" in input mode, the pin level of each bit is read out for those bits where input mode is selected.</p> <p>The Port 20 to 23 control registers (P20CON, P21CON, P22CON and P23CON) perform selection of input/output mode, selection of pull-down/pull-up resistance input/high-impedance input in input mode, selection of CMOS/NMOS open drain output in output mode, selection of sampling clocks when used as external interrupt input and selection of external interrupt enable/disable from Port 2. Selection of pull-down/pull-up resistance input is performed by Bit 2 (PUD) of the Port 01 control register (P01CON).</p>

Register name	Symbol	Address	Read/Write	Value at system reset
Port 3 register	P3	01H	R/W	0H
Port 30 control register	P30CON	14H	W	0H
Port 31 control register	P31CON	15H	W	0H
Port 32 control register	P32CON	16H	W	0H
Port 33 control register	P33CON	17H	W	0H



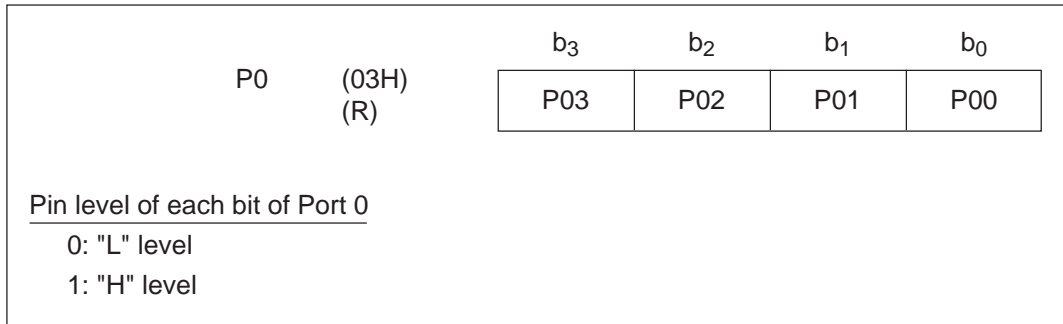




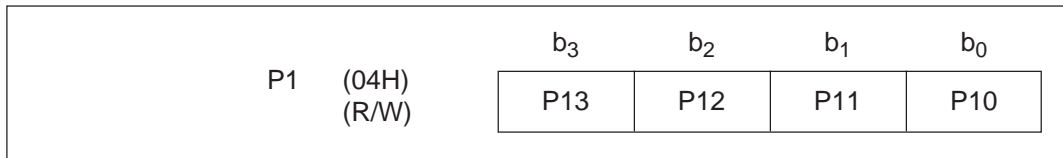
P33CON (17H) (W)		b ₃	b ₂	b ₁	b ₀
		P33IE	MON	P33DIR	P33MOD
<u>P3.3 Selection of external interrupt disable/enable</u>					
0: Interrupt disable (initial value)					
1: Interrupt enable					
<u>P3.3 Switching of /MON pin function</u>					
0: Input/output port function (initial value)					
1: RC oscillation clock monitor output					
<u>P3.3 Selection of input/output mode</u>					
0: Input mode (initial value)					
1: Output mode					
<u>P3.3 Selection of pull-down/pull-up resistance input or high impedance input (in input mode)</u>					
0: Pull-down/pull-up resistance input (initial value)					
1: High impedance input					
<u>P3.3 Selection of CMOS output/NMOS open drain output (in output mode)</u>					
0: CMOS output (initial value)					
1: NMOS open drain output					

Description
<p>The Port 3 register (P3) is a data register to output data to Port 3. When P3 is read out while Bit 1 (each DIR bit) of P30CON to P33CON is reset to "0" in input mode, the pin level of each bit is read out for those bits where input mode is selected.</p> <p>The Port 30 to 33 control registers (P30CON, P31CON, P32CON and P33CON) perform selection of input/output mode, selection of pull-down/pull-up resistance input/high-impedance input in input mode, selection of CMOS/NMOS open drain output in output mode, selection of sampling clocks when used as external interrupt input and selection of external interrupt enable/disable from Port 3. There is no selection function of sampling clocks for P3.3. Selection of pull-down/pull-up resistance input is performed by Bit 2 (PUD) of the Port 01 control register (P01CON).</p>

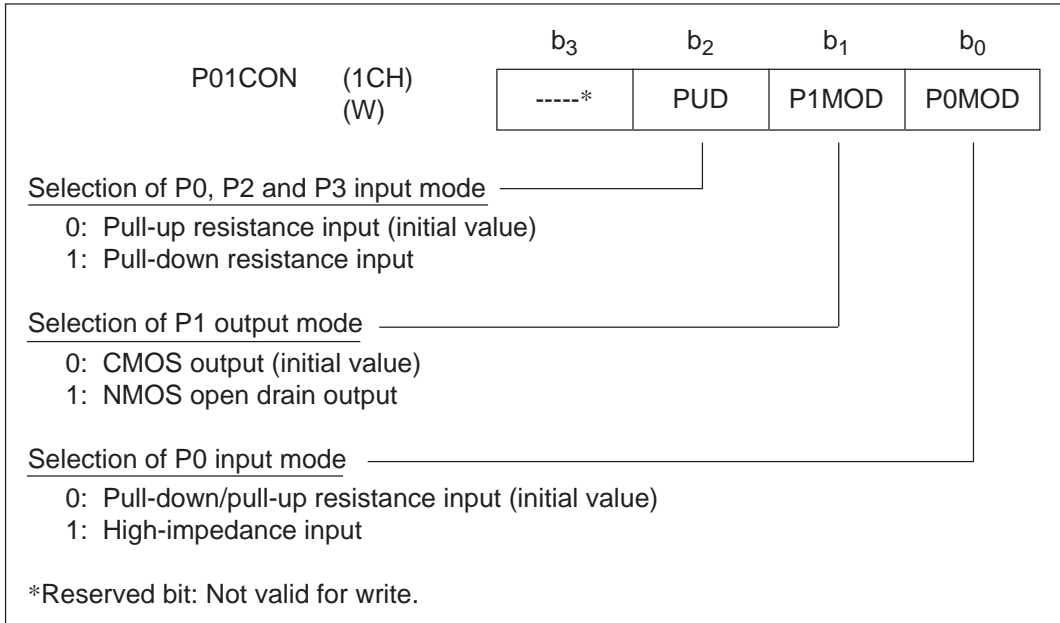
Register name	Symbol	Address	Read/Write	Value at system reset
Port 0 register	P0	03H	R	Depends on input value
Port 1 register	P1	04H	R/W	0H
Port 01 control register	P01CON	1CH	W	8H



Description	The Port 0 register (P0) is a read-only port and each pin level of Port 0 is read out.
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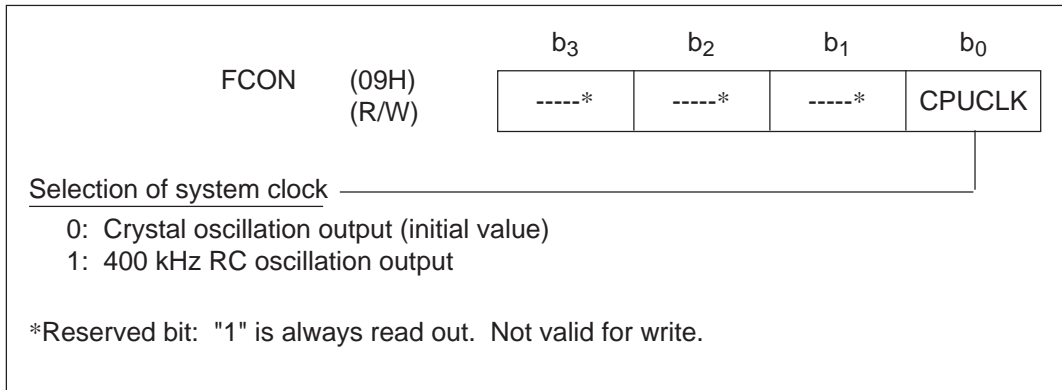


Description	The Port 1 register (P1) is a data register to output data to Port 1.
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Description
<p>Bit 2 (PUD) of the Port 01 control register (P01CON) selects pull-down resistance input or pull-up resistance input when pull-down/pull-up resistance input is selected at P0, P2 and P3.</p> <p>Bit 1 (P1MOD) of P01CON is to select CMOS output or NMOS open drain output of Port 1.</p> <p>Bit 0 (P0MOD) of P01CON selects pull-down/pull-up resistance input or high impedance input of Port 0.</p>

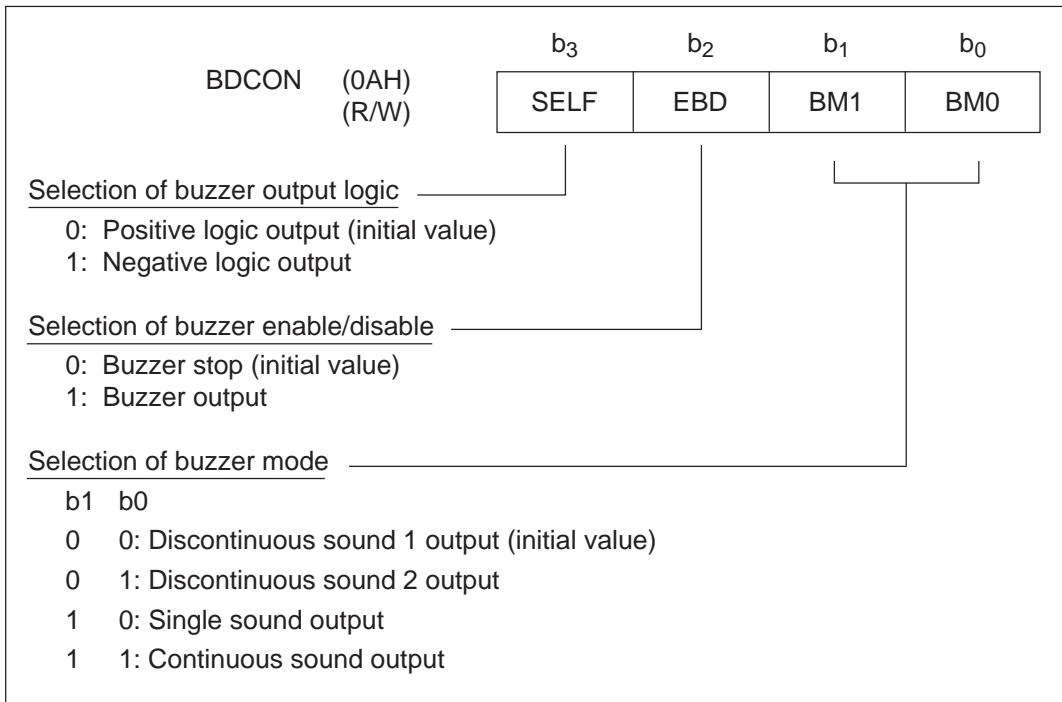
Register name	Symbol	Address	Read/Write	Value at system reset
Frequency control register	FCON	09H	R/W	0EH

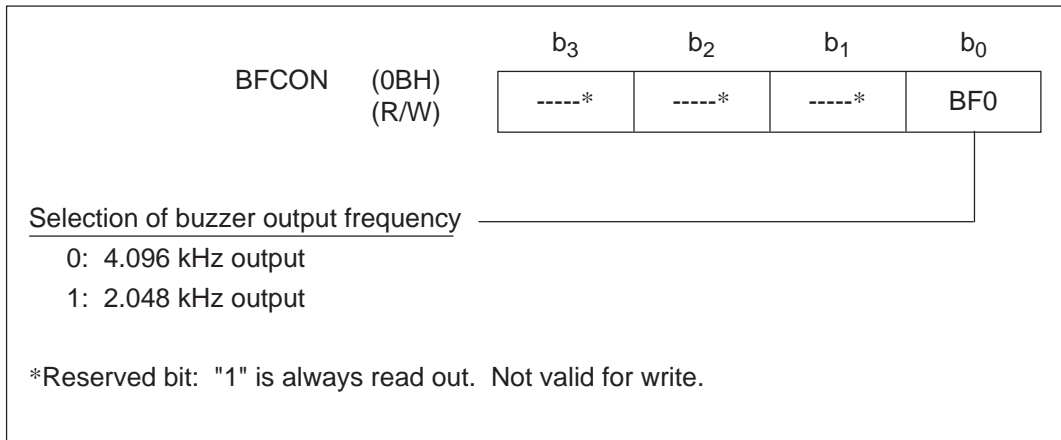


Description

The Frequency control register (FCON) selects system clocks. When reset to "0", the crystal oscillation output (32.768 kHz) is selected and when set to "1", the RC oscillation output is selected.

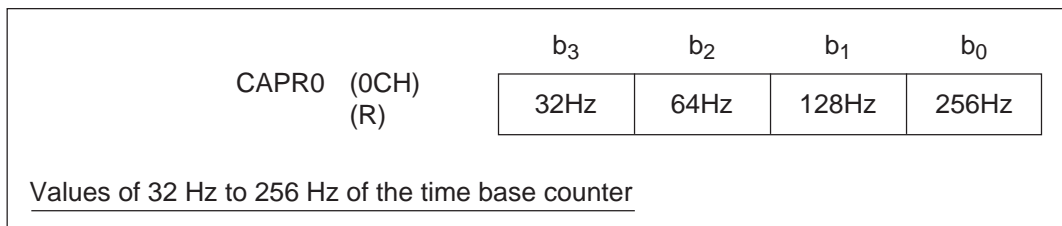
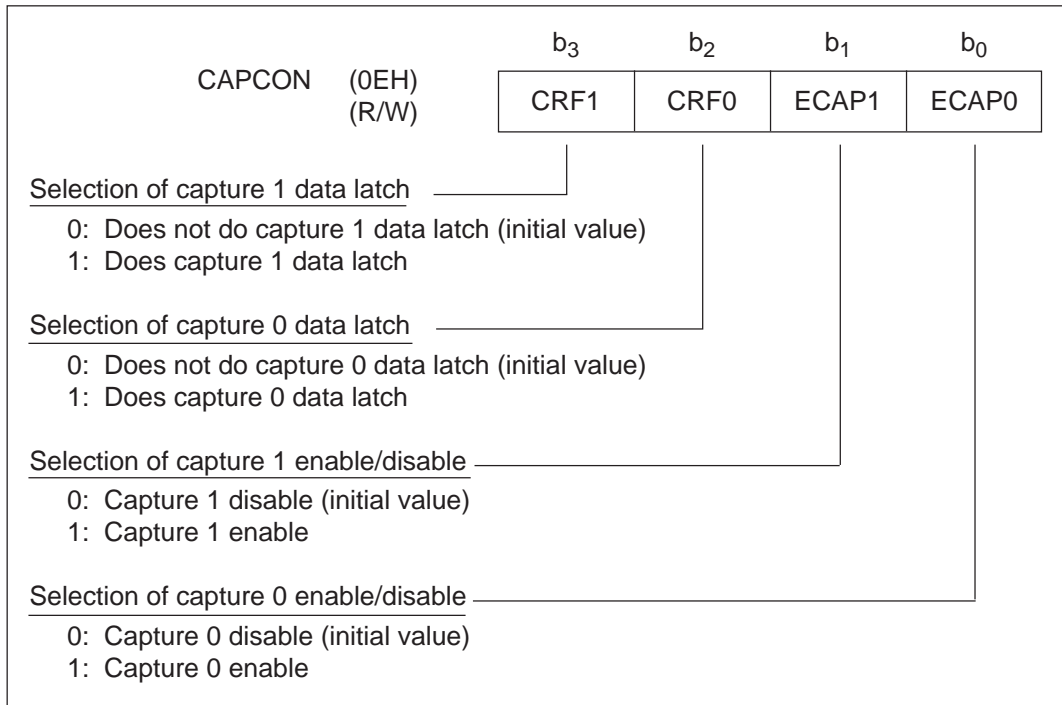
Register name	Symbol	Address	Read/Write	Value at system reset
Buzzer driver control register	BDCON	0AH	R/W	0H
Buzzer frequency control register	BFCON	0BH	R/W	0EH





Description	<p>The Buzzer driver control register (BDCON) is a register to select buzzer output logic, buzzer output enable/disable and buzzer sound mode.</p> <p>The Buzzer frequency control register (BFCON) is a register to select output frequencies of buzzer.</p>
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Register name	Symbol	Address	Read/Write	Value at system reset
Capture control register	CAPCON	0EH	R/W	0H
Capture register 0	CAPR0	0CH	R	0H
Capture register 1	CAPR1	0DH	R	0H



CAPR1 (0DH) (R)	b ₃	b ₂	b ₁	b ₀
	32Hz	64Hz	128Hz	256Hz
<u>Values of 32 Hz to 256 Hz of the time base counter</u>				

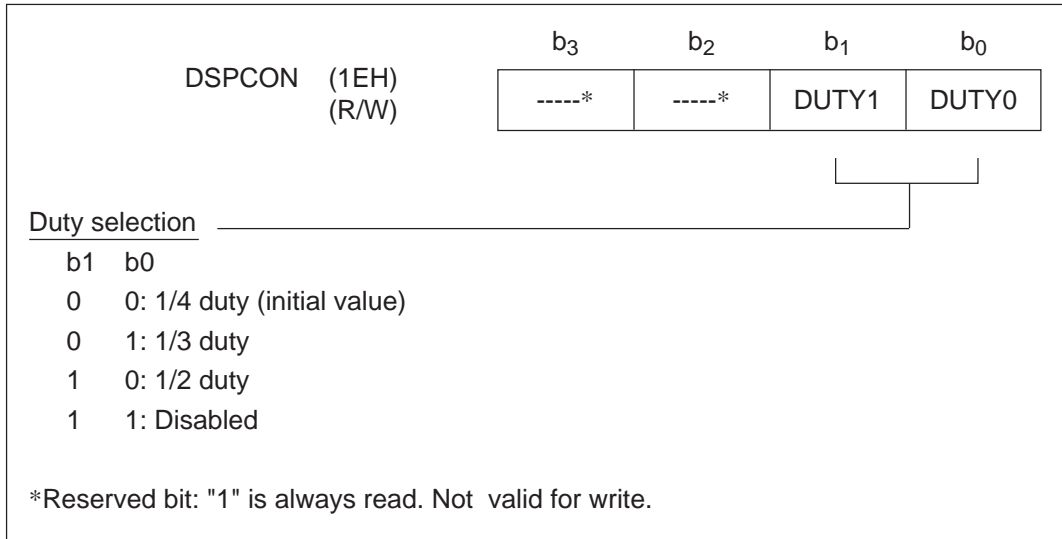
Description	<p>The Capture control register (CAPCON) selects latch and enable/disable of time base counter output data (32 to 256 Hz) of Capture 0 and Capture 1.</p> <p>The capture register 0 (CAPR0) and the capture register 1 (CAPR1) read time base counter output latch data of Capture 0 and Capture 1.</p>
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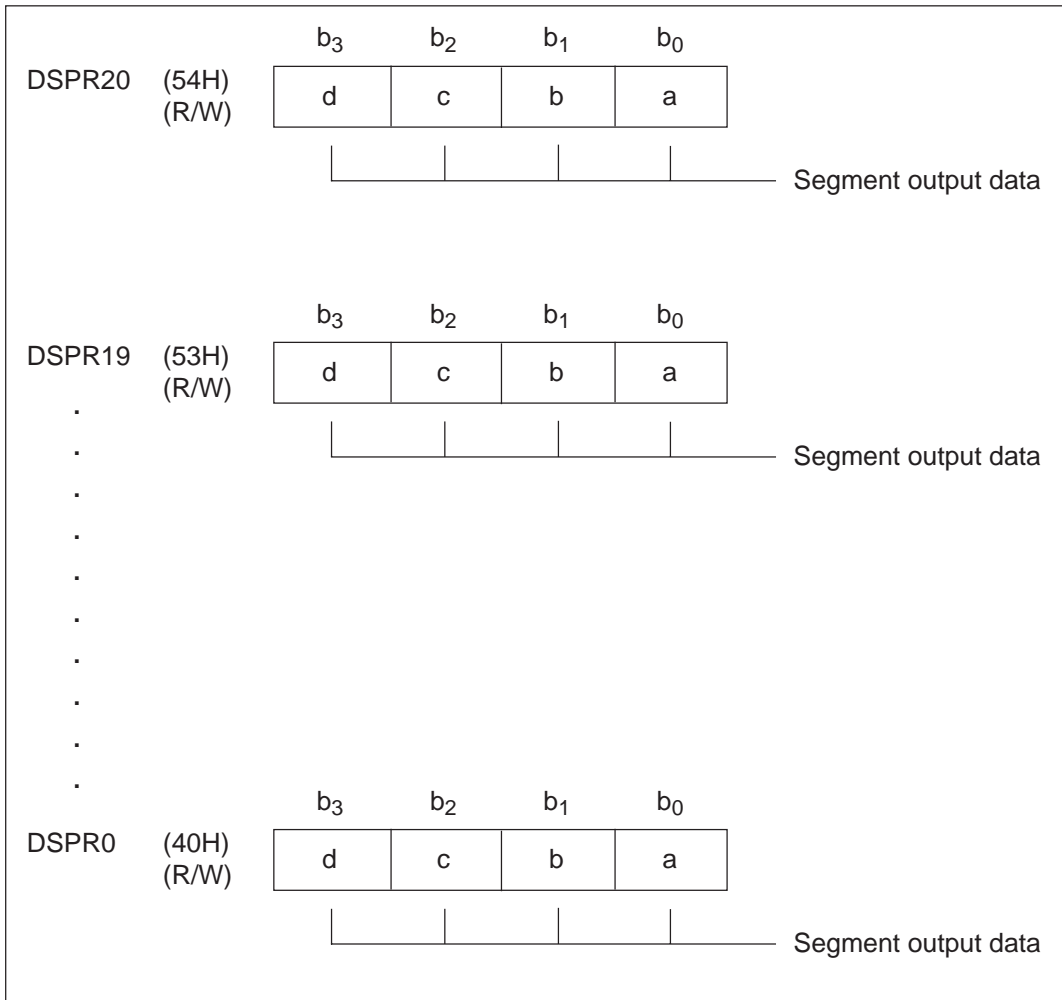
Register name	Symbol	Address	Read/Write	Value at system reset
Time base counter register	TBCR	0FH	R/W	0H

TBCR (0FH) (R/W)	b ₃	b ₂	b ₁	b ₀
	1Hz	2Hz	4Hz	8Hz
<u>Values of 1 Hz to 8 Hz of the time base counter</u>				

Description	<p>The Time base counter register (TBCR) outputs the contents of the time base counter when reading. When writing, 8 Hz, 4 Hz, 2 Hz and 1 Hz outputs of the time base counter are reset to "0".</p>
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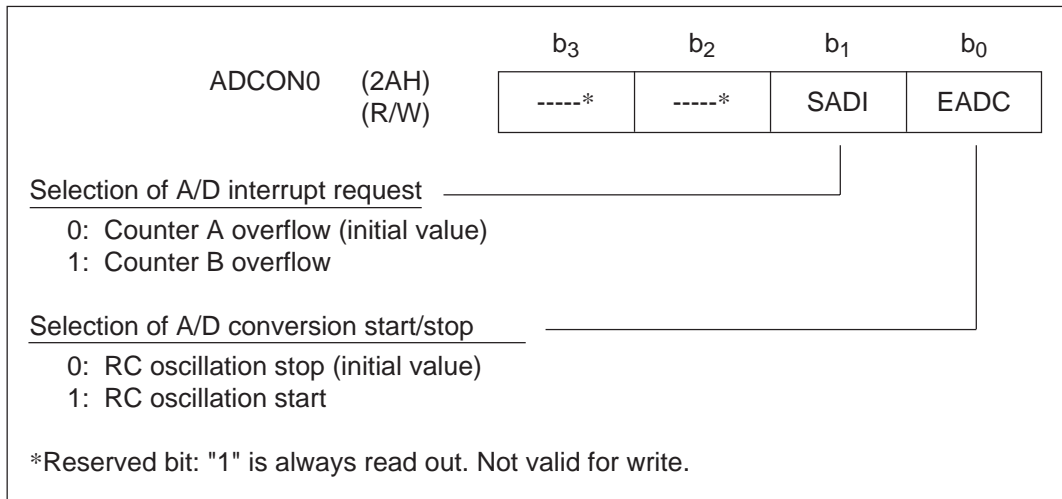
Register name	Symbol	Address	Read/Write	Value at system reset
Display control register	DSPCON	1EH	R/W	0CH
Display registers 0 to 20	DSPR0 to DSPR20	40H to 54H	R/W	0H

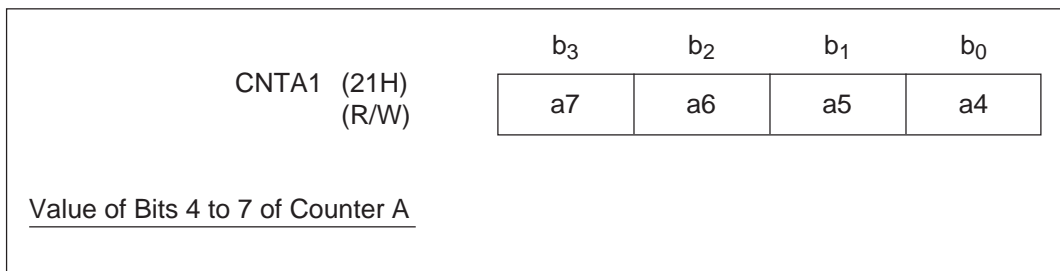
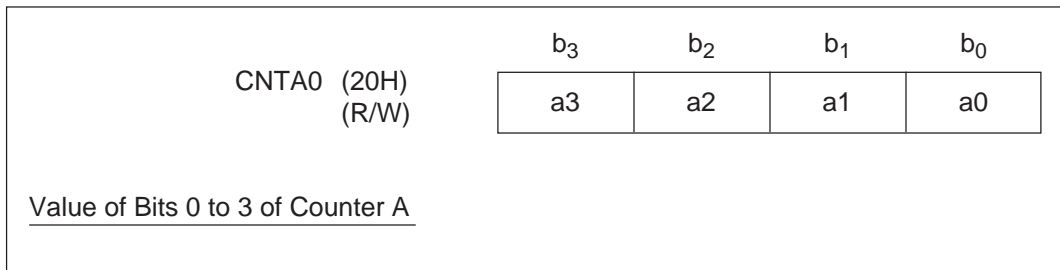
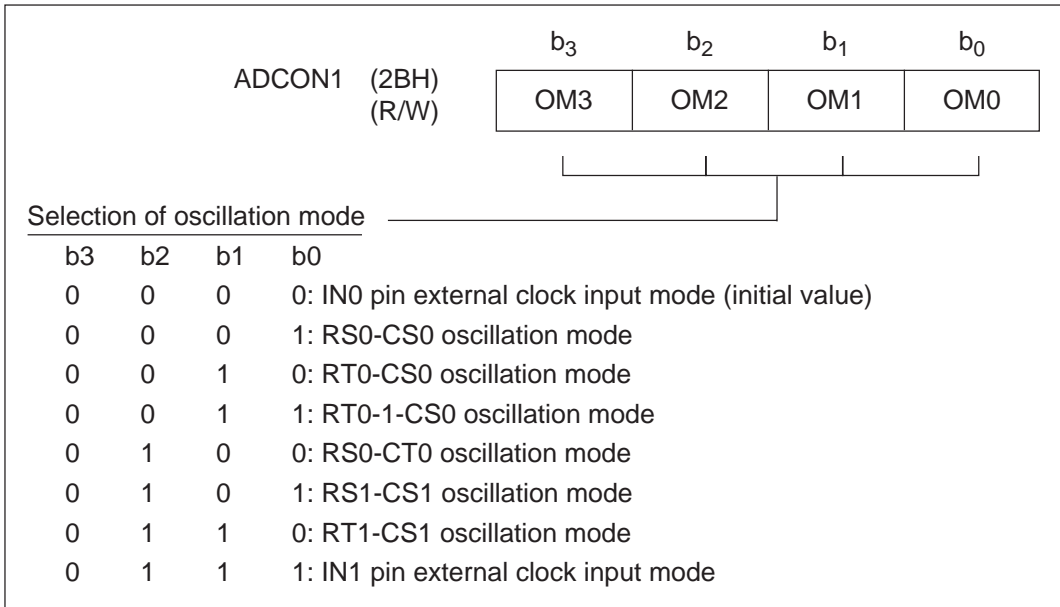




Description
<p>The Display control register (DSPCON) is a register to select duty of the LCD driver.</p> <p>The Display registers (DSPR0 to 20) are data registers for segment output of the LCD driver and can output data to each LCD driver by specifying the mask option of the LCD part.</p>

Register name	Symbol	Address	Read/Write	Value at system reset
A/D converter control register 0	ADCON0	2AH	R/W	0CH
A/D converter control register 1	ADCON1	2BH	R/W	0H
A/D converter counter A register 0	CNTA0	20H	R/W	0H
A/D converter counter A register 1	CNTA1	21H	R/W	0H
A/D converter counter A register 2	CNTA2	22H	R/W	0H
A/D converter counter A register 3	CNTA3	23H	R/W	0H
A/D converter counter A register 4	CNTA4	24H	R/W	8H
A/D converter counter B register 0	CNTB0	26H	R/W	0H
A/D converter counter B register 1	CNTB1	27H	R/W	0H
A/D converter counter B register 2	CNTB2	28H	R/W	0H
A/D converter counter B register 3	CNTB3	29H	R/W	0CH



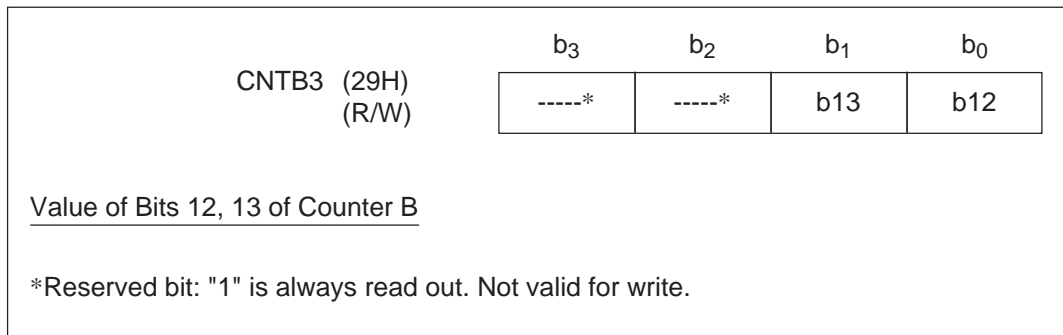
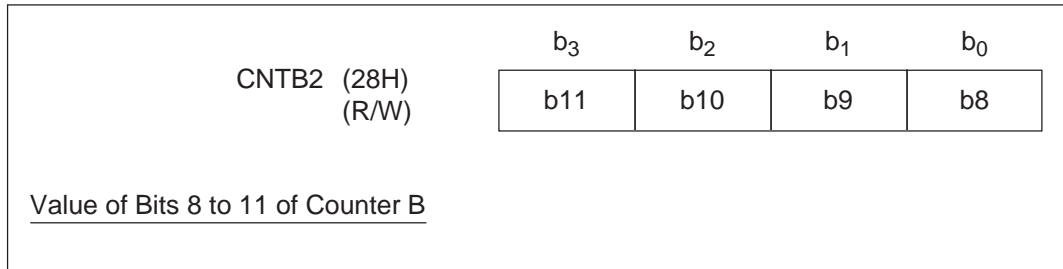
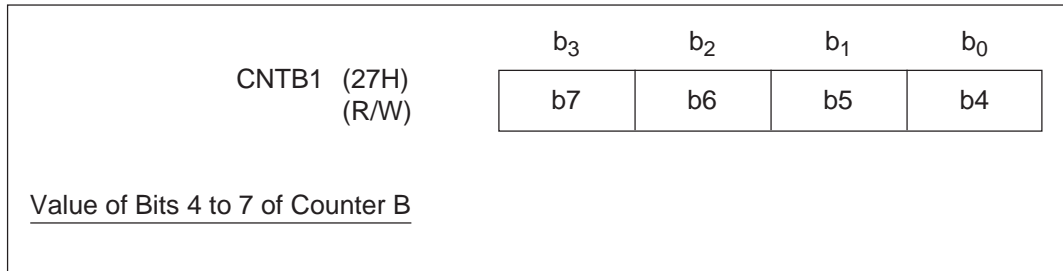


CNTA2 (22H) (R/W)	b ₃	b ₂	b ₁	b ₀
	a11	a10	a9	a8
<u>Value of Bits 8 to 11 of Counter A</u>				

CNTA3 (23H) (R/W)	b ₃	b ₂	b ₁	b ₀
	a15	a14	a13	a12
<u>Value of Bits 12 to 15 of Counter A</u>				

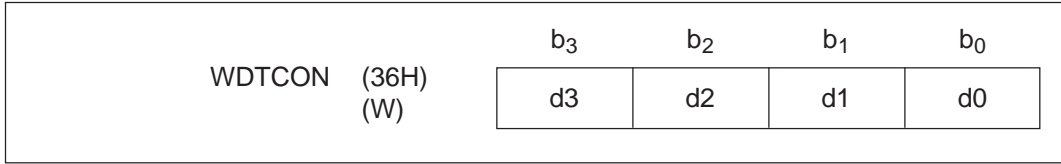
CNTA4 (24H) (R/W)	b ₃	b ₂	b ₁	b ₀
	-----*	a18	a17	a16
<u>Value of Bits 16 to 18 of Counter A</u>				
*Reserved bit: "1" is always read out. Not valid for write.				

CNTB0 (26H) (R/W)	b ₃	b ₂	b ₁	b ₀
	b3	b2	b1	b0
<u>Value of Bits 0 to 3 of Counter B</u>				



Description	<p>The A/D converter control register 0 (ADCON0) selects interrupt by overflow of either Counter A or Counter B and to select operation or stop of A/D conversion. The A/D converter control register 1 (ADCON1) is a register to select various RC oscillation modes. The A/D converter counter A registers 0 to 4 (CNTA0 to 4) are registers to read/write the contents of Counter A. The A/D converter counter B registers 0 to 3 (CNTB0 to 3) are registers to read/write the contents of Counter B.</p>
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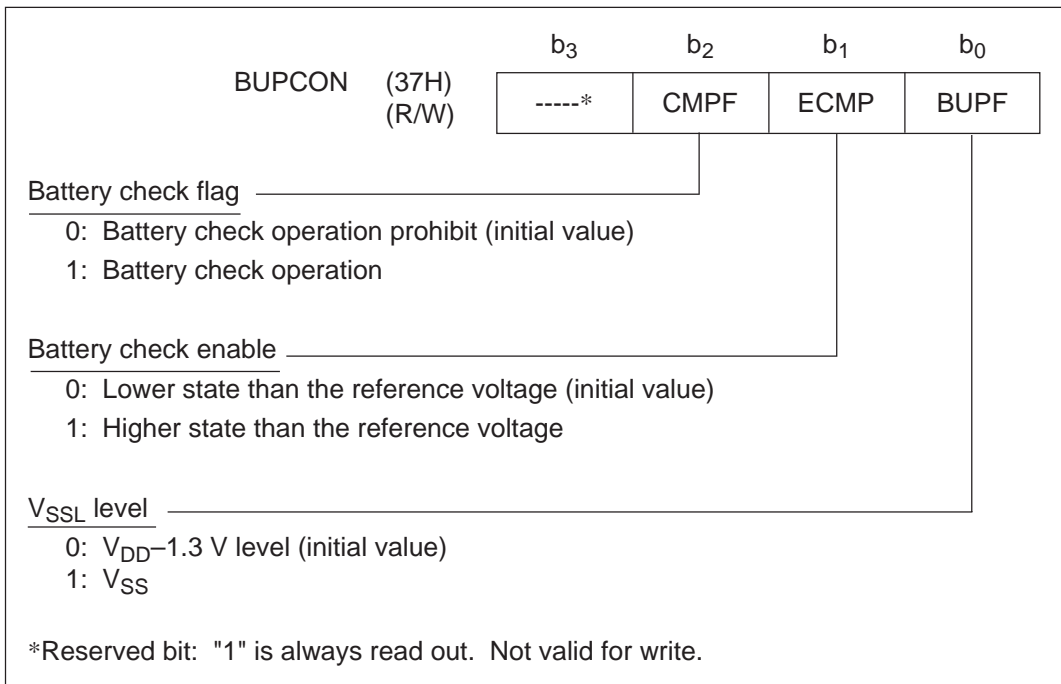
Register name	Symbol	Address	Read/Write	Value at system reset
Watchdog timer control register	WDTCON	36H	W	0H



Description

The Watchdog timer control register (WDTCON) is a register to reset the watchdog timer. WDTCON is a write-only register.

Register name	Symbol	Address	Read/Write	Value at system reset
Backup control register	BUPCON	37H	R/W	0EH

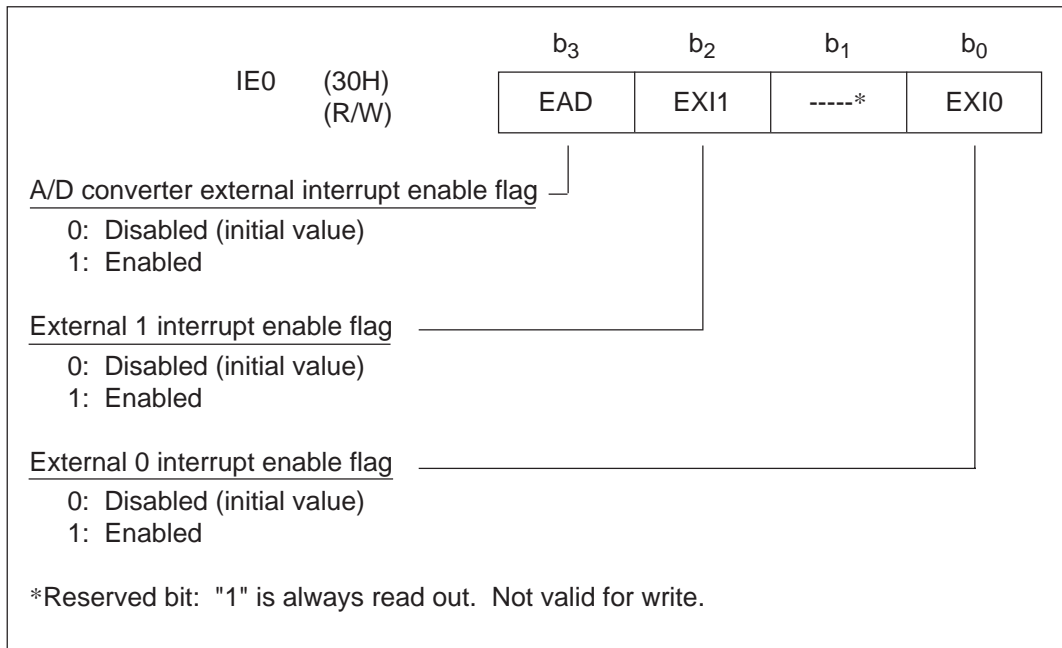


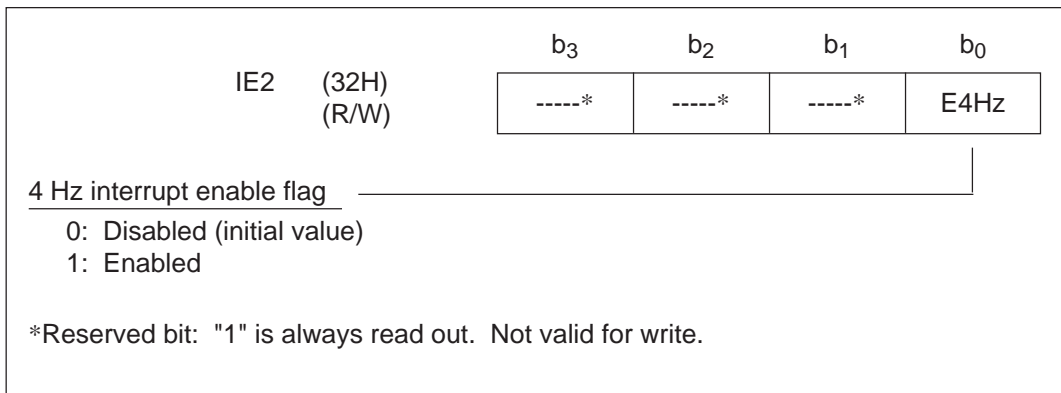
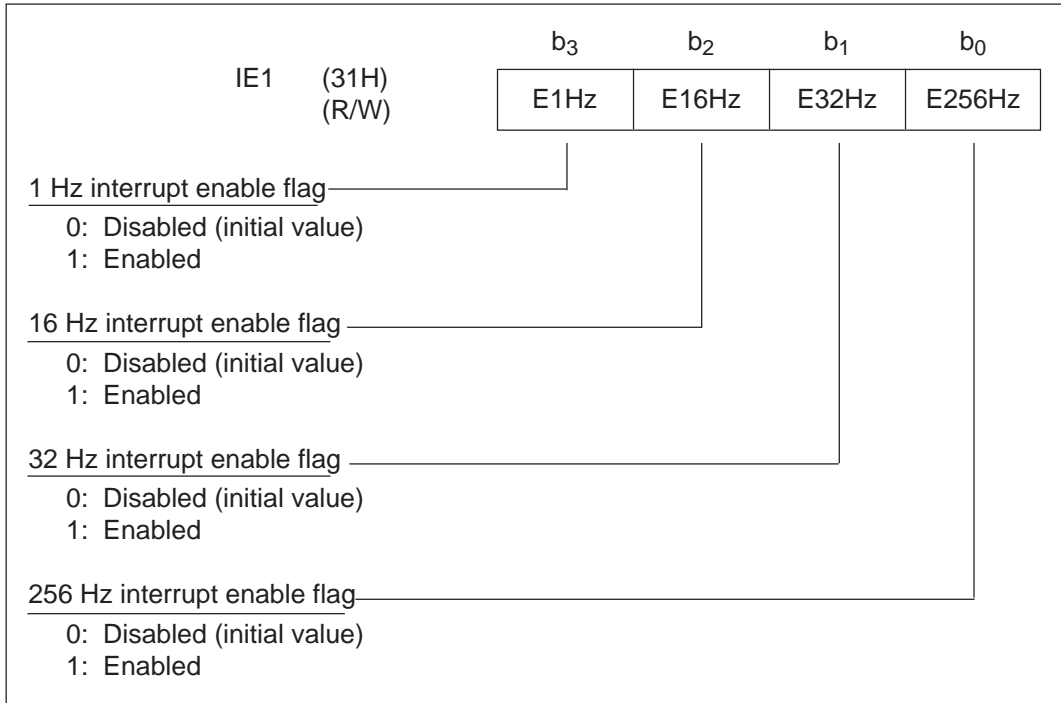
Description

The Backup control register is a register to control the voltage level of V_{SSL} or the battery check circuit.

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Appendix B

Register name	Symbol	Address	Read/Write	Value at system reset
Interrupt enable register 0	IE0	30H	R/W	2H
Interrupt enable register 1	IE1	31H	R/W	0H
Interrupt enable register 2	IE2	32H	R/W	0EH

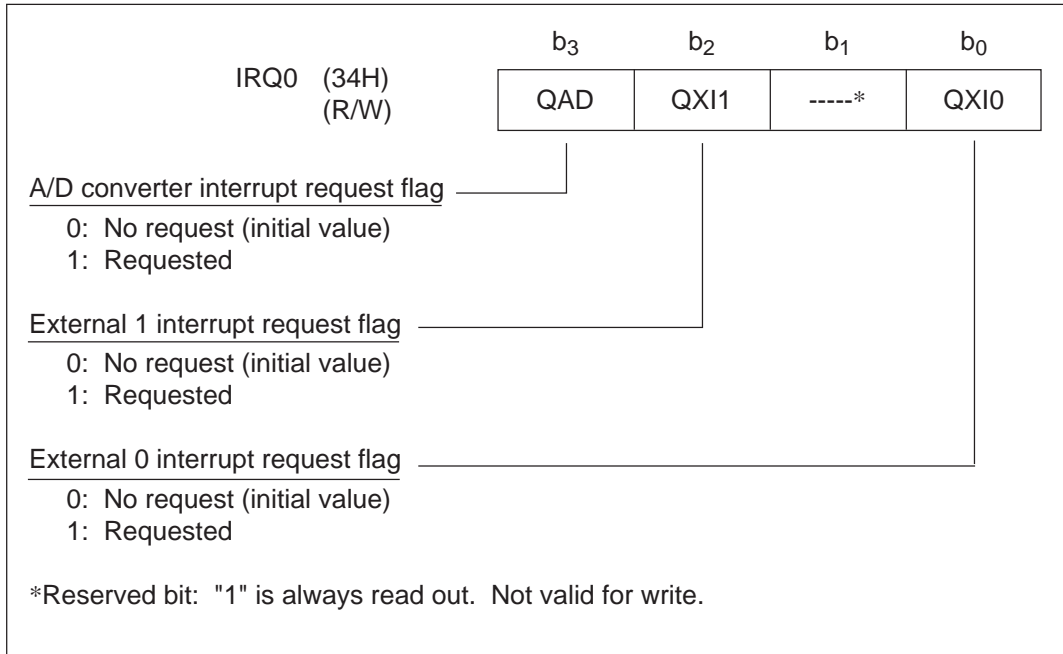


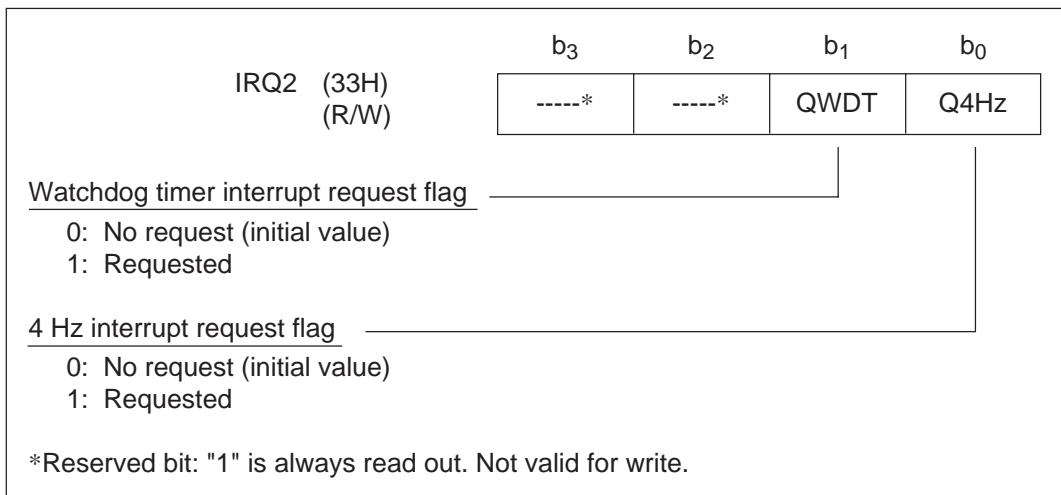
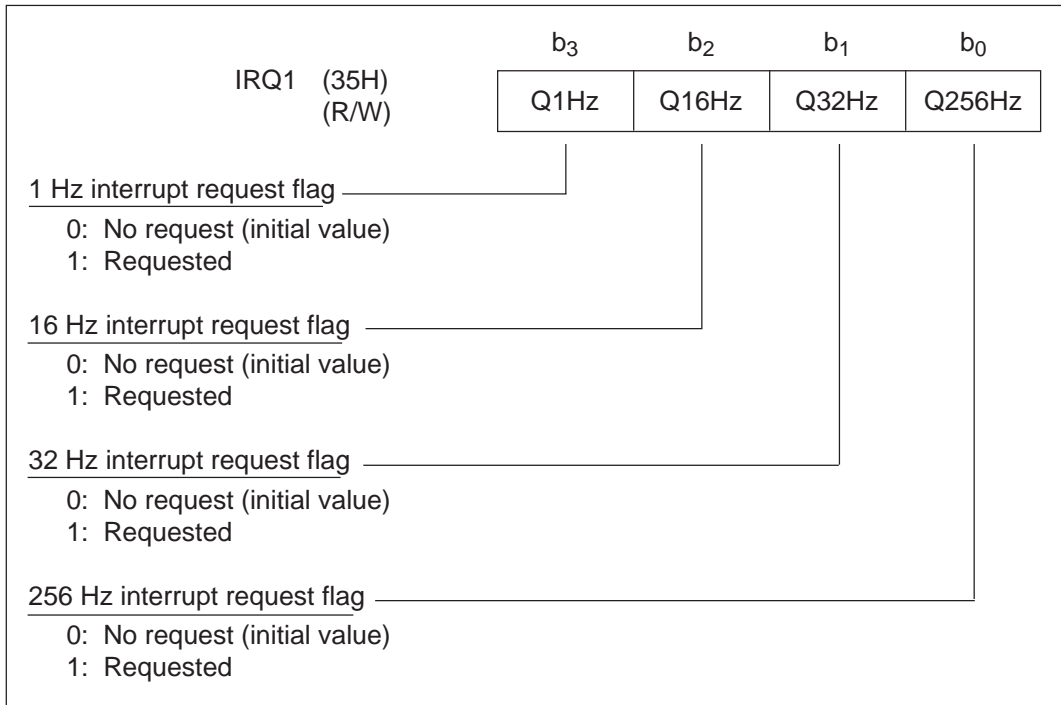


Description	These are registers to set disable/enable of each interrupt.
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Appendix B

Register name	Symbol	Address	Read/Write	Value at system reset
Interrupt request register 0	IRQ0	34H	R/W	2H
Interrupt request register 1	IRQ1	35H	R/W	0H
Interrupt request register 2	IRQ2	33H	R/W	0CH

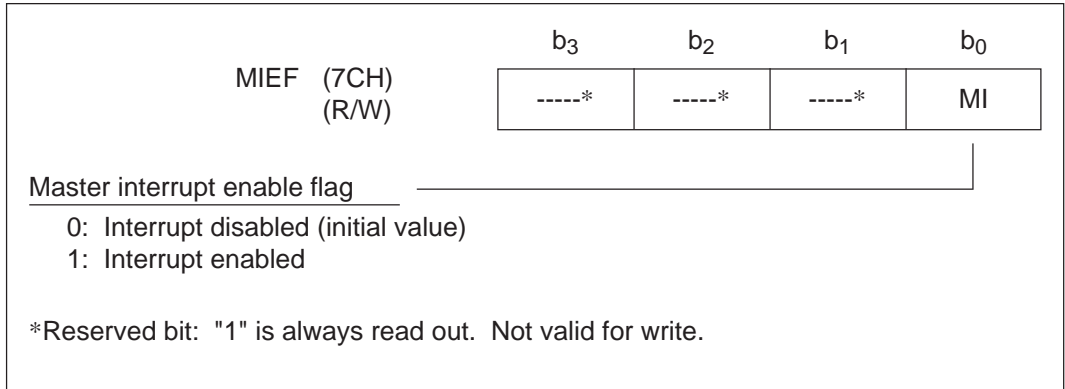




Description	<p>These bits are set by each interrupt request. When interrupt is enabled by (IE0, IE1 and IE2), the CPU receives interrupts only when the master interrupt enable flag (MI) is set to "1" and the execution is advanced to the vector address of each interrupt. The watchdog timer interrupt does not have interrupt mask functions by the IE register and the MI flag.</p>
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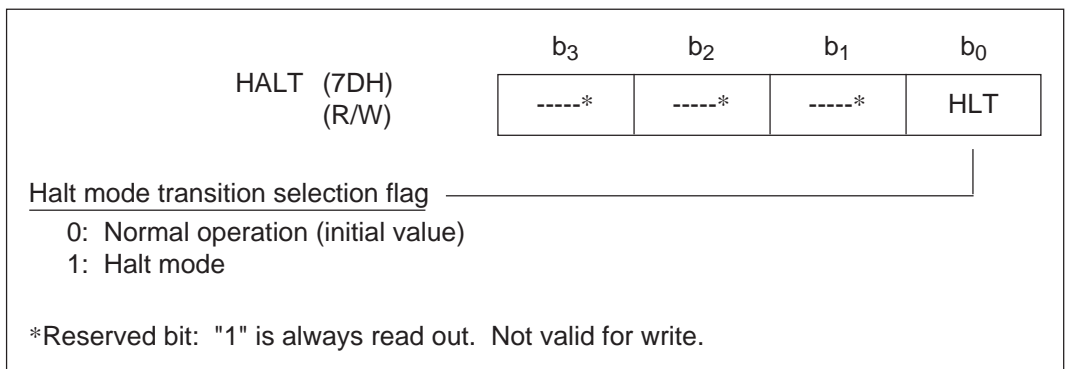
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Register name	Symbol	Address	Read/Write	Value at system reset
Master interrupt enable register	MIEF	7CH	R/W	0EH



Description	When MI is set to "1", interrupt is enabled and interrupts by the interrupt enable registers (IE0, IE1 and IE2) and the interrupt request registers (IRQ0, IRQ1 and IRQ2) are received by the CPU.
--------------------	--

Register name	Symbol	Address	Read/Write	Value at system reset
Halt mode register	HALT	7DH	R/W	0EH



Description	A flag to enter halt mode. When the HLT flag is set to "1", the CPU enters halt mode at the first machine cycle of the next instruction.
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Register name	Symbol	Address	Read/Write	Value at system reset
Stack pointer	SP	7EH	R/W	0FFH

		b ₇	b ₆	b ₅	b ₄	b ₃	b ₂	b ₁	b ₀
SP	(7EH) (R/W)	----*	SP6	SP5	SP4	SP3	SP2	SP1	----*

Contents of the stack pointer

*Reserved bit: "1" is always read out. Not valid for write.

Description	<p>This is a pointer to indicate a stack address. At reset, it becomes "0FFH" and addresses 0FFH and 0FEH on the data memory of Bank 7 are selected.</p> <p>An access to the stack pointer is valid only for byte access instructions as 8-bit transfer instructions and 8-bit arithmetic instructions.</p>
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Appendix C:

Package Dimension Diagram and Pad Coordinates

MSM64162A-xxxGS-BK

(Unit: mm)

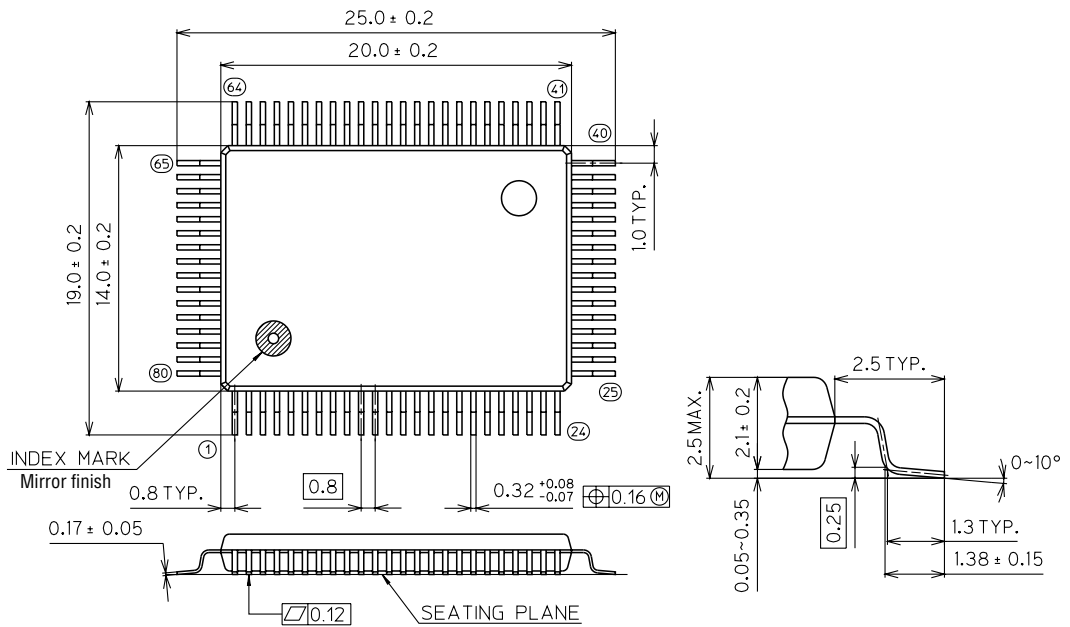


Figure C-1 80-Pin QFP

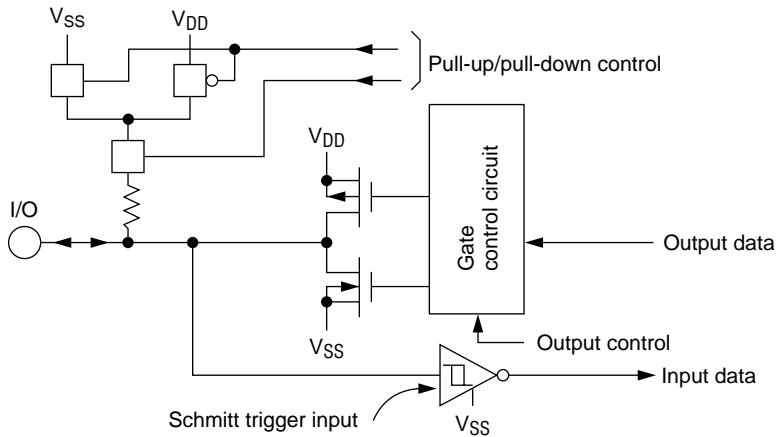
Table C-1 Pad Coordinates

Pad No.	Pad Name	X (μm)	Y (μm)	Pad No.	Pad Name	X (μm)	Y (μm)
1	P0.0	1828.80	-1940.40	41	L7	-1829.40	379.50
2	P0.1	1828.80	-1719.30	42	L8	-1829.40	199.50
3	P0.2	1828.80	-1539.30	43	L9	-1829.40	10.20
4	P0.3	1828.80	-1310.10	44	L10	-1829.40	-232.20
5	RT0	1828.80	-1048.50	45	L11	-1829.40	-412.20
6	CRT0	1828.80	-831.30	46	L12	-1829.40	-592.20
7	RS0	1828.80	-651.30	47	L13	-1829.40	-772.20
8	CS0	1828.80	-396.00	48	L14	-1829.40	-1008.00
9	IN0	1828.80	-208.20	49	L15	-1829.40	-1290.00
10	IN1	1828.80	-12.90	50	L16/P5.0	-1829.40	-1470.00
11	CS1	1828.80	175.50	51	L17/P5.1	-1829.40	-1710.00
12	RS1	1828.80	390.30	52	L18/P5.2	-1829.40	-1928.10
13	RT1	1828.80	580.50	53	L19/P5.3	-1495.20	-1957.50
14	P2.0	1828.80	794.10	54	L20/P6.0	-1226.70	-1957.50
15	P2.1	1828.80	1001.70	55	L21/P6.1	-958.80	-1957.50
16	P2.2	1828.80	1194.00	56	L22/P6.2	-694.80	-1957.50
17	P2.3	1828.80	1374.00	57	L23/P6.3	-448.80	-1957.50
18	P3.0	1828.80	1555.20	58	OSC1	-243.00	-1957.50
19	P3.1	1828.80	1735.20	59	OSC2	24.90	-1957.50
20	P3.2	1769.70	1957.80	60	V _{DD}	300.60	-1957.50
21	P3.3	1589.70	1957.80	61	XT	480.60	-1957.50
22	BD	1317.60	1957.80	62	\overline{XT}	660.60	-1957.50
23	P1.0	999.30	1957.80	63	\overline{RESET}	979.50	-1957.50
24	P1.1	674.70	1957.80	64	$\overline{TST1}$	1247.70	-1957.50
25	P1.2	354.90	1957.80	65	$\overline{TST2}$	1599.90	-1957.50
26	P1.3	30.30	1957.80				
27	V _{SS}	-231.00	1957.80				
28	V _{SS1}	-411.00	1957.80				
29	V _{SS2}	-647.10	1957.80				
30	V _{SSL}	-1289.40	1957.80				
31	V _{SS3}	-1469.40	1957.80				
32	C1	-1649.40	1957.80				
33	C2	-1829.40	1957.80				
34	L0	-1829.40	1704.00				
35	L1	-1829.40	1524.00				
36	L2	-1829.40	1344.00				
37	L3	-1829.40	1111.20				
38	L4	-1829.40	919.50				
39	L5	-1829.40	739.50				
40	L6	-1829.40	559.50				

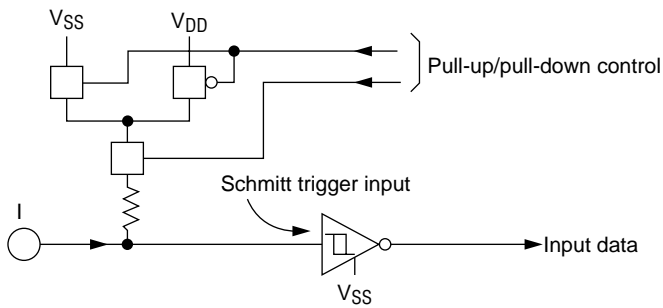
Appendix D:

Layout of Input/Output Circuits

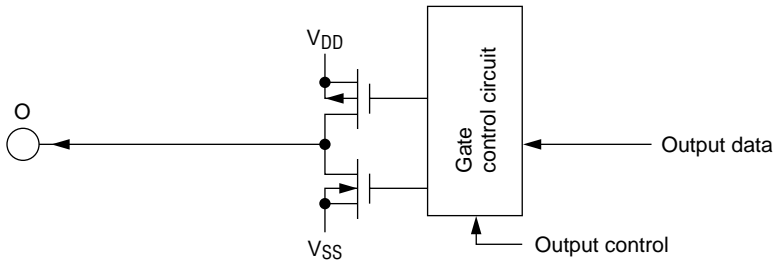
A. Input/output ports (P2.0 to P2.3, P3.0 to P3.3)



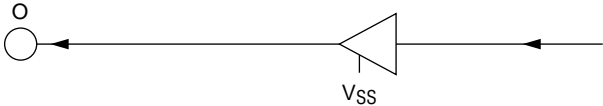
B. Input ports (P0.0 to P0.3)



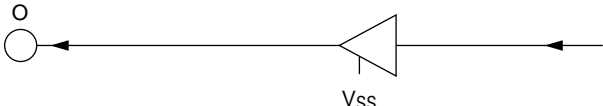
C. Output ports (P1.0 to P1.3)



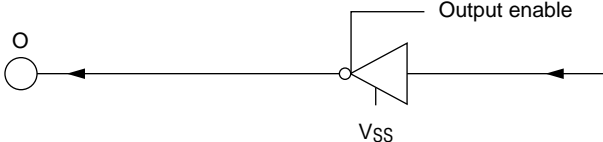
D. Output port (L16/P5.0 to L19/P5.3, L20/P6.0 to L23/P6.3 pins at the mask option)



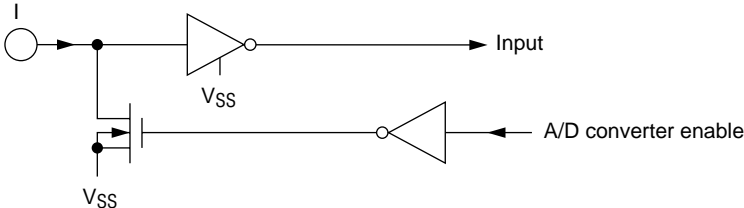
E. BD and CS1 outputs



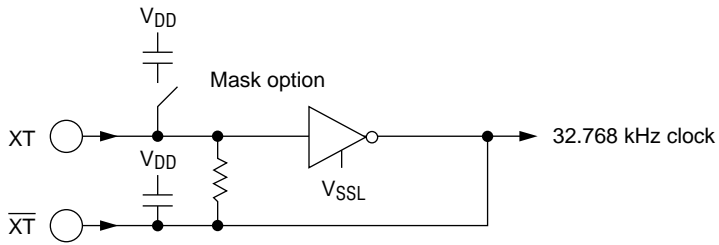
F. RS0, RS1, RT0, RT1, CS0 and CRT0 outputs



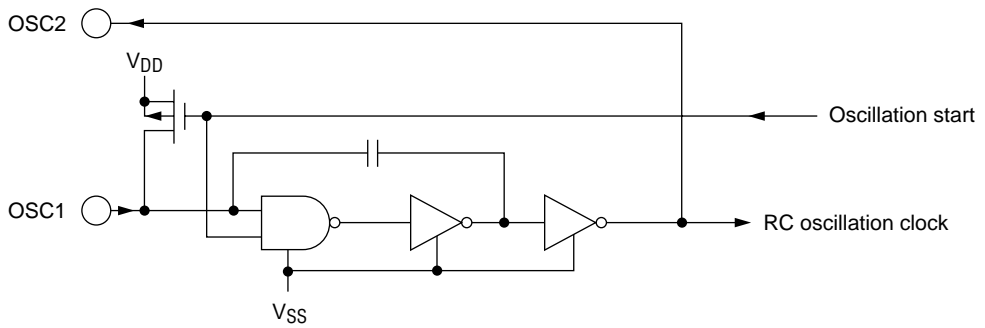
G. IN0 and IN1 inputs



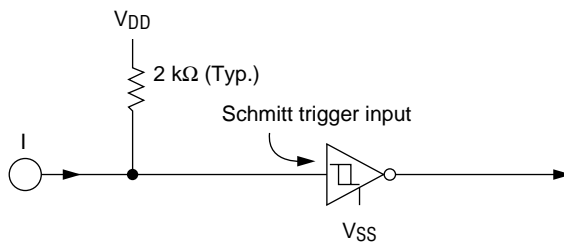
H. Crystal oscillation circuit



I. 400 kHz RC oscillation circuit

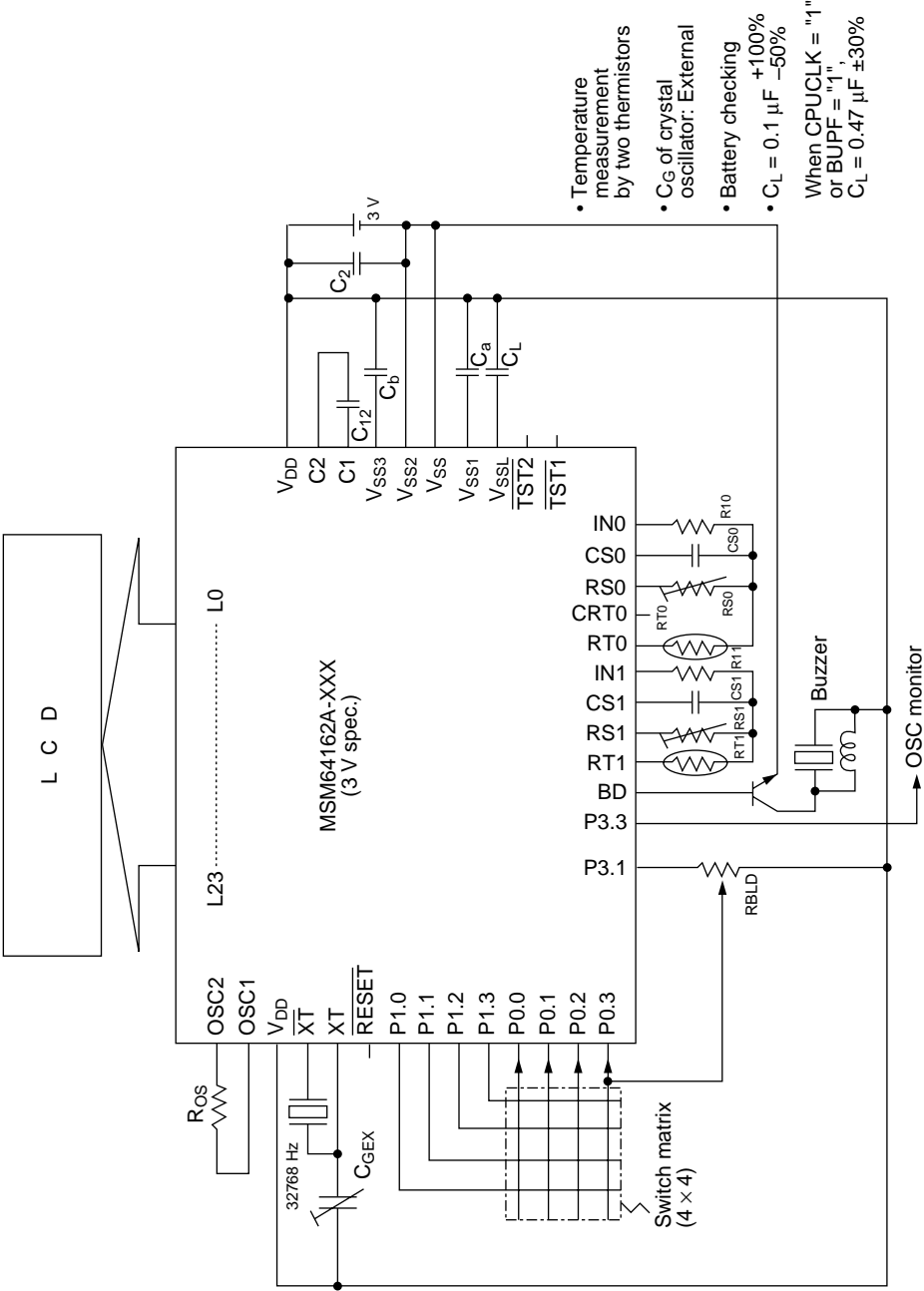


J. \overline{RESET} , $\overline{TST1}$, and $\overline{TST2}$ inputs



Appendix E:

Examples of Application Circuit



- Temperature measurement by two thermistors
 - C_G of crystal oscillator: External
 - Battery checking
 - C_L = 0.1 μF +100% -50%
- When CPUCLK = "1"
or BUJPF = "1"
C_L = 0.47 μF ±30%

Figure E-1 Example of 3 V Spec. Application Circuit

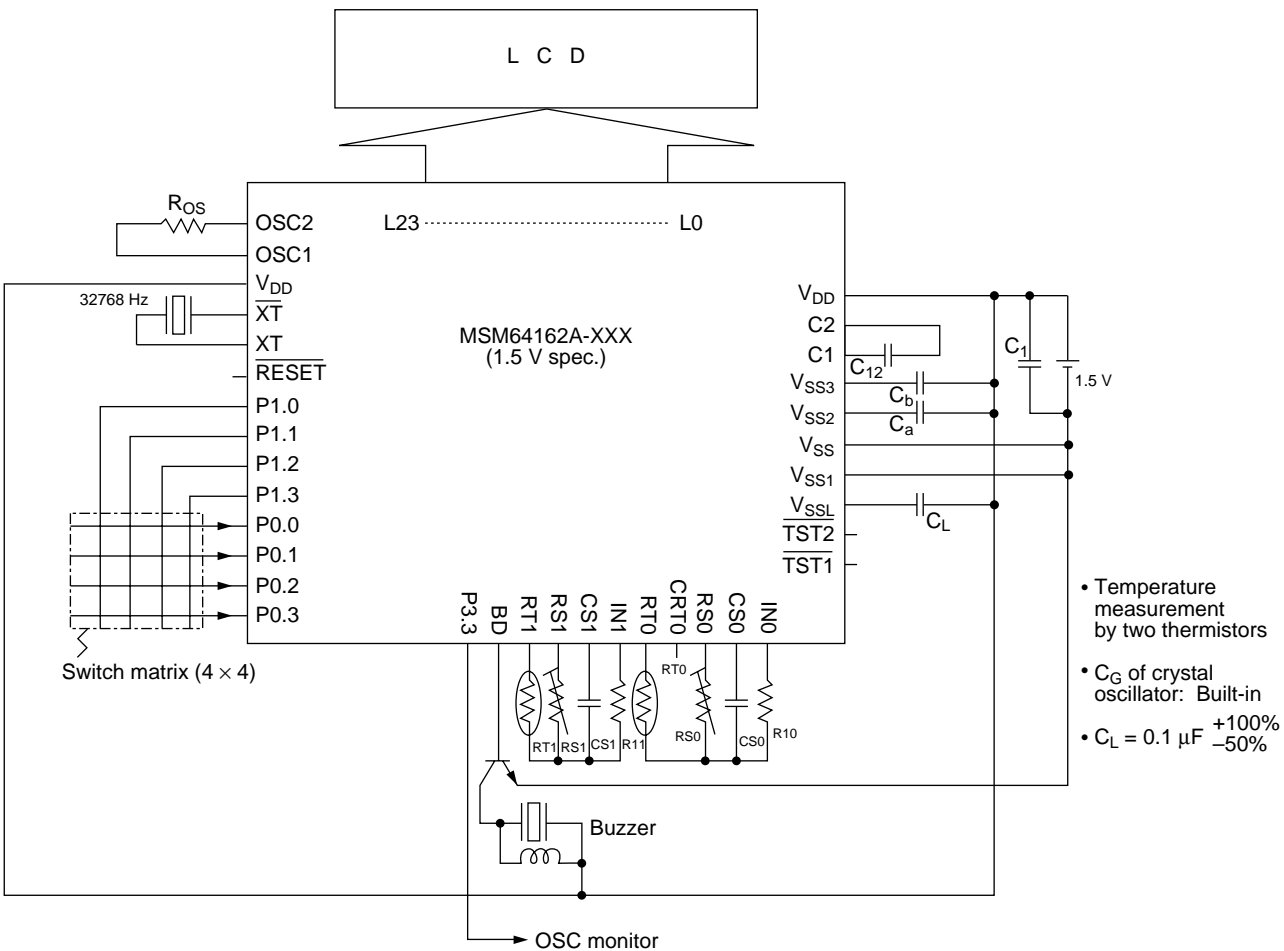


Figure E-2 Example of 1.5 V Spec. Application Circuit

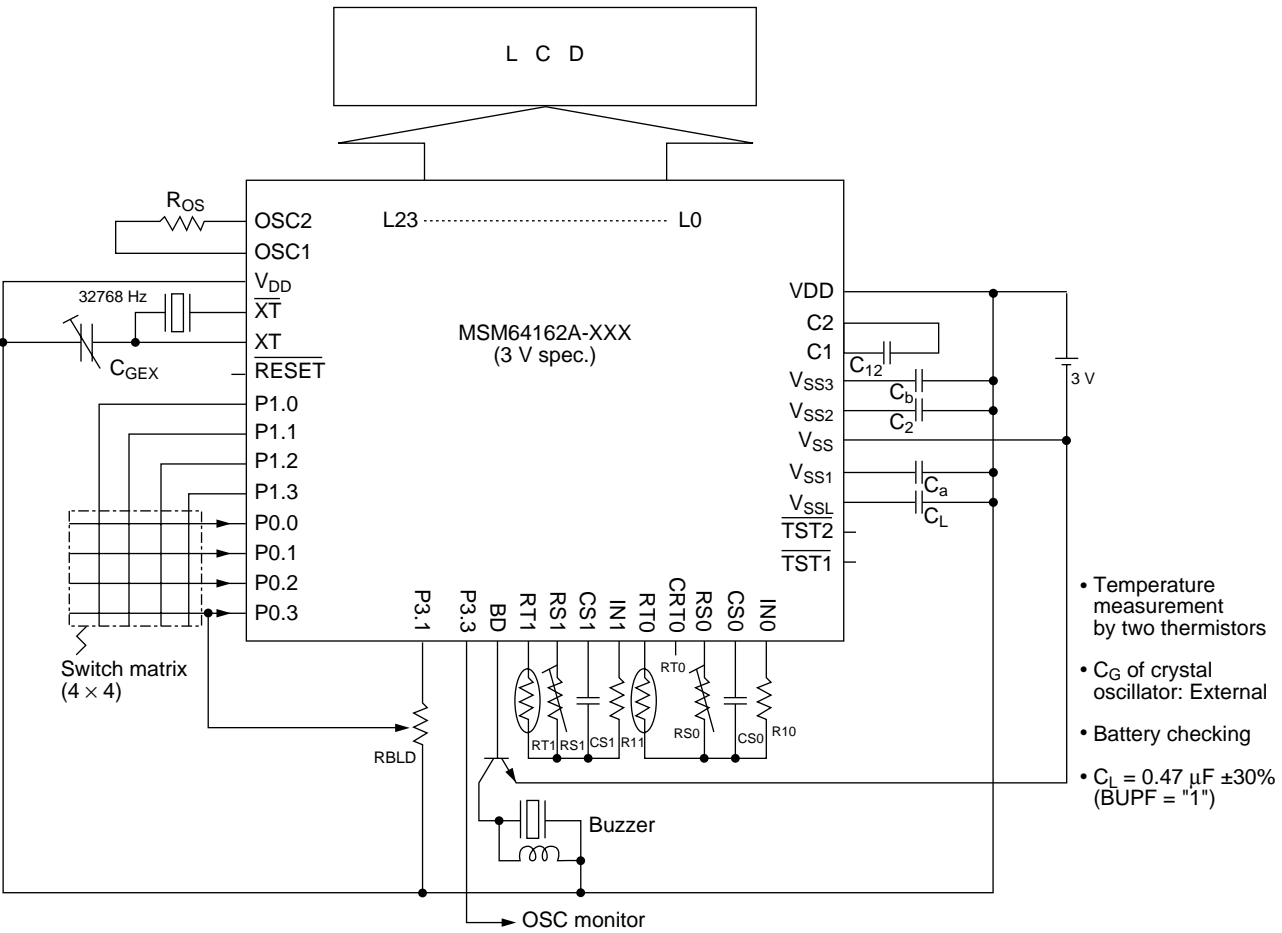


Figure E-3 Example of 3 V Spec. Application Circuit
(When constant voltage circuit for LCD is used)

Appendix F:

Mask Options

● Table of power supply voltage and C_G selection mask options

Item	Mask specification	Selection
Power supply voltage	1.5 V	
	3.0 V	
C _G of crystal oscillator	Built-in	
	External	
Voltage Regulator for LCD	Not used	
	Used	

● Table of LCD driver mask options

[Description of LCD driver mask options]

SEG LCD driver pin name

SIGNAL Writes the name of each segment corresponding to each the common signal.

C/S/P Indicates whether L0 to L23 of the LCD driver are selected as segment driver or common driver or output port. When selected as segment driver, "S" is written. When selected as common driver, "C" is written and when used as output port, "P" is written. When not used, blank is written.

DATA Writes the bit name of the display register corresponding to the signal name (a to d).

DSPR Writes the number of the display register (0 to 20). When not used, blank is written.

Notes:

- (1) There is no need to use all 0 to 20 of the display registers.
- (2) The same name (i.e. the same display register number and the same bit name) can be used for 2 or more than 2 segments.
- (3) When "P" is selected, DSPR becomes either 0 or 1. DATA and DSPR are assigned to COM1 when "P" is selected. Selection of "P" is possible only for the LCD drivers of L16 to L23.
- (4) To make a table of the mask options, use the MASK162 mask option generator. For details of input, refer to "MASK162 Mask Option Generator User's Manual".

[Example of how to make a LCD driver mask options]

- (5) When the display registers are used as data registers and flags, not for indication, the display registers must be assigned per bit by using the empty segments in the LCD driver mask option table.

When the empty segments do not exist on the LCD driver mask option table, the display registers cannot be used as data registers and flags.

[Example of how to make a LCD driver mask options]

(1) When L0 is assigned to Common 2, L1 to segment and L2 as unused (1/4 duty)

SEG	SIGNAL	C/S/P	COM1		COM2		COM3		COM4	
			DATA	DSPR	DATA	DSPR	DATA	DSPR	DATA	DSPR
L0	/ COM2 / /	C								
L1	ALARM / MODE/ 4f / 4g	S	b	5	d	6	b	14	c	14
L2	/ / /									

⋮

(2) When L17 is assigned to Common 1, L18 to segment and L19 as an output port (1/4 duty)

SEG	SIGNAL	C/S/P	COM1		COM2		COM3		COM4	
			DATA	DSPR	DATA	DSPR	DATA	DSPR	DATA	DSPR
L17	COM1 / / /	C								
L18	1a / 1b / 1c / DP1	S	a	2	b	2	c	2	d	2
L19	OUT / / /	P	a	0						

⋮

Table of LCD Driver Mask Options (1/4 duty)

(1/2)

SEG	SIGNAL	C/S/P	COM1		COM2		COM3		COM4	
			DATA	DSPR	DATA	DSPR	DATA	DSPR	DATA	DSPR
L0	/ / /									
L1	/ / /									
L2	/ / /									
L3	/ / /									
L4	/ / /									
L5	/ / /									
L6	/ / /									
L7	/ / /									
L8	/ / /									
L9	/ / /									
L10	/ / /									
L11	/ / /									
L12	/ / /									
L13	/ / /									
L14	/ / /									
L15	/ / /									
L16	/ / /									
L17	/ / /									
L18	/ / /									
L19	/ / /									
L20	/ / /									
L21	/ / /									

Table of LCD Driver Mask Options (1/4 duty)

(2/2)

SEG	SIGNAL	C/S/P	COM1		COM2		COM3		COM4	
			DATA	DSPR	DATA	DSPR	DATA	DSPR	DATA	DSPR
L22	/ / /									
L23	/ / /									

Table of LCD Driver Mask Options (1/3 duty)

(1/2)

SEG	SIGNAL		C/S/P	COM1		COM2		COM3	
				DATA	DSPR	DATA	DSPR	DATA	DSPR
L0	/	/							
L1	/	/							
L2	/	/							
L3	/	/							
L4	/	/							
L5	/	/							
L6	/	/							
L7	/	/							
L8	/	/							
L9	/	/							
L10	/	/							
L11	/	/							
L12	/	/							
L13	/	/							
L14	/	/							
L15	/	/							
L16	/	/							
L17	/	/							
L18	/	/							
L19	/	/							
L20	/	/							
L21	/	/							

Table of LCD Driver Mask Options (1/3 duty)

(2/2)

SEG	SIGNAL	C/S/P	COM1		COM2		COM3	
			DATA	DSPR	DATA	DSPR	DATA	DSPR
L22	/ /							
L23	/ /							

Table of LCD Driver Mask Options (1/2 duty)

(1/2)

SEG	SIGNAL	C/S/P	COM1		COM2	
			DATA	DSPR	DATA	DSPR
L0	/					
L1	/					
L2	/					
L3	/					
L4	/					
L5	/					
L6	/					
L7	/					
L8	/					
L9	/					
L10	/					
L11	/					
L12	/					
L13	/					
L14	/					
L15	/					
L16	/					
L17	/					
L18	/					
L19	/					
L20	/					
L21	/					

Table of LCD Driver Mask Options (1/2 duty)

(2/2)

SEG	SIGNAL	C/S/P	COM1		COM2	
			DATA	DSPR	DATA	DSPR
L22	/					
L23	/					

Appendix G:

Electrical Characteristics

(1) 1.5 V Spec.

● Absolute Maximum Ratings

(V_{DD} = 0 V)

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage 1	V _{SS}	T _a = 25°C	-2.0 to +0.3	V
Power supply voltage 2	V _{SS1}	T _a = 25°C	-2.0 to +0.3	V
Power supply voltage 3	V _{SS2}	T _a = 25°C	-4.0 to +0.3	V
Power supply voltage 4	V _{SS3}	T _a = 25°C	-5.5 to +0.3	V
Power supply voltage 5	V _{SSL}	T _a = 25°C	-2.0 to +0.3	V
Input voltage 1	V _{IN1}	V _{SS} input, T _a = 25°C	V _{SS} - 0.3 to +0.3	V
Input voltage 2	V _{IN2}	V _{SS1} input, T _a = 25°C	V _{SS1} - 0.3 to +0.3	V
Input voltage 3	V _{IN3}	V _{SSL} input, T _a = 25°C	V _{SSL} - 0.3 to +0.3	V
Output voltage 1	V _{OUT1}	V _{SS} output, T _a = 25°C	V _{SS} - 0.3 to +0.3	V
Output voltage 2	V _{OUT2}	V _{SS1} output, T _a = 25°C	V _{SS1} - 0.3 to +0.3	V
Output voltage 3	V _{OUT3}	V _{SS2} output, T _a = 25°C	V _{SS2} - 0.3 to +0.3	V
Output voltage 4	V _{OUT4}	V _{SS3} output, T _a = 25°C	V _{SS3} - 0.3 to +0.3	V
Output voltage 5	V _{OUT5}	V _{SSL} output, T _a = 25°C	V _{SSL} - 0.3 to +0.3	V
Storage temperature	T _{STG}	—	-55 to +150	°C

● Recommended Operating Conditions

(V_{DD} = 0 V)

Parameter	Symbol	Condition	Range	Unit
Operating temperature	T _{OP}	—	-40 to +85	°C
Operating voltage	V _{SS} , V _{SS1}	—	-1.7 to -1.25	V
400 kHz OSC external resistance	R _{OS}	—	250 to 500	kΩ
Crystal oscillation frequency	f _{XT}	—	30 to 35	kHz

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS1} = -1.5\text{ V}$, $T_a = -40\text{ to } +85^\circ\text{C}$ unless otherwise mentioned)

(1/4)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit	
V_{SS2} voltage	V_{SS2}	$C_a, C_b, C_{12} = 0.1\ \mu\text{F}$ +100% -50%	-3.2	-3.0	-2.8	V	1	
V_{SS3} voltage	V_{SS3}	$C_a, C_b, C_{12} = 0.1\ \mu\text{F}$ +100% -50%	-4.7	-4.5	-4.3	V		
V_{SSL} voltage	V_{SSL}	—	-1.5	-1.3	-0.6	V		
Supply current 1	I_{DD1}	CPU in halt state (400kOSC halt)	$T_a = -40\text{ to } +40^\circ\text{C}$ $T_a = +40\text{ to } +85^\circ\text{C}$	— 2	5 30	μA		
Supply current 2	I_{DD2}	CPU in operation state (400kOSC halt)	$T_a = -40\text{ to } +40^\circ\text{C}$ $T_a = +40\text{ to } +85^\circ\text{C}$	— 5	15 40	μA		
Supply current 3	I_{DD3}	CPU in operation state (400kOSC in operation)		—	40	80		μA
Supply current 4	I_{DD4}	CPU in halt state (400kOSC halt), A/D converter in oscillation state	$RT0 = 10\ \text{k}\Omega$	—	150	230		μA
			$RT0 = 2\ \text{k}\Omega$	—	600	900		
Supply current 5	I_{DD5}	Battery check in operation state, CPU in operation state (400kOSC halt)		—	25	125		μA
Crystal oscillation start voltage	V_{STA}	Less than 5 seconds for oscillation starts		—	—	-1.45		V
Crystal oscillation maintaining voltage	V_{HOLD}	—		—	—	-1.25		V
Crystal oscillation stop detection time	T_{STOP}	—		0.1	—	1000		ms
Crystal oscillation internal capacitance	C_G	—		10	15	20		pF
Crystal oscillation external capacitance	C_{GEX}	C_G external option		10	—	30		pF
Crystal oscillation internal capacitance	C_D	—		10	15	20		pF
400kOSC internal capacitance	C_{OS}	—		8	12	16		pF
400kOSC oscillation frequency	f_{OSC}	External resistance $R_{OS} = 300\ \text{k}\Omega$ $V_{SS1} = -1.25\text{ to } -1.7\ \text{V}$		80	220	350		kHz
POR generation voltage	V_{POR1}	V_{SS2} is within V_{POR1} to $-1.5\ \text{V}$ and POR generated		-0.4	—	0		V
POR non-generation voltage	V_{POR2}	V_{SS1} is within V_{POR2} to $-1.5\ \text{V}$ and no POR		-1.5	—	-1.2		V
Battery check reference voltage	V_{RB}	$T_a = 25^\circ\text{C}$		-0.73	-0.63	-0.53		V
VRB temperature variation	ΔV_{RB}	—		—	-2	—	mV/ $^\circ\text{C}$	

Notes:

- "400kOSC" refers to the 400 kHz RC oscillation circuit.
- "POR" refers to Power-On Reset.
- " T_{STOP} " refers to the generation of system reset when crystal oscillation stops oscillation for more than this duration.

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(2/4)

Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Output current 1 (P1.0)	I_{OH1}	$V_{OH1} = -0.5\text{ V}$	-2.1	-0.5	-0.1	mA	2
	I_{OL1}	$V_{OL1} = V_{SS} + 0.5\text{ V}$	1	3	9	mA	
Output current 2 (P1.1 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3)	I_{OH2}	$V_{OH2} = -0.5\text{ V}$	-2.1	-0.5	-0.1	mA	
	I_{OL2}	$V_{OL2} = V_{SS} + 0.5\text{ V}$	0.1	0.5	2.1	mA	
Output current 3 (BD)	I_{OH3}	$V_{OH3} = -0.7\text{ V}$	-1.8	-0.4	-0.1	mA	
	I_{OL3}	$V_{OL3} = V_{SS} + 0.7\text{ V}$	0.1	0.4	1.8	mA	
Output current 4 (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OH4}	$V_{OH4} = -0.1\text{ V}$	-1.1	-0.4	-0.2	mA	
	I_{OL4}	$V_{OL4} = V_{SS} + 0.1\text{ V}$	0.2	0.4	1.1	mA	
Output current 5 (When L16 to L23 are output ports)	I_{OH5}	$V_{OH5} = -0.5\text{ V}$	-1.5	-0.4	-0.08	mA	
	I_{OL5}	$V_{OL5} = V_{SS} + 0.5\text{ V}$	0.08	0.4	1.5	mA	
Output current 6 (OSC2)	I_{OH6}	$V_{OH6} = -0.5\text{ V}$	-2.1	-0.5	-0.1	mA	
	I_{OL6}	$V_{OL6} = V_{SS} + 0.5\text{ V}$	0.1	0.5	2.1	mA	
Output current 7 (L0 to L23)	I_{OH7}	$V_{OH7} = -0.2\text{ V}$ (V_{DD} level)	—	—	-4	μA	
	I_{OMH7}	$V_{OMH7} = V_{SS1} + 0.2\text{ V}$ (V_{SS1} level)	4	—	—	μA	
	I_{OMH7S}	$V_{OMH7S} = V_{SS1} - 0.2\text{ V}$ (V_{SS1} level)	—	—	-4	μA	
	I_{OML7}	$V_{OML7} = V_{SS2} + 0.2\text{ V}$ (V_{SS2} level)	4	—	—	μA	
	I_{OML7S}	$V_{OML7S} = V_{SS2} - 0.2\text{ V}$ (V_{SS2} level)	—	—	-4	μA	
	I_{OL7}	$V_{OL7} = V_{SS3} + 0.2\text{ V}$ (V_{SS3} level)	4	—	—	μA	
Output leak (P1.0 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OOH}	$V_{OH} = V_{DD}$	—	—	0.3	μA	
	I_{OOL}	$V_{OL} = V_{SS}$	-0.3	—	—	μA	

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(3/4)

Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Input current 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	I_{IH1}	$V_{IH1} = V_{DD}$ (pull-down)	2	10	60	μA	3
	I_{IL1}	$V_{IL1} = V_{SS}$ (pull-up)	-60	-10	-2	μA	
	I_{IH1Z}	$V_{IH1} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL1Z}	$V_{IL1} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 2 (IN0, IN1)	I_{IH2}	$V_{IH2} = V_{DD}$ (pull-down)	2	10	60	μA	
	I_{IH2Z}	$V_{IH2} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL2Z}	$V_{IL2} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 3 (OSC1)	I_{IL3}	$V_{IL3} = V_{SS}$ (pull-up)	-60	-18	-4	μA	
	I_{IH3Z}	$V_{IH3} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL3Z}	$V_{IL3} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 4 (RESET, TST1, TST2)	I_{IH4}	$V_{IH4} = V_{DD}$	0	—	1	μA	
	I_{IL4}	$V_{IL4} = V_{SS}$	-1.5	-0.75	-0.3	mA	
Input voltage 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	V_{IH1}	—	-0.3	—	0	V	4
	V_{IL1}	—	-1.5	—	-1.2	V	
Input voltage 2 (IN0, IN1, OSC1)	V_{IH2}	—	-0.3	—	0	V	
	V_{IL2}	—	-1.5	—	-1.2	V	
Input voltage 3 (RESET, TST1, TST2)	V_{IH3}	—	-0.3	—	0	V	
	V_{IL3}	—	-1.5	—	-1.2	V	

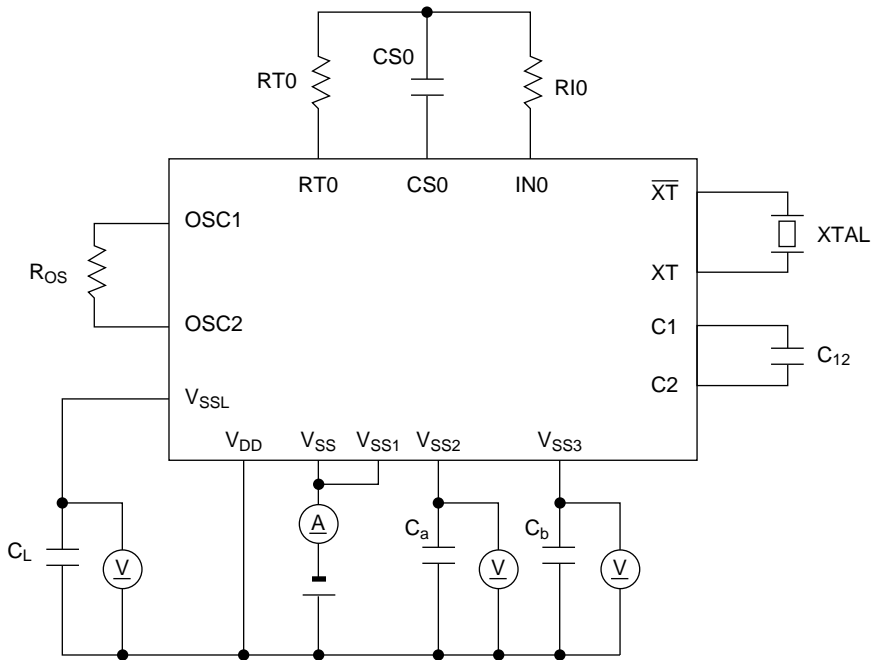
● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(4/4)

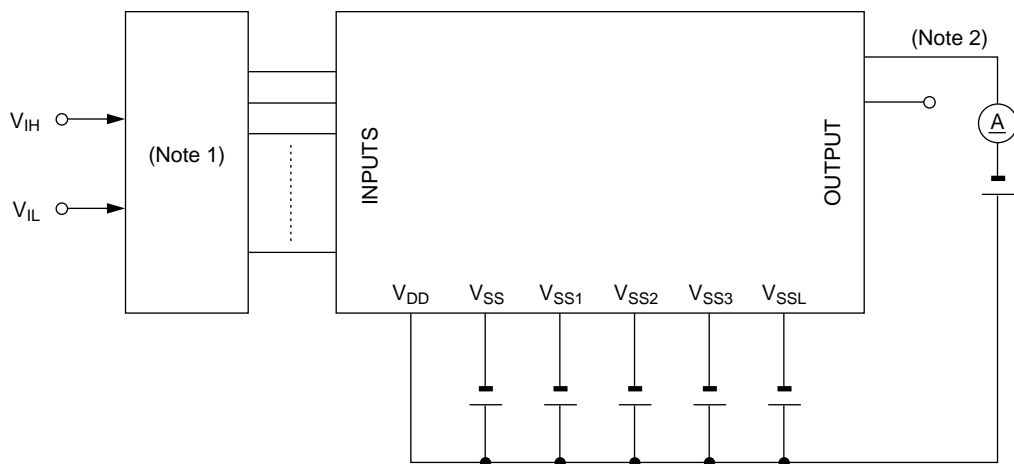
Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Hysteresis width (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	ΔVT_1	—	0.05	0.1	0.3	V	4
Hysteresis width ($\overline{\text{RESET}}$, $\overline{\text{TST1}}$, $\overline{\text{TST2}}$)	ΔVT_2	—	0.05	0.1	0.3	V	
Input pin capacitance (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	C_{IN}	—	—	—	5	pF	1

Measuring circuit 1

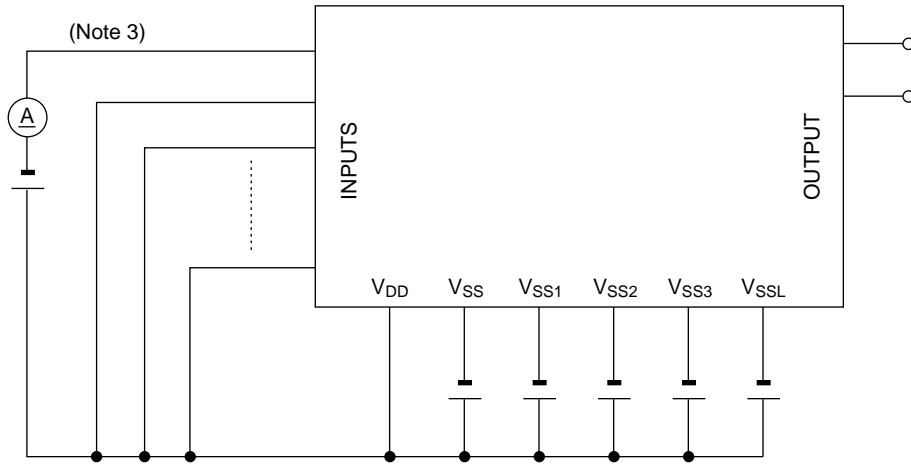


C_L	:	0.47 μF
C_a, C_b, C_{12}	:	0.1 μF
R_{OS}	:	300 $\text{k}\Omega$
XTAL	:	32.768 kHz
RT0	:	10 $\text{k}\Omega/2 \text{ k}\Omega$
CS0	:	820 pF
RI0	:	10 $\text{k}\Omega$

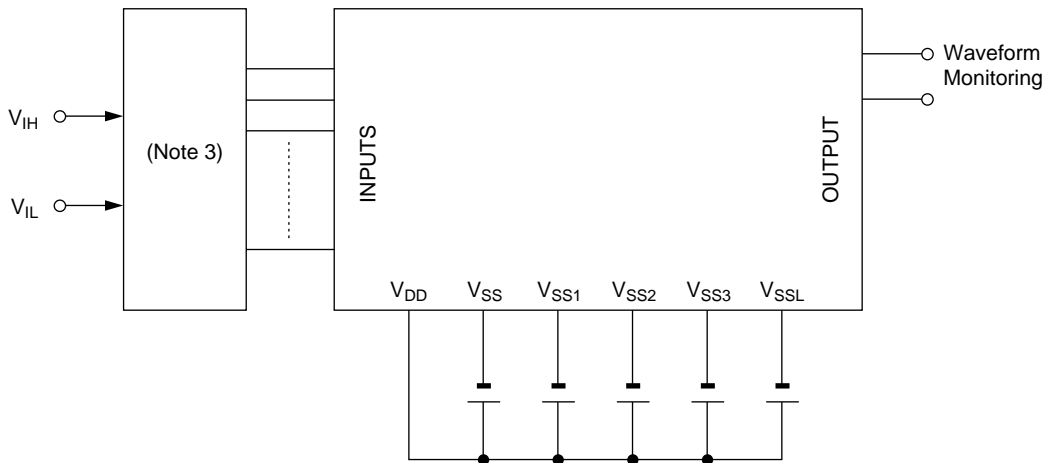
Measuring circuit 2



Measuring circuit 3



Measuring circuit 4



Note 1: Input logic circuit to determine the specified measuring conditions.

Note 2: Measured at the specified output pins.

Note 3: Measured at the specified input pins.

● A/D Converter Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS1} = -1.5\text{ V}$, $T_a = -40\text{ to }+85^\circ\text{C}$ unless otherwise mentioned)

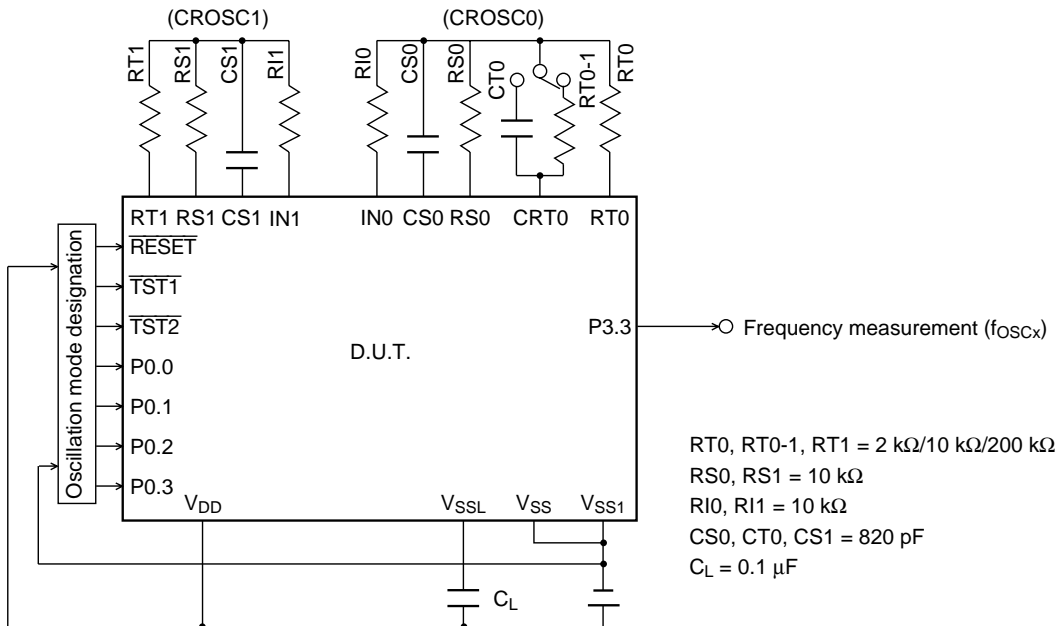
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Resistor for oscillation	RS0,RS1, RT0, RT0-1, RT1	$CS0, CT0, CS1 \geq 740\text{ pF}$	2	—	—	k Ω	5
Input current limiting resistor	RI0, RI1	—	1	10	—	k Ω	
Oscillation frequency	f_{OSC1}	Resistor for oscillation = 2 k Ω	165	221	256	kHz	
	f_{OSC2}	Resistor for oscillation = 10 k Ω	41.8	52.2	60.6	kHz	
	f_{OSC3}	Resistor for oscillation = 200 k Ω	2.55	3.04	3.53	kHz	
RS • RT oscillation frequency ratio (Note)	Kf1	RT0, RT0-1, RT1 = 2 k Ω	3.89	4.18	4.35	—	
	Kf2	RT0, RT0-1, RT1 = 10 k Ω	0.990	1	1.010	—	
	Kf3	RT0, RT0-1, RT1 = 200 k Ω	0.0561	0.0584	0.0637	—	

(Note) Kfx is the ratio of the oscillation frequency by a sensor resistor and the oscillation frequency by a reference resistor in the same condition.

$$Kfx = \frac{f_{OSCx}(\text{RT0-CS0 Oscillation})}{f_{OSCx}(\text{RS0-CS0 Oscillation})}, \quad \frac{f_{OSCx}(\text{RT0-1-CS0 Oscillation})}{f_{OSCx}(\text{RS0-CS0 Oscillation})}, \quad \frac{f_{OSCx}(\text{RT1-CS1 Oscillation})}{f_{OSCx}(\text{RS1-CS1 Oscillation})}$$

(x = 1, 2, 3)

Measuring circuit 5



(2) 3.0 V Spec.

● Absolute Maximum Ratings

(V_{DD} = 0 V)

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage 1	V _{SS}	Ta = 25°C	-4.0 to +0.3	V
Power supply voltage 2	V _{SS1}	Ta = 25°C	-2.0 to +0.3	V
Power supply voltage 3	V _{SS2}	Ta = 25°C	-4.0 to +0.3	V
Power supply voltage 4	V _{SS3}	Ta = 25°C	-5.5 to +0.3	V
Power supply voltage 5	V _{SSL}	Ta = 25°C	-4.0 to +0.3	V
Input voltage 1	V _{IN1}	V _{SS} input, Ta = 25°C	V _{SS} - 0.3 to +0.3	V
Input voltage 2	V _{IN2}	V _{SS2} input, Ta = 25°C	V _{SS2} - 0.3 to +0.3	V
Input voltage 3	V _{IN3}	V _{SSL} input, Ta = 25°C	V _{SSL} - 0.3 to +0.3	V
Output voltage 1	V _{OUT1}	V _{SS} output, Ta = 25°C	V _{SS} - 0.3 to +0.3	V
Output voltage 2	V _{OUT2}	V _{SS2} output, Ta = 25°C	V _{SS2} - 0.3 to +0.3	V
Output voltage 3	V _{OUT3}	V _{SS3} output, Ta = 25°C	V _{SS} - 0.3 to +0.3	V
Output voltage 4	V _{OUT4}	V _{SSL} output, Ta = 25°C	V _{SSL} - 0.3 to +0.3	V
Storage temperature	T _{STG}	—	-55 to +150	°C

● Recommended Operating Conditions

(V_{DD} = 0 V)

Parameter	Symbol	Condition	Range	Unit
Operating temperature	T _{OP}	—	-40 to +85	°C
Operating voltage	V _{SS} , V _{SS2}	Using LCD with "duty 1/2"	-3.5 to -2.2	V
		Except using LCD with "duty 1/2"	-3.5 to -2.0	
400 kHz OSC external resistance	R _{OS}	—	90 to 500	kΩ
Crystal oscillation frequency	f _{XT}	—	30 to 66	kHz

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS2} = -3.0\text{ V}$, $T_a = -40\text{ to } +85^\circ\text{C}$ unless otherwise mentioned)

(1/4)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
V_{SS1} voltage	V_{SS1}	$C_a, C_b, C_{12} = 0.1\ \mu\text{F}$ +100% -50%	-1.7	-1.5	-1.3	V	1
V_{SS3} voltage	V_{SS3}	$C_a, C_b, C_{12} = 0.1\ \mu\text{F}$ +100% -50%	-4.7	-4.5	-4.3	V	
V_{SSL} voltage	V_{SSL}	—	-1.9	-1.3	-0.6	V	
Supply current 1	I_{DD1}	CPU in halt state (400kOSC halt)	$T_a = -40\text{ to } +40^\circ\text{C}$ $T_a = +40\text{ to } +85^\circ\text{C}$	— 1.5	4.5 30	μA	
Supply current 2	I_{DD2}	CPU in operation state (400kOSC halt)	$T_a = -40\text{ to } +40^\circ\text{C}$ $T_a = +40\text{ to } +85^\circ\text{C}$	— 5	15 40	μA	
Supply current 3	I_{DD3}	CPU in operation state (400kOSC in operation)	—	220	450	μA	
Supply current 4	I_{DD4}	CPU in halt state (400kOSC halt), A/D converter in oscillation state	$R_{T0} = 10\ \text{k}\Omega$ $R_{T0} = 2\ \text{k}\Omega$	— 1300	450 2000	μA	
Supply current 5	I_{DD5}	Battery check in operation state, CPU in operation state (400kOSC halt)	—	55	150	μA	
Crystal oscillation start voltage	V_{STA}	Less than 5 seconds for oscillation starts	—	—	-2.0	V	
Crystal oscillation maintaining voltage	V_{HOLD}	—	—	—	-2.0	V	
Crystal oscillation stop detection time	T_{STOP}	—	0.1	—	1000	ms	
Crystal oscillation internal capacitance	C_G	—	10	15	20	pF	
Crystal oscillation external capacitance	C_{GEX}	C_G external option	10	—	30	pF	
Crystal oscillation internal capacitance	C_D	—	10	15	20	pF	
400kOSC internal capacitance	C_{OS}	—	8	12	16	pF	
400kOSC oscillation frequency	f_{OSC}	External resistance $R_{OS} = 100\ \text{k}\Omega$ $V_{SS2} = -2.0\text{ to } -3.5\ \text{V}$	300	400	620	kHz	
POR generation voltage	V_{POR1}	V_{SS2} is within V_{POR1} to $-3.0\ \text{V}$ and POR generated	-0.7	—	0	V	
POR non-generation voltage	V_{POR2}	V_{SS1} is within V_{POR2} to $-3.0\ \text{V}$ and no POR	-3	—	-2	V	
Battery check reference voltage	V_{RB}	$T_a = 25^\circ\text{C}$	-0.73	-0.63	-0.53	V	2
VRB temperature variation	ΔV_{RB}	—	—	-2	—	mV/ $^\circ\text{C}$	

Notes:

- "400kOSC" refers to the 400 kHz RC oscillation circuit.
- "POR" refers to Power-On Reset.
- " T_{STOP} " refers to the generation of system reset when crystal oscillation stops oscillation for more than this duration.

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS} = V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(2/4)

Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Output current 1 (P1.0)	I_{OH1}	$V_{OH1} = -0.5\text{ V}$	-6	-1.5	-0.4	mA	2
	I_{OL1}	$V_{OL1} = V_{SS} + 0.5\text{ V}$	3	8	25	mA	
Output current 2 (P1.1 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3)	I_{OH2}	$V_{OH2} = -0.5\text{ V}$	-6	-1.5	-0.4	mA	
	I_{OL2}	$V_{OL2} = V_{SS} + 0.5\text{ V}$	0.4	1.5	6	mA	
Output current 3 (BD)	I_{OH3}	$V_{OH3} = -0.7\text{ V}$	-6	-2	-0.4	mA	
	I_{OL3}	$V_{OL3} = V_{SS} + 0.7\text{ V}$	0.4	2	6	mA	
Output current 4 (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OH4}	$V_{OH4} = -0.1\text{ V}$	-2.5	-0.8	-0.3	mA	
	I_{OL4}	$V_{OL4} = V_{SS} + 0.1\text{ V}$	0.3	0.8	2.5	mA	
Output current 5 (When L16 to L23 are output ports)	I_{OH5}	$V_{OH5} = -0.5\text{ V}$	-1.5	-0.6	-0.15	mA	
	I_{OL5}	$V_{OL5} = V_{SS} + 0.5\text{ V}$	0.15	0.6	1.5	mA	
Output current 6 (OSC2)	I_{OH6}	$V_{OH6} = -0.5\text{ V}$	-6	-2	-0.4	mA	
	I_{OL6}	$V_{OL6} = V_{SS} + 0.5\text{ V}$	0.4	2	6	mA	
Output current 7 (L0 to L23)	I_{OH7}	$V_{OH7} = -0.2\text{ V}$ (V_{DD} level)	—	—	-4	μA	
	I_{OMH7}	$V_{OMH7} = V_{SS1} + 0.2\text{ V}$ (V_{SS1} level)	4	—	—	μA	
	I_{OMH7S}	$V_{OMH7S} = V_{SS1} - 0.2\text{ V}$ (V_{SS1} level)	—	—	-4	μA	
	I_{OML7}	$V_{OML7} = V_{SS2} + 0.2\text{ V}$ (V_{SS2} level)	4	—	—	μA	
	I_{OML7S}	$V_{OML7S} = V_{SS2} - 0.2\text{ V}$ (V_{SS2} level)	—	—	-4	μA	
	I_{OL7}	$V_{OL7} = V_{SS3} + 0.2\text{ V}$ (V_{SS3} level)	4	—	—	μA	
Output leak (P1.0 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OOH}	$V_{OH} = V_{DD}$	—	—	0.3	μA	
	I_{OOL}	$V_{OL} = V_{SS}$	-0.3	—	—	μA	

● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS} = V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(3/4)

Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Input current 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	I_{IH1}	$V_{IH1} = V_{DD}$ (pull-down)	20	60	300	μA	3
	I_{IL1}	$V_{IL1} = V_{SS}$ (pull-up)	-300	-60	-20	μA	
	I_{IH1Z}	$V_{IH1} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL1Z}	$V_{IL1} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 2 (IN0, IN1)	I_{IH2}	$V_{IH2} = V_{DD}$ (pull-down)	20	60	300	μA	
	I_{IH2Z}	$V_{IH2} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL2Z}	$V_{IL2} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 3 (OSC1)	I_{IL3}	$V_{IL3} = V_{SS}$ (pull-up)	-300	-110	-30	μA	
	I_{IH3Z}	$V_{IH3} = V_{DD}$ (high-impedance)	0	—	1	μA	
	I_{IL3Z}	$V_{IL3} = V_{SS}$ (high-impedance)	-1	—	0	μA	
Input current 4 (RESET, TST1, TST2)	I_{IH4}	$V_{IH4} = V_{DD}$	0	—	1	μA	
	I_{IL4}	$V_{IL4} = V_{SS}$	-3	-1.5	-0.75	mA	
Input voltage 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	V_{IH1}	—	-0.6	—	0	V	4
	V_{IL1}	—	-3.0	—	-2.4	V	
Input voltage 2 (IN0, IN1, OSC1)	V_{IH2}	—	-0.6	—	0	V	
	V_{IL2}	—	-3.0	—	-2.4	V	
Input voltage 3 (RESET, TST1, TST2)	V_{IH3}	—	-0.6	—	0	V	
	V_{IL3}	—	-3.0	—	-2.4	V	

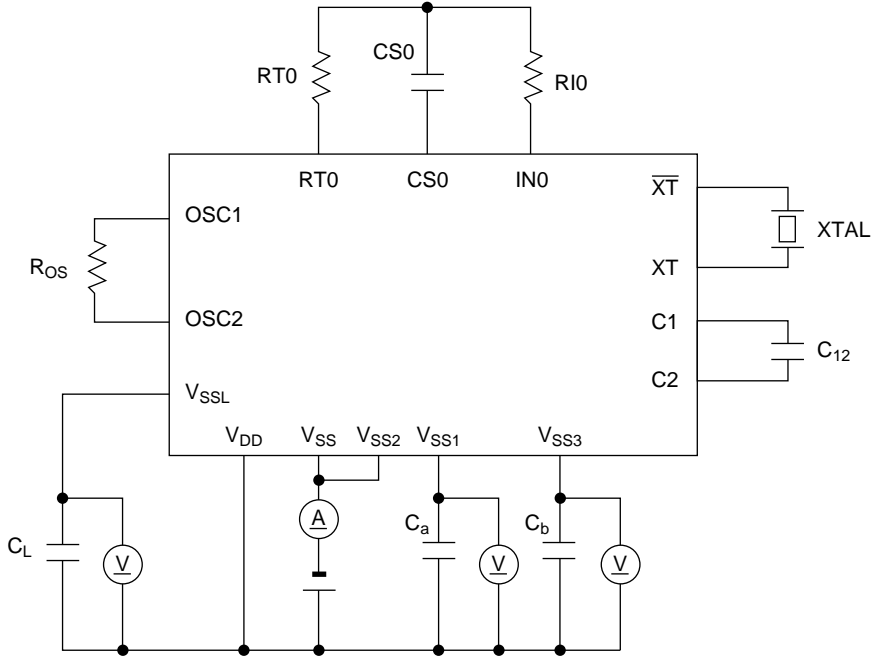
● DC Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS1} = V_{SSL} = -1.5\text{ V}$, $V_{SS} = V_{SS2} = -3.0\text{ V}$, $V_{SS3} = -4.5\text{ V}$, $T_a = -40$ to $+85^\circ\text{C}$ unless otherwise mentioned)

(4/4)

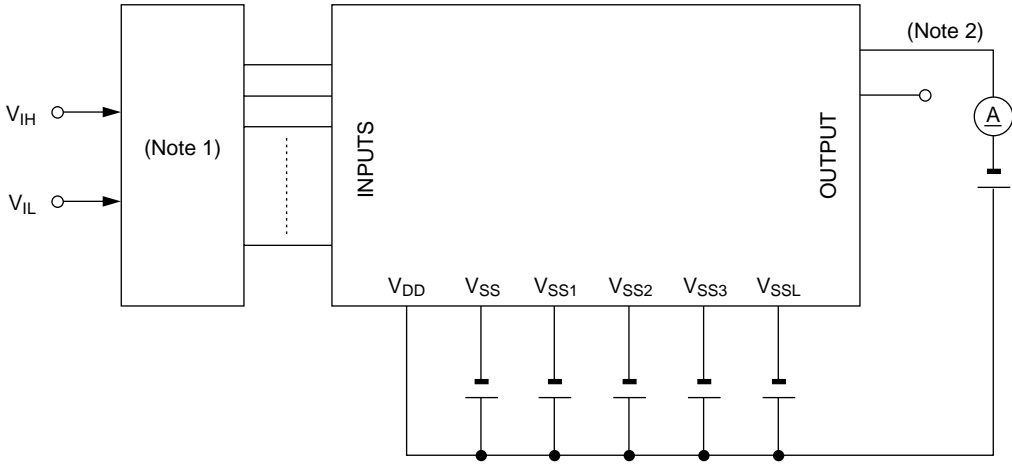
Parameter (pin name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Hysteresis width (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	ΔVT_1	—	0.2	0.5	1	V	4
Hysteresis width ($\overline{\text{RESET}}$, $\overline{\text{TST1}}$, $\overline{\text{TST2}}$)	ΔVT_2	—	0.2	0.5	1	V	
Input pin capacitance (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3)	C_{IN}	—	—	—	5	pF	1

Measuring circuit 1

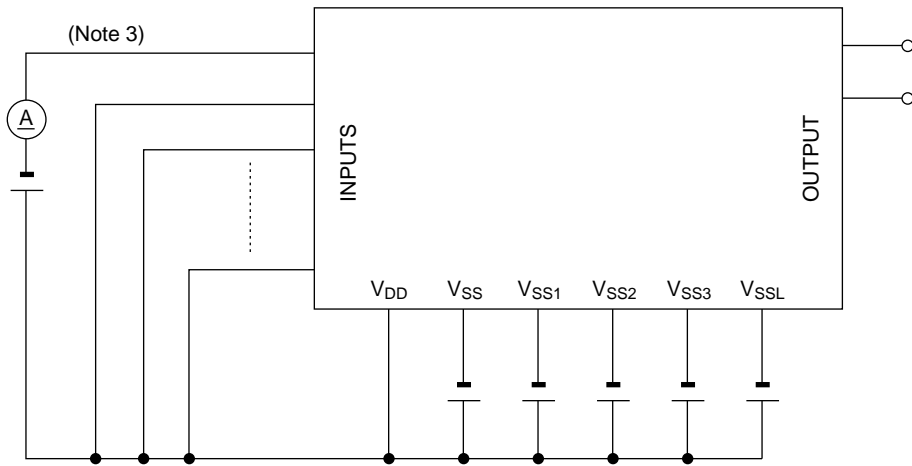


- C_L : 0.47 μ F
- C_a, C_b, C_{12} : 0.1 μ F
- R_{OS} : 100 k Ω
- XTAL : 32.768 kHz
- RT0 : 10 k Ω /2 k Ω
- CS0 : 820 pF
- R10 : 10 k Ω

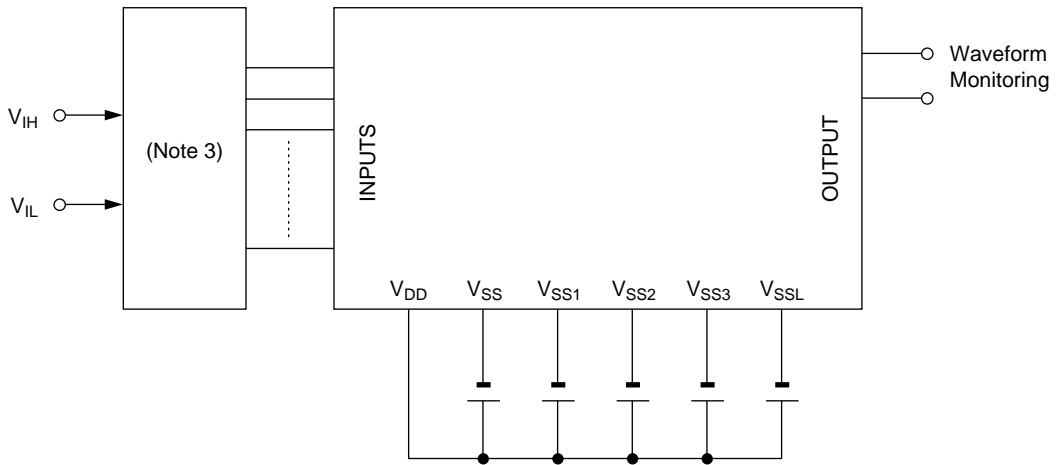
Measuring circuit 2



Measuring circuit 3



Measuring circuit 4



Note 1: Input logic circuit to determine the specified measuring conditions.

Note 2: Measured at the specified output pins.

Note 3: Measured at the specified input pins.

● A/D Converter Characteristics

($V_{DD} = 0\text{ V}$, $V_{SS} = V_{SS2} = -3.0\text{ V}$, $T_a = -40\text{ to }+85^\circ\text{C}$ unless otherwise mentioned)

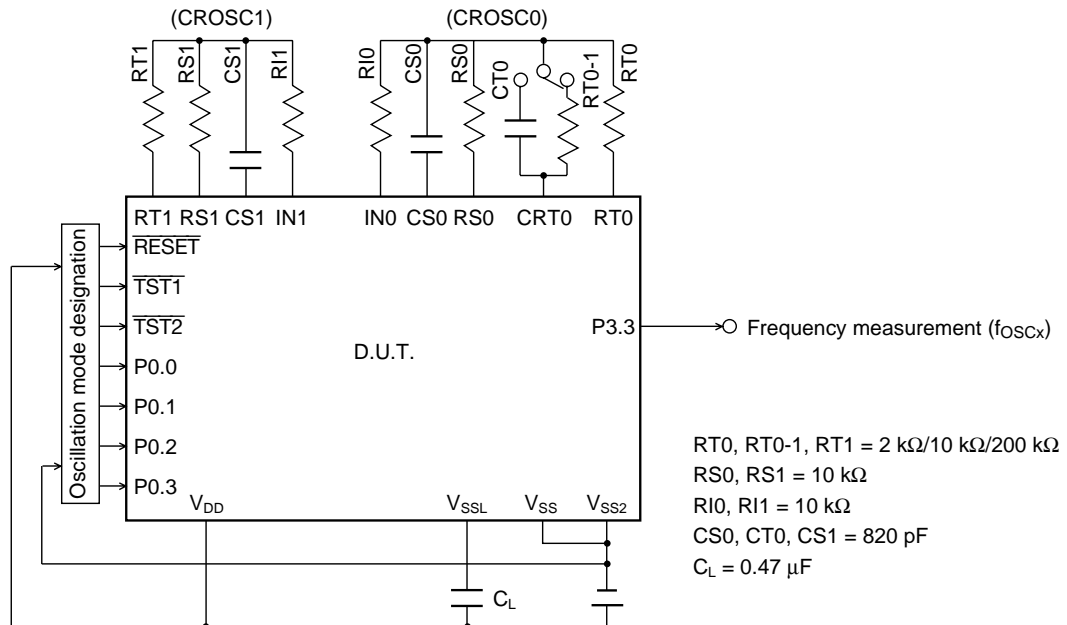
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit
Resistor for oscillation	RS0,RS1, RT0, RT0-1, RT1	CS0, CT0, CS1 $\geq 740\text{ pF}$	1	—	—	k Ω	5
Input current limiting resistor	RI0, RI1	—	1	10	—	k Ω	
Oscillation frequency	f_{OSC1}	Resistor for oscillation = 2 k Ω	200	239	277	kHz	
	f_{OSC2}	Resistor for oscillation = 10 k Ω	46.5	55.4	64.3	kHz	
	f_{OSC3}	Resistor for oscillation = 200 k Ω	2.79	3.32	3.85	kHz	
RS • RT oscillation frequency ratio (Note)	Kf1	RT0, RT0-1, RT1 = 2 k Ω	4.115	4.22	4.326	—	
	Kf2	RT0, RT0-1, RT1 = 10 k Ω	0.990	1	1.010	—	
	Kf3	RT0, RT0-1, RT1 = 200 k Ω	0.0573	0.0616	0.0659	—	

(Note) Kfx is the ratio of the oscillation frequency by a sensor resistor and the oscillation frequency by a reference resistor in the same condition.

$$Kfx = \frac{f_{OSCx}(\text{RT0-CS0 Oscillation})}{f_{OSCx}(\text{RS0-CS0 Oscillation})}, \frac{f_{OSCx}(\text{RT0-1-CS0 Oscillation})}{f_{OSCx}(\text{RS0-CS0 Oscillation})}, \frac{f_{OSCx}(\text{RT1-CS1 Oscillation})}{f_{OSCx}(\text{RS1-CS1 Oscillation})}$$

(x = 1, 2, 3)

Measuring circuit 5



(3) When Constant Voltage Circuit for LCD is Used

- Recommended Operating Conditions

($V_{DD} = 0\text{ V}$)

Parameter	Symbol	Condition	Range	Unit
Operating temperature	T_{Op}	—	-40 to +85	°C
Operating voltage	V_{SS}	—	-3.5 to -1.25	V
400 kHz OSC external resistance	R_{OS}	$V_{SS} = -1.7\text{ V to }-1.25\text{ V}$	250 to 500	kΩ
		$V_{SS} = -3.5\text{ V to }-2.0\text{ V}$	90 to 500	
Crystal oscillation frequency	f_{XT}	—	30 to 66	kHz

- DC Characteristics

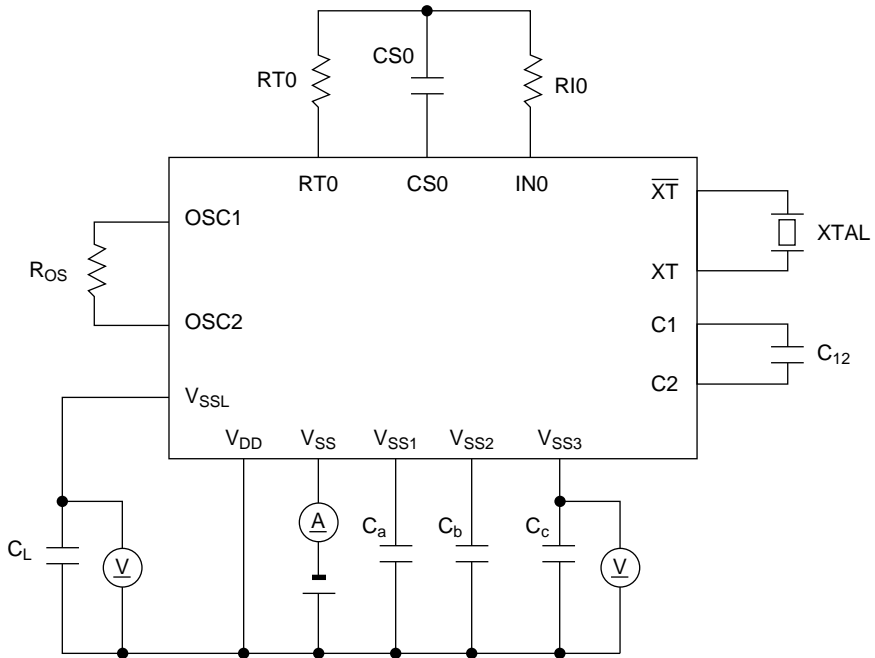
($V_{DD} = 0\text{ V}$, $V_{SS} = 3.0\text{ V}$, $T_a = -40\text{ to }+85^\circ\text{C}$ unless otherwise mentioned)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring circuit	
V_{SS1} voltage	V_{SS1}	$V_{SS} = -3.5\text{ to }-1.25$, $T_a = 25^\circ\text{C}$	-1.35	-1.2	-1.05	V	1	
	ΔV_{SS1}	—	—	-4	—	mV/°C		
V_{SS2} voltage	V_{SS2}	$V_{SS} = -3.5\text{ to }-1.25$	Typ.-0.1 V	$2 \times V_{SS1}$	Typ.+0.1 V	V		
V_{SS3} voltage	V_{SS3}	$V_{SS} = -3.5\text{ to }-1.25$	Typ.-0.2 V	$3 \times V_{SS1}$	Typ.+0.2 V	V		
Supply current 1	I_{DD1}	$V_{SS} = -1.5\text{ V}$ (CPU in halt state)	$T_a = -40\text{ to }+40^\circ\text{C}$	—	2.5	7.5		μA
			$T_a = +40\text{ to }+85^\circ\text{C}$	—	2.5	35		
		$V_{SS} = -3.0\text{ V}$ (CPU in halt state)	$T_a = -40\text{ to }+40^\circ\text{C}$	—	2.3	7.5		
			$T_a = +40\text{ to }+85^\circ\text{C}$	—	2.3	35		
Supply current 2	I_{DD2}	$V_{SS} = -1.5\text{ V}$ (CPU in operation state)	$T_a = -40\text{ to }+40^\circ\text{C}$	—	5	15		μA
			$T_a = +40\text{ to }+85^\circ\text{C}$	—	5	40		
		$V_{SS} = -3.0\text{ V}$ (CPU in operation state)	$T_a = -40\text{ to }+40^\circ\text{C}$	—	5	15		
			$T_a = +40\text{ to }+85^\circ\text{C}$	—	5	40		

Note:

- Other electrical characteristics are equal to those of 1.5 V spec and 3.0 V spec.

● Power Supply Voltage Connection Example



C_L	:	0.47 μF
C_a, C_b, C_c, C_{12}	:	0.1 μF
R_{OS}	:	100 $\text{k}\Omega$
XTAL	:	32.768 kHz
RT0	:	10 $\text{k}\Omega/2 \text{ k}\Omega$
CS0	:	820 pF
R10	:	10 $\text{k}\Omega$

Appendix H:

Instruction List

"B" indicates the byte length of an instruction.
"C" indicates the number of execution machine cycles of an instruction.

Mnemonic	Op-code	B	C	Operation
ADC		1	1	$A, C \leftarrow A + M(HL) + C$
ADC	@XY	2	2	$A, C \leftarrow A + M(XY) + C$
ADCB		1	2	$BA, C \leftarrow BA + M_b(HL) + C$
ADCB	@XY	2	3	$BA, C \leftarrow BA + M_b(XY) + C$
ADCS		1	1	$A, C \leftarrow A + M(HL) + C$, Skip if Carry = 1
ADCS	@XY	2	2	$A, C \leftarrow A + M(XY) + C$, Skip if Carry = 1
ADS		1	1	$A \leftarrow A + M(HL)$, Skip if Carry = 1
ADS	@XY	2	2	$A \leftarrow A + M(XY)$, Skip if Carry = 1
ADSB		1	2	$BA \leftarrow BA + M_b(HL)$, Skip if Carry = 1
ADSB	@XY	2	3	$BA \leftarrow BA + M_b(XY)$, Skip if Carry = 1
AIS	n4	1	1	$A \leftarrow A + n_4$, Skip if Carry = 1
AND		1	1	$A \leftarrow A \wedge M(HL)$
AND	@XY	2	2	$A \leftarrow A \wedge M(XY)$
ANDI	n4	2	2	$A \leftarrow A \wedge n_4$
CAB		1	1	Skip if A = B
CAI	n4	2	2	Skip if A = n4
CAL	a11	2	4	$ST \leftarrow PC + 2$, $PC_{10 \text{ to } 0} \leftarrow a_{11}$, $SP \leftarrow SP - 2$
CAM		1	1	Skip if A = M (HL)
CAM	@XY	2	2	Skip if A = M (XY)
CAMB		1	2	Skip if BA = M _b (HL)
CAMB	@XY	2	3	Skip if BA = M _b (XY)
CAMD	m8	2	2	Skip if A = M (m8)
CLI	n4	2	2	Skip if L = n4
CMA		2	2	$A \leftarrow \overline{A}$
CMI	n4	2	2	Skip if M (HL) = n4
CZP	a5	1	4	$ST \leftarrow PC + 1$, $PC_4 \text{ to } 0 \leftarrow a_5$, $PC_{10 \text{ to } 5} \leftarrow 0$ $SP \leftarrow SP - 2$ (a5 indicates the even number between 10H and 1EH.)

Mnemonic	Op-code	B	C	Operation
DCA		1	1	$A \leftarrow A - 1$, Skip if $A = 0FH$
DCH		1	1	$H \leftarrow H - 1$, Skip if $H = 0FH$
DCL		1	1	$L \leftarrow L - 1$, Skip if $L = 0FH$
DCM		1	1	$M(HL) \leftarrow M(HL) - 1$, Skip if $M(HL) = 0FH$
DCM	@XY	2	2	$M(XY) \leftarrow M(XY) - 1$, Skip if $M(XY) = 0FH$
DCMD	m8	2	2	$M(m8) \leftarrow M(m8) - 1$, Skip if $M(m8) = 0FH$
DCX		1	1	$X \leftarrow X - 1$, Skip if $X = 0FH$
DCY		1	1	$Y \leftarrow Y - 1$, Skip if $Y = 0FH$
EOR		1	1	$A \leftarrow A \vee M(HL)$
EOR	@XY	2	2	$A \leftarrow A \vee M(XY)$
EORI	n4	2	2	$A \leftarrow A \vee n4$
INA		1	1	$A \leftarrow A + 1$, Skip if $A = 0$
INH		1	1	$H \leftarrow H + 1$, Skip if $H = 0$
INL		1	1	$L \leftarrow L + 1$, Skip if $L = 0$
INM		1	1	$M(HL) \leftarrow M(HL) + 1$, Skip if $M(HL) = 0$
INM	@XY	2	2	$M(XY) \leftarrow M(XY) + 1$, Skip if $M(XY) = 0$
INMD	m8	2	2	$M(m8) \leftarrow M(m8) + 1$, Skip if $M(m8) = 0$
INX		1	1	$X \leftarrow X + 1$, Skip if $X = 0$
INY		1	1	$Y \leftarrow Y + 1$, Skip if $Y = 0$
JA		1	1	$PC5 \text{ to } 0 \leftarrow BA$ (bit 0 to bit 5)
JCP	a6	1	1	$PC5 \text{ to } 0 \leftarrow a6$
JM		1	3	$PC \leftarrow M_b(HL), BA$
JP	a11	2	2	$PC10 \text{ to } 0 \leftarrow a11$
LAB		2	2	$A \leftarrow B$
LAH		1	1	$A \leftarrow H$
LAI	n4	1	1	$A \leftarrow n4$ (Vertical Stack Instruction)
LAL		1	1	$A \leftarrow L$
LALB		2	2	$BA \leftarrow HL$
LAM		1	1	$A \leftarrow M(HL)$
LAM	@XY	2	2	$A \leftarrow M(XY)$

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Appendix H

Mnemonic	Op-code	B	C	Operation
LAMB		1	2	$BA \leftarrow M_b(HL)$
LAMB	@XY	2	3	$BA \leftarrow M_b(XY)$
LAMD	m8	2	2	$A \leftarrow M(m8)$
LAMDB	m8	2	2	$BA \leftarrow M_b(m8)$
LAMM	n2	1	1	$A \leftarrow M(HL), H \leftarrow H \vee n2$
LAM+		1	2	$A \leftarrow M(HL), L \leftarrow L + 1, \text{Skip if } L = 0$
LAM-		1	2	$A \leftarrow M(HL), L \leftarrow L - 1, \text{Skip if } L = 0FH$
LAX		1	1	$A \leftarrow X$
LAY		1	1	$A \leftarrow Y$
LAYB		2	2	$BA \leftarrow XY$
LBA		2	2	$B \leftarrow A$
LBAI	n8	2	2	$BA \leftarrow n8$
LBS0I	n3	2	2	$BSR0 \leftarrow n3$
LBS1I	n3	2	2	$BSR1 \leftarrow n3$
LCAL	a11	3	5	$ST \leftarrow PC + 3, PC \leftarrow a11, SP \leftarrow SP - 2$
LHA		1	1	$H \leftarrow A$
LHI	n4	2	2	$H \leftarrow n4$
LHLI	n8	2	2	$HL \leftarrow n8$
LJP	a11	3	5	$PC \leftarrow a11$
LLA		1	1	$L \leftarrow A$
LLAB		2	2	$HL \leftarrow BA$
LLI	n4	1	1	$L \leftarrow n4$ (Vertical Stack Instruction)
LMA		1	1	$M(HL) \leftarrow A$
LMA	@XY	2	2	$M(XY) \leftarrow A$
LMAB		1	2	$M_b(HL) \leftarrow BA$
LMAB	@XY	2	3	$M_b(XY) \leftarrow BA$
LMAD	m8	2	2	$M(m8) \leftarrow A$
LMADB	m8	2	2	$M_b(m8) \leftarrow BA$
LMA+		1	2	$M(HL) \leftarrow A, L \leftarrow L + 1, \text{Skip if } L = 0$
LMA-		1	2	$M(HL) \leftarrow A, L \leftarrow L - 1, \text{Skip if } L = 0FH$

Mnemonic	Op-code	B	C	Operation
LMBI	n8	2	2	$M_b(\text{HL}) \leftarrow n_8$
LMBI	@XY, n8	3	3	$M_b(\text{XY}) \leftarrow n_8$
LMI	n4	2	2	$M(\text{HL}) \leftarrow n_4$
LMTB	a3	2	3	$M_b(\text{HL}) \leftarrow T(a_3, \text{XY})$
LXA		1	1	$X \leftarrow A$
LXI	n4	2	2	$X \leftarrow n_4$
LXYI	n8	2	2	$\text{XY} \leftarrow n_8$
LYA		1	1	$Y \leftarrow A$
LYAB		2	2	$\text{XY} \leftarrow \text{BA}$
LYI	n4	2	2	$Y \leftarrow n_4$
NOP		1	1	No operation
OR		1	1	$A \leftarrow A \vee M(\text{HL})$
OR	@XY	2	2	$A \leftarrow A \vee M(\text{XY})$
ORI	n4	2	2	$A \leftarrow A \vee n_4$
POP	BA	1	2	$\text{SP} \leftarrow \text{SP} + 1, \text{BA} \leftarrow \text{ST}$
POP	HL	1	2	$\text{SP} \leftarrow \text{SP} + 1, \text{HL} \leftarrow \text{ST}$
POP	BSR	1	2	$\text{SP} \leftarrow \text{SP} + 1, \text{BSR} \leftarrow \text{ST}$
PUSH	BA	1	2	$\text{ST} \leftarrow \text{BA}, \text{SP} \leftarrow \text{SP} - 1$
PUSH	HL	1	2	$\text{ST} \leftarrow \text{HL}, \text{SP} \leftarrow \text{SP} - 1$
PUSH	BSR	1	2	$\text{ST} \leftarrow \text{BSR}, \text{SP} \leftarrow \text{SP} - 1$
RAL		1	1	$C \leftarrow A_3, A_3 \leftarrow A_2, A_2 \leftarrow A_1, A_1 \leftarrow A_0, A_0 \leftarrow C$
RAR		1	1	$C \leftarrow A_0, A_0 \leftarrow A_1, A_1 \leftarrow A_2, A_2 \leftarrow A_3, A_3 \leftarrow C$
RBC		1	1	$\text{BCF} \leftarrow 0$
RBE		1	1	$\text{BEF} \leftarrow 0$
RC		1	1	$C \leftarrow 0$
RMB	n2	1	1	$M(\text{HL})[n_2] \leftarrow 0$
RMB	@XY, n2	2	2	$M(\text{XY})[n_2] \leftarrow 0$
RMBD	m8, n2	2	2	$M(m_8)[n_2] \leftarrow 0$
RT		1	3	$\text{PC} \leftarrow \text{ST}, \text{SP} \leftarrow \text{SP} + 2$
RTI		1	5	$\text{PC} \cdot \text{C} \cdot \text{HL} \cdot \text{BA} \leftarrow \text{ST}, \text{SP} \leftarrow \text{SP} + 4, \text{MI} \leftarrow 1$
RTS		1	3	$\text{PC} \leftarrow \text{ST}, \text{SP} \leftarrow \text{SP} + 2, \text{Then skip}$

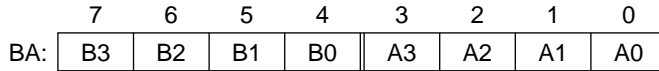
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Appendix H

Mnemonic	Op-code	B	C	Operation
SBC		1	1	$BCF \leftarrow 1$
SBE		1	1	$BEF \leftarrow 1$
SC		1	1	$C \leftarrow 1$
SMB	n2	1	1	$M(HL)[n2] \leftarrow 1$
SMB	@XY, n2	2	2	$M(XY)[n2] \leftarrow 1$
SMBD	m8, n2	2	2	$M(m8)[n2] \leftarrow 1$
SUBC		1	1	$A, C \leftarrow A - M(HL) - C$
SUBC	@XY	2	2	$A, C \leftarrow A - M(XY) - C$
SUBCB		1	2	$BA, C \leftarrow BA - M_b(HL) - C$
SUBCB	@XY	2	3	$BA, C \leftarrow BA - M_b(XY) - C$
SUBCS		1	1	$A, C \leftarrow A - M(HL) - C$, Skip if Borrow = 0
SUBCS	@XY	2	2	$A, C \leftarrow A - M(XY) - C$, Skip if Borrow = 0
SUBS		1	1	$A \leftarrow A - M(HL)$, Skip if Borrow = 1
SUBS	@XY	2	2	$A \leftarrow A - M(XY)$, Skip if Borrow = 1
SUBSB		1	2	$BA \leftarrow BA - M_b(HL)$, Skip if Borrow = 1
SUBSB	@XY	2	3	$BA \leftarrow BA - M_b(XY)$, Skip if Borrow = 1
TAB	n2	1	1	Skip if $A[n2] = 1$
TC		1	1	Skip if $C = 1$
TMB	n2	1	1	Skip if $M(HL)[n2] = 1$
TMB	@XY, n2	2	2	Skip if $M(XY)[n2] = 1$
TMBD	m8, n2	2	2	Skip if $M(m8)[n2] = 1$
XAB		1	2	$A \leftrightarrow B$
XAM		1	1	$A \leftrightarrow M(HL)$
XAM	@XY	2	2	$A \leftrightarrow M(XY)$
XAMB		1	2	$BA \leftrightarrow M_b(HL)$
XAMB	@XY	2	3	$BA \leftrightarrow M_b(XY)$
XAMD	m8	2	2	$A \leftrightarrow M(m8)$
XAMDB	m8	2	2	$BA \leftrightarrow M_b(m8)$
XAMM	n2	1	1	$A \leftrightarrow M(HL)$, $H \leftarrow H \vee n2$
XAM+		1	2	$A \leftrightarrow M(HL)$, $L \leftarrow L + 1$, Skip if $L = 0$
XAM-		1	2	$A \leftrightarrow M(HL)$, $L \leftarrow L - 1$, Skip if $L = 0FH$

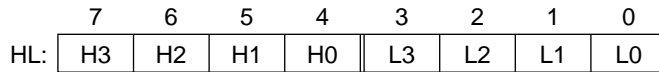
[Explanation of Symbols]

The meanings of the symbols used in the following sections are explained below.

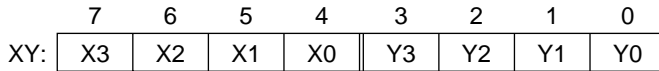
- A Accumulator
- C Carry flag
- B, H, L, X, Y Working registers
- BA Indicates 8-bit data of the content of B registers (B3 to B0), and accumulators (A3 to A0), with B register at the MSB side



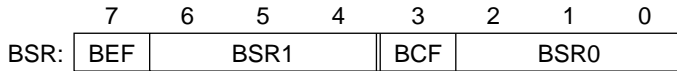
- HL Indicates 8-bit data of the content of H, L registers, with H register at the MSB side



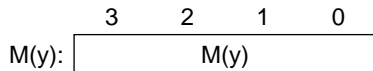
- XY Indicates 8-bit data of the content of X, Y registers, with X register at the MSB side



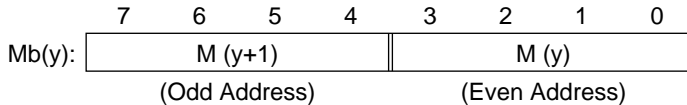
- BSR Indicates bank select registers (BSR1, BSR0), bank common flag (BCF) and bank enable flag (BEF)



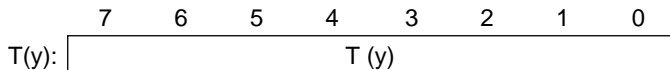
- M (y) Indicates 4-bit data memory content in address indicated by y



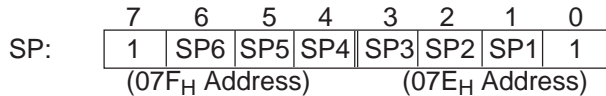
- Mb (y) Indicates 8-bit data memory content in address indicated by y. The data configuration is shown below. The LSB side is always an even address.



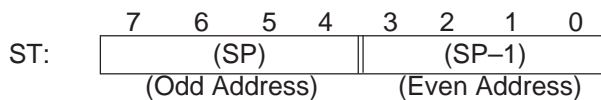
- T (y) Indicates 8-bit program memory (ROM) content in address indicated by y (for ROM table data).



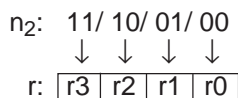
- PC Indicates contents of program counter (max. 11 bit). The PC value is the program memory address.
- SP Indicates contents of stack pointer (8-bit). SP value is the stack address in data memory. SP is allocated to 7FH, 7EH addresses of data memory bank0.



- ST Indicates contents of 8-bit stack. This is 8-bit data indicated by SP in data memory. The configuration is shown below.



- MI Indicates the master interrupt enable flag. MI is allocated to 7CH address, bit 0 of data memory bank0.
- @XY Indicates XY indirect addressing mode instruction. An indirect address mode instruction without this symbol is HL indirect addressing.
- n_x Indicates x-bit of immediate data.
- In Indicates n-bit of immediate data. (n = 0, 1, 2 •••)
- a_x Indicates immediate data to be loaded to PC as an x-bit program memory (ROM) address. x-bit is usually from bit 0, but in the table address it is from bit 8.
- m₈ Indicates immediate data to be the low order 8-bit address for direct addressing to data memory.
- r [n₂] Indicates value of bit shown as n₂ (see figure below) in content of r (data memory, working registers, accumulators, etc.).



- ∨ Indicates OR.
- ∧ Indicates AND.
- ⊕ Indicates exclusive-OR (EOR).
- X_H "H" indicates that "X" is a hexadecimal value.

- Skip if The next instruction is skipped if the condition is met, that is, the machine cycle time of the next instruction is spent and the next instruction is not executed.
- Carry Indicates the carry of an operation result.
- Borrow Indicates the borrow after an operation result.

